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Credits

1 Getting Started

This chapter describes the T-Spice documentation conventions and user interface, and provides a simple tutorial on basic T-Spice usage.

Documentation Conventions

This section contains information about the typographical and stylistic conventions used in this user guide.

Special Fonts

The following references in the text are represented by a bold font:

- Menu and simulation commands (For example: .print tran v(out).)
- Literal user input (For example: Enter 14.5.)
- Program output (For example: S-Edit generates names for the ports on the symbol based on the PAD string.)
- All dialog elements—fields, checkboxes, drop-down menus, titles, etc. (For example: Click Add.)

Freestanding quotations of input examples, file listings, and output messages are represented by a constant-width font—for example:

.ac DEC 5 1MEG 100MEG

Variables for which context-specific substitutions should be made are represented by bold italics—for example, *myfile.tdb*.

Sequential steps in a tutorial are set off with a checkbox $(\mathbf{\nabla})$ in the margin.

References to mouse buttons are given in all capitals—for example, MOVE/EDIT. When a key is to be pressed and held while a mouse button is used, the key and button are adjoined by a plus sign (+). For example, **Shift**+SELECT means that the **Shift** key is pressed and held while the SELECT mouse button is used.

The terms "left-click," "right-click," and "middle-click" all assume default mappings for mouse buttons.

Menu Commands and Dialog Titles

Elements in hierarchical menu paths are separated by a > sign. For example, File > Open means the Open command in the File menu.

Tabs in dialog boxes are set off from the command name or dialog box title by a dash. For example, **Setup > Layers—General** and **Setup Layers—General** both refer to the **General** tab of the **Setup Layers** dialog.

Special Keys

Special keys are represented by the following abbreviations:

Key	Abbreviation
Shift	Shift
Enter	Enter
Control	Ctrl
Alternate	Alt
Backspace	Back
Delete	Del
Escape	Esc
Insert	Ins
Tab	Tab
Home	Home
End	End
Page Up	PgUp
Page Down	PgDn
Function Keys	F1 F2 F3
Arrow Keys	\downarrow , \leftarrow , \rightarrow , \uparrow

When keys are to be pressed simultaneously, their abbreviations are adjoined by a plus sign (+). For example, Ctrl+R means that the Ctrl and R keys are pressed at the same time.

When keys are to be pressed in sequence, their abbreviations are separated by a space (). For example, Alt+E R means that the Alt and E keys are pressed at the same time and then released, immediately after which the R key is pressed.

Abbreviations for alternative key-presses are separated by a slash (/). For example, Shift+ \uparrow / \downarrow means that the Shift key can be pressed together with either the up (\uparrow) arrow key or the down (\downarrow) arrow key.

User Interface

The T-Spice user interface consists of the following elements:

- Title bar
- Menu bar

- Toolbars
- Status bar
- Simulation Manager
- Simulation Status window

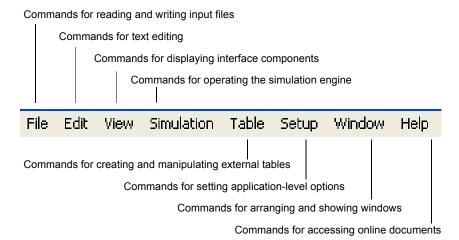
Commands on the View menu toggle display of the last four items.

Text windows in the display area display the contents of input and output files.

Title bar	Menu bai	- Too	lbar	Simulatio	n Statu
<u>E</u> ile <u>E</u> dit ⊻iew	imulation Status v Simulation Iable Options Window		II 63		
* Innoved * I	cir INVERT_OP a Wirelist Created with V d_subcir.cir ject NAND SUBCIR	Version 6.3.4			×
* * Inn * Ir M1 * Or M2 * Le C1 * V1	Ject NAMD_SOBLIK worden Wirzelist. Created at Simulation Status Input file: Inand_subcir.cir Progress: Simulation completed Time = \$00.000000ns 101	Output file: n	and_subcir.out		
VDD .SUF MT4 MT1 MT3 MT2	Total devices: 7 Passi Transient Analysis	ve devices: 0	Independent sources: Controlled sources:	3 0	-
					-
Status finished	Input file C\projects\tsppro\tutorial\nand_subci			mber 26,2001 15:40:59 (Elapsed Time 00:00:10
Feady Fext win	dows	Simulation	Manager	Status bar	

Menu Bar

The menu bar contains the names of the T-Spice command menus. The **Edit** and **Window** menus are only available when the active window contains a text file.

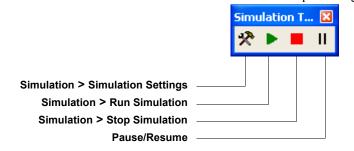


Toolbars

commands. Standard Toolbar X 🗅 🚅 🖬 🎒 🔃 🦓 👗 🗎 🛍 🗠 🗠 ₹ ۲ File > New -File > Open File > Save -File > Print File > Print Preview -Edit > Find -Edit > Cut -Edit > Copy -Edit > Paste -Edit > Undo -Edit > Redo -Edit > Insert Command _ Launch W-Edit -Help > T-Spice User Guide _

The Simulation toolbar contains buttons with icons representing simulation commands.

The Standard toolbar contains buttons with icons representing the most commonly used menu



Status Bar

When the pointer is positioned over a button in the toolbar, the left side of the status bar contains a short description of the button's function. When a text window in the display area is active, the status bar provides information useful for editing.

Application				
Cursor positio	on (line and column numbers)—			
Ready		Ln 5	, Col 8	CAP NUM SCRL OVR //
Cap lock -				
Num lock-				
Scroll lock-				
Editing mode (Insert or Overwrite)				

Display Area

The *display area* consists of the entire T-Spice window not occupied by the title, menu bar, toolbars, Simulation Manager, Simulation Status window, or status bar. In this area, input files are viewed and edited and simulation status information is displayed.

Simulation Manager

The Simulation Manager allows you to control and monitor all T-Spice simulations. Use **View > Simulation Manager** to display or hide the Simulation Manager. You can use the Simulation Manager to monitor multiple simulations at one time. Each simulation occupies one row, and each row has five attributes.

Status	Input file	Output file	Start Date/Time	Elapsed Time
failed	Y:\My Documents\\InverterDC.sp	InverterDC.out	March 12, 2008 16:29:44	00:00:02
failed	Y:\My Documents\\InverterOP.sp	InverterOP.out	March 12, 2008 16:30:12	00:00:03
failed	Y:\My Documents\\InverterOP.sp	InverterOP.out	March 12, 2008 16:30:27	00:00:02
finished	Y:\My Documents\\InverterTRAN.sp	InverterTRAN.out	March 12, 2008 16:30:47	00:00:02
running	Y:\My Documents\\RingOscillatorTRAN.sp	RingOscillatorTRAN.out	March 12, 2008 16:31:05	00:00:03

Simulation Status

The Simulation Status window displays output messages from the T-Spice simulation engine. When you select a simulation in the Simulation Manager, the Simulation Status window displays the results for that simulation.

M Simulatio	n Status					
	ingvco.cir Simulation complete	d	Output file:	ringvcotest		
Total nodes: Total devices	45 : 64	Active devices: Passive devices:	61 0	Independent sources: Controlled sources:	3 0	
Total		1	12.53 seco:	nds		^
Simula	tion comple	ted with 11	. Warnings			~
<		Ш				<u> </u>

Command Tool

T-Spice also provides a *Command Tool*, which presents a categorized listing of T-Spice simulation commands and options. You can use this tool as a guide in composing commands for the input file.

T-Spice Command Tool		<
Analysis Current source Files Initialization Output Settings Table Voltage source Optimization	Analysis AC Transient DC operating point Transfer function DC transfer sweep Parametric sweep	-
	Fourier	
	Noise	
	Insert Command Close	

Simulating a Design—a Simple Example

This section illustrates some basic principles of T-Spice operation using a simple example.

Creating a New Input File

Create a new input file by clicking the **New File** button (\square) or selecting **File > New**.

When you click the **New File** button, T-Spice opens a new text window with the default filename **T-Spice1**. T-Spice increments the default name for additional new files, assigning them **T-Spice2**, **T-Spice3**, etc.

When you select **File > New**, a dialog appears that prompts you to specify the type of file you wish to create:

New File	
File type: SPICE Netlist C Macro	ОК
Text	Cancel

The extension shown in parentheses will be the default file format.

- SPICE Netlist (.sp)
- C Macro (.c)
- Text (.**txt**)

Selecting **T-Spice** enables color-coding for T-Spice commands and comments. An empty active window appears in the display area; it is provisionally called **T-Spice1** (or **T-Spice2**, **T-Spice3**, etc.). Change the name to **test.sp** as follows:

- Use the File > Save command (or click in the toolbar).
- Type test.sp under File name in the Save As dialog.
- Press Return or click OK.

T-Spice will change the window title accordingly.

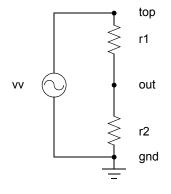
Entering the Circuit Description

Device Statements

Type the following text in the test.sp window, pressing Enter after each line:



The first line is a *comment*. (T-Spice always treats the first line of an input file as a comment, whether or not it begins with a comment symbol.) The next three lines, beginning with **vv**, **r1**, and **r2**, are *device statements* comprising a SPICE description of the elementary voltage divider schematically represented below.



For information on comments, see "Input Conventions" on page 52. For information on device statements, see "Device Statements" on page 152.

Simulation Commands

With the blinking cursor at the beginning of the next blank line in the **test.sp** window, use the **Edit > Insert Command** command (shortcut **Ctrl+M** or use the toolbar icon \blacksquare) to open the *Command Tool*.

The first category on the left is **Analysis**. Expand that category and select the **Transient** command. T-Spice displays the appropriate options in the right-hand pane of the Command Tool.

T-Spice Command Tool		×
Analysis Analysis AC DC operating point DC transfer sweep Transient Transfer function Parametric sweep Files Initialization Output Settings Table Voltage source Optimization	Simulation length: 500n se	
	Sweep Not used	
	Insert Command Canc	el

In the Command Tool:

- For Maximum Time Step enter 5n.
- For Simulation Length enter 500n (nanoseconds).
- Click Insert Command.

The full command is placed as a line of highlighted text into test.sp, and the Command Tool closes.

Click at the end of this line to deselect it, then press **Enter** to create another blank line. Open the Command Tool again, and select the **Output** category and the **Transient results** command.

T-Spice Command Tool		х
 Analysis Current source Files Initialization Output AC results AC small-signal model DC results DC results Power Transient results Noise results Measure Settings Table Voltage source Optimization 	Print transient analysis results Plot type: Voltage Node name: out Reference node (GND):	
	Insert Command Cancel	

In the Command Tool:

- For Plot type, select Voltage.
- For Node name enter top. Then click the Add button.
- Replace the name **top** with the name **out**, and click the **Add** button again.
- Click the Insert Command button.

test.sp now looks like this:

📸 test. sp	- 🗆 ×
* Test circuit	
vv top gnd SIN(0 1 10MEG)	
r1 top out 1	
r2 out gnd 2	
.tran/op 5n 500n method=bdf	
.print tran v(top) v(out)	
1	

The last two lines (beginning with **.tran** and **.print**) are the simulation command sequence, directing T-Spice to perform a transient analysis for 500 nanoseconds with a maximum time step of 5 nanoseconds, and to report the results of the transient analysis for the voltages at nodes **top** and **out**.

Alternatively, simulation commands can be incorporated directly into a circuit schematic. Then the commands will be present in the netlist when it is exported.

For information on the commands used in this example, see "Simulation Commands" on page 60.

Save **test.sp**. The circuit description is now complete and the simulation can be run.

Running the Simulation

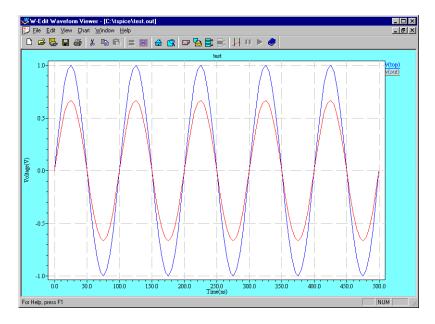
Use the Simulation > Run Simulation command (or click r in the toolbar) to initiate simulation.

The status of the simulation is shown in the Simulation Status window.

💥 Simulation Output				
Input file test.sp Progress: Simulation complete Time = 500.000000	ď	le: test.out		
Total nodes: 3 Total devices: 3	Active devices: 0 Passive devices: 2	Independent sources: Controlled sources:	1 0	
DC operating point Transient Analysis	0.33 seco: 0.27 seco:			A
Total	2.35 seco:	nds		

Text within the scrolling portion of the Simulation Status window can be copied for pasting into another input window.

At the same time, the output of the simulation is shown graphically in a separate W-Edit window. For information on W-Edit, see the *W-Edit User Guide*.



The voltage at node **out** is, correctly, two-thirds of the voltage at node **top**.

Simulation Queueing

You can submit multiple simulations... they will run in the order they were submittedr.

You can also run batch simulations from a DOS or Unix command-line using T-Spice's -batch option, which passes the simulation commands listed in a text batch file to the T-Spice engine. See "Command-Line Options" on page 27 for a description of command-line options.

Setup Options

The three tabs in **Setup > Application** control global options in T-Spice.

T-Spice Server

An internal http server in T-Spice allows other Tanner applications to launch it and run a simulation. This setup tab indicates the status of the server, the port on which it is active and whether to log simulation jobs sent to the server.

When a remote request is sent to launch T-Spice, it initiates a sequence of checks to determine whether T-Spice is installed on the local PC, whether the user has a current license and whether the version of the remote application is compatible with the version of T-Spice.

Setup Application	
Text Editor Text Style T-Spice Server	
Status Server running.	Start
Network protocol settings	Pause
Port #: 5885	Stop
Logging	
Log file:	
	OK Cancel

Status	Indicates the status of the internal T-Spice server. Use the Start , Pause and Stop buttons to control the simulation job.
Network protocol settings	Enter the port to use to search for the T-Spice executable.
Logging	When Enable logging is checked, you can enter a name in the Log file field and location (using the browse button) for a log file.

Text Editor

Determines T-Spice behavior in file saving operations. The most recently used settings are kept as defaults.

Setup Application
Text Editor Text Style T-Spice Server
Auto-Load
Modified text files Prior to running DRC, Extract, LVS, Simulation, or UPI and text files for these application have been modified:
C Save all changes
Prompt to save changes
C Don't save changes
OK Cancel

Auto-Load	When checked, T-Spice automatically loads changes whenever a ile is modified outside T-Spice. No warning will be provided.	text
Modified text files	Controls how files modified within T-Spice will be saved prior to imulation operations. Options are:	0
	Save all changes —automatically saves all active windows when one of the above operations is invoked.	
	Prompt to save changes —T-Spice will display a prompt w there are unsaved changes in the simulation input file. Selec Yes to save the input file and proceed with simulation. If yo select No , the Run Simulation command is ignored.	t
	Don't save changes—modified files will not be saved and	the

 Don't save changes—modified files will not be saved and the operation will use the stored version of those files.

When Auto-Load is disabled, T-Spice will open a checklist of all the files open in the text editor that have been modified elsewhere. You will have the option to reload modified files (checked) or not.

Files that have also been modified in the text editor will be highlighted. Similarly, when **Prompt to save changes** is selected, T-Spice will open a checklist of the modified files associated with the operation you are running. For example, you might open a text file in T-Spice, then later overwrite it by

reexporting a netlist. In such a case, T-Spice will display the following message to warn you that the file on disk has changed since you opened it in T-Spice:

]I:\T-Spice\10).04\examples\ga	asamp\gaasamp_tran	.cir	
olor indicates I	ument will not be ru he documents has hanges will be los	s been modified in tex	t Uncheck All	Check All

If you click **Yes**, T-Spice updates the file in memory.

Text Style

Use this tab to define the types of text (**keyword** groups) that will be highlighted when displayed in the T-Spice text editor, and their formatting. You can set text formats for SPICE netlists, C macro and text files.

Setup Application Text Editor Text Style T-Spice Server		
File Type: SPICE Netlist Font Face Name: Size: Courrier New 10 1	Paragraph Tab Size: 3	
Groups Normal text SPICE Keywords SPICE Options Keywords Preprocessor directives String Constants Numbers Comments	Keyword Group Add Edit Remove	
Colors Foreground: Background:		
	OK Cancel	

Each file type has a set of predefined keyword groups that cannot be edited or deleted. Use this tab to view those settings, and to add or remove your own keyword groups with customized characteristics.

File Type

A drop down list of the file types for which keywords are or can be defined.

Font	Allows you to set the typeface (Face Name) and point Size in which a given keyword group will appear.	
Paragraph	Allows you to set the increment, in spaces, of the Tab Size used by the text editor.	
Groups	Displays the keyword groups defined for the active file type. Use Add to enter the name of a new keyword group. Use Edit to enter the keywords belonging to a group. Use Remove to delete a keyword group.	
Keyword Group	• Use Add to enter the name of a new keyword group.	
	• Use Edit to enter the keywords belonging to a group.	
	• Use Remove to delete an entire keyword group.	
Colors	Use Foreground and Background to set the respective colors for a keyword group.	

Adding Keywords to a Group

Edit keyword groups opens the **Keywords** dialog, which allows you to enter keywords and to specify whether the case is evaluated (**Case sensitive keywords** checkbox enabled) when highlighting is applied.

Keywords Keywords for syntax highlighting List of comma separated keywords.	
.option, .precise, .mod	X
Case sensitive keywords Allow in keywords	
ак	Cancel

External Programs

This tab is used to configure external executables used by T-Spice. In particular, the diff program that can compare two (or three) text files is specified here.

Setup Application	\mathbf{X}
Text Editor Text Style T-Spice Server	External Programs
Diff Program:	

Command-Line Options

T-Spice supports command-line options that allow you to alter simulation commands or options without changing the input netlist. There are two ways to use command-line options in T-Spice:

- You can use any command-line option in conjunction with the tspcmd.exe executable to run simulations in a command-line environment, such as DOS or Unix.
- Most command-line options are also available within the T-Spice user interface; you can type them
 in the Simulation > Run Simulation dialog before you begin a simulation.

Command descriptions follow these conventions:

- Variables to be replaced by actual names, numbers, or expressions are indicated by *italics*.
- Square brackets [] enclose items that are *not required*. The brackets should *not* be typed on the command line.

Some command-line options allow you to specify an included or referenced file. Use the following rules to specify filenames in the command line:

- Specify filenames relative to the working directory, or using a fully qualified pathname. The working directory is the one that contains the main input file.
- Filenames containing spaces must be enclosed in single or double quotes.

T-Spice supports the following command-line options:

Option	When on	When off (default)
- batch <i>batchfile</i> (Not available in T-Spice GUI.)	Processes the simulations listed in the text file batchfile in series. See "Running T-Spice From the Command-Line" on page 29 for batchfile syntax. This option is only available with the tspcmd.exe executable.	
-c	Estimate MOSFET drain and source areas and perimeters from MOSFET lengths and widths. Equivalent to " .options " (page 109) moscap=1 .	Set drain and source areas (if not specified in MOSFET statements) to zero.
-C	Disable the connectivity check.	Enable the connectivity check.
-d [probefile]	Turns on probing and optionally specifies the binary output filename. This option is equivalent to adding the following commands to the input netlist: .probe .probe noise dn(*,tot) [.options probefilename=filename]	No probing commands are specified, unless explicitly stated in the input netlist.
	If a filename is specified, it will override the command .options probefilename in the netlist.	
-h headerfile	Specify a header file to be processed at the start of T-Spice simulation.	Parse only the contents of the current T-Spice input file.
-i "TSCommand"	Executes the T-Spice command enclosed in double quotes. Input commands added with -i are parsed after the header file, but before other input files.	
-1	Echoes all parsed input lines to the Simulation Status window or stderr output. This is equivalent to setting .options echo=1 .	Input lines are not shown in simulation output.
-m <i>modelfile</i>	Include model definitions from <i>mfile</i> . Equivalent to the .model <i>mfile</i> command.	Use model parameters specified in the input file, if available.
-n	Disables splash screen.	Splash screen appears on application startup.
-o outfile	Print results to ofile .	Print results to standard output (the screen or the Simulation Window).

Option	When on	When off (default)
-P parameter =value	Assign a <i>value</i> (a plain number or an expression enclosed by single quotes) to <i>parameter</i> . Parameter assignments made with this option override assignments made with the ". <i>param</i> " (page 116) command in the input file. This option can be used as many times as desired.	Use parameters specified in the input file, if any.
-q	"Quiet" mode: disable the simulation status display.	Enable the simulation status display.
-U	Print a usage message and quit.	_
-V	Print the version number and acknowledgments and quit.	_
netlistfile	Use netlistfile as the circuit description. Netlists generally have the extension .sp or .cir .	[The argument is required when running tspcmd.exe .]

Running T-Spice From the Command-Line

The **tspcmd.exe** executable file allows you to run the T-Spice engine, without a graphical interface, from a command-line environment such as DOS or Unix. To run T-Spice from a command-line, use the following syntax:

```
tspcmd [-aqlCUV] [-batch batchfile]
    [-d [probefile]] [-P parameter=value]
    [-m modelfile] [-o outfile] [-i "command"] netlistfile
```

The **-batch** option is available *only* in command-line environments; you cannot use this option in the T-Spice **Run Simulation** dialog.

Batch Simulations from the Command Line

The command-line option:

-batch batchfile

allows you to pass a list of simulations to T-Spice for serial execution. The **batchfile** specifies a text file that contains a list of simulations and accompanying command-line options. Each simulation and its associated options must be listed on a separate line, using the following syntax:

```
[-acqruCMTUV] [-d probefile]
[-P param=value][-m modelfile][-o outfile]
[-i "TScommand"] netlistfile
```

Simulation Algorithms

T-Spice is designed to solve a wide variety of circuit problems. Its flexibility is due to robust *algorithms* which can be optimized by means of user-adjustable *parameters*. This chapter contains an overview of T-Spice's algorithms and parameters.

In what follows, when reference is made to an "*option*" (such as the **numnd** option) it means that the corresponding quantity is controlled with the **.options** command. For information on the **.options** command, see "Simulation Commands" on page 60.

Kirchoff's Current Law

T-Spice uses Kirchoff's Current Law (KCL) to solve circuit problems. To T-Spice, a *circuit* is a set of *devices* attached to *nodes*. The circuit's state is represented by the voltages at all the nodes. T-Spice solves for a set of node voltages that satisfies KCL (implying that the sum of the currents flowing into each node is zero).

In order to evaluate whether a set of node voltages is a solution, T-Spice computes and sums all the currents flowing out of each device into the nodes connected to it (its *terminals*). The relationship between the voltages at a device's terminals and the currents through the terminals is determined by the *device model*. For example, the device model for a resistor of resistance R is $i = \Delta v / R$, where Δv represents the voltage difference across the device.

DC Analysis

Most T-Spice simulations start with a DC operating point calculation. A circuit's *DC operating point* is its steady state, which would in principle be reached after an infinite amount of time if all inputs were held constant. In DC analysis, capacitors are treated as open circuits and inductors as short circuits.

Because many devices, such as transistors, are described by nonlinear device models, the KCL equations that T-Spice solves in DC analysis are nonlinear and must therefore be solved by iteration. On each iteration, T-Spice tries to find a set of node voltages that satisfies KCL more closely than the previous set. When the KCL equations are satisfied "well enough" (the sums of currents into nodes are small enough), the process stops.

The **abstol** and **reltol** options determine how closely KCL must be satisfied. The **numnd** option imposes a limit on the number of iterations. If **numnd** iterations are reached without a solution being found, then nonconvergence is declared.

T-Spice sometimes uses a technique called *source stepping* to find a circuit's DC operating point. In source stepping, all voltage and current sources are ramped up from zero to their final values. This allows T-Spice to find the DC operating points of difficult-to-converge circuits. Source stepping is used only in non-converging cases of initial DC operating point calculations, and not during DC analysis sweeps. The smallest source step that T-Spice will take is controlled by the **minsrcstep** option.

g_{min} Stepping

Some non-convergence errors can be eliminated by ensuring a sufficient conductance across capacitors. The option **gmindc** specifies a conductance that is added in parallel with all *pn* junctions during DC analysis. T-Spice applies the **gmindc** conductance to various elements as follows:

- diode—conductance is added across the positive/negative terminals.
- BJT—conductance is added across the base/emitter and the base/collector terminals.
- MOSFET—conductance is added across the source/bulk, drain/bulk, and the source/drain terminals.
- MESFET—conductance is added across the source/gate, drain/gate, and source/drain terminals.

The default value for **gmindc** is 10^{-12} .

When a DC operating point non-convergence occurs, T-Spice can begin a g_{min} stepping algorithm to find the minimum conductance that yields a convergent solution. The g_{min} stepping algorithm is triggered when a non-convergence occurs and the value of option **gramp** is greater than zero. Together, the options **gmindc** and **gramp** specify a search range for the minimum required conductance, g_{min} :

$gmindc \le g_{min} \le gmindc \cdot 10^{gramp}$

T-Spice's g_{min} stepping algorithm searches the specified conductance range in two steps. First, T-Spice performs a binary search between **gmindc** and **gmindc** $\cdot 10^{\text{gramp}}$. T-Spice searches for the smallest value of g_{min} that results in a converged solution. T-Spice automatically ends the binary search when it reaches a Δg_{min} that is less than or equal to a factor of 10.

Starting with binary search results, T-Spice then begins reducing the value of g_{min} by a factor of 10 in each iteration. Once a non-convergence occurs, the previous convergent iteration provides the final solution.

Transient Analysis

In transient analysis, T-Spice solves for a circuit's behavior over some time interval. In this mode, T-Spice takes small time steps, solving for the circuit's state at each step. At each time step, two approximations are made.

First, a small error — the *discretization* error — is introduced because T-Spice cannot take infinitely small time steps. The **chargetol** and **relchargetol** options determine the acceptable limits of discretization error. In general, taking smaller time steps decreases the discretization error, so tightening the tolerances has the effect of higher accuracy at the expense of smaller time steps and therefore longer simulation times and larger output files. The discretization error is also affected by the order of the time integration method used, adjusted with the **maxord** option.

Second, just as in DC analysis, T-Spice solves the nonlinear KCL equations iteratively at each time step. The accuracy is affected by an iteration stopping criterion. The same tolerances as in DC analysis — **abstol** and **reltol** —affect this solution process. The iteration count limit for a transient analysis time step is **numnt**, which is typically much smaller than **numnd**; the previous time step always provides a good initial guess for a transient analysis Newton iteration, so that fewer iterations are typically required than for DC analysis, where a good initial guess is usually not available. Another iteration limit, **numntreduce**, affects time step selection after a successful time step. If T-Spice took less than **numntreduce** iterations to find the solution at a time step, the next time step is adjusted (often increased) according to the discretization error tolerances **chargetol** and **relchargetol**. But if the number of iterations required is between **numntreduce** and **numnt**, then the time step is always decreased on the next step (even if the step was successful).

As in DC analysis, some non-convergence errors can be avoided by adding a small conductance across capacitors. For transient analysis, the option **gmin** specifies a conductance that is added in parallel with all pn junctions. The default value of **gmin** is 10^{-12} .

Trapezoidal Integration Method

T-Spice's default method for transient analysis uses trapezoidal integration with the lvltim=1 delta-voltage time step control algorithm.

The trapezoidal formula calculates the average slope of the present and next time point to approximate the value of the integral of the differential equations used in the time range calculations, as follows in simplified form. The following approximation is used to discretize the differential equation:

$$V_{n+1} = V_n + \frac{h}{2} \left(\frac{dV_{n+1}}{dt} + \frac{dV_n}{dt} \right)$$
(2.1)

where

$$V_{n+1} = present unknown voltage value$$

$$V_n = previous time-point solution$$

$$h = time step length$$

$$n = time interval$$
(2.2)

Gear's BDF Method

T-Spice's alternate method for transient analysis uses Gear's backward differentiation formulas (BDF). In this method, the time derivative of charge in the KCL equations is replaced by an approximation involving the solution at the last few time points. The first-order BDF method uses only one previous time point, and it is equivalent to the well-known Backward Euler method. In this method, the discretization error is a linear function of the step size. The second order method uses two previous time points, and its discretization error is proportional (for small time step sizes) to the time step size squared. In general, the *k*th order BDF method uses *k* previous time points.

T-Spice uses a variable-step-size, variable-order, and variable-coefficient implementation of the BDF method. T-Spice automatically adjusts the time step size and BDF order (between 1 and 4) to minimize the number of time steps required to meet the given error tolerances. The maximum order used can be adjusted with the **maxord** option. The variable-coefficient implementation was chosen over the fixed-coefficient and fixed-leading-coefficient methods because it offers the best stability properties, especially with frequently varying time step sizes.

At each time step, the BDF discretization results in a nonlinear system of equations (representing KCL) which is solved iteratively as described above. If the iteration succeeds, the discretization error is examined (by comparison with an explicit predictor). For example, in the order 1 case, the difference between the Forward Euler predictor and the computed BDF (Backward Euler) solution provides a bound on the discretization error. If the error is within the prescribed tolerance (defined by **chargetol** and **relchargetol**), the step is accepted, and the error is used to adjust the step size for the next time step. If the error is too large, the time step is rejected and reattempted with a smaller step size. This will produce answers which approach a more stable numerical solution. Gear integration often produces superior results for power circuitry simulations, due to the fact that high frequency ringing and long simulation periods are often encountered.

Small-Signal Analysis

Some of T-Spice's analysis commands use *small-signal* models. Small-signal analysis linearizes the KCL equations about an operating point. Subsequent computations are performed on the linearized circuit, which can be solved in one matrix-vector operation. In AC analysis, for example, one matrix-vector solve is done at each frequency point to find the AC solution; no iteration is necessary. The linearized small-signal model is valid *only locally*, so if the operating point changes, then a new linearized model has to be computed.

Tolerances

T-Spice's simulation speed and accuracy are controlled by various tolerance values. Computer-based simulators like T-Spice solve circuit equations using finite precision arithmetic. This means that numerical approximations are made at several steps of the solution process. The errors introduced by these approximations in T-Spice are bounded by tolerance settings.

Each approximation is controlled by a relative tolerance *trel* and an absolute tolerance *tabs*. In most cases, the relative tolerance is used — the approximation error may not exceed *trel* × |v|, where v is the value of the quantity to be approximated. The absolute tolerance is used when the approximated quantity's value is close to zero; in that case, the error may not exceed *tabs*. In general, the error must be less than the maximum of *trel* × |v| and *tabs*.

abstol — reltol

Corresponding to each node in a circuit is an equation which expresses Kirchoff's Current Law (KCL), according to which the branch currents flowing into the node must be zero. The actual sum of these branch currents at a node is called the "residual current" for that node, and it is a function of all node voltages. In a sense, then, the value of this current at a given node is a measure of how well KCL holds at that node. T-Spice attempts to find a solution (a set of node voltages) that causes KCL to be satisfied at all nodes. The correctness of the solution is measured by the norm of the vector of residual currents at all nodes.

In general, the KCL equations are complicated and nonlinear, and T-Spice solves them by numerical iteration. Each iteration results in an improved approximation of the true solution of the KCL equation, in the sense that the norm of the residual currents decreases with each iteration. However, it is often impossible to make the residual current exactly zero, because of the finite precision arithmetic used. Even if infinite precision arithmetic were available, it might take infinitely many iterations to make the residual current zero. Therefore, the iteration is considered to have converged to a solution when the residual current is within the tolerances defined by **abstol** and **reltol**. Thus, **abstol** and **reltol** control how small the residual currents must be — how far from satisfying KCL the nodes can be — before the system is considered solved.

To be more precise, **reltol** and **abstol** are applied as relative and absolute tolerances, as described above, to the residual currents at each node. The tolerance used at a particular node is $max(abstol, reltol \times imax)$, where *imax* is the largest branch current (in absolute value) flowing into the node in question. The **abstol** and **reltol** tolerances are used whenever T-Spice solves the KCL equations for a DC solution or a transient analysis time step.

The default value for **reltol** is 1×10^{-4} , or 0.01%. The default value of **abstol** is 0.5 nanoamps. These values should be reduced for sensitive analog designs.

numnd — numnt — numntreduce

numnd defines the maximum number of iterations allowed during the solution of the KCL equations during a DC analysis. If, after **numnd** iterations, the **abstol/reltol** tolerances have not been satisfied, the iteration is considered to have failed and nonconvergence is declared. T-Spice then stops the iteration and reacts appropriately:

- On initial DC operating point calculations, source stepping is invoked.
- During DC transfer analysis, the transfer step size is reduced.

During source stepping, the maximum number of iterations for each source step is **numnd** /10. If **numnd** /10 iterations are exceeded during source stepping, the source step size is reduced. If the minimum source step size (**minsrcstep** option) is violated, then nonconvergence is declared for the DC operating point computation.

If the initial DC operating point computation fails at the beginning of a transient analysis, T-Spice attempts a powerup simulation. In a powerup simulation, all voltage and current sources are slowly ramped up from zero to their actual values. The default ramp period is 0.1% of the transient simulation final time, and it can be overridden using the **poweruplen** option.

numnt determines the maximum number of iterations allowed during the solution of the KCL equations for a transient analysis time step. Another option, **numntreduce**, is used in the time step size after a successful time step. Together, **numnt** and **numntreduce** work as follows. If a time step requires more than **numnt** iterations, the iteration is considered to have failed, and the same time step is reattempted with a smaller step size. If fewer than **numntreduce** iterations are needed for a time step, the next time step is adjusted (often increased) according to the discretization error tolerances (**chargetol** and **relchargetol**). If the number of iterations required is between **numntreduce** and **numnt**, the step size for the next time step is always reduced.

The number of iterations it takes to converge to a circuit solution depends heavily on the circuit to be simulated. Stable circuits with well-defined, steady-state conditions generally require fewer iterations, whereas circuits with poorly defined or unstable steady-state conditions require more iterations. Convergence is also sensitive to the starting point (initial guess) of the iteration. If the starting point is close enough to the operating point, then the iteration will eventually converge (although it might take many iterations in some cases). But if the starting point is not close to the solution, then the iteration may not converge at all. Different starting points (initial guesses) may be specified with the **.nodeset** command. For information on the **.nodeset** command, see "Simulation Commands" on page 60.

chargetol — relchargetol

Kirchoff's Law contains a term that represents the time derivative (rate of change) of charge. In transient simulations, T-Spice must replace this derivative by a divided difference approximation. The approximation becomes more accurate as the time step size decreases. T-Spice chooses its time step size so that the error caused by this approximation remains below another tolerance called the "charge tolerance." You can specify both an *absolute* and a *relative* charge tolerance with the **chargetol** and **relchargetol** options. By decreasing (or increasing) these tolerances, you can force T-Spice to take smaller (or larger) time steps if you believe that the results of transient simulation are not accurate enough (or too accurate for your time constraints).

The value of **relchargetol** is by default the same as **reltol**, so that **reltol** controls the overall relative simulation accuracy. For example, if you would like 0.001% accuracy, simply set **reltol** to 1×10^{-5} ; this also sets **relchargetol** to 1×10^{-5} . The **relchargetol** option should be used only to override the general relative tolerance **reltol**.

In general, the KCL tolerances **abstol** and **reltol**, as well as the charge tolerances **chargetol** and **relchargetol**, trade off speed for accuracy such that tightening these tolerances increases simulation accuracy at the expense of speed. However, if the KCL tolerances are too loose relative to the charge tolerances, the simulator may take small time steps because of numerical noise introduced by residual currents. These residual currents exist only because the KCL equations are not being solved exactly, but they may cause the charge tolerances to be violated, leading to excessively small time steps. If this happens, reducing **abstol** and/or **reltol** will result in larger time steps and faster (as well as more accurate) simulation.

Parametric Analysis

Under many circumstances, T-Spice will be required to study the effects on circuit performance of variations in parameter values. For example, parametric analysis can be used to evaluate multidimensional trends in the output over defined ranges of input values, or the sensitivity of circuit behavior to random fluctuations in fabrication conditions.

A large range of parameters may be systematically and automatically varied:

- External parameters (such as temperature)
- Simulation parameters (such as tolerances)
- Device parameters (such as input voltage level)
- Model parameters (such as transistor length)

Three types of parametric analysis are made possible by T-Spice: *parameter sweeping*, *Monte Carlo analysis*, and *optimization*. Discussions of T-Spice syntax and corresponding examples are included for all three analysis types in the chapter titled "Parametric Analysis" on page 495

In a *parameter sweep*, a specified parameter is held or initialized at a given value, on the basis of which all analyses requested by the input file are performed, and the results recorded. Then the parameter is incremented by a set amount, and the same analyses are repeated. This cycle is continued while the parameter is incremented through a defined range of values.

Parameter values may be swept *linearly* — in identical increments, typically through a limited range — or *logarithmically* — in exponential increments, typically through a range spanning multiple orders of magnitude.

An example illustrating T-Spice input for parameter sweeping is given in "Parameter Sweeps" on page 496.

Monte Carlo Analysis

Monte Carlo analysis generates "random" variations in parameter values by drawing them *probabalistically* from a defined distribution. For each value thus chosen, all analyses requested by the input file are performed, and the results recorded. Monte Carlo analysis is performed using the keyword **sweep**; syntax is described in "**.step**" (page 141).

Parameter values may be drawn from tunable uniform, Gaussian, or random limit distributions.

For a more detailed description of Monte Carlo analysis, see "Monte Carlo Analysis" on page 499.

If an aspect (or aspects) of the desired circuit performance can be specified quantitatively, T-Spice can search through a multidimensional "space" of parameters — that is, vary several parameters systematically and simultaneously — to determine the combination of parameter values that *optimizes* the specified performance measure (or set of measures).

Each run, using a particular combination of parameter values, produces a new value for each performance measure studied. Optimization is achieved by varying parameters in an attempt to minimize

$$\sum_{i} \left[w_i \frac{(G_i \angle R_i)}{G_i} \right]^2 \tag{2.3}$$

where G_i is the *goal* or desired value of the *i*th performance measure; R_i is the *result* or actual value of the *i*th performance measure, for a particular combination of parameters; and w_i is the *weight* or importance assigned to the *i*th performance measure relative to the other measures used. The quantity $w_i(G_i \angle R_i)/G_i$ is also called the *error*.

The choice of the *next* combination of parameters to test after each run, on the basis of the current total error, is the heart of the optimization algorithm. The algorithm employs *gradient descent*; that is, it attempts to find the steepest (fastest) "path" through the "space" of parameters that will lead to the minimum, by estimating the gradient in various directions.

For a description of T-Spice input needed to set up and invoke optimization, see "Optimization" on page 502. This section also includes a tutorial example illustrating optimization (see "Example 3: Optimization" on page 503).

Error Types and Correction

The highly compressed, text-based nature of the SPICE circuit description language, while rendering it efficient, portable, and flexible, also makes it prone to user errors of various kinds — errors that, while they will seldom crash the program, often result in wrong answers or problems with convergence.

T-Spice makes some corrections automatically, replacing improbable values with default ones or ignoring improper commands and specifications. In other cases, the Simulation Window shows the line number of the input file on which the error was found, or the name of the device whose specification T-Spice could not parse properly, and a brief description of the error. The most common errors can be divided into several categories.

Syntax Errors

- Unsupported commands or statements.
- Wrong spelling of commands, statements, or options.
- Failure to abide by conventions for names, comments, line continuation, numeric formats, unit abbreviations, or expressions.
- Wrong number or order of arguments on a simulation command or device statement.
- Numbers out of range.

Connectivity Errors

- Floating (unconnected) nodes.
- Nodes connected to only one device (except power supply and output nodes).
- Identical nodes referenced by different names.
- Different nodes referenced by identical names.
- Devices referred to that have not been previously defined.

Unless naming inconsistencies interfere with proper connectivity — producing floating nodes or devices with unconnected terminals — they will not be caught by T-Spice; it will simply assume that what is written is what is meant, and will produce misleading, implausible, or impossible results.

Convergence Errors

- Wrong metric prefix (order-of-magnitude error). For example, forgetting the p on a number intended to represent picofarads will not be caught by the syntax or connectivity checks but will probably lead to wildly wrong results.
- Ill-chosen tolerances.

To help prevent errors, use a *schematic export tool* to automate part of the process of writing a circuit description. These translate a *graphical* description of the circuit into a *textual* (SPICE-format) description. As long as the schematic has been drawn consistently (and this is easier to do graphically than textually), connections will be specified and nodes and devices named properly.

In addition, *use comments liberally*. Take advantage of the multiple ways by which comments can be indicated in a T-Spice input file to add structure and clarity to the circuit description. This will make later use of the file, whether for further study or for debugging, much simpler.

To deal with a *syntax error*, note the line number or device name in the input file at which T-Spice found the error, and check the syntax there.

To deal with a *connectivity error*, check the structure of the circuit, as described in the input file, carefully against the original schematic or plan. (This will be easier if T-Spice's own connectivity checker detected the error and provided the appropriate line number or device name.)

To deal with a *convergence error*, check the input file carefully, making sure that any metric prefixes used are plausible. Adjust the tolerances if necessary.

For information on comments, see "Input Conventions" on page 52. For information on syntax specifications, see "Simulation Commands" on page 60 and "Device Statements" on page 152.

Multi-Threaded Processing

T-Spice offers multi-threading options to provide accelerated performance on shared memory multiprocessor or multiple core computers.

Traditional SPICE simulation runtimes are dominated by two major computational areas: first, the transistor and device model evaluations, in which all terminal currents, charges, and derivatives are computed as a function of the device terminal voltages. Secondly, a sparse linear system is formed and

solved, in order to compute iterates to the Newton-Raphson solution of the overall nonlinear algebraic circuit equations.

The model evaluations and linear system solutions comprise well over 95% of the solution time for T-Spice. For medium size circuits, the model evaluation time will be greater than the linear system solution time, but with larger circuits the linear solution component will grow to dominate the overall solution time. The multi-threading feature of T-Spice provides for computational operations to be decomposed and solved in parallel during both stages of processing.

Model evaluation parallel processing is controlled via a single option, **.option threads**. T-Spice requires a circuit to have over 100 devices for multi-threading to be enabled. When the threads option is enabled, T-Spice will automatically decompose the workload into small tasks, and dynamically distribute these tasks to multiple threads for processing. The number of threads and size of the tasks are controlled via internal variables that you can set as shown in the following table. The linear system solution, or matrix factorization and solve, is performed using a multi-threaded sparse linear solver.

The threads option works as follows:

threads=0	Disable multi-threading.
threads=1	Enable threading, using a number of threads to match the number of processors available, i.e. on dual-core processors use 2 threads, on quad-core use 4 threads, etc.
threads=2	Enable threading with two threads.
threads= <i>x</i>	Enable threading with <i>x</i> number of threads, where <i>x</i> is a postive integer.

Threads=1 is the typical setting you should use to enable multi-threading. However, if you have a quadcore system and want to use the computer for additional work while the simulation is running, then it is advisable to use **threads=2**.

Running Simulations

Input Files

3

At the heart of T-Spice's operation is the *input file* (also known as the *circuit description*, the *netlist*, or the *input deck*). This is a plain text file that contains the *device statements* and *simulation commands*, drawn from the SPICE *circuit description language*, with which T-Spice constructs a model of the circuit to be simulated. Input files can be created and modified with any text editor, though the text editor integrated with T-Spice is ideal as it includes default and fully-customized syntax highlighting.

Input files can be very long and complex, but they do not have to be written from scratch; they can be efficiently created using the export facility of a schematic editor (Tanner's S-EditTM), or the extraction facility of a layout editor (Tanner's L-EditTM). In addition, T-Spice includes a "**Command Tool**" (page 17) that automates error-free SPICE language entry.

Any number of text files can be open at once, each in its own window in the display area. However, only one window can be "active" at any given time, and only an input file displayed in an *active* window can be edited and simulated.

File Synchronization

T-Spice has file synchronization features that allow you to control how files are saved and updated.

For input files, you can set an application-level default (auto-load) so that text files open within T-Spice are automatically reloaded if they are modified outside of T-Spice. You can also set a default for text files that have been modified inside T-Spice so that prior to being used they are automatically saved (or not, or with a prompt). Similarly, you can set a global default for output files so that they will always be overwritten without a prompt (see "Setup Options" on page 23).

If the file synchronization feature poses an inconvenience due to a network configuration or other issues, you can disable it by starting T-Spice with the **-y** command-line flag (see "Command-Line Options" on page 27).

<\$singlepage>backslash:literal;

Path Name

Opening SPICE Files

You can use **File > New** or **File > Open** to launch the text editor window in T-Spice. There is also a special command **File > Open Folder Containing {***filename***}**, that opens a browser window directly to the folder containing the result files for the active SPICE file as well as the folder path.

File Edit View Favorites T	Tools Help				
G Back - 🕤 - 🎓	🔎 Search 💫 Folders 🔢				
Address 🛅 Y:\My Documents\doc\"	TannerToolsShippingFiles\T-Spice\S	inulationResults			🔽 🔁 Go
Folders	K Name 🔺	Date Modified	Size	Туре	
🗉 🧰 Libraries	🚬 🖬 DLatchTRAN. dat	9/17/2007 11:51 AM	1,353 KB	DAT File	
🗉 🧰 S-Edit	DLatchTRAN.out	9/17/2007 11:51 AM	224 KB	OUT File	
T-Spice	DLatchTRAN.sp	9/17/2007 11:51 AM	4 KB	SPICE Netlist	
E C ADC8	InverterDC.dat	7/17/2007 11:40 AM	56 KB	DAT File	
🗉 🧰 AnalysisExarr	InverterDC.log	3/14/2008 2:03 PM	1 KB	Text Document	
🗉 🧰 CVS	InverterDC.out	3/14/2008 2:03 PM	1 KB	OUT File	
🗄 🧰 GaAsAmp	MInverterDC.sp	7/17/2007 11:40 AM	3 KB	SPICE Netlist	
C SimulationRes	InverterOP.log	3/14/2008 2:58 PM	1 KB	Text Document	
🗉 🚞 220A	InverterOP.out	3/14/2008 2:58 PM	1 KB	OUT File	
E C emergency response	M InverterOP.sp	3/14/2008 2:02 PM	2 KB	SPICE Netlist	
everything else	InverterTRAN.dat	7/17/2007 11:47 AM	81 KB	DAT File	
E 🚵 (bergstr's Music	InverterTRAN.log	3/14/2008 1:37 PM	1 KB	Text Document	
E 📇 ibergstr's Pictures	InverterTRAN.sp	7/17/2007 11:47 AM	3 KB	SPICE Netlist	
My eBooks	G OpAmpAC.dat	9/28/2007 3:13 PM	71 KB	DAT File	
My Google Gadgets	DpAmpAC.out	9/28/2007 3:13 PM	32 KB	OUT File	
E C My Cooge Couges	OpAmpAC.sp	9/28/2007 3:13 PM	4 KB	SPICE Netlist	
Tanner EDA	DpAmpAC.bar	9/28/2007 3:13 PM	1 KB	TXR File	
E C TannerToolsShippingFiles	OpAmpAC.wdb	8/15/2007 2:53 PM	10 KB	W-Edit Document	
Updater5	PreviewMode.log	3/14/2008 2:00 PM	3 KB	Text Document	
III Co Weekly Reports	PreviewMode.out	3/14/2008 2:00 PM	79 KB	OUT File	
DVD Drive (Z:)	PreviewMode.sp	9/20/2007 2:46 PM	3 KB	SPICE Netlist	
Control Panel	E RingOscillatorTRAN.log	3/12/2008 4:31 PM	4 KB	Text Document	
Iv Network Places	RingOscillatorTRAN.out	3/12/2008 4:31 PM	437 KB	OUT File	
tecycle Bin	RingOscillatorTRAN.sp	9/18/2007 12:29 PM	4 KB	SPICE Netlist	
ocyclo biri	Subcircuit TRAN.dat	9/21/2007 12:49 PM	131 KB	DAT File	

Editing Text Files

When the pointer is in an active text window, it becomes an I-beam. The position in the input file at which text is to be added is marked by a *blinking cursor*, and the status bar displays the cursor position, editing mode, and other information as described in "Status Bar" on page 16. You can toggle between the two editing modes by pressing the **Ins** key. In Insert mode, text is added *between* the characters separated by the blinking cursor. In Overwrite mode, text is added *in place* of the character to the right of the blinking cursor.

The cursor can be moved by clicking the pointer at the desired location. Sections of text can be selected by clicking and dragging the pointer. Double-clicking selects a word.

Alternatively, all these functions are accessible from the keyboard, as follows.

Keys	Functions
$\uparrow \downarrow \leftarrow \rightarrow$	Move the cursor in the indicated direction
Home / End	Move the cursor to the beginning or end of the line
PgUp / PgDn	Move the cursor up or down one page (scrolling the window with it)
$Shift + \uparrow \downarrow \leftarrow \rightarrow$	Extend the selection in the indicated direction
Shift + Home / End	Extend the selection to the beginning or end of the line
Shift + PgUp / PgDn	Extend the selection up or down one page
Shift + Ctrl + Home / End	Extend the selection to the beginning or end of the file

Text selections can be manipulated with the **Cut**, **Copy**, **Paste**, and **Clear** commands in the **Edit** menu (or, in the case of the first three, by clicking *****, **•**, and **•**, and **•**, in the toolbar). The **Cut** and **Copy** commands put deleted or duplicated text onto the clipboard, and from there the text can be placed elsewhere with the **Paste** command. The **Clear** command simply deletes text without adding it to the Clipboard.

Comment Delimiters

T-Spice allows several different characters to be used as comment delimiters, including the asterisk (*), dollar sign (\$), semicolon (;), and C-language style slash (I* or *I). However, the T-Spice text editor will only color-code comment text when:

- An asterisk (*) used as delimiter is placed in the first column of the text editor
- A dollar sign (\$) is used as delimiter in any column of the text editor

C-style comments delimited by */ or /* and midline comments delimited by an asterisk will not be colorcoded. The T-Spice simulation engine will correctly interpret them as comments, however.

Undo and Redo

The Edit > Undo command (Ctrl+Z or ____) reverses changes made to the text of the input file.

Undo reverses the most recent of the editing operations stored in the undo buffer. The previous 100 editing operations are stored in the undo buffer; they are of the following types:

- Typing, including delete and backspace keystrokes.
- Edits made with the **Cut**, **Copy**, **Paste**, or **Clear** commands.
- Edits made with Insert Command (see "Simulation Commands" on page 19).

Undo is unavailable under the following circumstances:

- Immediately after T-Spice is launched.
- Immediately after an input file is created or opened.

The **Edit > Redo** command (**Ctrl+Y** or \frown) restores changes reversed with a previous **Undo** command. Each of the events stored in the undo buffer can be redone one at a time in reverse order.

Search and Replace

The T-Spice text editor supports string and regular expression search and replace operations.

Edit > Goto Line

Prompts for a line number, then places the cursor at the beginning of the corresponding line in the active window.

oTo
ancel

Edit > Find

The **Edit > Find** (**Ctrl+F**) command opens the **Find** dialog which prompts for text to be searched for (the *target string*)

Find			
Find what:	capacitorarray_c	ode 💌	Find Next
 Match wh ✓ Match cas ✓ Regular E 	-	Direction	Cancel

Find what	String to be searched for in the text file. Use the \blacktriangleright button to insert the special character codes used to search for a manual line break, tab break, white space, or the carat (^) character.
Match whole word only	T-Spice searches only for whole words that match the specified search string.
Match case	Causes T-Spice to find only strings whose case matches that of the search string.
Regular expression	Activates Unix-style regular expression searching in the target string. The Match whole word only option is not available in Regular expression mode. See "Regular Expression Rules," below for further information.
(Special)	Opens a submenu of special character codes that can be inserted in the target string. These codes are prefixed by the caret character (^) unless they are UNIX-style regular expressions. Options include:
	Manual Line Break
	 Tab Break
	White Space
	Caret Character
Direction	• Up —searches backward in the active window.
	• Down —searches forward in the active window.
Find Next	Finds the next occurrence of the target string in the active window and closes the dialog.
Replace	Opens the "Edit > Replace " (page 44) dialog.

Regular Expression Rules

The **Regular expression** option in the **Find Item** or **Replace** dialogs causes T-Spice to interpret the search string as a Unix-style regular expression. Instead of interpreting the caret combinations t , l , and w as special sequences, T-Spice replaces them with Unix-style combinations that use the backslash ($^$) escape character.

The following table lists the rules T-Spice will follow when searching in regular expression mode:

Syntax	Description	Example
\n	Line break.	
\t	Tab character.	
^	Beginning of line.	
\$	End of line.	
	Any character except line break.	p.n matches pin and pan .
[]	One of the characters enclosed in the brackets.	p[ai]n matches pin and pan but not pun .
[^set]	Any character not enclosed in square brackets.	p[^i]n matches pan but not pin.
[sef]	A set of characters including any character from the set enclosed in square brackets.	[0-9] matches any digit. [spice] matches any of the characters (s p i c e) .
[sef]*	Zero or more occurrences of the set enclosed in square brackets.	[0-9]*1 matches 1 and 11 and 381.
[sef]+	One or more occurrences of the set enclosed in square brackets.	[0-9]+ matches 2 and 4532 .
-	Optional match.	12- matches 1 and 12 .
N(Begin tag.	A\([0-9]+\) matches A123 and substitutes 123 for the first tag (\1) in the replacement string.
)	End tag.	
\n	Text matching the <i>n</i> th parenthesized component of the regular expression, where <i>n</i> is a single digit.	If the search string is \(ab\)\(cd\) and the replacement string is \2\1 , T-Spice will replace abcd with cdab .
&	The entire matched regular expression.	If the search string is Windows and the replacement string is MS-& , T-Spice will replace Windows with MS-Windows .
\0	The entire matched regular expression.	
N	Literal backslash	a\\n matches a\n.
\&	Literal ampersand, to avoid expression substitution	If the search string is 123 and the replacement string is &\&& , T-Spice will replace 123 with 123&123 .

Edit > Replace

Prompts for text to be searched for (the *target string*) and replaced (the *replace string*) in the active window. The **Replace** dialog provides one input field and two options additional to the fields in the **Find** dialog (see "Edit > Find" (page 42)):

Replace			
Find what: 13u		• •	<u>F</u> ind Next
Replace with: HOPSCOTC	Н	•	<u>R</u> eplace
Match whole word only	Replace in		Replace <u>A</u> ll
☐ Match <u>c</u> ase	C Selection		Cancel
🔲 Regular Expression	O Wh <u>o</u> le file		

Replace with	The replace string, which can include <i>character codes from the</i> • <i>submenu</i> .
Replace	Replaces the next instance of the search string with the replace string.
Replace All	Replaces every instance of the search string with the replace string.
Replace in	• Selection replaces only the instances of the search string in the text that is selected.
	• Whole file replaces all instances of the search string in the file.

Command Tool

The **Command Tool** automates the insertion of T-Spice commands and device statements, in correct SPICE format, into the active window. You also can use it to specify filenames and command-line options before launching a T-Spice simulation.

T-Spice Command Too	ol –	
Analysis Current source Bit Bus Constant Current-controlled Exponential FM Piecewise linear Pulse		Constant Source Name Current source name: Positive terminal: Negative terminal (GND):
- Files		DC value: A
Include file Library file Table file		AC values Magnitude (0): A
Delete library file DC guess Initial condition Output Settings	~	Phase (0): deg
		Insert Command Close

Edit > Insert Command

This command opens the **T-Spice Command Tool**, which lists the T-Spice simulation commands in a hierarchical arrangement, with general categories that expand into individual commands for each category.

You expand or collapse a category by double-clicking it or clicking the plus or minus sign next to the category. When you click on a category name in the left-hand tree, fields representing individual commands open in the right-hand pane of the dialog.

Commands are inserted to the right of the cursor position or replacing highlighted text (above the current line if nothing is selected and below the current line if something is selected.)

Setting Simulation Options

Simulation > Simulation Settings

Also accessible from the toolbar button (3), the **Simulation Settings** command allows the user to specify options that will be used for all subsequent simulations. A multi-tab dialog is used to configure these options:

Options

Simulation Settings
Options Output W-Edit
Simulation
Command line arguments: (e.g.: -M -c -PX=3)
Include path: C:\demo\pcells;C:\Documents and Settings\mass\My Documents
Additional SPICE commands:
.include "C:/Documents and Settings/mass/My Documents/include.sp"
Verlog-A Include path:
OK Cancel

Command line arguments	Use this field to enter command-line options, which modify a simulation without altering the input file. You can enter as many options as desired, separating each with a space. Refer to "Command-Line Options" on page 27 for a description of available options and their proper syntax.
Include path	A semicolon-separated list of folders, used to search for include files, model files, and subcircuit definitions.
Additional SPICE commands	Commands that are prepended to the user's spice deck. These are often useful for setting simulator options, and/or including specific header files.
Verilog-A Include path	A semicolon-separated list of folders, used to search for Verilog-A model source code.

Output

Simulation Settings	×
Options Output W-Edit	
Output folder:	
✓ Automatically create a subfolder in the output folder, each time a simulation is run.	
Always overwrite T-Spice output files without prompting.	

Output folder

The output file(s) are created in the specified directory. This directory can be an absolute path, or a path relative to the input file

Automatically create a subfolder	If this option is selected, each simulation run creates a new subfolder in the output folder; output files for that simulation run are placed in this subfolder. The subfolder name is based on the input file name, and includes additional timestamp information.	
	This option allows the user to preserve all results from every simulation. A copy of the input file is also kept in this subfolder	
Always overwrite T-Spice output files without prompting	This option is available if the "create subfolder" option is not enabled. If this option is selected, preexisting output files will be overwritten without asking for confirmation from the user.	

W-Edit

Options Output W-Edit	
W-Edit waveform display	
Show during simulation	
C Show after simulation completes	
C Do not show	

W-Edit waveform display

Options for displaying simulation progress in W-Edit. Check an option to make it active.

- Show during simulation—displays traces in W-Edit while the simulation is running.
- Show after simulation completes—displays traces in W-Edit once the simulation is complete.
- Do not show—does not open W-Edit.

Launching a Simulation

Simulation > Run Simulation

The **Simulation > Run Simulation** command (shortcut F5 or toolbar button), launches a T-Spice simulation on the currently active document. If a simulation is already in progress, the new simulation is added to the queue of jobs awaiting simulation. This queue is displayed in the **Simulation Manager** window.

Simulation Manager

The Simulation Manager allows you to control and monitor all T-Spice simulations. It queues files for simulation, displays their processing status, and allows you to stop or pause a simulation. You can also highlight one or more files in this window to view simulation results in the **Simulation Status** window or the W-Edit waveform viewer.

You can right-click ion any simulation entry to access the pop-up menu with shortcuts to the controls described above, as well as additional menu items that open a new file (**New**), specify whether the Simulation Manager will be visible (**Hide**) and whether it will be docked (**Docking view**).

There is only one **Simulation Status** window, and all simulations display their output in this window. When you select a simulation in the Simulation Manager, the Simulation Status window displays the results for that simulation.

View > Simulation Manager

Use **View > Simulation Manager** to display or hide the Simulation Manager. This window can be displayed using a docked or undocked view (see "Docking and Undocking the Simulation Manager" on page 48.) Each simulation occupies one row, and each row has fiveattributes.

Status	Input file	Output file	Start Date/Time	Elapsed Time	
failed	Y:\My Documents\\InverterDC.sp	InverterDC.out	March 12, 2008 16:29:44	00:00:02	
failed	Y:\My Documents\\InverterOP.sp	InverterOP.out	March 12, 2008 16:30:12	00:00:03	
failed	Y:\My Documents\\InverterOP.sp	InverterOP.out	March 12, 2008 16:30:27	00:00:02	
finished	Y:\My Documents\\InverterTRAN.sp	InverterTRAN.out	March 12, 2008 16:30:47	00:00:02	
running	Y:\My Documents\\RingOscillatorTRAN.sp	RingOscillatorTRAN.out	March 12, 2008 16:31:05	00:00:03	

Status

Input file

Outp

Simulation status. Possible states include:

- **Queued**—the simulation is in the queue and will run when the simulation engine is available.
- **Running**—the simulation is underway.
- Paused—simulation has been suspended by the user.
- **Finished**—the simulation ran and output is available.
- Stopped—the simulation was stopped by the user.
- **Failed**—the simulation failed to run.

Full pathname	of the inpu	t file
· · · · · ·	· · · ·	

out file	Full pathnam	ne of the o	output fil
utille	run patnnan	ie or the c	Juipul II

- Start Date/Time The date and time at which the simulation began execution.
- **Elapsed Time** The total simulation run time in **hh:mm:ss** format. Pausing a simulation will not interrupt the measurement of elapsed time.

Docking and Undocking the Simulation Manager

The Simulation Manager can also be docked or undocked by right-clicking in any field and checking or unchecking **Docking view** in the pop-up menu. When it is docked, you can double-click on any edge of the dialog box or click-and-drag one of the sides to undock it.

Simulation Manager Commands

When the Simulation Manager is undocked, the following commands are available to control queued simulations.

5imulation №	1anager		×
Status	Input file	Output file	Run Simulation
failed finished	Y:\My Documents\\InverterTRAN.sp Y:\My Documents\\PreviewMode.sp	InverterTRAN.out PreviewMode.out	
failed	Y:\My Documents\\InverterOP.sp	InverterOP.out	
			Stop
			Pause
			Delete
<		>	Empty List
	Show <u>W</u> aveform	ist Show <u>O</u> utput	

Run Simulation	Invokes "Edit > Replace " (page 44). If a file is highlighted, the appropriate file and path names will automatically populate the Input file and Output file fields.
Stop	Stops simulation processing for the highlighted file. Once a simulation is stopped, it cannot be resumed.
Pause/Resume	Pauses simulation when the status of the highlighted file is Running , and resumes simulation when the status of the highlighted file is Paused .
Delete	Removes the highlighted file from the simulation queue. If the simulation is running or paused, you will be prompted to stop processing on the file before it is deleted.
Empty List	Removes all files from the simulation queue. If any simulations are running or paused, you will be prompted to stop processing before they are deleted.
Show Waveform	Invokes the W-Edit waveform viewer for the selected simulation. If the active window is a file that has been previously simulated and the file is still in the Simulation Manager queue, the corresponding .out file will be displayed when W-Edit opens.
Show Netlist	Opens a window with the selected input file. If the selected file is already open, makes that window active.
Show Output	Opens a window with the output file (.out) corresponding to the selected simulation. If already open, makes that window active.

Simulation Manager Context Menu

Right-clicking in any field of the Simulation Manager (either docked or undocked) opens a pop-up menu with the following options:

New...

Setup Simulation	Brings up the Setup Simulation dialog. Options selected here will apply to subsequent simulation jobs.
Delete	Removes the line from the Simulation Manager. No files are deleted.
Empty List	Removes all lines from the Simulation Manager
Show Waveform	Show the output data file in W-Edit
Show Netlist	Open the input netlist file
Show Output	Open the output data file in a T-Spice text editor
Diff Copied Inputs	You can compare two input files by selecting both rows in the Simulation Manager, then right-clicking on Diff Copied Inputs . This option is only available if the files are located in different directories. In the case where simulation output subfolders are automatically created, the diff runs on the copied input files that are created in each folder. For this option to work, either two or three lines must be selected in the Simulation Manager and a Difference must have been
	the Simulation Manager, and a Diff program must have been specified in the Setup Application External Programs dialog.
Diff Output	Textually compare the output files of two simulations.
	For this option to work, either two or three lines must be selected in the Simulation Manager, and a Diff program must have been specified in the Setup Application External Programs dialog.
Hide	Show the Simulation Manager
Docking view	If selected, the Simulation Manager is docked at the bottom of the T-Spice window frame

Simulation Status

The **Simulation Status** window shows simulation statistics and progress information, as well as any warnings or error messages, for the currently running or most recently completed simulation

View > Simulation Status

Use View > Simulation Status to toggle visibility of the Simulation Status window.

M Simulation S	Status	×
	vco.cir Output file: ringvcotest	•
Total nodes: Total devices:	45 Active devices: 61 Independent sources: 3 64 Passive devices: 0 Controlled sources: 0	
Total	12.53 seconds	^
Simulati	ion completed with 11 Warnings	~
<		

Input file	Name of the input file.
Output file	Name of the output file.
Progress	The type of simulation, duration in nanoseconds, and percentage of the simulation completed.
Total nodes	Total number of nodes simulated.
Total devices	Total number of devices simulated.
Active devices	Total number of active devices simulated.
Passive devices	Total number of passive devices simulated.
Independent sources	Total number of independent sources simulated.
Controlled sources	Total number of controlled sources simulated.

When a simulation is run, the input file is interpreted by the T-Spice parser. For T-Spice to function efficiently and as compatibly as possible with other versions of SPICE, the parser must enforce a number of language conventions. This chapter summarizes those conventions. (For more information, see "Simulation Commands" on page 60 and "Device Statements" on page 152.)

Names

All nodes and devices in the circuit must be identified uniquely by their *names*. Node and device names have the following features.

- Their length is unlimited (except by hardware constraints).
- They can include all characters except tabs, spaces, semicolons (;), single quotes ('), curly braces ({), parentheses and equal signs (=).
- The dollar sign (\$) can appear in names, but it cannot be the first character of the name or be a name by itself.
- They are case insensitive.

Model names cannot start with digits.

The following examples are all valid names:

in Alpha16 ONE[21]3 72

Reserved Names

T-Spice uses *reserved* node names for the default system ground: **gnd**, **GND**, **Gnd**, and **0** (zero). All instances of these nodes are connected and treated as the same node, which is fixed at a potential of 0.0 volts.

The following *keywords* (in any combination of uppercase and lowercase letters) cannot be used as names:

ac	bit	biti	bus
busi	dc	exp	inoise
off	onoise	params	pie
piei	pwl	pwlfile	poly
pulse	r	repeat	round
rounding	sffm	sin	sini
transfer			

Device Names

Most device statements are of the form

Zxxx ...

where the variable **Z** represents the required key letter which uniquely specifies the device type, and the variable **xxx** represents a user-supplied alphanumeric string.

For example, MOSFET statements have a form following this example:

mtran1 d g s b nmos l=2um w=2um

In this example, **m** is the required key letter and **tran1** is the user-supplied string. The device's name is **mtran1** (not **tran1**).

A particular device may be indicated in the input file by *either* case, for example, \mathbf{m} or \mathbf{M} , of the key letter — but the case must remain constant for the same device throughout the file.

Hierarchical Names

Hierarchical node names are used to refer to nested subcircuit nodes. Each level in the name of a node is separated by a period (.).

For example, the internal node ing in the xnand subcircuit contained in the xadder subcircuit is specified as

xadder.xnand.ing

Subcircuit Pin Name Aliasing

T-Spice recognizes subcircuit pin node names by their internal names as well as their global names.

For example, the netlist

```
.subckt test a b
r1 a c 100
r2 c b 100
.ends
x1 a1 b1 test
```

creates three nodes: **a1**, **b1**, and **x1.c**. **a1** and **b1** are globally recognized node names; but they may also be referred to by aliases **x1.a** and **x1.b**, respectively —for example, within a command such as .**print dc v(x1.a**).

Comments

Comments provide information about the circuit, but are not processed as part of the formal circuit description. Comments are generally indicated by the presence of special characters called *delimiters*.

However, T-Spice always treats the first line of the input file as a comment, even without comment delimiters.

Other comments may be placed anywhere in the circuit description.

Several comment styles are allowed, for compatibility with other versions of SPICE:

- An asterisk (*), dollar sign (\$), or semicolon (;) in the first column of a line indicates that the entire line is a comment.
- A dollar sign or semicolon, but *not* an asterisk, anywhere in a line *other* than in the first column indicates that the rest of the line is a comment.
- C-style comments, enclosed by the delimiters /* and */, can be used anywhere, except in the middle of multi-word commands (such as .print tran) or arguments. A C-style comment is not restricted to one line.

The comments in the following examples are highlighted:

A C-style comment that interrupts a command or argument may cause an error message. However, comments may appear *between* arguments.

The first two lines in the following examples would cause error messages:

```
.print /* wrong */ tran v(1)
.options prtdel /* wrong */ = 0.01
.options abstol=1e-8 /* OK */ reltol=1e-4
```

Line Continuation

Input file lines may be of any length; however, it is often convenient to break up long lines for readability.

A plus sign (+) in the first column denotes line continuation. For example:

```
.model nmes NMF
+ vto=-2.5 rs=100 rd=200 pb=0.7
+ alpha=2.0 cgs=500.0f cgd=100.0f
```

Comments in Continued Lines

Comments may appear between continued lines. However, blank lines may not appear between continued lines.

A continued line may include a dollar sign (\$) or semicolon (;) comment symbol, in which case the rest of the line is ignored.

No plus sign is needed for a comment line, a line continuing a C-style comment, or a line continuing an expression (see "Parameters" on page 56).

For example:

Expressions and Continued Lines

Plus signs cannot be used to indicate addition in the first column within multi-line expressions.

For example:

```
.options numnd = '7 +
log(10.1) $ will be added to previous term
+ 2' $ will NOT be added - `+' is ignored
```

Numbers and Units

Some commands and statements require arguments representing physical quantities with attached units (such as seconds or volts). Such numbers can be expressed in floating point, scientific, or fixed-point notation, and can be followed by metric abbreviations indicating order of magnitude.

The base units $(\mathbf{s}, \mathbf{v}, \mathbf{a}, \mathbf{f}, \mathbf{h})$ are implicit from the context and are optional. For example, the following expressions can all specify 12 nanoseconds in the appropriate context:

12ns 12e-9 .012u 12000p

Acceptable metric abbreviations are as follows.

Abbreviation	Prefix	Meaning
t or T	tera-	10 ¹²
g or G	giga-	109
meg or MEG	mega-	10 ⁶
x or X	mega-	106
k or K	kilo-	10 ³
m or M	milli-	10 ⁻³
ʻu or U	micro-	10-6
n or N	nano-	10 ⁻⁹
p or P	pico-	10 ⁻¹²
f or F	femto-	10 ⁻¹⁵

The abbreviation **f** is ambiguous because it can mean either the scale indicator "femto-" or the unit "farad." T-Spice employs the following convention: **f** by itself means "femto-." Thus **100f** means "100 femto-," where the unit is clear from the context. Where **f** precedes a base unit, as in **ff** and **fs**, or follows

a metric abbreviation, as in **uf**, there is no ambiguity. When "farad" by itself is meant, no unit should be used.

A commonly used unit abbreviation is **mil** (or **MIL**), representing 10^{-3} inch.

Parameters

You can declare parameters and assign them values with the **.param** command. Parameters cannot be reassigned values within an input file.

Parameter names can contain any characters except tabs, spaces, commas, curly braces, parentheses, single quotes, square brackets, equal signs, and algebraic operators $(+ - * / ^{\circ})$.

Expressions

Any number in a command or statement may be replaced by an algebraic *expression*. Expressions must conform to the following conventions.

- They must be enclosed by single quotes (').
- They may span several lines. The plus sign (+) is *ignored* if it appears in the first column of a continued expression.
- They may include comments that do not interrupt numeric values or parameter names.

Expressions may involve any valid combination of numbers, parameters (".param" (page 116)), operations, algebraic functions, and user-defined functions. T-Spice evaluates expressions according to a standard mathematical operator precedence, shown below. Level 1 has the highest operator precedence, and level 10 has the lowest.

Priority	Operation	Description
Level 1	(x)	Parentheses
Level 2	f(x)	Function call
Level 3	х^у	Exponentiation
Level 4	- X	Unary negation
Level 5	x×y x/y	Multiplication Division
Level 6	х+у х-у	Addition Subtraction
Level 7	<, <=, >, >=	Relational operators
Level 8	==, !=	equality and inequality
Level 9	x && y	logical AND
Level 10	$x \parallel y$	logical OR

Operation	Description
(<i>x</i>)	Parentheses — to override operator precedence
x + y	Addition
x – y	Subtraction
x * y	Multiplication
x / y	Division
x^y, x**y	Exponentiation (x^{ν})
-x	Unary negation
x < y, x <= y, x > y, x >= y	Relational operators - return 1 if the relation is true, otherwise 0
x == y, x != y	Equality operators - return 1 if the (in)equality is true, otherwise 0
х && у	Logical AND - returns 1 if x and y are true (non-zero), otherwise 0
х у	Logical OR - returns 1 if x or y is true (non-zero), otherwise 0

The operations and functions available in T-Spice are summarized in the following tables (in which the variables x and y represent numbers, parameter names, or subexpressions). All angles are in radians.

Built-in Functions

Function	Description
abs(<i>x</i>)	Absolute value of x (same as fabs)
acos(x)	inverse cosine of x (error if $ x > 1$)
asin(<i>x</i>)	Inverse sine of x (domain error if $ x > 1$)
atan(x)	Inverse tangent of <i>x</i> (range: $[-\pi/2, \pi/2]$)
atan2(<i>x</i> , <i>y</i>)	Inverse tangent of y/x (range: $[-\pi, \pi]$)
ceil(<i>x</i>)	Smallest integer not less than x
cos(<i>x</i>)	Cosine of x
cosh(<i>x</i>)	Hyperbolic cosine of <i>x</i>
db (x)	x in decibels: (sign of x) \cdot 20 \cdot log ₁₀ (x)
err(x,y)	error analysis; $abs(x-y) / max(x,y)$
exp(<i>x</i>)	e ^x
fabs(<i>x</i>)	Absolute value of x (same as abs)
floor(<i>x</i>)	Largest integer not greater than x
fmod(<i>x</i> , <i>y</i>)	Remainder of x/y (error if $y = 0$)
if(<i>c,a,b</i>) or c ? a : b	conditional statement, if <i>c</i> is true, then <i>a</i> , else <i>b</i> . Two syntax variations are supported for the conditional statement - the if() function call, and the C style of conditional expression
int(x)	Convert <i>x</i> to an integer, removing the fractional portion
ldexp(<i>x</i> , <i>y</i>)	$x \times 2y$ for integer y

Function	Description
log(x)	Natural logarithm of <i>x</i> (error if $x \le 0$)
log10(<i>x</i>)	Logarithm (base 10) of x (error if $x \le 0$)
log2(<i>x</i>)	Logarithm (base 2) of x (error if $x \le 0$)
$\max(x1, x2)$	Evaluates to the maximum of the two arguments.
$\min(x1, x2)$	Evaluates to the minimum of the two arguments.
pow(<i>x</i> , <i>y</i>)	Exponentiation (x^{ν})
pwr(<i>x,y</i>)	In HSPICE compatibility mode (default): (sign of x)· $ x ^y$ In PSPICE compatibility mode (.option spice=pspice) exponentiation (x^y), equivalent to pow(x,y)
pwrs(<i>x,y</i>)	signed power function, (sign of x) $ x ^{y}$
sgn(x)	Sign of x: -1 if $x < 0$ 0 if $x = 0$ 1 if $x > 0$
sign(x,y)	$(\text{sign of } y) \cdot x $
sin(<i>x</i>)	Sine of x
sinh(<i>x</i>)	Hyperbolic sine of <i>x</i>
sqrt(<i>x</i>)	Square root of x (-sqrt($ x $) if $x < 0$)
<pre>stp(expression) or stp(expression1, expression2)</pre>	The first syntax evaluates to 0 if expression is negative, and 1 otherwise. The second syntax evaluates to 0 if <i>expression1</i> is less than <i>-expression2</i> , to 1 if <i>expression1</i> is greater than <i>expression2</i> , and to <i>(expression1+expression2)/(2*expression2)</i> otherwise. The second syntax thus provides a continuous approximation to a step function.
table (x, x1, y1, x2, y2, ,xn, yn)	All arguments of the table function may themselves be subexpressions. The table function evaluates the piecewise linear function defined by the points $x1$, $y1$, $x2$, $y2$,, xn , yn , connected by straight lines. The function value is the <i>y</i> -value of that function at <i>x</i> .
	The points are automatically sorted in ascending order of x values to form the piecewise linear function. If x is less than the smallest x_k then the return value is the y -value corresponding to the smallest x_k . Similarly, if x is greater than the largest x_k then the return value is the y -value corresponding to the largest x_k .
tan(x)	Tangent of x
tanh(<i>x</i>)	Hyperbolic tangent of <i>x</i>

Differentiation and Integration functions

In addition to the Standard math library functions, T-Spice provides a set of functions for computing integrals and derivatives of data.

The ddt(f), d2dt(f), and idt(f) (aka sdt(f)) functions compute the time derivatives and integrals of transient simulation data.

The ddx(f,x), d2dx(f,x), and idx(f,x) (*aka* sdx(f,x)) functions compute the derivatives and integrals of the variable or expression f with respect to the independent variable or expression x.

The time-based integration and differentiation functions, and the generic x dependent forms of the functions, both use polynomial fits to the data for computing the integrals and derivatives. In the case of the transient functions, the order of the polynomial tracks that of the transient simulation engine, which is controlled by the "maxord" (page 244) option. The generic x dependent functions use a second-order polynomial fit, by default.

The order of the function equations can be changed using the **const_dt_maxord**, and **const_dx_maxord** options:

```
.options const_dt_maxord=[0-4] ;default value is 0, selecting transient order .options const_dx_maxord=[1-4] ;default value is 2
```

Note:

The quality of integrals is highly dependent upon the order of the fitting polynomial. It is important to select an order of equations which is an appropriate fit to the data. If the dependent function f is highly irregular or is a square-shaped digital signal, then a 1st or 2nd order integration is best. Higher order equations should only be used for very smooth data.

If the integration solutions are suspicious, perhaps containing very large integral values, then the solutions should be verified by re-running the simulation with the function integral order set to 1, which results in a piecewise summation of integrands, without higher order effects.

Function	Description
ddt(f)	Derivative of \boldsymbol{f} with respect to time
d2dt(<i>f</i>)	Second derivative of f with respect to time
idt(f) sdt(f)	Integrate f in time
ddx(<i>f</i> , <i>x</i>)	Derivative of \boldsymbol{f} with respect to \boldsymbol{x}
d2dx(<i>f</i> , <i>x</i>)	Second derivative of \boldsymbol{f} with respect to \boldsymbol{x}
$idx(f,x) \mid sdx(f,x)$	Integrate f in x

5 Simulation Commands

Introduction

This chapter describes features, outlines syntax, and gives examples for the *simulation commands* of the T-Spice circuit description language.

The commands are listed in alphabetical order. Many commands have *options*, which branch to different modes, and *arguments*, which indicate expressions, nodes, or devices to be operated on. Options and arguments must be separated by spaces or new lines (with line continuation).

The Syntax sections follow these conventions:

- Italics indicate variables to be replaced by actual names, numbers, or expressions.
- Curly braces { } indicate alternative values for the same option or argument.
- Square brackets [] enclose items that are *not required*.
- Vertical bars | separate alternative values for the same option or argument.
- Ellipses ... indicate items that may be repeated as many times as needed.

Brackets, vertical bars, and ellipses are *not* typed in the input file. All other characters are typed as shown. For further information, see: "Input Conventions" on page 52; "Device Statements" on page 152.

.ac

Performs AC analysis to characterize the circuit's dependence on small-signal input frequency: the DC operating point is computed, a linearized small-signal model is constructed at the DC operating point, and the circuit's response over a range of frequencies is measured.

- Small-signal parameters are reported to the main simulation output file. You can disable this
 reporting or specify a different output file using the command ".acmodel" (page 64). Reporting is
 automatically disabled if the simulation contains more than 1000 nodes.
- AC analysis results can be reported with the commands .print ac, .probe ac (for binary output), or .measure ac. For additional information on these commands, see ".print" (page 122), ".probe" (page 136), and ".macro /.eom" (page 90).
- The frequency can be varied linearly, by octaves, or by decades, by specifying a total number of test points, or by listing specific test frequencies.

Syntax

```
.ac {lin|oct|dec} num start stop [sweep swinfo] [analysisname=name]
or
.ac list f1 f2 ...fn [sweep swinfo] [analysisname=name]
or
.ac poi num f1 f2 ...fn [sweep swinfo] [analysisname=name]
```

Parameters

lin oct dec	Frequency variation mode.	
	 lin: linear sweep. 	
	• oct : logarithmic sweep by octaves.	
	• dec : logarithmic sweep by decades.	
list	Using the list keyword with .ac allows the user to specify a list of frequencies (<i>values</i>) for which the analysis is to be performed.	
роі	Using the poi keyword with .ac allows the user to specify a list of frequencies (<i>values</i>) for which the analysis is to be performed. The poi mode of processing is the same as the list mode, except that the syntax for poi requires that the number of frequencies, <i>N</i> , be specified next.	
num	Frequency count.	
	• Linear mode: Number of frequencies between start and stop.	
	• Octave mode: Number of frequencies per octave between start and stop.	
	• Decade mode: Number of frequencies per decade between <i>start</i> and <i>stop</i> .	
	• poi mode: Total number of frequency values.	
start	First frequency. (Unit: Hertz.)	
stop	Last frequency. (Unit: Hertz.)	
sweep	Specifies the parameter values of the sweep for which analysis will be performed. The sweep keyword is equivalent to ". step " (page 141) and uses the same parameter syntax. However, sweep applies only to one analysis command, while . step applies to all analysis commands in the input file. If sweep is specified on an analysis command and . step is present, the sweep sweep is nested inside the . step sweep. The parameter sweep may be used to specify a parametric sweep, Monte Carlo analysis, or optimization.	
analysisname	Specifies an analysis name that will be referenced by an .optimize simulation command. For further information, see " .optimize " (page 107).	

Examples

.ac DEC 5 1MEG 100MEG

Defines a frequency sweep from 1 MHz to 100 MHz by decades, with 5 points per decade.

.ac LIN 100 10K 100MEG

Defines a linear frequency sweep from 10 kHz to 100 MHz with 100 equally spaced points.

.ac list 5 50 500 5000 sweep rval dec 10 1 1000

Performs a logarithmic sweep of the parameter **rval** from 1 to 1000, using 10 points per decade; also performs an AC analysis at the four specified frequencies for each value of **rval**.

.acmodel

Modifies reporting of small-signal model parameters and operating points for specified devices in conjunction with AC analysis or DC operating point analysis. Small-signal parameters are automatically reported to the main simulation output file with the use of either **.ac** or **.op** in the input file.

- If ".ac" (page 61) and ".op" (page 105) are missing from the input file, .acmodel is ignored.
- No small-signal data is reported if the simulation model has more than 1000 nodes.
- Small-signal data are available for diodes, resistors, BJTs, JFETs, MESFETs, MOSFETs, and devices modeled with user-defined external models.

Syntax

 .acmodel [output file] { [device [[,] device ...]] }

 output file
 Output filename. If no filename is specified, then the output will be reported to the main simulation output file.

 device
 Device(s) for which small-signal model parameters and operating points are to be given. If no devices are specified, then no small-signal data is reported.

Examples

.acmodel {mt1 mt2}

Prints data for devices mt1 and mt2.

.acmodel {}

Turns off all small-signal parameter reporting.

.alter

Causes a simulation to be repeated with slight changes as specified after the **.alter** command. Multiple **.alter** commands can appear in the same netlist. T-Spice performs the first simulation with all commands that occur before the first **.alter** command; the second simulation incorporates changes between the first and second **.alter** commands; the third simulation incorporates changes between the second and third **.alter** commands, and so on. The optional **altername** string identifies the **.alter** block that follows and is used to identify the corresponding simulation output in output files.

A **.alter** block can contain any legal T-Spice statement. This command occurs at the end of a complete input file.

- Elements, option values, parameter values, and ".connect" (page 69) and ".model" (page 99) statements in a .alter block replace equivalent statements in the main netlist if the name of the element, parameter, option, data set, or model parameter set matches. If no name match can be made, the statement in the .alter block is simply added to the simulation.
- Statements are cumulative and progressive from one .alter block to the next such that any additions or changes made in block N will also occur (unless superseded) in block N+1.
- Initial conditions (".hdl" (page 81)) and ".nodeset" (page 103) replace equivalent commands that operate on the same nodes or devices. If no equivalent command is found in the main netlist, the command is simply added.
- If a .alter block contains a ".temp" (page 146) command, any .temp commands in the original netlist are replaced with the new .temp command.
- The commands ".lib" (page 87) and ".if ... / .elseif ... / .else / .endif" (page 84) can be used within ".alter" (page 65) blocks to include command and element statements.
- The ".del lib" (page 73) command can be used to delete a library section included in the original input file. All commands and elements in the library section are ignored during the "altered" simulation.
- Simulation commands such as ".ac" (page 61), ".tran" (page 148), and ".step" (page 141) do not replace commands in the original input file, but are simply added on as new commands.

Syntax

.alter [altername]

Examples

v1 1 0 1 r1 1 2 1k r2 2 0 1k .op .alter r1 1 2 2k .alter r2_4k r2 2 0 4k .end

This performs three simulations:

The first uses r1=1k, r2=1k, and is identified by alter=0; the output is v(2)=0.5.

The second uses r1=2k, r2=1k, and is identified by alter=1; the output is v(2)=0.333333 (1/3).

The third uses r1=2k, r2=4k, and is identified by alter=r2_4k; the output is v(2)=0.6666667 (2/3).

The abbreviated output would be:

```
*SEDIT: Alter=0
*SEDIT: Analysis types DCOP 1 ACMODEL 0 AC 0 TRANSIENT 0 TRANSFER 0 NOISE 0
* BEGIN NON-GRAPHICAL DATA
DC ANALYSIS - alter=0
v(2) = 5.0000e-001
v(1) = 1.0000e+000
i(v1) = -5.0000e-004
* END NON-GRAPHICAL DATA
*SEDIT: Alter=1
*SEDIT: Analysis types DCOP 1 ACMODEL 0 AC 0 TRANSIENT 0 TRANSFER 0 NOISE 0
* BEGIN NON-GRAPHICAL DATA
DC ANALYSIS - alter=1
v(2) = 3.3333e-001
v(1) = 1.0000e+000
i(v1) = -3.3333e-004
* END NON-GRAPHICAL DATA
*SEDIT: Alter=2
*SEDIT: Analysis types DCOP 1 ACMODEL 0 AC 0 TRANSIENT 0 TRANSFER 0 NOISE 0
* BEGIN NON-GRAPHICAL DATA
DC ANALYSIS - alter=r2 4k
v(2) = 6.6667e - 001
v(1) = 1.0000e+000
i(v1) = -1.6667e - 004
* END NON-GRAPHICAL DATA
```

.assert

You can characterize the safe operating area (SOA) of your circuit using the assert command. Assert establishes upper and lower limits on values of netlist parameters, model parameters, device instance parameters, and simulation electrical state variables. Violations of the established SOA limits will be logged to the Simulation Status window and to the safe operating area violations log file, *.tsoa.

Syntax

.assert name

```
[ sub=subcircuit ]
[ dev=instance ]
[ mod=model ]
[ primitive=primitive ]
[ expr='expression' ]
[ param=param ]
[ modelparam=modelparam ]
[ modeltype=modeltype ]
[ modelclass=modelclass ]
[ min=value ]
[ max=value ]
[ abs min=value ]
[ abs max=value ]
[ start=x start value ]
[ stop=x_stop_value ]
[ duration=x duration value ]
[ message="message"]
[ level= warning | error ]
[ info= yes | no ]
[ when= ac | dc | noise | op | setup | tf | tran ]
```

name	A label for the assert item.	
subcircuit	Constrains the SOA limits to elements within a particular subcircuit and it's sub-hierarchy.	
instance	Device instance name for device parameter checking.	
model	Model name for model parameter checking.	
primitive	Device type specifier, which may be either the standard initial character of the name - d (diode), m (mosfet), q (bjt), etc. or the full device name - diode, mosfet, bjt, etc.	
expression		
param	A device parameter name.	
modelparam	A model parameter name.	
modeltype	A model type, for filtering the devices or models to only be of a certain type. The type name is any one of the .model command types, i.e. nmos, nmf, npn, sw, etc.	
modelclass	A model class name, for filtering the devices or models to only be a certain class of models, e.g. bsim3, BJT, Jfet, moslevel2, etc.	

value	A real-valued limit, or an expression.	
x_start_value	The initial independent variable value for performing the assert test.	
x_stop_value	The final independent variable value for performing the assert test.	
x_duration_value	The minimum independent variable range that will trigger an SOA violation.	
message	A log message which will be printed only once if a violation occurs. This overrides the message that is generated automatically and is repeatedly printed for each violation.	
level	The degree of simulator error resulting from the SOA violation.	
info	Causes the parameter value to always be logged.	
when	Selects when the assert test should be performed, during setup or specific analyses. This option may be set repeatedly within one command, i.eassert when=dc when=tran.	

Examples

```
.assert CapLimit primitive=c param=c max=1n
.assert Isupply dev=vdd param=i1 abs_max=1A
.assert TotalPower max=.1w expr='power()'
```

Note:

SOA limits may be specified as expressions, e.g. max='i1(r1)*v(r1)'

.connect

This command will connect two nodes in your circuit, so that the two nodes will be simulated as only one node. In essence, one node name becomes an alias for another node name.

Both nodes must be at the same level in the circuit design that you are simulating: you cannot connect nodes that belong to different subcircuits

Syntax

.connect node1 node2

If you connect node2 to node1, you can then refer to either node1 or node2 in other simulation commands, and it will refer to the same node.

Examples

```
vcc 0 cc 5v
r1 0 1 5k
r2 1 cc 5k
.tran 1n 10n
.print i(vcc) v(1)
.alter
.connect cc 1
.end
```

The first .tran simulation includes two resistors. Later simulations have only one resistor, because r2 is shorted by connecting cc with 1.

You may also use multiple .connect statements to connect several nodes together:

.connect node1 node2 .connect node2 node3

connects both node2 and node3 to node1. The T-Spice simulation evaluates node voltages and related terms only for node1; node2, and node3 are the same node as node1.

Note:

If you set .option node, T-Spice prints out a node connection table.

.data

Used to incorporate external numerical data into simulations. The data can be used to specify reference data for error measurements, which is often used in conjunction with optimization for model parameter extraction. Also used to specify parametric sweeps in which several variables are swept simultaneously.

Syntax

```
.data dataname
+ colname [colname [...]]
+ value [value [...]]
+ value [value [...]]
...
.enddata
```

The number of columns is equal to the number of values per row.

dataname	Name assigned to the data set.	
colname	Name assigned to a column of data within the data set.	
value	Numeric parameter value. These values may be expressions, but must not depend on other parameter values.	

A data set can be used with the ".macro /.eom" (page 90) command to compute differences between simulation output curves and corresponding external data.

A data set can also be used to define a parameter sweep on an ".ac" (page 61), ".dc" (page 72), ".step" (page 141), or ".tran" (page 148) command.

The syntax for the **sweep** parameter on those commands is as follows:

data=dataname

where **dataname** refers to a .data statement of the same name. Each row of numbers in the .data statement corresponds to a sweep step, and each column refers to a sweep parameter (which must be a global parameter defined using .param) and the values which the parameter takes on. The **colname** strings identify the parameters to be swept. For each sweep step, the sweep parameters take on the values listed in a row of data.

Examples

```
.data idsdata
+ time vldat
+ 0 0
+ 1u 0
+ 1.1u 5
+ 2u 5
.enddata
.tran 0.1u 2u
.measure tran vlfit err1 vldat v(1)
```

This example computes the difference between the externally supplied data curve **v1dat** and the simulated transient analysis response voltage v(1).

```
.data idsdata
+ vds
              ids
+ 0.0000e+00 0
+ 5.0000e-01
            4.8565e-10
+ 1.0000e+00 2.2752e-06
+ 1.5000e+00
             1.2558e-05
+ 2.0000e+00
              3.1509e-05
+ 2.5000e+00 5.9462e-05
+ 3.0000e+00 9.6027e-05
+ 3.5000e+00 1.4135e-04
+ 4.0000e+00 1.9569e-04
+ 4.5000e+00 2.5978e-04
+ 5.0000e+00
             3.2942e-04
.enddata
.param vds=0 ids=0
vd drain source vds
m1 drain gate source bulk nmos 1=2u w=2u
.dc data=idsdata
.measure dc idsfit err1 ids id(m1)
```

This example computes the (relative) difference between the externally supplied data curve **ids** and the simulated MOSFET drain current **id(m1)**. This is particularly useful in conjunction with optimization for model parameter extraction, where the purpose of the simulation is to select model parameter values which yield the best match between simulated and measured data curves.

.dc

Performs DC transfer analysis to study the voltage or current at one set of points in a circuit as a function of the voltage or current at another set of points. Can also be used for linear or logarithmic sweeps of DC voltage or current; for sweeps of parameters other than voltage and current source values; and for Monte Carlo analysis or optimization.

- Transfer analysis is done by *sweeping* the source variables over specified ranges, and recording the output.
- Up to three parameters can be specified per .dc command.
- When two or more sources are specified, the last-named source "controls" the sweeping process (see "Examples," below).
- The specified current or voltage sources must exist—that is, be defined by i or v device statements elsewhere in the input file.
- DC transfer analysis results can be reported with the ".print" (page 122) dc, ".probe" (page 136) dc, and ".macro /.eom" (page 90) dc commands.

Syntax

.dc swinfo [[sweep] swinfo [[sweep] swinfo]]

Refer to ".step" (page 141) for a syntax description of swinfo.

Examples

.dc isrc 0 1e-6 0.1e-6

Current source **isrc** is swept from 0 to 1 microampere in 0.1-microampere steps.

.dc vin 0 5 0.05 VCC 4 6 0.5

Names two voltage sources: vin, to be swept from 0 to 5 volts in 0.05-volt steps, and VCC, to be swept from 4 to 6 volts in 0.5-volt steps. The second source "controls" the sweep: VCC is initially set to 4 volts, while vin is swept over its specified range. Then VCC is incremented to 4.5 volts, and vin is again swept over its range. This process is repeated until VCC reaches the upper limit of its specified range.

• •	lata	sweep_params	
+	vds	r2	length
+	0.0	1 k	10u
+	1.0	500	12u
+	2.0	100	14u
.enddata			
•	dc da	ata=sweep_params	

This example performs a DC sweep defined using a .data statement. There are three sweep steps, and the parameters vds, r2, and length are varied in the sweep. On the first sweep step, vds=0, r2=1000, and length=10u; on the second sweep step, vds=1, r2=500, and length=12u; on the third sweep step, vds=2, r2=100, and length=14u.

.del lib

Used to delete a section from a library file previously included using the ".lib" (page 87) command. The .del lib command is used in ".alter" (page 65) blocks, typically to replace a library section with a different one.

Syntax

.del lib filename section

filename	Name of the referenced library file. If the referenced filename or path contains a space, enclose the entire path in single or double quotation marks.
section	Name of the library section in <i>filename</i> that is to be deleted.

Examples

```
.lib bsim3model.md typical
.alter
.del lib bsim3model.md typical
.lib bsim3model.md fast
.alter
.del lib bsim3model.md fast
.lib bsim3model.md slow
.end
```

T-Spice input such as shown above might be used to run a simulation three times, first with **typical**, then with **fast**, and finally with **slow** model parameters. First, the library section called **typical** is loaded for the first simulation. The second simulation incorporates changes between the first and second **.alter** commands, so that the **typical** library section is deleted and replaced with the **fast** library section. Similarly, the third simulation replaces the **fast** library section with the **slow** one.

.end

Signifies the end of the circuit description.

- Any text in the input file after the **.end** command is ignored.
- The .end command is optional in T-Spice but is included for compatibility with generic SPICE.

Syntax

.end [comment]

.enddata

Signifies the end of a .data statement.

• The .enddata command *must* accompany a ".data" (page 70) command.

Syntax

.enddata [comment]

.endl

Signifies the end of a library definition.

• The .endl command *must* accompany a ".lib" (page 87) command.

Syntax

.endl [comment]

.ends

Signifies the end of a subcircuit definition.

• The .ends command *must* accompany a ".subckt" (page 145) command.

Syntax

.ends [comment]

.four

- Fourier components (magnitude and phase) are computed for a given fundamental frequency and corresponding to a specified number of integer multiples of the fundamental frequency.
- The DC Fourier component is computed, as well as the total harmonic distortion, defined as

$$\frac{1}{R_1} \cdot \left(\sum_{m=2}^{nfreqs} R_{m^2} \right)$$
(5.1)

where Rm is the magnitude of the mth Fourier component.

• The .four command is ignored if no .tran command is found.

Syntax

.four F list [nfreqs=N] [npoints=P] [interpolate=I]
F	Fundamental frequency.
list	Output variables for which the analysis is to be performed. Each of these can be any valid output item from a " .print " (page 122) tran command, including output expressions.
Ν	Number of frequencies for which Fourier components are determined. (Default: 9.)
Ρ	Number of points over which transient analysis data is interpolated to fit. These points equally divide the analysis interval $(T-J,T)$, where T is the final time specified on the corresponding " .tran " (page 148) command, and $J = 1/F$. Increasing P improves accuracy but increases simulation time and memory use. (Default: 100.)
I	If 0, T-Spice inserts an actual computed time point at each place where a Fourier analysis time point is needed without interpolating transient data to fit on np . If 1, Fourier analysis is based on interpolated data. (Default: 1.)

Examples

v1 2 0 sin (4 10 9e6 0 0 20) v2 1 2 sin (0 3 3e6 0 0 -50) .tran lu 10u .four 3e6 v(1) npoints=1000

$$v(1) = 4 +$$

$$10\sin[2\pi(9 \times 10^{6}t + 20/360)] +$$

$$3\sin[2\pi(3 \times 10^{6}t \angle 50/360)]$$
(5.2)

The analytic Fourier response for this formula is as follows:

- The DC component is 4.
- The first harmonic (at a frequency of 3 MHz) has a magnitude of 3 and a phase of -50 degrees.
- The third harmonic (at a frequency of 9 MHz) has a magnitude of 10 and a phase of 20 degrees.
- All other harmonics have a zero Fourier component.

The output will be:

```
* BEGIN NON-GRAPHICAL DATA
FOURIER ANALYSIS RESULTS
```

```
Fourier components of transient response v(1)
```

```
DC component = 4.0011e+000
```

Harmonic no	Frequency <hz></hz>	Fourier comp	Normalized FC	Phase <deg></deg>	Normalized phase
1	3.0000e+006	2.9989e+000	1.0000e+000	-4.9651e+001	0.0000e+000
2	6.0000e+006	2.4224e-002	8.0777e-003	3.5132e+001	8.4783e+001
3	9.0000e+006	9.9949e+000	3.3328e+000	2.0564e+001	7.0215e+001
4	1.2000e+007	3.4401e-002	1.1471e-002	-1.6494e+002	-1.1529e+002
5	1.5000e+007	1.8803e-002	6.2701e-003	-1.6786e+002	-1.1821e+002
6	1.8000e+007	1.3374e-002	4.4595e-003	-1.6966e+002	-1.2001e+002
7	2.1000e+007	1.0534e-002	3.5126e-003	-1.7085e+002	-1.2120e+002
8	2.4000e+007	8.7570e-003	2.9201e-003	-1.7169e+002	-1.2204e+002
9	2.7000e+007	7.5266e-003	2.5098e-003	-1.7229e+002	-1.2264e+002

Total harmonic distortion = 333.3 percent

* END NON-GRAPHICAL DATA

where the DC component is 4.0011e+000, the first harmonic has a magnitude of 2.9989 and a phase of - 4.9651e+001, the third harmonic has a magnitude of 9.9949e+000 and a phase of 2.0564e+.001.

Note that harmonics one and three have the exponent e+000, while the magnitude of the other harmonics—e-002 or even e-003—is quite small in comparison.

.global

Specifies nodes with global scope.

- Global node names refer to the *same* nodes both inside and outside subcircuit definitions.
- Ground (**0**, **gnd**, **Gnd**, or **GND**) is automatically defined to be a global node.

Syntax

```
.global node1 [[,] node2 ...]
```

.hdl

Loads a Verilog-A module into the simulator, and optionally declares that the module will be used to simulate all devices of a specified type, level, and version.

When the **type**, **level**, and **version** parameters are used in the **.hdl** command, T-Spice will use the Verilog-A module as the modeling code for all matching devices, i.e. devices of the specified type which reference a **.model** of the specified level and version. This capability may be used to either introduce new model levels and versions into T-Spice, or to replace the existing built-in T-Spice models with your own.

Syntax

.hdl filename [modulename [type=type [level=level [version=version]]]]

filename	The Verilog-A file to be loaded. It must exist in the current directory or in the T-SpiceVerilog-A search path. Absolute or relative path names (according to the conventions of the operating system) can be used. If the referenced filename or path contains a space, enclose the entire path in single or double quotation marks.
modulename	The name of a specific module within the file. Only this one module will be loaded into the simulator, and other modules within the file will be ignored.
type	The type of devices that will use this module
level	The level number of the models that will use this module
version	The version number of the models that will use this module

The device **type** keyword is limited to the following:

Type keyword	Device
C or capacitor	Capacitors
D or diode	Diodes
J or jfet	JFETs
R or resistor	Resistors
M or mosfet	MOSFETs
Q or bipolar	BJTs
Z or mesfet	MESFETs

Examples

.hdl pll.va .hdl bsim3v34.va bsim3 type=mosfet level=49 version=3.4 The second of the above examples demonstrates how a Verilog-A module can be used instead of the built-in device evaluation code. In this case, a Verilog-A representation of the BSIM3 model will be used instead of T-Spice's internal BSIM3 analysis code for those MOSFETs which reference a model that is level 49 and version 3.4.

Note: If the **level** or **version** is not specified or has a value of zero, then all levels and versions will be matched and simulated using the Verilog-A module

.ic

Sets node voltages or inductor currents for the duration of a DC operating point calculation.

- DC operating points are calculated by the ".ac" (page 61), ".dc" (page 72), ".op" (page 105), ".tf" (page 147), and ".tran" (page 148) commands.
- The .ic command adds a voltage source present only in DC (not transient) simulations.
- The specified nodes are allowed to float if a transient analysis is subsequently requested in the input file. For further information on transient analysis, see ".tran" (page 148).
- Nodes and devices within subcircuits can be accessed with hierarchical notation in the form xinstance.xinstance.node.
- To set initial guesses for node voltages, use the ".nodeset" (page 103) command.
- .ic commands within subcircuit definition (".subckt" (page 145)/".ends" (page 77)) blocks are replicated for each subcircuit instance.

Syntax

<pre>.ic node=X [[,] node=X] .ic v(node [,node])=X [[,] v(node [,node])=X] .ic i(inductor)=X [[,] i(inductor)=X]</pre>		
node	Node whose voltage is to be initialized. (Default reference node: ground.)	
inductor	Inductor whose current is to be initialized.	
X	Node-to-node or node-to-ground voltage or inductor current value. (Unit: volts or amperes.)	

Examples

.ic a=5, b=5, c=5

Assigns initial voltages of 5 volts (relative to ground) to nodes **a**, **b**, and **c**.

.ic v(a,b)=5

Sets the initial voltage *between* nodes **a** and **b** to 5.

.if ... / .elseif ... / .else / .endif

The .if, .elseif, .else, and .endif conditional statements may be used in a netlist to control which simulation commands, device statements, and device models will be included in the simulation.

The .if and .elseif commands have required conditional statements which will be evaluated to either true or false (non-zero or zero). Processing will then proceed, according to the conditional value. The first condition block which evaluates to true will be the selected block, or the .else block will be evaluated if no other blocks are true.

- Conditional statements may be nested.
- You can have an unlimited number of .elseif statements in your conditional.
- Parameter assignments that are contained within a condition's statement block do not effect the condition evaluation.
- Statements that are part of a condition statement block are only evaluated if and when the containing condition statement is evaluated to true.

Syntax

condition	A value or an expression, enclosed in parentheses or quotes, which will be evaluated to control the selection of one of the statement blocks. Any non-zero expression value will be considered true , and a zero value is false .
statement block	Any valid T-Spice statements

Examples

The simplest example of a conditional statement has a single conditional .if block:

```
.param debug=1
.if (debug)
        .options echo=1
        .options verbose=2
        .options list nomod=0 node
.endif
```

An example which demonstrates all types of conditional statements:

```
.if (technology==49 && fast)
    .lib mos49.md FF
.if (technology==49 && fast==0)
    .lib mos49.md TT
.elseif (technology==53)
    .lib mos53.md TT
.else
    .lib mos2.md TT
.endif
```

.include

Includes the contents of the specified file in the input file.

• The .include command can be nested (included files can include other files, and so on) as deeply as hardware and operating system constraints permit.

Syntax

.include filename

filename The file to be included. It must exist in the current directory or in the T-Spice search path. Absolute or relative path names (according to the conventions of the operating system) can be used. If the referenced filename or path contains a space, enclose the entire path in single or double quotation marks.

.lib

.lib

Within a SPICE or included file, specifies a library file or section to be included. Within a library file, indicates the beginning of a library section.

T-Spice accepts two different library file formats. The **.lib** command is used to access library files of both formats. It is also used to delimit library sections within library files if the first library format is used. Specific model and subcircuit definitions are read in only if needed.

Syntax

Library File Format I:

The first T-Spice library file format is a sequence of library sections. Each library section begins with a **.lib** command and ends with a **.endl** command. The **.lib** command assigns a name to each section. Within each library section any sequence of SPICE circuit elements or commands may occur.

When **.lib** is used with both a file name and section name, it is equivalent to **.include** except that only the part of the file within the specified library section is included.

.lib filename [section]

filename	The file to be included. It must exist in the current directory or in the T-Spice search path. If the referenced filename or path contains a space, enclose the entire path in single or double quotation marks.
section	If specified, designates a section of the library file to be searched.

Examples

A file test.lib might contain:

```
.lib sub1
.subckt s1 a b
rl a b lk
.ends
.endl
.lib sub2
.subckt s2 a b
r1 a b 2k
.ends
.endl
.lib sub3
.subckt s3 a b
r1 a b 3k
.ends
.endl
The command:
```

.lib test.lib sub2

would cause T-Spice to include the library section **sub2** and therefore the definition for subcircuit **s2**.

Library file format II:

The second T-Spice library file format consists simply of a sequence of **.model** commands and **.subckt** definition blocks. A library file of this second format may be included in a simulation by using the **.include** command in a main input file or included file. T-Spice will search the specified file for device model and subcircuit definitions if they are not found in the main input file or included files, and read in only those that are needed.

.include filename

filename	The library file to be searched for ".model" (page 99), ".param" (page 116), and ".subckt" (page 145) definitions. The file must exist in the current directory or in the T-Spice search path.
	If the referenced filename or path contains a space, enclose the entire

path in single or double quotation marks.

Examples

A file **test2.lib** might contain:

```
.subckt s1 a b
r1 a b 1k
.ends
.subckt s2 a b
r1 a b 2k
.ends
.subckt s3 a b
r1 a b 3k
.ends
```

Suppose the main input file contains:

```
.include test2.lib
x1 1 0 s3
```

The .include command would cause the file test2.lib to be searched for model and subcircuit definitions. The instance x1 references subcircuit s3, causing T-Spice to read and include the subcircuit definition for s3 in test2.lib. Assuming that subcircuits s1 and s2 are not referenced elsewhere, their definitions in test2.lib would not be read in.

.load

Input the contents of the specified file. The file presumably was created using the ".save" (page 138) command, and contains either ".hdl" (page 81) or ".nodeset" (page 103) commands for restoring the bias point of the circuit. The .save and .load commands can be used in combination to reduce simulation time by performing a compute-intensive operating point calculation once, saving the bias information, and then using the .load command in subsequent simulations to initialize the circuit to that state.

Syntax

```
.load [file=filename]
```

filename

Name of the file to be read. If the **file** parameter is not entered, then the filename is derived from the simulation input filename, with a **.ic** file extension.

Examples

.load file=baseline.ic

.macro /.eom

.macro is synonymous with .subckt, and .eom is synonymous with .ends.

The .macroeom naming convention for defining subcircuits is provided for compatibiliity with other simulators which use this syntax rather than .subcktends.

.malias

Assigns an alias to a model name which was defined in a **.model** command. Device references to model names may use either the original model name or the alias name throughout the circuit netlist.

Alias name assignments may also refer to binned model base names. That is, given binned models *nch.1*, *nch.2*, *nch.3*, etc. you may declare an alias name *nmosmodel* for model name *nch*.

Syntax

```
.malias ModelName=AliasName1 [ AliasName2 [ AliasName3 [ ... ] ] ]
```

Examples

```
.model nch.1 nmos level=49 ...
.model nch.2 nmos level=49 ...
.malias nch=nmosmodel
```

or

```
.model dio d ...
.malias dio=zenerdiode
```

.measure

Used to compute and print electrical specifications of a circuit, such as delay between signals, rise and fall times, and minimum and maximum values of a signal. Also used for optimization in conjunction with the following commands:

- ".ac" (page 61)
- ".dc" (page 72)
- ".connect" (page 69)
- ".step" (page 141)
- ".tran" (page 148)

For parameter sweeps, T-Spice generates a separate output section plotting measurement results versus swept parameter values. A data set can be used with the error measurement syntax of **.measure** to compute differences between simulation output curves and corresponding external data. In this case, **out1** or **out2** in the error function measurement syntax may refer to a column name of a **.data** statement.

A .measure command within a .subckt block is replicated for each instance of the subcircuit.

For optimization, you can use **.optgoal** instead of **.measure** with the **goal** and **minval** parameters to set the minimum value for the denominator in the error expression and the scalar value that specifies the relative importance of two or more measurements.

Note:

When the ".options" (page 109) autostop field is set to 1, T-Spice automatically terminates any transient analysis when all .measure results have been found. The autostop option does not affect preview transient analyses.

Syntax

The **.measure** command syntax has several formats, each of which is described below. Each **.measure** command should be used in conjunction with DC transfer, AC, data, step, or transient analysis.

The general syntax of the .measure command is:

```
.measure {dc|ac|tran} result list [goal=goal]
+ [minval=minval] [weight=weight] [off]
```

dc ac tran	Denotes the analysis type (dc , ac , or tran) for which the measurement is to be done. For dc analysis, the independent variable is a swept parameter. For ac analysis, the independent variable is frequency. For transient analysis (tran), the independent variable is time.
result	Name of the measurement result. This name is used to identify the measurement result in the output file, and it can also be used in subsequent equation evaluation measurements.

List of keywords and parameters whose syntax depends on the type of measurement to be made. Possible measurement types include:	
 "Trigger/Target Measurements" on page 93 	
 "Signal Statistics Measurements" on page 94 	
• "Find-When and Derivative Measurements" on page 95	
 "Expression Evaluation Measurements" on page 97 	
 "Error Function Measurements" on page 97 	
Desired value of the measurement, for use in optimization. In optimization, T-Spice attempts to minimize the relative error, (<i>goal-result</i>)/ <i>goal</i> . For error measurement optimizations, T-Spice minimizes simply (<i>goal-result</i>), because in that case <i>result</i> is itself a relative value, and <i>goal</i> is usually zero. Default value: zero.	
Minimum value for the denominator in the error expression above. Default: 1.0e-12.	
Scalar value that is multiplied by the relative error. This value is used to specify the relative importance of two or more measurements in optimization. Default: 1.	
Optional keyword that prevents T-Spice from printing output from this .measure command.	

Note:

The .measure keyword can be abbreviated to .meas.

Trigger/Target Measurements

The trigger/target format of the **.measure** command is used to make independent variable (time, frequency, or swept parameter) difference measurements. The **trigger** and **target** specifications determine the beginning and end, respectively, of the measurement. The value of the measurement is the difference in the independent variable value between the trigger and the target. Common examples of trigger/target measurements include delay time, rise time, fall time, and bandwidth measurements.

The syntax of the *parameters* field for trigger/target measurements is:

```
trig outvar val=val [td=td] {cross=cross | rise=rise |
    fall=fall}
+ targ outvar val=val [td=td] {cross=cross | rise=rise | fall=fall}
or
trig at=at_value targ outvar val=val [td=td] {cross=cross | rise=rise |
    fall=fall}
at_value Specifies an explicit independent variable value for the trigger.
```

outvar	Specifies an output signal on which the trigger or target measurement is performed. This can be any output plot item that is legal on a .print command for the appropriate analysis type. For .measure ac commands, .print noise plot items are allowed. outvar may be an output expression enclosed in single quotes.
val	Specifies the value of outvar at which the trigger or target counter for cross , rise , or fall is incremented.
td	Specifies a time delay before the measurement is enabled and crossings, rises, and falls are counted. Default: 0.
cross	Indicates which occurrence of the trigger or target crossing is to be used for the measurement. A crossing occurs when the trigger or target outvar takes on the value <i>val</i> . The special syntax cross=last indicates that the last crossing is to be used.
rise	Indicates which occurrence of the trigger or target rise crossing is to be used for the measurement. A rise crossing occurs when the trigger or target outvar takes on the value val while increasing. The special syntax rise=last indicates that the last rise crossing is to be used.
fall	Indicates which occurrence of the trigger or target fall crossing is to be used for the measurement. A fall crossing occurs when the trigger or target outvar takes on the value val while decreasing. The special syntax fall=last indicates that the last fall crossing is to be used.

Note:

For a particular trigger or target, only one of **cross**, **rise**, or **fall** may be specified.

Trigger/target measurement output reports the independent variable value difference between the trigger and the target, as well as the independent variable values at the trigger and target. The measurement result may be negative if the target independent variable value is less than the trigger independent variable value.

For syntax examples, see "Trigger/Target Example" on page 98.

Signal Statistics Measurements

Signal statistics measurements are used to perform data reduction operations on signals. T-Spice can compute average, RMS (root-mean-square), minimum, maximum, and peak-to-peak values for a signal. In addition, T-Spice can report the independent variable (argument) value at the minimum or maximum of a signal.

The syntax of the *parameters* field for signal statistics measurements is:

type outvar [from=from] [to=to] [output=output]

type

- Specifies the type of measurement, and is one of the following:
 - amax computes the independent variable value at the point where the signal's maximum value is reached.

	•	amin computes the independent variable value at the point where the signal's minimum value is reached. If the minimum value occurs more than once, amin reports the first instance.
	•	avg computes the average value of the signal, defined as the integral of the signal divided by the length of the measurement interval.
	•	integral computes the integral of the signal over the measurement interval. Can be abbreviated to integ .
	•	max computes the maximum value of the signal.
	•	min computes the (global) minimum value of the signal. The computation is independent of signal derivative (<i>i.e.</i> , min may be a signal endpoint).
	•	pp reports the difference between the maximum and minimum values of the signal (peak-to-peak measurement).
	•	rms computes the root-mean-square value of the signal, defined as the square root of the integral of the signal squared, divided by the length of the measurement interval.
outvar	Specifies the output signal on which the measurement is to be performed. It can be any output plot item that is legal on a .print command for the appropriate analysis type. For .measure ac commands, .print noise plot items are allowed. outvar may be an output expression enclosed in single quotes.	
from	swe	cifies the value of the independent variable (time, frequency, or ep parameter) at the beginning of the measurement. The default be beginning of the analysis.
to	swe	cifies the value of the independent variable (time, frequency, or ep parameter) at the end of the measurement. The default is the of the analysis.
output	be e	max and min type measurements, specifies the output signal to evaluated at the point at which the maximum or minimum is shed.

For syntax examples, see "Signal Statistics Example" on page 98.

Find-When and Derivative Measurements

Find-when measurements are used to measure values of dependent or independent output variables when some specific event occurs. The event specification is similar to the trigger specification in trigger/target measurements: the event occurs when a signal crosses a value, or a signal crosses another signal, or when a certain independent variable "at" value is reached. If a "find" signal is specified, the measurement output is the value of the find signal at the event. If no "find" signal is given, then the measurement result is the independent variable value at the event.

Find-when measurements can also be used to compute derivatives of functions. If the **find** keyword is replaced with **derivative**, the derivative of **outvar1** is computed as the measurement result.

The syntax of the *list* field for find-when measurements is:

.measure

```
[find outvar1 | derivative outvar1] when outvar2=val [td=td] {cross=cross |
                     rise=rise | fall=fall}
                 or
                 [find outvar1 | derivative outvar1] when outvar2=outvar3 [td=td]
                      {cross=cross | rise=rise | fall=fall}
                 or
                 {find outvar1 | derivative outvar1} at=at value
Note:
                 For a particular trigger or target, only one of cross, rise, or fall may be specified.
                 at_value
                                                Specifies an explicit independent variable value for the event.
                 outvar1
                                                Specifies the output signal to be evaluated as the measurement result
                                                at the event of interest. This can be any output plot item that is legal
                                                on a .print command for the appropriate analysis type. For .measure
                                                ac commands, .print noise plot items are allowed. outvar1 may be
                                                an output expression enclosed in single quotes.
                 outvar2
                                                Specifies an output signal to be evaluated for locating the
                                                measurement event. This can be any output plot item that is legal on
                                                a .print command for the appropriate analysis type. For .measure ac
                                                commands, .print noise plot items are allowed. outvar2 may be an
                                                output expression enclosed in single quotes.
                 val
                                                Specifies the value of outvar2 at which the event counter for
                                                crossings, rises, or falls is incremented.
                 outvar3
                                                Specifies a second output signal to be evaluated for locating the
                                                measurement event. This can be any output plot item that is legal on
                                                a .print command for the appropriate analysis type. For .measure ac
                                                commands, .print noise plot items are allowed. outvar3 may be an
                                                output expression enclosed in single quotes.
                 td
                                                Specifies a time delay before the measurement is enabled and
                                                crossings, rises, and falls are counted. Default: 0.
                 cross
                                                Indicates which occurrence of the event crossing is to be used for the
                                                measurement. A crossing occurs when outvar2 takes on the value val
                                                or the value of outvar3. The special syntax cross=last indicates that
                                                the last crossing is to be used.
                                                Indicates which occurrence of the trigger or target rise crossing is to
                 rise
                                                be used for the measurement. A rise crossing occurs when outvar2
                                                takes on the value val or the value of outvar3 while increasing. The
                                                special syntax rise=last indicates that the last rise crossing is to be
                                                used.
                 fall
                                                Indicates which occurrence of the trigger or target fall crossing is to
                                                be used for the measurement. A fall crossing occurs when outvar2
                                                takes on the value val or the value of outvar3 while decreasing. The
                                                special syntax fall=last indicates that the last fall crossing is to be
                                                used.
```

For syntax examples, see "Find-When and Derivative Example" on page 98.

Expression Evaluation Measurements

T-Spice can compute expressions that are functions of previous **.measure** command results. The syntax of the **parameters** field for expression evaluation measurements is:

param=' expression'

where *expression* is an algebraic expression involving **.param** parameter values, subcircuit parameter values, and previous **.measure** result names. The expression may not contain plot items such as node voltages or branch currents. The expression may contain the same operators and functions as used in **.print** output expressions.

Error Function Measurements

The error function measurement reports a relative difference between two output variables. Four methods for calculating this error are available.

The syntax of the *parameters* field for error function measurements is:

errtype out1 out2 [from=from] [to=to]

errtype	Specifies the method of computing the total error. Must be one of err , err1 , err2 , err3 .
out1, out2	Specifies the output signals to be compared. These can be any output plot items that are legal on a .print command for the appropriate analysis type. For .measure ac commands, .print noise plot items are allowed. out1 and out2 may be output expressions enclosed in single quotes.
from	Specifies the value of the independent variable (time, frequency, or sweep parameter) at the beginning of the measurement. The default is the beginning of the analysis.
to	Specifies the value of the independent variable (time, frequency, or sweep parameter) at the end of the measurement. The default is the end of the analysis.
The error computation	depends on the <i>errtype</i> and is as follows:
err, err1	The error is the RMS value of the relative difference between the two signals, normalized to the length of the measurement interval.
err2	The error is the integral over the measurement interval of the absolute value of the relative difference of the two signals.
err3	The error is the integral over the measurement interval of the relative difference of the logs of the two signals.

The relative difference of the two signals is defined as:

(out1-out2)/max(minval, |out1|+|out2|)

The relative difference of their logs is defined as the absolute value of:

log(|out1|/max(minval, |out2|))/log(max(minval, |out1|+|out2|))

For syntax examples, see "Error Function Example" on page 98.

Examples

Trigger/Target Example

```
.measure tran delaytime trig v(1) val=2.5 fall=3
+ targ v(2) val=2.5 rise=3
```

measures the time delay from the third falling edge of signal v(1) to the third rising edge of signal v(2). The measurement begins when v(1) falls through 2.5V for the third time, and ends when v(2) rises through 2.5V for the third time.

```
.measure tran risetime trig v(1) val=0.5 rise=1
+ targ v(1) val=4.5 rise=1
```

measures the first rise time of the voltage at node 1.

Signal Statistics Example

.measure ac maxgain max vm(out)

measures the maximum value of vm(out) over the frequency range covered during an AC analysis.

.measure ac resfreq amax vm(out)

measures the frequency at which the maximum value of vm(out) is achieved.

.measure ac phase_at_resonance max vm(out) output=vp(out)

measures the phase vp(out) at the frequency where vm(out) is at its maximum.

Find-When and Derivative Example

```
.measure tran v1 find v(1) when v(2)=2 cross=1
```

measures the voltage at node 1 when the voltage at node 2 crossed 2V for the first time.

.measure ac f1 when vm(out)=1

measures the frequency at which the voltage gain at node **out** is 1.

.measure tran d1 derivative v(1) at=100ns

measures the derivative of v(1) with respect to time at 100ns.

Error Function Example

.measure tran v1v2 err1 v(1) v(2)

measures the difference between the signals v(1) and v(2).

.model

Specifies device model parameters to be used by one or more devices.

Syntax

```
.model modelname type [level=L][parameter=value [parameter=value [...]]]
[ako: akomodel]
```

modelname	Model name.
type	Device type (see below).
L	Model level, required for device models with multiple levels.
parameter	The parameter list is predefined for each standard device model. (See the chapter "Device Models" on page 330.)

type is one of the following:

c	Capacitor
срІ	Coupled transmission line.
csw	Current-controlled switch element.
d	P-N diode.
npn	NPN-type BJT.
pnp	PNP-type BJT.
njf	N-type JFET.
pjf	P-type JFET.
nmf	N-type MESFET.
opt	Controls the optimization algorithm. For additional information, see "Optimization Algorithm Parameters," below.
pmf	P-type MESFET.
nmos	N-type MOSFET.
pmos	P-type MOSFET.
r	Two-terminal resistor (or three-terminal resistor if a capacitance is specified).
sw	Voltage-controlled switch element.

external External model. The parameter list of a **.model** command of type **external** must specify the name of the file that contains the external model. These special model parameters vary according to platform and take the following form:

- winfile=file (Windows)
- solfile=file (Solaris 2.x)
- sunfile=file (SunOS 4.x)
- sgifile=file (SGI IRIX)
- hpfile=file (HPUX)

If the external model filename has a **.c** extension, T-Spice will interpret the model file. If it has any other extension, T-Spice will treat it as a compiled DLL or shared library.

External model parameters can be numbers or strings. Strings and filenames must be enclosed in double quotes ("").

Optimization Algorithm Parameters

The T-Spice optimization algorithm is controlled using the **.model** command with a model type of **opt**. The syntax is:

.model name opt [parameter=value [parameter=value [...]]] [ako: akomodel]

modelname	Model name matched with the model name specified in an analysis command
parameter	Model parameter name
value	Value assigned to the model parameter
akomodel	Another opt model statement. If akomodel is specified, this model is considered to be "a kind of" the model defined with name akomodel ; that is, all model parameters defined in the akomodel .model statement are included in this model unless overridden in this model.

Valid alternatives for *value* are listed below:

Parameter	Description	Default
cendif	Gradient value below which more accurate derivative computation methods are used to compute the gradient.	1e-9
close	Estimate of how close the optimization parameters' initial value estimates are to the solution. close is a multiplier for computing new parameter estimates. Larger values result in larger steps toward the solution.	0.001

cut	Modifies close from one iteration to the next. If an iteration was unsuccessful, close is divided by cut ; if an iteration is successful, close is multiplied by cut squared.	2
difsiz	Determines the increment in a parameter value used to compute numerical derivatives. The increment used is difsiz*max (<i>value</i> , parmin), where <i>value</i> is the parameter value. If delta is specified on the . param command, then delta is used as the increment.	1e-3
grad	Convergence tolerance for the gradient. If the gradient is less than <i>grad</i> , then convergence may have been achieved, depending on the outcome of the additional relin and relout tests.	1e-6
itropt	Maximum number of optimization loop iterations.	20
level	Optimization method used. Level=1 selects a modified Levenberg-Marquardt algorithm.	1
max	Upper limit for close	600,000
parmin	Used in increment selection for derivative computation; see difsiz parameter, above	0.1
relin	Relative input parameter variation for convergence. If all optimization parameters (defined with .param) vary by less than this amount (0.1% by default) from one iteration to the next, convergence is declared	0.001
relout	Relative output parameter variation for convergence. If the total error defined by measurement results varies by less than this amount from one iteration to the next, convergence is declared.	0.001

Note:

When no model parameters are specified, all models take on their default values.

Examples

.r	nodel nmos nmos		
+	Level=2	Ld=0.0u	Tox=225.00E-10
+	Nsub=1.066EV+16	Vto=0.622490	Kp=6.326640E-05
+	Gamma=.639243	Phi=0.31	Uo=1215.74
+	Uexp=4.612355E-2	Ucrit=1746677	Delta=0.0
+	Vmax=177269	Xj=.9u	Lambda=0.0
+	Nfs=4.55168E+12	Neff=4.68830	Nss=3.00E+10
+	Tpg=1.000	Rsh=60	Cgso=2.89E-10
+	Cgdo=2.89E-10	Cj=3.27E-04	Mj=1.067
+	Cjsw=1.74E-10	Mjsw=0.195	

Specifies the parameters for an *n*-type MOSFET model called **nmos**.

```
.model resmodel external winfile="res.dll" solfile="res.sl" a=20 b="name"
```

Defines a model called **resmodel** that can be referred to by an instance (**x**) statement. In Windows, **res.dll** is loaded as a DLL; under Solaris **res.sl** is loaded as a shared library. Under all other platforms, an error message is issued because no external model name is specified. The numeric parameter **a=20** and the string parameter **b="name"** are passed to the external model as model parameters.

.nodeset

Sets an "initial guess" for the iterative DC operating point calculation.

- DC operating points are calculated by the ".ac" (page 61), ".dc" (page 72), ".op" (page 105), ".tf" (page 147), and ".tran" (page 148) commands.
- DC operating points are calculated by iteration, and .nodeset sets starting points for iteration. Convergence properties can be very sensitive to the initial guess; .nodeset can be used (1) to enable convergence for difficult-to-converge circuits and (2) to cause T-Spice to converge to one particular solution if more than one solution exists.
- After numndset iterations, or when the convergence criteria have been met, the specified nodes are allowed to float.
- Nodes and devices within subcircuits can be accessed with hierarchical notation in the form xinstance.xinstance.node.
- To set node voltages for the duration of the operating point calculation, use the ".hdl" (page 81) command.
- .nodeset commands inside subcircuit definition blocks are replicated for each subcircuit instance.

Syntax

```
.nodeset node=X [[,] node=X ...]
.nodeset v(node)=X [[,] v(node)=X ...]
node Node to be initialized.
X Node voltage relative to ground. (Unit: volts.)
```

Examples

```
.nodeset n1=5V n2=2
.nodeset v(n1)=5V v(n2)=2
```

The two examples are identical except for syntax.

.noise

Computes the effect of circuit noise on output voltage in conjunction with AC analysis.

- If the ".ac" (page 61) command is missing from the input file, the .noise command is ignored.
- Noise analysis is performed at the same frequencies as specified by the ".ac" (page 61) command.
- Noise models take the form of frequency-dependent mean-square currents (since the underlying phenomena are "random") generated by adding a current source to the circuit for each modeled noise source.
- Noise sources at different points in the circuit are uncorrelated.
- Noise models are available for resistors and semiconductor devices (diodes, BJTs, JFETs, MESFETs, and MOSFETs). Semiconductor device models may contain noise model parameters which affect the size of noise sources.
- External model devices may also contain noise sources.
- Noise analysis results can be reported with the ".print" (page 122) noise command.

Syntax

.noise v(node1 [[,] node2]) source interval

node1	Output node.
node2	Reference node. (Default: ground.)
source	Input voltage or current source, at which noise can be considered to be concentrated for the purposes of estimating the equivalent noise spectral density.
interval	Report interval. A noise report will be printed to the simulation log which lists every device and the noise contribution and noise components. This report will be printed for the first frequency and each <i>interval</i> frequency. (Default: 0)

.op

Performs a DC operating point calculation and outputs all node voltages and voltage source currents.

- DC operating points are calculated on the assumption that there are no charge effects in the system: capacitors are open and inductors are shorted.
- The ".hdl" (page 81) command can be used to impose initial conditions on nodes. Initial conditions are represented by voltage sources present for the duration of the DC operating point calculation, and removed for transient simulations.
- The ".nodeset" (page 103) command can be used to set initial guesses for the iterative solution process for DC operating points.
- The results of the **.op** command are written automatically to the specified output file. Other results can be reported with the "**.print**" (page 122) **dc** command.
- Small-signal transfer function data can be reported with the ".tf" (page 147) command.

Syntax

.op [noprint]

noprint

Turns off automatic **.op** output.

.optgoal

Note that during an optimization run, all **.optgoal** commands with the same **optname** are used as optimization results, in addition to any measurements specified in the results list on the sweep optimize syntax of a **.step** or one of the analysis commands. (See the following example.)

If the .measure command does not exist in the netlist, an error message will be returned.

The formula for optimization functions is:

$$\sum_{k} \left(W_k \cdot \frac{(G_k \ge M_k)}{max(minval, |G_k|)} \right)^2$$
(5.3)

where Wk is the weight, Gk is the goal, and Mk is the measurement value.

Syntax

.optgoal optname measname=goal [minval=minval] [weight=weight]

optname	Name of the optimization run.
measname	A .measure result to be used as the goal.
goal	Optimization goal value.
minval	The minimum denominator value for the optimization error computation. Defaults to the value in the .measure command identified by measname , or if not specified there, to1.0e-12.
weight	A relative importance of the optimization goal with respect to other goals for the same optimization run. Defaults to the value in the .measure command identified by measname , or if not specified there, to1.

Examples

.ac dec 10 1 100k sweep optimize=opt1 results=gain model=optmod .measure ac gain max vdb(out) goal=30 .measure ac bandwidth when vdb(out)=10 .optgoal opt1 bandwidth=5k

results in both the gain and bandwidth measurements contributing to the overall optimization goal.

.optimize

Invokes an optimization run using parameters and goals specified using **.paramlimits** and **.optgoal** commands with the same **optname**.

.ac, .dc, .step and .tran use the parameter analysis to identify analysis commands from the .optimize command. However, it is possible to avoid assigning an analysis name. If the analysis name on the .optimize command is the name of an analysis type ("ac", "tran", "dc", or "step",) and no analysis of that name exists, T-Spice will perform the optimization on the first analysis of that type. (See "Examples" on page 107.)

Syntax

.optimize optname model=modelname analysis=analysisname		
optname	Name of the optimization run.	
modelname	Refers to a .model command of type opt which specifies optimization algorithm parameters such as iteration count limits and convergence tolerances.	
analysisname	Identifies a .step, .ac, .dc, or .tran command of the same name that will be performed to evaluate the measurements for the optimization.	

Examples

.ac dec 10 1 100k analysisname=ac1 .optimize opt1 model=optmod analysisname=ac1

invokes an optimization around an AC analysis. This AC analysis optimization syntax is equivalent to:

```
.ac dec 10 1 100k
.optimize opt1 model=optmod analysisname=ac
.param r=1k c=1u
r1 1 0 'r'
c1 1 0 'c'
.options autostop reltol=1e-6
.ic v(1)=1
.tran 0.1m 100m
.print tran v(1)
.measure tran decaytime when v(1)=0.5
```

Optimization commands:

```
.optimize opt1 model=optmod analysisname=tran
.model optmod opt level=1 itropt=40
.optgoal opt1 decaytime=300u
.paramlimits opt1 r minval=10 maxval=100k
.paramlimits opt1 c minval=0.01u maxval=100u
.end
```

This is a transient analysis of a simple RC circuit. The **.measure** command measures the amount of time it takes for the voltage at node 1 to decay to half its initial value. Theoretically, this decay time is equal to R*C*In(2). The **.optimize** command invokes an optimization run called **opt1**. The **.optgoal**

command sets the optimization goal (**300u**sec) for the decay time, and the **.paramlimits** commands specify ranges for the **R** and **C** parameters.

During the optimization run, \mathbf{R} and \mathbf{C} can be varied within their ranges in order to achieve the decay time goal of 300 microseconds. The output for this simulation is as follows:

Optimized parameter values:

```
r = 6.5783e+02
c = 6.5775e-07
```

```
* END NON-GRAPHICAL DATA
```

```
*WEDIT: .tran 0.0001
                          0.1
TRANSIENT ANALYSIS - OPTIMIZE=opt1
Time<s>
               v(1)<V>
   0.0000e+00 1.0000e+00
   1.9207e-08 9.9996e-01
   1.8027e-06 9.9584e-01
   3.4447e-06 9.9207e-01
              9.5994e-01
   1.7692e-05
              9.4109e-01
   2.6271e-05
   3.4134e-05
               9.2415e-01
   4.2453e-05
               9.0655e-01
   5.3935e-05
               8.8281e-01
               8.4953e-01
   7.0558e-05
   8.9536e-05
               8.1308e-01
   1.2194e-04
               7.5440e-01
   1.5149e-04
               7.0461e-01
   1.8663e-04
              6.4965e-01
   2.2571e-04
               5.9354e-01
   2.6455e-04
              5.4257e-01
              4.9745e-01
   3.0212e-04
```

```
* BEGIN NON-GRAPHICAL DATA
```

MEASUREMENT RESULTS - OPTIMIZE=opt1

decaytime = 3.0000e-04

* END NON-GRAPHICAL DATA

Note that the optimized **R** and **C** values achieve the optimization goal of **300u**. This is consistent with theoretical prediction: for the optimized **R** and **C** values of 657.83 Ohms and 657.75 nanofarads, the theoretically predicted decay time is 299.92 microseconds.

.options

Syntax

.options field=X [field=X ...]

Fields that toggle actions on or off can be specified as **true/false**, **t/f**, **1/0**, or **yes/no**. Specifying a **true/false** field without a value automatically sets the field to **true**.

Option fields are described in detail in the following chapter, "Simulation Options" on page 205. The following tables list a summary of simulation options; click on the option name for a full description.

Accuracy and Convergence Options

Field	Description	Default
"absi abstol " (page 207)	Maximum allowed RMS of residual branch currents when kcltest = true .	$1 \times 10^{-10} \mathrm{A}$
"absv vntol " (page 208)	Maximum absolute node voltage change allowed between iterations when kvitest = true .	$1 \times 10^{-6} \mathrm{V}$
"accurate" (page 209)	Triggers changes to other option settings to maximize simulation accuracy.	false
"bypass " (page 210)	Controls the diode and transistor bypass algorithm	true
"bytol" (page 211)	Sets the relative tolerance for the bypass algorithm terminal voltage values	0.0
"cshunt" (page 212)	Capacitance added from each node to ground.	0.0 F
"dchomotopy " (page 213)	Algorithm used to correct DC operating point non- convergences. Can be set to none , source , gmin , pseudo , or all .	all
"dcmethod " (page 215)	Default method for solving a DC operating point problem. Can be set to standard , source , gmin , or pseudo .	standard
"dcstep" (page 216)	Controls the conductance added across the terminals of each capacitor during DC operating point computation. $(g=c/dcstep)$, where <i>c</i> is the device capacitance.)	0.0
"extraiter[ations] newtol" (page 217)	Number of additional iterative steps to calculate after convergence criteria have been met.	0
"fast" (page 218)	Triggers changes to other options settings to maximum simulation speed.	false
"gmin " (page 219)	Conductance added in parallel with all <i>pn</i> junctions during transient analysis.	$1 \times 10^{-12} \Omega^{-1}$
"gmindc" (page 220)	Conductance added in parallel with all <i>pn</i> junctions during DC operating point analysis.	$1\times 10^{\text{-}12}\Omega^{\text{-}1}$

Field	Description	Default
"gramp" (page 221)	Specifies the range over which the gmindc variable is swept during g_{min} stepping. (gmindc $\leq g_{min} \leq$ gmindc $\times 10^{gramp}$)	4
"gshunt" (page 222)	Conductance added from every node to ground.	0.0 Ω ⁻¹
"kcltest" (page 223)	Enables the current tolerance test for convergence.	true
"kvitest " (page 224)	Enables the voltage tolerance test for convergence in transient analysis (always true for DC analysis).	false
"maxdcfailures " (page 225)	Maximum number of non-convergence failures allowed in a DC sweep simulation.	4
"mindcratio " (page 226)	Minimum fractional step size allowed in source ramping for DC sweep analysis.	1 × 10 ⁻⁴
"minsrcstep " (page 227)	Minimum fractional step size for source stepping in DC operating point analysis.	1 × 10 ⁻⁸
"numnd itl1 " (page 228)	Newton iteration limit for DC operating point computation.	250
"numndset " (page 229)	The maximum number of Newton iterations during which the .nodeset nodes will be held at their user-specified voltage values.	numnd / 10
"numns itl6 " (page 230)	Newton iteration limit for source stepping attempts in DC operating point analysis.	50
"numnx itl2 " (page 231)	Newton iteration limit for DC sweep computation.	100
"numnxramp " (page 232)	Newton iteration limit for DC sweep computation during source ramping.	50
"precise" (page 233)	Triggers changes to other options settings to maximize simulation precision.	false
"reli reltol " (page 235)	Maximum relative change in RMS branch current allowed between iterations when kcitest = true .	5 × 10 ⁻⁴
"relv " (page 236)	Maximum relative change in node voltage allowed between iterations when kvitest = true .	1 × 10 ⁻³

Timestep and Integration Options

Field	Description	Default
"absdv absvar " (page 238)	Threshold absolute voltage change between two consecutive time steps; used to calculate voltage variance when $lvltim=1 3 4$.	0.5 V
"absq chgtol chargetol" (page 239)	Minimum capacitor charge or inductor flux used to compute Local Truncation Error for timestep control (lvltim= 2).	$1 \times 10^{-14} \mathrm{C}$
"ff " (page 240)	Fraction by which the timestep is reduced if a transient analysis solution does not converge within <i>numnt</i> iterations.	0.25

Field	Description	Default
"lvltim" (page 241)	Algorithm used to control timestep sizes in transient analysis: 1 = Iteration count algorithm with voltage variance test 2 = Local Truncation Error algorithm 3 = Iteration count algorithm with voltage variance and timestep reversal 4 = voltage variance test for timestep prediction plus Local Truncation Error algorithm for timestep reversal (hybrid of lvltim 1 and 2)	1
"maxord" (page 244)	Maximum time integration order for Gear's BDF calculation.	2
"method" (page 245)	Method of numerical integration for estimating time derivatives of charge during transient analysis.	trap
" mintimeratio rmin " (page 246)	Relative minimum timestep size for transient simulations.	1 × 10 ⁻⁹
"mu xmu " (page 247)	Coefficient for varying integration between the backward Euler formula and the trapezoidal formula. Used when method = trap .	0.5
"numnt itl4 imax" (page 248)	Newton iteration limit for transient analysis solutions.	10
"numntreduce itl3" (page 249)	Threshold number of Newton iterations for controlling decrease or increase of the next timestep.	3
"poweruplen " (page 250)	Length of the powerup ramp during powerup transient analysis.	0.1% total . tran time
"reldv relvar " (page 251)	Maximum relative voltage change between time steps; used to calculate the voltage variance when $ v tim = 1 3$.	0.35
"relq relchgtol " (page 252)	Maximum relative error in predicted charge; used to adjust timestep sizes in the LTE algorithm (IvItim = 2).	5×10^{-4}
"rmax" (page 253)	Maximum allowed timestep, given as a multiple of the timestep specified with .tran .	2
"trextraiter[ations] trnewtol" (page 254)	Number of additional iterative steps to calculate at each timestep after convergence criteria have been met	0
"trtol " (page 255)	Corrective factor for estimation of the local truncation error (LTE) when lvltim =2.	10

Model Evaluation Options

Field	Description	Default
"dcap " (page 257)	Model selector for calculating depletion capacitances.	2
"dccap" (page 258)	Flag to compute device charge and capacitance values in DC analysis	false
"defad" (page 259)	Default MOSFET drain diode area.	$0.0 \ {\rm m}^2$
"defas" (page 260)	Default MOSFET source diode area.	0.0 m ²

Field	Description	Default
" defl " (page 261)	Default MOSFET channel length.	$1 \times 10^{-4} \text{m}$
"defnrd" (page 262)	Default number of diffusion squares for a MOSFET drain resistor.	0.0
"defnrs" (page 263)	Default number of diffusion squares for a MOSFET source resistor.	0.0
"defpd" (page 264)	Default MOSFET drain diode perimeter.	0.0 m
"defps" (page 265)	Default MOSFET source diode perimeter.	0.0 m
"defw" (page 266)	Default MOSFET channel width.	$1 \times 10^{-4} \text{m}$
"deriv" (page 267)	Selects the method for computing dq/dv and di/dv derivatives.	0
"minresistance resmin" (page 268)	Minimum (floor) resistance value for all resistors.	$1 \times 10^{-5} \Omega$
"moscap" (page 270)	Enables automatic source/drain area/perimeter estimation for MOSFETs.	false
"scale" (page 272)	Scales the physical dimensions of capacitors, MESFETs, MOSFETs, and resistors.	1.0
"scalm" (page 273)	Default scaling factor for resistors and capacitors.	1.0
"tnom " (page 274)	Nominal temperature.	25 deg. C
"wl " (page 275)	Reverses MOSFET length and width specifications.	false

Linear Solver Options

Field	Description	Default
"linearsolver " (page 277)	Selects the linear equation solver — best , sparse , or superlu .	best
"pivtol" (page 278)	Minimum pivoting tolerance for real matrices.	1×10^{-14}
" zpivtol " (page 279)	Minimum pivoting tolerance for complex matrices.	1×10^{-6}

General Options

Field	Description	Default
"autostop" (page 281)	Terminates transient analysis after all .measure results have been found.	false
"casesensitive" (page 282)	Case sensitivity for names of models, subcircuits, library sections, parameters, and nodes.	false
"compatibility" (page 283)	Specifies input syntax and option setting compatibility with other simulators - Berkeley SPICE, HSPICE, or PSPICE.	HSPICE
" conncheck " (page 284)	Enables connectivity checking.	true

Field	Description	Default
"parhier " (page 285)	Establishes the scoping algorithm for selection of parameter values in a hierarchical design.	local
"persist" (page 287)	Instructs T-Spice to continue simulation when the specified levels of warnings or errors are generated.	1
"search" (page 288)	Search path for library and include files.	
"spice " (page 289)	Changes other option settings to be compatible with Berkeley SPICE.	false
"threads" (page 290)	Enables parallel processing.	0
"vasearch" (page 324)	Search path for locating Verilog-A files.	

Output Options

Field	Description	Default
"acct" (page 292)	Tracks and reports iteration counts and other accounting statistics.	false
"acout " (page 293)	Calculation method for AC magnitude/phase differences.	1
"brief" (page 294)	Minimizes the amount of diagnostics printout which is written to the simulation status window.	false
"captab" (page 295)	Lists capacitances for each node in the netlist.	false
"csdf" (page 296)	Generates output in CSDF mode.	false
"dnout" (page 297)	Selects noise spectral density units.	0
"echo" (page 298)	Causes T-Spice to print each line of input to the error log as it is read.	false
"expert" (page 299)	Produces a listing of node and device convergence residual information.	false
"ingold" (page 300)	Controls the format of numbers printed in the AC small- signal output and the device listings. (0=engineering format, 1=g format, 2=e format)	0
"list" (page 301)	Produces a listing of all circuit devices.	false
"maxmsg" (page 302)	Sets the maximum number of duplicate warning message printouts.	5
"node" (page 303)	Prints a node cross-reference table.	false
"nomod" (page 304)	Controls the printout of diode and transistor models. Set nomod to 1 (true) to disable printout.	1
"numdgt" (page 305)	Minimum number of decimal places included in each .print output value.	4
"nutmeg" (page 306)	Generates output compatible with the <i>Nutmeg</i> graphics program.	false
"opts" (page 307)	Prints the settings of all control options.	false
"outputall" (page 308)	Causes all listings of nodes, devices, or options to include items that are internal or normally hidden to the user.	false
"pathnum" (page 309)	Prefixes subcircuit node and element names with a number rather than the full subcircuit path name.	false
"prtdel" (page 310)	Fixed time delay between output points in transient analysis.	0.0 s
"prtinterp" (page 311)	Determines how solutions are calculated at time intervals set by prtdel .	0
"statdelay" (page 312)	Minimum delay (real time) between status display updates in the T-Spice GUI.	0.5 s
"tabdelim" (page 313)	Toggles tab-delimited output columns.	false
"verbose" (page 314)	Level of circuit and simulation detail printed to the Simulation Window.	1

Field	Description	Default
" xref " (page 315)	Generates a listing of various circuit cross-reference information: conditional statement tree, symbol definitions, subcircuit listings.	false

Probing Options

Field	Description	Default
"binaryoutput " (page 317)	Specifies the form of binary output created with .probe.	3
"probei " (page 318)	Includes device terminal current values in the output data from .probe and .print (when used without arguments).	false
"probeq" (page 319)	Includes device terminal charge values in the output data from .probe and .print (when used without arguments).	false
"probev" (page 320)	Includes node voltage values in the output data from .probe and .print (when used without arguments).	false
" probefilename " (page 321)	Filename for binary output produced by .probe .	<i>outputfile</i> .dat

.param

•	Parameters can be used in expressions to replace numeric values.
•	.param statements are sequential. A parameter must be defined before it is used in the expression of another parameter value.
	User-defined functions are very similar to the set of built-in algebraic functions. User-defined

Defines and assigns values to parameters, or creates a user-defined function.

- functions may take any number of arguments, and are defined using an algebraic expression which performs operations on the function arguments.
- The scope of defined parameters extends to files referenced by ".if ... / .elseif ... / .else / .endif" (page 84) commands.
- Parameters placed in subcircuit definition blocks are valid only within that subcircuit definition, and override global parameters of the same name.
- Parameters placed outside subcircuit definition blocks are valid globally.

Note:

To view a listing of all parameters that are defined in the input files, use the command .option xref.

Syntax

```
param parameter={X |mc_distribution|opt_limits}[[,]
    {X |mc_distribution|opt_limits} ...]
```

parameter	Parameter name.
x	Any number or valid expression. Expressions must be enclosed by single quotes.
mc_distribution	Defines probability distributions used in Monte Carlo iterations. For additional information, see Monte Carlo Parameters, below.
opt_limits	Defines optimization parameters. For additional information, see "Optimization Parameters" on page 118.

User-Defined Functions

The syntax for defining a function is:

.param funcname([arg1 [, arg2 [, arg3 [...]]])='body'

funcname	The name of the user function, which may not be the same as a built- in algebraic function, or the same as a parameter name.
arg1 arg2	Function arguments which will be passed into the function from the function reference.
body	An algebraic expression which solves the functional equation.

Monte Carlo Parameters

For each Monte Carlo iteration, T-Spice will report the values of all expressions evaluated using probability distributions defined by the following syntax:

```
.param parameter=unif(nominal_val, rel_variation [, multiplier])
or
.param parameter=aunif(nominal_val, abs_variation [, multiplier])
or
.param parameter=gauss(nominal_val, rel_variation, sigma [, multiplier])
or
```

```
.param parameter=agauss(nominal_val, abs_variation, sigma [, multiplier])
```

```
or
```

```
.param parameter=limit(nominal_val, abs_variation)
```

parameter	Name of the parameter to be varied in the Monte Carlo analysis.
unif	Selects a uniform distribution with relative variation specification.
aunif	Selects a uniform distribution with absolute variation specification
gauss	Selects a Gaussian distribution with relative variation specification.
agauss	Selects a Gaussian distribution with absolute variation specification.
limit	Selects a random limit distribution function using absolute variation. The result is either nominal_val-abs_variation or nominal_val+abs_variation , with 50% probability for each.
nominal_val	Nominal value for the parameter.
abs_variation	Largest deviation from <i>nominal_val</i> that can be obtained from a uniform or limit distribution, or the standard deviation multiplied by <i>sigma</i> for a Gaussian distribution.
rel_variation	Relative variation specification. The corresponding absolute variation is <i>rel_variation*nominal_val</i> .
sigma	Sigma-level at which the absolute or relative variation is specified for a Gaussian distribution. For example, if sigma =3, the standard deviation is abs_variation /3.
multiplier	Number of times the distribution function is evaluated. The largest deviation from the nominal value of all evaluations is the one that is used as the result. The resulting distribution is bimodal. (<i>Default</i> : 1.)

Note:

Multiple parameters can be assigned on the same **.param** command. Probability distributions are reevaluated with every use of **paramname** in expressions.

Optimization Parameters

When **.param** is used to define optimization parameters, the **parameter** argument uses the following syntax:

.param parameter=optname(guess, min, max [, delta])

parameter	Global parameter name.
name	References a particular optimization run name.
guess	Initial (nominal) value for the parameter.
min	Minimum values the parameter can take on.
max	Maximum values the parameter can take on.
delta	Used for discrete optimization. The final parameter values must differ from the initial guess by an integer multiple of <i>delta</i> . This is useful for optimizing quantities that can only take on discrete values, such as transistor lengths and widths.

Note: Multiple optimization parameters can be assigned on the same **.param** command.

The parameter *parameter* is allowed to vary within its range when an optimization of the appropriate **name** is invoked on an analysis command. During such an optimization, the parameter is initially assigned its **guess** value, but is allowed to vary within its range (defined by **min** and **max**) during subsequent optimization iterations.

For additional information on the optimization syntax for individual analysis commands, see ".ac" (page 61), ".dc" (page 72), or ".tran" (page 148).

Examples

```
.param pi='4*atan(1)' tf='1E-6*sin(pi/2))'
.tran 'tf*0.01' 'tf'
```

The **.param** command defines and assigns a value to parameter **tf**, which is subsequently used (enclosed by single quotes) in place of a numeric value in the "**.tran**" (page 148) command.

```
.param res=agauss (100, 10, 1)
```

Specifies that the resistance is chosen from a normal distribution of mean 100 and standard deviation 10.

.param w1=opt1 (10u, 2u, 20u, 0.25u)

Specifies that **w1** is to be varied in optimization run **opt1** within the limits 2×10^{-6} and 20×10^{-6} . The initial guess for **w1** in the optimization is 10×10^{-6} , and the final value will be a multiple of 0.25×10^{-6} .

```
.param safedivision(a,b)='if(abs(b)<1e-100, 1e100, a/b)'
.print tran impedance='safedivision(v(n1), i1(dev1))'</pre>
```

Creates a function named safedivision which divides one number by another without a *division by zero* error. This function is then used in a print expression.

.paramlimits

Sets optimization parameter ranges. Allows the same parameter to be varied in multiple optimizations with different optimization run names.

This command specifies that the parameter **paramname** (specified using **.param** elsewhere) is to be varied and optimized during an optimization run **optname**. Multiple instances of **.paramlimits** may not exist in the netlist for the same optimization run and the same parameter name, but are allowed for the same **optname** but for different **paramname** values.

Note:

T-Spice supports sequential optimization—multiple optimizations may be performed in series from one input file, and the optimization results used in subsequent optimizations.

Syntax

.paramlimits optname p [delta=delta]	aramname [guessval= guess] minval= min maxval= max
optname	Name of the optimization run.
paramname	References a particular parameter.
guess	Initial (nominal) parameter value for the optimization. If not used, the initial value defaults to the value specified in the .param command.
min	Minimum value of the range in which the parameter may vary.
max	Maximum value of the range in which the parameter may vary.
delta	If specified, the parameter can change only in integer multiples of this value. This is useful for optimizing quantities which can only take on discrete values, such as transistor lengths and widths.

Examples

.paramlimits opt1 r minval=10 maxval=100k .paramlimits opt1 m1width minval=1u maxval=10u delta=0.25u

.power

Computes power dissipation in conjunction with transient analysis.

- If the ".tran" (page 148) command is missing from the input file, the .power command is ignored.
- The average power consumption, the instantaneous maximum power, and the instantaneous minimum power (in watts) and the times of maximum and minimum power consumption (in seconds) are reported at the end of the transient simulation.
- The instantaneous power P(t) dissipated by a voltage source at time t is the current through the source multiplied by the voltage drop across the source. The average power P for a time interval (t1,t2) is computed by using the trapezoidal rule approximation to evaluate the integral

$$\overline{P}(t_1, t_2) = \frac{1}{t_1 \angle t_2} \int_{t_1}^{t_2} P(\tau) d\tau$$
(5.4)

- Multiple .power commands can be used in a single simulation.
- Power results can also be reported with the ".print" (page 122) tran command.

Syntax

.power source [A [Z]]	
source	Voltage source whose power consumption is to be computed.
Α	Time at which power recording begins. (Unit: seconds. Default: simulation start time.)
Z	Time at which power recording ends. (Unit: seconds. Default: simulation end time.)

Examples

.power vtest 3e-7

Computes the power dissipated by voltage source **vtest** between the given time (0.3 microsecond) and the end of the simulation. It might produce the following sample output:

```
Power Results
vtest from time 0 to 3e-007
Average power consumed -> 1.249948e-002 watts
Max power 2.490143e-002 at time 9.76e-006
Min power 2.282279e-030 at time 1e-005
```

.print

Reports simulation results.

- If an output filename is not specified, the output file specified in the Start Simulation dialog is used. (If that file cannot be opened, the results are written to the Simulation Window.)
- Multiple .print commands can be used to direct different types of output to separate files.
- Transient analysis results are printed in columns, with time values in the first column.
- AC and noise analysis results are printed in columns, with frequency values in the first column.
- DC transfer analysis results are printed in columns, with sweep values from the first source listed on the ".dc" (page 72) command in the first column.
- DC operating point analysis results are printed line by line, each argument to a line.
- Expressions can be printed by themselves, with or without reference to physical quantities at specific nodes.
- Nodes and devices within subcircuits can be accessed with hierarchical notation in the form xinstance.xinstance.node.
- .print commands inside subcircuit definition blocks are replicated for each instance.
- If no arguments are given, all node voltages and source currents are printed. If neither mode or arguments are given, **.print** applies to all analysis types. If arguments are given, a mode must also be specified.
- Wildcards may be entered as part of the **.print** command node names, devices names, terminal names, or terminal numbers. Wildcards are expanded to match any available elements which match the name specification.
- Device State print statements are a means of obtaining very detailed information about devices and device internal states. Data such as the current, charge, capacitance, and voltage values can be listed, as well as certain model evaluation variable (threshold voltage, beta, etc.).

Syntax

<pre>.print [mode] ["filename"] [arguments]</pre>		
mode	Analysis mode (see below).	
filename	Output filename. Must be enclosed by double quotes.	
arguments	Information to be printed (see below). <i>arguments</i> may include valid expressions involving other arguments or global parameters.	
<i>mode</i> is one of the following:		
tran	Print results from transient analysis.	
dc	Print results from DC transfer analysis and DC operating point analysis.	
ac	Print results from AC analysis.	
noise	Print results from noise analysis.	

.print

arguments take one or more of a number of values, depending on *mode*. When no arguments are given, all node voltages and source currents are printed.

When an argument includes an expression, the expression must be enclosed by single quotes (''). A string can also be used as a column heading in the output file, and the string can be followed by an optional unit specifier, enclosed by angle brackets (<>). The unit is then displayed on the W-Edit *y*-axis.

Some entries in the argument tables below involve the variable z, to be replaced by a key letter or number representing a device terminal. The key letters and numbers corresponding to particular device terminals are as follows (alternatives are separated by slashes):

- Diodes: anode = P/1; cathode = N/2.
- BJTs: collector = C/1; base = B/2; emitter = E/3; substrate = S/4.
- JFETs/MESFETs: drain = D/1; gate = G/2; source = S/3.
- MOSFETs: drain = D/1; gate = G/2; source = S/3; bulk = B/4.

Wildcards provide an easy and compact method of printing a large number of node or device values which have related names. The T-Spice **.print** command supports several types of wildcards in the specification of the node name, device name, terminal number, and terminal name. The '*' character (asterisk) will be expanded to match any combination of alpha-numeric characters. The '?' character (question mark) will be expanded to match any single alpha-numeric character. And, '[...]' will be expanded to match any single character enclosed within the square brackets.

The arguments for transient, transfer, and DC analysis (.print tran, .print dc) are as follows.

n	Voltage at node <i>n</i> relative to ground.
i(<i>d</i> , <i>n</i>)	Current at node <i>n</i> of device <i>d</i> (inward current positive).
iz(d)	Current at terminal \boldsymbol{z} of device \boldsymbol{d} (inward current positive).
p(<i>d</i>)	Power consumed by voltage source <i>d</i> . This result can also be reported with the .power command.
q(<i>d</i> , <i>n</i>)	Charge at node <i>n</i> of device <i>d</i> .
qz(<i>d</i>)	Charge at terminal z of device d .
v(n1[[,]n2])	Voltage at node n1 relative to node n2 . (Default reference node: ground.)
'time()'	Simulation time. Must be or be part of an expression enclosed by single quotes. (Transient analysis only.)

The *arguments* for AC analysis mode (.print ac) are as follows.

idb(<i>d</i> , <i>n</i>)	Current magnitude at node <i>n</i> of device <i>d</i> . (Unit: decibels.)
idb <i>z(d</i>)	Current magnitude at terminal z of device d . (Unit: decibels.)
ii(<i>d</i> , <i>n</i>)	Imaginary component of the complex current at node \boldsymbol{n} of device \boldsymbol{d} .
iiz(d)	Imaginary component of the complex current at terminal \mathbf{z} of device \mathbf{d} .

im(<i>d</i> , <i>n</i>)	Current magnitude at node <i>n</i> of device <i>d</i> .
im <i>z(d</i>)	Current magnitude at terminal z of device d .
ip(<i>d</i> , <i>n</i>)	Current phase at node <i>n</i> of device <i>d</i> .
ip <i>z(d</i>)	Current phase at terminal z of device d .
ir(d,n)	Real component of the complex current at node \boldsymbol{n} of device \boldsymbol{d} .
irz(d)	Real component of the complex current at terminal z of device d .
vdb(n1[[,]n2])	Voltage magnitude at node n1 relative to node n2 (Unit: decibels. Default reference node: ground.)
vi(n1[[,]n2])	Imaginary component of the complex voltage at node n1 relative to node n2 . (Default reference node: ground.)
vm(<i>n1</i> [[,] <i>n2</i>])	Voltage magnitude at node n1 relative to node n2 . (Default reference node: ground.)
vp(<i>n1</i> [[,] <i>n2</i>])	Voltage phase at node <i>n1</i> relative to node <i>n2</i> . (Default reference node: ground.)
vr(n1[[,]n2])	Real component of the complex voltage at node <i>n1</i> relative to node <i>n2</i> . (Default reference node: ground.)
'frequency()'	AC frequency. Must be or be part of an expression enclosed by single quotes.

The *arguments* for noise analysis mode (.**print noise**) include *any* of the arguments for AC analysis mode *in addition* to the following:

dn(<i>d</i> [, <i>t</i>])	Output noise spectral density contributions corresponding to the noise sources associated with device d . If the noise type t (see below) is not specified, then results for all applicable noise types are printed.
inoise	Equivalent input noise spectral density magnitude. (Unit: volts/ $\sqrt{\text{Hertz}}$.)
inoise(db)	Equivalent input noise spectral density magnitude. (Unit: decibels.)
inoise(tot)	Total input noise—the integral of the input noise spectral densities over the analysis frequency interval. (Unit: volts.)
onoise	Output noise spectral density magnitude (Unit: volts/ \sqrt{Hertz} .)
onoise(db)	Output noise spectral density magnitude. (Unit: decibels.)
onoise(tot)	Total output noise—the integral of the output noise spectral densities over the analysis frequency interval. (Unit: volts.)
transfer	AC transfer function between input and output. As the frequency approaches zero, this value approaches the result from the .tf command. (Unit: volts /ampere, for transresistance; or no unit, for voltage gain.)

The units for the **.print noise dn(***d***,** *t***)** command are volts/ $\sqrt{\text{Hertz}}$ by default. However, this can be changed to Volts²/Hertz by use of the option "dnout" (page 297).

The noise types **t** available for the **.print noise dn(***d***,** *t***)** command vary according to the device type (BJT, Diode, JFET, etc.) as shown in the following tables:

noise type	BJT (Gummel-Poon) Noise Types description	
FN	Flicker noise due to base current	
IB	Shot noise due to base current.	
IC	Shot noise due to collector current.	
RB	Thermal noise due to base resistance.	
RC	Thermal noise due to collector resistance.	
RE	Thermal noise due to emitter resistance.	
RX	Transresistance from flicker noise source to output.	
тот	Total device output noise.	

BJT (VBIC) Noise Types

noise type	BJT (VBIC) Noise Types description
IBE	Base-Emitter shot noise
IBEFN	Base-Emitter flicker noise
IBEP	Parasitic base-emitter shot noise
IBEPFN	Parasitic base-emitter flicker noise
ICCP	Parasitic base-collector shot noise
ITZF	Forward transport current shot noise
RBI	Thermal noise due to intrinsic base resistance
RBP	Thermal noise due to parasitic base resistance
RBX	Thermal noise due to extrinsic base resistance
RCI	Thermal noise due to intrinsic collector resistance
RCX	Thermal noise due to extrinsic collector resistance
RE	Thermal noise due to emitter resistance
RS	Thermal noise due to source resistance
RX	Transresistance from flicker noise source to output.
тот	Total device output noise.

noise type	Diode Noise Types description
FN	Flicker noise
ID	Shot noise.
RX	Transresistance from flicker noise source to output.
тот	Total device output noise.

JFET and MESFET Noise Types noise type description FN Flicker noise. ID Thermal noise due to channel. RD Thermal noise due to drain resistance. RG Thermal noise due to gate resistance. RS Thermal noise due to source resistance. RX Transresistance from flicker noise source to output. тот Total device output noise.

noise type	MOSFET Noise Types description
FN	Flicker noise.
ID	Thermal noise due to channel.
RD	Thermal noise due to drain resistance.
RG	Thermal noise due to gate resistance.
RS	Thermal noise due to source resistance.
RX	Transresistance from channel or flicker noise source to output.
тот	Total device output noise.

Examples

.print tran in out i1(r2) id(M2)

Prints transient analysis results: the voltages at nodes in and out and the currents into terminal 1 of device r2 and the drain terminal of device M2.

.print dc I10/in, I10/out, I11/in, I11/out

.print ac "acdata" im(M2,g1) vm(out) vdb(out)

Writes AC analysis results to output file **acdata**: the magnitude of the current flowing into node **g1** of device **M2**, the magnitude of the voltage at node **out**, and the same magnitude expressed in decibels.

.print noise inoise transfer dn(mn1) onoise(tot)

Prints noise analysis results: the equivalent input noise spectral density, the input/output transfer function, all noise information corresponding to device **mn1**, and the total output noise.

```
.print tran 'v(out)*sin(time()*sf)'
```

Prints the transient value of an expression involving the voltage at node **out**, the simulation time **time()**, and parameter **sf** (defined elsewhere with a **.param** command).

```
.print tran diff<V>='v(2)-v(1)'
```

Prints the transient value of an expression subtracting the voltage at node 1 from the voltage at node 2. The string **diff** is used as a column heading with the letter V as a unit designation.

.print

Prints all node voltages and voltage source currents for all analyses to a text file.

```
.print tran
```

Prints all node voltages and voltage source currents for transient analysis to a text file.

```
.print v(n*)
```

Prints the voltages for all nodes whose name begins with the letter 'n'.

.print i[12](m*) i?(q*)

Prints the drain and gate currents (terminals 1 and 2) for every MOSFET device, and each terminal current for every BJT.

The format of the device state plot request is always *state(d)*, where *state* is the state data identifier, and *d* is the device name.

The device state data which is available for each device type is as follows:

state identifier	description
cap_be	cbe capacitance
cap_ibc	internal base-collector capacitance
cap_sbc	csc/csb substrate-collector/substrate-base capacitance
cap_xbc	external base-collector capacitance
cbo	base current
ссо	collector current
cexbc	base-collector equivalent current
cqbc	current due to the base-collector charge
cqbe	current due to the base-emitter charge
cqbx	current due to the base-internal base charge
cqcs	current due to the collector-substrate charge
g0	∂ic/∂vce
gm	∂ic/∂vbe
gpi	∂ib/∂vbe
gu	∂ib/∂vbc
isub	substrate current
qbc	base-collector charge
qbe	base-emitter charge
qbx	base-internal base charge
qcs	collector-substrate charge
rb	base resistance
rgn	operating region: -2=inverse, -1=saturation, 0=off, 1=on
vbc	base-collector voltage
vbci	rb and rc offset internal base-collector voltage
vbe	base-emitter voltage
vbei	rb and re offset internal base-emitter voltage
vsub	substrate voltage

	BJT (Gummel-Poon)	Device State	printout identifiers
~	decomination		-

BJT state identifier	(VBIC) Device State printout identifiers description
cbco	parasitic Base-Collector overlap capacitance (fixed)
cbeo	parasitic Base-Emitter overlap capacitance (fixed)
cqbc	Base-Collector charge current
cqbco	currents from Cbco charge
cqbcp	currents from Cbcp charge
cqbcx	currents from Cbcx charge
cqbe	Base-Emitter charge current
cqbeo	currents from Cbeo charge
cqbep	currents from Cbep charge
cqbex	currents from Cbex charge
cqcxf	currents from Ccxf charge
flxf	Excess phase circuit flux
ibc	intrinsic Base-Collector current
ibcp	parasitic Base-Collector current
ibe	intrinsic Base-Emitter current
ibep	parasitic Base-Emitter current
ibex	extrinsic Base-Emitter current
igc	weak avalanche current
irbi	intrinsic Base resistor modulated current
irbp	parasitic Base resistor modulated current
irbx	external Base resistor current
irci	intrinsic Collector resistor modulated current
ircx	external Collector resistor current
ire	external Emitter resistor current
ith	thermal (heat generation) source, power dissipation
itxf	forward transport current, with excess phase
itzf	forward transport current, zero phase
itzr	reverse transport current, zero phase
ixxf	forward transport current, with excess phase
ixzf	forward transport current, with excess phase
qbc	Base-Collector charge
qbco	parasitic Base-Collector charge (depletion)

state identifier	BJT (VBIC) Device State printout identifiers description
qbcp	parasitic Base-Collector charge (depletion)
qbcx	parasitic Base-Collector charge (depletion)
qbe	Base-Emitter charge
qbeo	parasitic Base-Emitter charge (depletion and diffusion)
qbep	parasitic Base-Emitter charge (depletion and diffusion)
qbex	extrinsic Base-Emitter charge (depletion)
qcxf	Excess phase circuit capacitance
rbi	intrinsic Base resistance (modulated)
rbip	parasitic Base resistance (modulated)
rbx	extrinsic Base resistance (fixed)
rci	intrinsic Collector resistance (modulated)
rex	extrinsic Collector resistance (fixed)
re	Emitter resistance (fixed)
rgn	operating region
rs	Substrate resistance (fixed)
vb	Base voltage
vbc	Base-Collector voltage
vbci	Rb and Rc offset internal Base-Collector voltage
vbe	Base-Emitter voltage
vbei	Rb and Re offset internal Base-Emitter voltage
vbi	Bi internal Base voltage
vbp	Bp parasitic Base voltage
vbx	Bx external Base voltage
vc	Collector voltage
vci	Ci internal Collector voltage
vcx	Cx external Collector voltage
ve	Emitter voltage
vei	Ei internal Emitter voltage
VS	Substrate voltage
vsi	Si internal Substrate voltage

state identifier	description
ceff	effective capacitance
curr	current
dq	∂q/∂v
q	charge
volt	voltage potential

Capacitor Device State printout identifiers

f element (CCCS) Device State printout identifiers description

state identifier	description
curr	source current
di or di1	derivative of source current w.r.t. first control
di2	derivative of source current w.r.t. second control
di3	derivative of source current w.r.t. third control
volt	voltage potential across the CCCS

h element (CCVS) Device State printout identifiers

state identifier	description
curr	source current
dv or dv1	derivative of source voltage w.r.t. first control
dv2	derivative of source voltage w.r.t. second control
dv3	derivative of source voltage w.r.t. third control
volt	voltage potential across the CCVS

Diode Device State printout identifiers description

state identifier	description	
c	total diode capacitance	
curr	current through the diode	
di	∂i/∂v	
dq	∂q/∂v	
gd	conductance	
id	current, excluding the series resistor	

state identifier	description
ir	current through the series resistor
qd	charge
rgn	operating region: -1=breakdown, 0=reverse, 1=forward
vd	voltage potential, excluding the series resistor
volt	voltage across the diode
vr	voltage across the series resistor

Diode Device State printout identifiers

Inductor Device State printout identifiers description

state identifier	description	
curr	current through the inductor	
ic	current through the component capacitor	
ir	current through the component resistor	
leff	effective inductance	
vc	voltage across the component capacitor	
volt	voltage across the inductor	
vr	voltage across the component resistor	

MOSFET Device State printout identifiers description

state identifier	description
betaeff	effective beta
cap_bd	bulk-drain capacitance
cap_bs	bulk-source capacitance
cbdbo	∂Qb/∂Vd
cbdo	DC drain-bulk diode current
cbgbo	∂Qb/∂Vg
cbsbo	∂Qb/∂Vs
cbso	DC source-bulk diode current
cddbo	∂Qd/∂Vd
cdgbo	∂Qd/∂Vg
cdo	DC drain current
cdsbo	∂Qd/∂Vs
cgdbo	∂Qg/∂Vd

state identifier	MOSFET Device State printout identifiers <i>description</i>
cggbo	∂Qg/∂Vg
cgsbo	∂Qg/∂Vs
cqb	current due to the intrinsic bulk charge
cqd	current due to the intrinsic drain charge
cqg	current due to the intrinsic gate charge
cqs	current due to the intrinsic source charge
deltal	channel length modulation
gammaeff	effective gamma
gbdo	Conductance of the drain diode
gbso	conductance of the source diode
gdso	DC drain-source transconductance
gmbso	DC substrate transconductance
gmo	DC gate transconductance
qbi	intrinsic bulk charge
qbd	bulk-drain diode charge
qbs	bulk-source diode charge
cqbd	current due to bulk-drain diode charge
cqbs	current due to bulk-source diode charge
qdi	intrinsic drain charge
qgi	intrinsic gate charge
qsi	intrinsic source charge
rgn	operating region: -1=subthreshold, 0=linear, 1=saturation
ueff	effective mobility
vbs	bulk-source voltage
vbsi	Rs offset internal bulk-source voltage
vds	drain-source voltage
vdsat	saturation voltage
vdsi	Rd and Rs offset internal drain-source voltage
vfbeff	effective Vfb
vgs	gate-source voltage
vgsi	Rs offset internal gate-source voltage
vth	Threshold voltage

state identifier	Resistor Device State printout identifiers description
cap1	capacitance of the first capacitor
cap2	capacitance of the second capacitor
curr	current through the resistor
di	∂I/∂V
g	conductance
ic1	current through the first capacitor
ic2	current through the second capacitor
qc1	charge of the first capacitor
qc2	charge of the second capacitor
r	effective resistance
vc1	voltage across the first capacitor
vc2	voltage across the second capacitor
volt	voltage across the resistor

Resistor Device State printout identifiers

g element (VCCS) Device State printout identifiers

state identifier	g element (VCCS) Device State printout identifiers description
curr	VCCS source current
di or di1	derivative of source current w.r.t. the first control
di2	derivative of source current w.r.t. the second control
di3	derivative of source current w.r.t. the third control
dq or dq1	derivative of source charge w.r.t. the first control
dq2	derivative of source charge w.r.t. the second control
dq3	derivative of source charge w.r.t. the third control
q	VCCS source charge
volt	voltage across the VCCS

e element (VCVS) Device State printout identifiers description

•	-
curr	VCVS source current
dv or dv1	derivative of source voltage w.r.t. the first control
dv2	derivative of source voltage w.r.t. the second control

state identifier

volt

voltage across the VCVS

.probe

Reports simulation results in binary format. **.probe** exactly as **.print**, except that output is binary instead of text. If **arguments** are given, the **mode** must be specified.

The file specified with the ".options" (page 109) probefilename command becomes the default for the .probe output file. If an output filename is not specified, T-Spice uses an ASCII output file name with no extension.

Syntax

.probe [mode] ["filena	me"] [arguments]
mode	Analysis type (see below). If <i>mode</i> is omitted, the .probe command applies to all analysis types.
filename	Specifies the binary output filename. The suggested extension is .dat . Must be enclosed by double quotes.
arguments	Specifies plot variables to be included in the output file. If arguments is omitted, T-Spice includes all node voltages and voltage source currents in the output. The format and types of arguments are the same as for the " .print " (page 122) command.

mode is one of the following:

tran	Print results from transient analysis.
dc	Print results from DC transfer analysis and DC operating point analysis.
ac	Print results from AC analysis.
noise	Print results from noise analysis.

Examples

.probe

Saves all node voltages and voltage source currents for all analyses to a binary file.

.probe tran

Saves all node voltages and voltage source currents for transient analysis to a binary file.

.probe tran v(2)

Saves the transient voltage at node 2 to a binary file.

.probe tran Output < v > = 'v(2) - v(1)'

Saves the transient value of an expression subtracting voltage at node 1 from voltage at node 2 and prints it in a column with the heading **Output**.

.protect / .unprotect

The **.protect** and **.unprotect** commands are used for temporarily turning input file echoing off and on. Input file echoing is initially turned on with the command **.option echo**. Subsequent use of **.protect** will turn off the echoing, until the **.unprotect** command is encountered. In this manner sensitive data, such as model libraries, can be protected from distribution, or excessive amounts of netlist echoing can be trimmed down.

Syntax

.protectunprotect

.save

Saves bias point information to a file. All of the non-internal node voltage values will be saved to the file using either the **.ic** or the **.nodeset** T-Spice command syntax. Subsequent simulations may use the **.load** command to read the file and execute the **.nodeset** or the **.ic** commands.

Syntax

.save [file=filename]	[type=ic nodeset] [time=time]
filename	Name of the file to be written. If the file parameter is not entered, then the filename is derived from the simulation output filename, with a .ic file extension.
type	Denotes the type of node initialization command which will be written to the file for each non-internal circuit node. Either ic , to have .ic commands generated, or nodeset , for .nodeset commands. (<i>Default</i> : nodeset)
time	The transient analysis time at which the bias information should be saved. Ordinarily, the .save command saves the DC operating point bias information. If a time parameter has been specified, and the simulation performs a transient analysis, then the bias at the specified timepoint will be saved.

Examples

.save type=ic time=50n

Saves bias point information to a file. Node voltage values will be saved to the file using either the .ic or the .nodeset T-Spice command syntax. Subsequent simulations may use the .load command to read the file and execute the .nodeset or the .ic commands.

Note:

The .save and the .savebias commands perform essentially the same task, but use a different syntax and have different options.

.save is provided for HSPICE command compatibility, while .savebias provides PSPICE command compatibility.

The *saved* file from either command can be loaded into a subsequent simulation using the .load command.

Syntax

```
.savebias filename [op | dc | tran] [alter = alternum] [dc = dcvalue]
  [step = stepvalue] [temp = temperature] [ time = timevalue [ repeat ] ]
  [ic | nodeset] [internal] [nosubckt]
```

filename	Name of the file to be written.
op dc tran	Indicates the type of analysis for which voltage values will be saved. (Default: op)
alternum	Identifies the alter block index number for which data should be saved. (Default: 0)
dcvalue	Identifies the DC sweep value for which data should be saved. (Default: all)
stepvalue	Identifies the .step value for which data should be saved. (Default: all)
temperature	Identifies the .temp temperature for which data should be saved. (Default: all)
timevalue	Identifies the transient timepoint at which data should be saved. (Default: 0)
repeat	For transient timepoint saving, indicates that the output file should repeatedly be overwritten for each timepoint which is an integral multiple of <i>timevalue</i> .
ic	Indicates that the node initialization command which is written should be the .ic command.
nodeset	Indicates that the node initialization command which is written should be the .nodeset command.
internal	Indicates that all internal node values should be included in the output. Internal nodes are those nodes which were not in the input circuit, but were automatically generated internal to devices.
nosubckt	Indicates that only the top level circuit nodes, excluding subcircuit nodes, should be written.

Examples

.savebias ring.ic tran ic time=100n repeat

.savebias dc alter=2 dc=2.5 temp=75 internal

.step

Performs a parametric sweep of a sweep variable, performing all analyses in the input file for all parameter values in the sweep.

The .step command produces a separate output section for each parameter value of the sweep. For example, an input file with .step and ".tran" (page 148) produces one transient analysis output section for each parameter value in the sweep. In addition, all ".macro /.eom" (page 90) results are plotted as traces with the swept variable as the x-axis. The output format for this is similar to that of the ".dc" (page 72) command.

Note:

The .step command can be abbreviated to .st.

Syntax

```
.step sweep [[sweep] sweep [[sweep]]
where sweep is in one of the following formats:
[lin] variable start stop inc
or
dec|oct variable start stop npoints
or
variable lin|dec|oct npoints start stop
or
variable list value [value [...]]
or
list variable value [value [...]]
or
variable poi npoints [value [...]]
or
data=dataname
or
monte=mcruns [seed=seedval]
or
optimize=optname results=measname [measname [...]] model=optmodelname
```

variable specifies the parameter whose value is to be swept. It is one of the following:

temp	Specifies a temperature sweep.
	<i>Note:</i> Use .dc to to plot voltage/current vs. temperature, not .temp and .step temp.
param <i>paramnam</i> e	Sweeps a global parameter named paramname defined using the .param command.
source sourcename	Sweeps the DC value of a voltage or current source value named sourcename .
[modparam] parname(modelname)	Sweeps the value of model parameter <i>parname</i> for the device model <i>modelname</i> .
paramname	Sweeps a global parameter (as with param) or DC source value (as with source). T-Spice first looks for a matching .param parameter, and then for a source name.

Other parameters include the following:

Specifies the beginning of a linear or logarithmic sweep.
Specifies the end of a linear or logarithmic sweep.
Specifies the increment for a linear sweep.
Specifies the total number of points for a linear or poi sweep, or the number of points per decade or octave for a logarithmic sweep.
Specifies a single value which <i>variable</i> takes on for one step of the sweep.
Specifies the number of runs to be performed for Monte Carlo analysis.
An integer specifying a seed for initializing the random number sequence for Monte Carlo analysis. If seedval is negative, T-Spice uses the system clock to generate a different seed each time the simulation is run. A seedval of zero is equivalent to not specifying a seed value at all.
Specifies the name of a ".connect" (page 69) statement to be used for the sweep. The column names in the .data statement must correspond to global ".param" (page 116) parameters. For each sweep step, those parameters are assigned the values found in one row of data produced by the .data statement.
Specifies that analysis be performed for all parameter values of the sweep and indicates the beginning of the next nested sweep variable specification. The sweep keyword can be omitted if the previous sweep is not of the list or poi type or if one of the keywords lin , dec , oct , list , poi , temp , param , source , or modparam follows immediately.
Specifies a linear sweep.
Specifies a logarithmic sweep by decades.

oct	Specifies a logarithmic sweep by octaves.
list	Specifies a sweep over a list of values (P-Spice compatible syntax).
роі	Specifies a sweep over a list of values (HSPICE compatible syntax).
data	Specifies a sweep defined using a .data statement.
monte	Specifies a Monte Carlo sweep. For each Monte Carlo run, random circuit parameter values are generated from probability distributions. A Monte Carlo sweep must be the outermost sweep if sweeps are nested.
optimize	Specifies an optimization sweep. During an optimization sweep, T-Spice runs many analyses in an attempt to optimize a circuit performance objective. The user may specify a set of parameters to be varied and a set of measurements to be included in the optimization goal. Optimization sweeps may not be nested within other optimization sweeps. For further information on setting up an optimization run, see "Optimization" on page 502.
optname	Selects a set of parameters to be varied in an optimization run. The parameters to be optimized are specified using ".param" (page 116) with a matching optname .
results= <i>measname</i>	Specifies circuit measurement results to be used for defining an optimization goal. Each <i>measname</i> refers to a ".macro /.eom" (page 90) command of the same name and contributes to the optimization goal. The complete optimization goal is the RMS of all measurements listed. For further information on specifying circuit measurement results, see "Defining Optimization Goals" on page 503.
model=o <i>ptmodelname</i>	Specifies an optimization algorithm model name. It is matched with a ".model" (page 99) statement of type opt and name <i>modelname</i> . That .model statement specifies parameters for the optimization algorithm. For further information on specifying an optimization algorithm, see "Optimization" on page 502.

Examples

.step vin 0 5 0.1

sweeps the DC value of voltage source vin from 0 to 5V with 0.1V increments.

.step lin param ml 2 3 0.5 sweep vdd 3 5 0.1 $\,$

performs a nested linear sweep of the parameter **ml** and the voltage source **vdd**.

.step list temp 0 27 100 150 -50

sweeps the circuit operating temperature over the five values listed.

```
.step optimize=opt1 results=bandwidth,delay model=optmod
.param p1=opt1(1e-3,1e-5,1) p2=opt1(150,100,200)
.model optmod opt level=1 itropt=40
.measure ac bandwidth trig vm(out) val=0.5 cross=1
+ targ vm(out) val=0.5 cross=2
+ goal=2kHz
```

.measure tran delay when v(1)=2.5 goal=10ns

invokes an optimization of parameters p1 and p2. T-Spice will attempt to find values for p1 and p2 which result in a bandwidth of 2 kHz and a delay of 10 ns. An AC and a transient analysis would be performed for each optimization function evaluation.

.subckt

Defines a hierarchical set of devices and nodes to be used repeatedly in a higher-level circuit.

- Subcircuits are replicated by means of the instance (x) statement.
- When invocations of the following commands appear within subcircuit definitions and refer to nodes inside the subcircuit, the commands are executed for each instance of the node: ".acmodel" (page 64), ".hdl" (page 81), ".macro *l.eom*" (page 90), ".nodeset" (page 103), ".noise" (page 104), ".print" (page 122), and ".probe" (page 136), and ".ff" (page 147).
- Node and device names have local scope in subcircuits unless global node names (defined elsewhere with the ".global" (page 80) command) are used.
- Subcircuit blocks cannot be nested: after one .subckt command, the ".ends" (page 77) command must appear before another .subckt command can be used.

Syntax

```
.subckt name node1 [node2 ...] [parameter=X ...]
subcircuit
.ends
```

name	Name of subcircuit.
node1 node2	Nodes used as "external" connections to the subcircuit.
parameter	Parameter(s), with default value(s) assigned. X can be a number or an expression. Subcircuit parameters have local scope. Parameters can be written in any order in both definition and instances. Parameter values specified in the definition are used as defaults when not specified in instances. Within the definition, parameter values are referenced (in place of numbers) by enclosing their names in single quotes. Alternatively, the " .param " (page 116) command may be used within the definition, with the same results. Parameters created outside the definition with the " .param " (page 116) command may be used inside the definition, but an assignment made with the .subckt command to an externally defined parameter always overrides its external value.
subcircuit	Subcircuit definition (may be multiple lines).

Examples

.subckt inv in out Vdd length=1.25u nwidth=2u pwidth=3u mtl out in GND GND nmos l='length' w='nwidth' mt2 out in Vdd Vdd pmos l='length' w='pwidth' c2 out GND 800f .ends inv

This subcircuit could be instanced as follows:

xinv1 a1 a2 Vdd inv nwidth=4u pwidth=6u

.temp

Specifies the temperatures at which the circuit is to be simulated.

- Changing the temperature affects the behavior of diode, resistor, BJT, JFET, MESFET, and MOSFET models. It may also affect the behavior of user-defined external models.
- The .temp command has no effect on external tables, which should be regenerated to reflect the new temperature.

Syntax

```
.temp temperature [temperature [...]]]
```

temperature Temperature. (Unit: °C. Default: 25.)

Using **.TEMP** and **.STEP** displays voltage vs. voltage plots with different temperatures displaying as different traces. For example,

.DC vin 0 5 0.1 .TEMP 25 30 35 40 50

To plot voltage vs. temperature, use the following so that the first sweep variable in the DC analysis will become the X axis:

.DC temp 25 40 5 VIN 0 5 0.1

.tf

Computes and reports the value of the small-signal DC transfer function between the specified output and input, and the corresponding input and output resistances, at the DC operating point.

- The .tf command automatically performs (but does not report the results from) a DC operating point calculation.
- Results are reported under the heading SMALL-SIGNAL TRANSFER FUNCTION (to the specified output file or in the Simulation Window).
- The transfer function value corresponds to a voltage $(V \ N)$ or current $(I \ A)$ gain, a transconductance $(I \ N)$, or a transresistance $(V \ A)$.

Syntax

.tf arguments source

arguments	Any arguments appropriate for the ".print" (page 122) dc command.
source	Voltage or current input source.

Examples

.tf i(mb1,out1) ii1

Computes transfer function results between node out1 of device mb1 and current source ii1.

.tran

Performs large-signal time-domain (transient) analysis of the circuit to determine its response to initial conditions and time-dependent stimuli.

- The time step is adaptively varied throughout the simulation to ensure accuracy.
- Results for nodes selected by the .print tran, .probe tran, and .measure tran commands will be output for every time step, unless otherwise specified by the .options prtdel command. For additional information on these commands, see ".print" (page 122), ".probe" (page 136), ".macro *l.eom*" (page 90) and ".options" (page 109).

Syntax

<pre>.tran[/mode] S L [start=A] [UIC] [sweep sweep]</pre>		
Analysis mode (see below). This parameter must immediately follow the keyword .tran and be preceded by a slash (/).		
Maximum time step allowed. By default, the time step is dynamically adapted to resolve the output values. (Unit: seconds.)		
Total simulation time. (Unit: seconds.)		
Output start time. Execution of the .print tran command will not start until this time. (Unit: seconds. Default: 0.)		
Instructs T-Spice to skip the DC operating point analysis for determining the time=0 circuit state. Instead, only the initial conditions specified using .ic commands are used to set the time=0 voltages. Voltages which cannot be determined using .ic commands are set to zero.		
For a description of the syntax for this field, see ".step" (page 141).		
<i>mode</i> takes one of the following values:		
Performs a DC operating point calculation before simulation to determine initial steady-state node voltages. The commands ".nodeset" (page 103) or ".hdl" (page 81) can be used to impose initial conditions.		
Performs a "powerup" simulation. All nodes are at the same potential at time zero, and the voltage sources are ramped gradually to their final values.		
Steps through the input signals without simulating the circuit. Input waveforms will be reported as specified by the ".print" (page 122) tran command.		

If **mode** is not specified, T-Spice first performs a DC operating point analysis, without printing the DC operating point analysis results.

sweep indicates the beginning of the next nested sweep variable specification. The **sweep** keyword can be omitted if the previous sweep is not of the **list** or **poi** type or if one of the keywords **lin**, **dec**, **oct**, **list**, **poi**, **temp**, **param**, **source**, or **modparam** follows immediately.

Using the **sweep** option with .tran or ".ac" (page 61) causes that analysis to be performed for all parameter values of the sweep. It is equivalent to ".step" (page 141), except that it applies only to one analysis command, while .step applies to all analysis commands in the input file. If **sweep** is specified on an analysis command and .step is present, the **sweep** sweep is nested inside the .step sweep. The **sweep** parameter may be used to specify a parametric sweep, Monte Carlo analysis, or optimization.

Examples

.tran 0.5n 100n

Defines a transient simulation lasting 100 nanoseconds, using time steps of at most 0.5 nanosecond. By default, a DC operating point calculation will first be performed to define a starting condition.

```
.tran/preview 4n 4000n
```

The input waveforms are reported for 4000 nanoseconds; the rest of the circuit is ignored.

.tran 1ns 100ns

Specifies a maximum time step of 1 nanosecond and a total simulation time of 100 nanoseconds.

.tran/powerup 1ns 100 ns

Specifies a powerup simulation with no operating point computation.

.tran 1ns 100 ns start=50ns

Produces output starting at time 50 nanoseconds.

.tran 1n 100n sweep temp list 0 27 100 150 -50

Performs five transient analysis runs, one for each temperature listed. The keyword **temp** specifies the sweep *variable*, as defined in ".step" (page 141).

.tran 1n 400n sweep temp -50 150 50

This performs five transient analyses at temperatures -50, 0, 50, 100, and 150 degrees Celsius.

.tran 0.5u 100u sweep monte=20

This performs 20 transient simulations as part of a Monte Carlo analysis. The keyword **monte** defines one of the many **sweep** options described in ".step" (page 141)). For each of the 20 transient analyses, values are randomly chosen for circuit variables, which are assigned probability distributions according to the specified "Monte Carlo Parameters" (page 117).

For a demonstration of Monte Carlo analysis in T-Spice, see "Example 2: Monte Carlo Analysis" on page 500.

.tran 1n 200n sweep temp list 0 25 75 150

This example performs four transient analysis runs at temperatures 0, 25, 75, and 150 degrees Celsius.

.vector

Names a bus and specifies how many bits the bus will contain.

- The bus is connected to a vector-valued current or voltage source, defined by a i or v statement with the **bus** keyword.
- The input source generates signals composed of bit strings of the length specified in the **.vector** command.

Syntax

<pre>.vector bus {node1 [[,] node2]]}</pre>		
bus	Bus name.	
node1 node2	Input nodes. If there are n nodes in a bus, the rightmost n bits of the input waveform (a binary number) are assigned one by one to these nodes. The last-named (n th) node is assigned the least-significant (rightmost) bit; the (n -1)th node is assigned the next bit to the left; and so on. Extra bits are discarded. Extra nodes are set to zero.	

Examples

.vector bus1 {b7 b6 b5 b4 b3 b2 b1 b0}

Defines a bus **bus1** and lists its eight input nodes. The input waveform to these nodes is specified as some number or numbers, convertible to a binary string with at least eight bits, in the accompanying voltage or current source statement.

Chapter 5: Simulation Commands

Introduction

This chapter documents the device statements of the T-Spice circuit description language.

The *device types* are listed in alphabetical order; each type is associated with a *key letter* (in parentheses). Many statements have "options," which branch to different modes, and "arguments," which indicate expressions, nodes, or devices to be used. In the input file, a device statement must begin with its key letter in the first column of the line containing it (no leading spaces). Options and arguments must be separated by spaces or new lines (with line continuation).

Syntax sections in this documentation follow these conventions:

- Italics indicate variables to be replaced by actual names, numbers, or expressions.
- Curly brackets {} indicate alternative values for the same option or argument.
- Square brackets [] enclose items that are *not required*.
- Vertical bars | separate alternative values for the same option or argument.
- Ellipses ... indicate items that may be repeated as many times as needed.

These characters are not typed in the input file. All other characters are typed as shown.

For more information, see "Input Conventions" on page 52 and "Simulation Commands" on page 60.

BJT (q)

A transistor with up to four terminals: collector, base, emitter, and (optional) substrate. (BJT stands for *bipolar junction transistor*.)

Several types of bipolar models are supported in T-Spice: SPICE Gummel-Poon model (level 1) Vertical Bipolar Inter-Company (VBIC) (level 9) Philips MEXTRAM (levels 6, 503, and 504) Philips Modella (level 10 and 500)

The substrate is optional so that both discrete and IC BJTs may be modeled correctly.

Syntax

```
qname collector base emitter [substrate] model [[area=]A] [areab=B]
[areac=C] [M=M] [SCALE=S]
```

Parameter	Symbol	Description	Default
name		BJT name	
collector		Collector terminal	
base		Base terminal	
emitter		Emitter terminal	
substrate		Substrate terminal	
model		BJT model name. The model is specified elsewhere in the input file in the form .model name npn pnp [parameters].	

The following device options are available for Gummel-Poon models.

Parameter	Symbol	Description	Default
area	А	Area scale factor	1
areab	В	Base area scale factor	А
areac	С	Collector area scale factor	А
Μ	М	Multiplicity - the number of devices to be placed in parallel.	1

VBIC device statements are different from the Gummel-Poon bipolars. The VBIC model does not contain any terms for explicitly defining geometry or junction areas.

qname collector base emitter [substrate] [tmode] model [M=M] [SCALE=S]
[tnodeout]

Tmode refers to the thermal node (dt), and *Tnodeout* is the flag indicating that the last node in the list of device nodes is the thermal node; otherwise it when four nodes are specified it is unclear as to whether that node is a substrate node or thermal node. (With five nodes the fifth is always thermal.)

Instead, the device **SCALE** parameter is provided for linearly scaling the device currents and charges. For compatibility with Gummel-Poon devices, the VBIC device statement will also accept the **M** multiplicity factor as a synonym for the **SCALE** parameter.

Parameter	Symbol	Description	Default
scale	S	Scale factor	1

Examples

qout1 r32 r23 gnd sub1 npnmod qout2 r32 r23 gnd sub1 npnmod area=2

The area factor scales the generated current; thus, qout2 generates twice as much current as qout1.

Capacitor (c)

A two-terminal capacitor. A nonlinear capacitor can be created using the **g**- element with an expression and the **chg** keyword. See "Nonlinear Capacitor" on page 195.

Syntax

```
cname node1 node2 CapValue[C=CapValue[=C] [M=M] [scale=scale] [tc1=T1]
  [tc2=T2] [dtemp=dtemp]
.or
cname node1 node2 POLY c0 [c1 [...]] [M=M]
```

or

```
cname node1 node2 modelname [c=C] [M=M] [scale=scale] [tc1=T1] [tc2=T2]
[dtemp=dtemp] [1=length] [w=width]
```

or

```
cname node1 node2 modelname C [T1 [T2 ]] [M=M] [scale=scale] [dtemp=dtemp]
[1=length] [w=width]
```

Parameter	Symbol	Description	Default	Units
name		Capacitor name.		
node1		Positive terminal		
node2		Negative terminal.		
С	С	Capacitance.		F
POLY		Keyword indicating that the capacitance is a polynomial function.		
c0, c1,	C ₀ , C ₁ ,	Coefficients of the polynomial function for capacitance.		
Μ	М	Multiplicity - the number of devices to be placed in parallel.	1	
scale	S	Element scale factor	1	
T1	T_1	First temperature coefficient for capacitance.	0	1/deg
Т2	T ₂	Second temperature coefficient for capacitance.	0	(1/deg ²)
dtemp	D _{temp}	Difference between the capacitor and the circuit temperatures.	0	deg
I	L	Length of capacitor.		m
w	W	Width of capacitor		m

Equations

If the first syntax is employed the capacitance is calculated as

$$C = M \cdot S[1 + T_1(\Delta T) + T_2(\Delta T)^2] \cdot C_0$$
(6.5)

where

$$\Delta T = T_{circuit} + D_{temp} \angle T_{nom}$$
(6.6)

where $T_{circuit}$ is set in .temp and T_{nom} in .options thom.

If the second syntax is employed, capacitance is calculated as

$$C = c_0 + c_1 V + c_2 V^2 + \dots ag{6.7}$$

where V denotes the voltage between **node1** and **node2**.

If the third or fourth syntax is employed, there must be a matching ".model" on page 99.

Note: When the calculated capacitance is greater than 0.1 F, T-Spice issues a warning message.

Examples

cwire w1 gnd 82f

The example defines a capacitor with a value of 82 femtofarads. A common error is to omit the metric abbreviation on the capacitance value, which can lead to unexpected results.

cxx 1 0 poly 0.08 2.08 3.08

This example defines a capacitor \mathbf{cxx} connected between nodes **1** and **0**. The capacitance of \mathbf{cxx} is described as

$$C = 0.08 + 1.08V + 2.08V^{2} + 3.08V^{3}$$
(6.8)

where V is the voltage between nodes 1 and 0.

A capacitor exhibiting polynomial dependence on its applied voltage can be modeled using the **POLY** keyword:

c1 n+ n- POLY c0 'c0*vcc'

The waveform for this capacitor is illustrated in "Nonlinear Capacitor" on page 195.

c1 10 20 capxx 0.02 1.5e-2 5.0e-4 dtemp=20

This example illustrates the fourth syntax. The capacitor is named **c1**. Its terminals are connected to nodes **10** and **20**. Its model name is **capxx**. It has two temperature coefficients, **tc1 = 1.5e-2** and **tc2 = 5.0e-4**. Its **dtemp = 20**. As the model name is **capxx**, the corresponding **.model** statement must also contain the word **capxx**.

Coupled Transmission Line (u)

A set of coupled transmission lines.

There is no limit (besides physical memory) on the number of transmission lines that can be coupled.

Syntax

uname in1 [in2 [...]] in0 out1 [out2 [...]] out0 model length=L [lumps=X]
[lumptype=Y]

Parameter	Symbol	Description	Default	Units
name		Coupled transmission line name.		
in1 in2		Input terminals (as many as needed).		
out1 out2		Output terminals (as many as needed);.		
 in0		Input reference terminal.		
out0		Output reference terminal.		
model		CPL coupling model name. The model is specified elsewhere in the input file in the form .model name cpl level=l [[r]={matrix}] [c]={matrix} [l]={matrix} [[g]={matrix}]		
length	L	Physical length.		m
lumps	Х	Number of lumps used for iterative ladder circuit (ILC) expansion.	1	
lumptype		Type of lumps used for ILC expansion. Y is one of the following: 0 = "Gamma" type lumps 1 = "Tee" type symmetric lumps 2= "Pi" type symmetric lumps 3= Hybrid RGT lumps	3	1/deg

Examples

ufine in1 in2 in3 refin out1 out2 out3 refout + cplmod l=1m lumps=3 lumptype=1

Current Source (i)

A two-terminal ideal current supply.

Exponential, pulse, piecewise linear, frequency-modulated, sinusoidal, and customizable (vectorized) waveforms can be specified.

To specify a current source with an equation, use the "Voltage-Controlled Current Source (g)" on page 192 with an expression that may involve the **time()** function.

Syntax

iname nodel node2 [[DC] I] [AC M [P]] [waveform]

name	Voltage source name.
node1	Positive terminal—or bus named by an associated .vector command.
node2	Negative terminal.
I	DC level. (Unit: A)
М	AC Magnitude. (Unit: A)
Р	AC Phase (Unit: degrees. Default: 0.)
waveform	Waveform identifier and parameters (see below).

DC, AC, and transient values can be specified independently and in any order.

waveform is one of the following:

Exponential Waveform

exp (Ii Ip [Dr [Tr [Df [Tf]]])

li	Initial current. (Unit: amperes.)
lp	Peak current. (Unit: amperes.)
Dr	Rise time delay. (Unit: seconds. Default: 0.)
Tr	Rise time constant. (Unit: seconds. Default: 0.)
Df	Fall time delay. (Unit: seconds. Default: 0.)
Tf	Fall time constant. (Unit: seconds. Default: 0.)

The formula used is:

$$I_{i} \qquad 0 \le t \le D_{r}$$

$$I(t) = I_{i} + (I_{p} \angle I_{i}) \left(1 \angle \exp\left(\frac{\angle (t \angle D_{r})}{T_{r}}\right) \right) \qquad D_{r} \le t \le D_{f}$$

$$I_{i} + (I_{i} \angle I_{p}) \left(1 \angle \exp\left(\frac{\angle (t \angle D_{f})}{T_{f}}\right) \right) \qquad D_{f} \le t$$
(6.9)

Pulse Waveform

pulse (Ii Ip [D [Tr [Tf [Pw [Pp]]]]) [ROUND=RND]

li	Initial current. (Unit: amperes.)
lp	Peak current. (Unit: amperes.)
D	Initial delay. (Unit: seconds. Default: 0.)
Tr	Rise time. (Unit: seconds. Default: time step from .tran.)
Tf	Fall time. (Unit: seconds. Default: time step from .tran.)
Pw	Pulse width. (Unit: seconds. Default: stop time from .tran.)
Рр	Pulse period. (Unit: seconds. Default: stop time from .tran.)
RND	Rounding half-interval. A corner at time <i>T</i> is replaced by a smoothly differentiable polynomial in the interval (<i>T</i> – <i>RND</i> , <i>T</i> + <i>RND</i>). The maximum <i>RND</i> is half the distance to the nearest neighboring corner. (<i>Default:</i> 0—no rounding.)

Note that beginning with version 11, T-Spice interprets rise time as the time to go from the initial voltage to the pulse voltage, regardless of which is larger.

Piecewise Linear Waveform

pwl (<i>T1 I1</i> [<i>T2 I2</i>])[ROUND=RND] [REPEAT[=Tr]] [TD=DELAY]
T1 T2	Time at corner 1, 2, and so on. (Unit: seconds.)
11 12	Current at corner 1, 2, and so on. (Unit: amperes.)
ROUND	Rounding half-interval. A corner at time <i>T</i> is replaced by a smoothly differentiable polynomial in the interval $(T-RND,T+RND)$. The maximum <i>RND</i> is half the distance to the nearest neighboring corner. (<i>Default:</i> 0—no rounding.)
REPEAT	Starting time within the specified waveform for an infinite number of repetitions of the subwaveform. If Tr is not specified, the entire waveform repeats indefinitely (i.e., $Tr=0$). Tr must be less than or equal to the duration of the waveform. Waveforms can only repeat if the start and end points match. If they do not match, the repeat option is ignored. The REPEAT keyword can be abbreviated to R .

TD

Time delay added to the beginning of the waveform. If you specify corners *T1*, *T2*, *etc*. and **TD**=*DELAY*, then the defined current values will actually be applied at effective corner times *T1*+*DELAY*, *T2*+*DELAY*, *etc*.

Piecewise Linear Waveform File

pwlfile filename [ROUN	D=RND] [REPEAT[=Tr]] [TD=DELAY]
filename	Input file which contains the piecewise linear waveform definition in a series of time, current pairs, one per line.
ROUND	Same meaning as with pwl waveforms
REPEAT	Same meaning as with pwl waveforms
TD	Same meaning as with pwl waveforms

Frequency-Modulated Waveform

sffm (Io Ip [Fc [Xm [Fs]]])

lo	Offset current. (Unit: amperes.)
lp	Peak current. (Unit: amperes.)
Fc	Carrier frequency (<i>Unit:</i> Hertz. <i>Default:</i> 1/ <i>T</i> , where <i>T</i> is the stop time from .tran .)
Хт	Modulation index. (Default: 0.)
Fs	Signal frequency. (<i>Unit:</i> Hertz. <i>Default:</i> 1/ <i>T</i> , where <i>T</i> is the stop time from .tran .)

The formula used is:

$$I(t) = I_o + I_p \cdot \sin[(2\pi \cdot F_c \cdot t) + Xm \cdot \sin(2\pi \cdot F_s \cdot t)]$$
(6.10)

Sinusoidal Waveform

sin (Io Ip [Fr [De [Da [Ph]]]])

ю	Offset current. (Unit: amperes.)
lp	Peak current. (Unit: amperes.)
Fr	Frequency. (<i>Unit:</i> Hertz. <i>Default:</i> 1/ <i>T</i> , where <i>T</i> is the stop time from .tran .)
De	Delay time. (Unit: seconds.)
Da	Damping factor. (Unit: 1/seconds.)

Ph

1. . 1.

Phase advance. (Unit: degrees.)

The formula used is:

$$I(t) = I_o + I_p \cdot \sin\left(2\pi \cdot \left(F_r \cdot (t \angle t_d) + \frac{P}{360}\right)\right) \cdot \exp(\angle((t \angle t_d) \cdot D))$$
(6.11)

Vectorized Waveform

bit bus	<pre>({pattern}</pre>	[on= A]	[off=Z]	[delay= D]	[pw= <i>P</i>]	[rt=R]	[ft= <i>F</i>]	[1t= L]
[ht=]	H]) [ROUND=H	RND						

• .•

c

. •

. •

pattern	An expression consisting of one or more string or string-multiplier combinations (see below).
Α	On current (Unit: amperes. Default: 0.001.)
Z	Off current. (Unit: amperes. Default: 0.)
D	Delay time. (Unit: seconds. Default: 0.)
Ρ	Pulse width: $\mathbf{P} = \mathbf{R} + T_A = \mathbf{F} + T_Z$, where T_A is the time during a pulse where the current is "on" ($V = \mathbf{A}$) and $T\mathbf{Z}$ is the time during a pulse where the current is "off" ($V = \mathbf{Z}$). (Unit: seconds. Default: 10×10^{-9} .)
R	Rise time. (Unit: seconds. Default: 1×10^{-9} .)
F	Fall time. (Unit: seconds. Default: 1×10^{-9} .)
L	Low time: $\boldsymbol{L} = \boldsymbol{F} + T_{\boldsymbol{Z}}$, where $T_{\boldsymbol{Z}}$ is the time during a pulse where the current is "off" ($V = \boldsymbol{Z}$). (Unit: seconds. Default: 10×10^{-9} .)
Н	High time: $\mathbf{H} = \mathbf{R} + T_A$, where T_A is the time during a pulse where the current is "on" ($V = \mathbf{A}$). (Unit: seconds. Default: 10×10^{-9} .)
RND	Rounding half-interval. A corner at time <i>T</i> is replaced by a smoothly differentiable polynomial in the interval (T – RND , T + RND). The maximum RND is half the distance to the nearest neighboring corner. (<i>Default:</i> 0—no rounding.)

A *bit* pattern consists of a set of numbers (possibly associated with multiplier factors) whose binary representations sequentially specify the "on"/"off" structure of the waveform. The pattern takes the form $a(b(x) c(y) \dots$), where a, b, and c are the optional multiplier factors and x and y are the numbers.

A *bus* pattern consists of a set of numbers (possibly associated with multiplier factors) whose binary representations—"bit strings"—are grouped together as a waveform bus and treated as a single input. The length of the bit strings is specified by the **.vector** command. If there are n nodes in a vector, then T-Spice assigns the first n bits of each bit string to those nodes. Extra bits are discarded. If there are not enough bits, the highest-order bits are set to zero. The leftmost node name in the **.vector** command takes the most significant bit.

Numbers are specified on the device statement in binary, hexadecimal (suffixed by \mathbf{h}), octal (suffixed by \mathbf{o}), or decimal (suffixed by \mathbf{d}) notation. (For decimal representations the number of lower-order bits to be collected is also given.)

Examples

i1 a b 4.5u AC 1.0m 0.0

i1 has a DC value of 4.5 microamps, an AC magnitude of 1 milliampere, and an AC phase shift of 0 degrees.

i2 n2 GND pwl (0n 0 100n 0 101n 5 300n 5 301n 0 + 500n 0 680n 5 700n 0 880n 5 900n 0)

i2 generates a **pwl** (piecewise linear) input: a single pulse followed by a pair of sawtooth cycles.

i3 n3 GND bit ({01010 11011} on=5.0u off=0.0 pw=50n rt=10n ft=30n)

i3 generates a bit input. Enclosed in braces $\{ \}$ are two binary-valued five-bit patterns specifying the waveform. The two patterns alternate in time. The **on** current value is 5.0 microamps; the **off** current value is zero. The pulse width (**pw**), 50 nanoseconds, is the time the wave is either (ramping up and) on, or (dropping down and) off. The rise time (**rt**), 10 nanoseconds, is the time given for the wave to ramp from off to on; and the fall time (**ft**), 30 nanoseconds, the time given for the wave to drop from on to off.

i4 n4 GND bit ({5(01010 5(1))} pw=10n on=5.0u off=0.0)

i4 generates a *repeating* **bit** input. Two distinct patterns are given again, but now *multiplier factors* are included. The wave consists of two alternating patterns: the first pattern contains five bits, the second is a single bit. The five-bit pattern is followed by five successive repetitions of the single-bit pattern, and this combination is repeated five times. (The same pattern could be described by **{5(3(01) 4(1))}**.) The pulse width and on and off voltages are again specified, but the rise and fall times take default values.

```
.vector bb {n5 n6 n7 n8}
ib bb GND bus ({50(Ah) 30(7d4) 20(1000)} pw=5n on=5.0u off=0.0)
```

The **.vector** command defines the bus waveform generated by current source **ib**. The command assigns the bus a name (**bb**) and specifies by name the number of bits the bus waveform will have (four: **n5** through **n8**). The current source statement, which contains the **bus** keyword, specifies waveforms with one or more patterns, along with pulse width and level information.

- The first pattern is Ah (hex) = 1010 (binary). Thus, using the names given on the .vector command, n5=1, n6=0, n7=1, and n8=0. The pattern is repeated 50 times (that is, maintained for a time period equal to the pulse width multiplied by 50).
- The next pattern is 7d4—that is, 7 (decimal) = 111 (binary), or, to four lower-order bits, 0111. So n5=0, n6=1, n7=1, and n8=1. The pattern is repeated 30 times.
- The last pattern is **1000** (binary), so **n5**=1, **n6**=0, **n7**=0, and **n8**=0. The pattern is repeated 20 times.

Current-Controlled Current Source (f)

A two-terminal ideal DC current supply with a level that is a function of one or more control currents.

Syntax

Linear

fname nodel node2 vname1 K [Options]

Polynomial

fname nodel node2 POLY(N) vname1 [vname2 [vname3]] P₀ P₁ P₂... [Options]

fname	Current-controlled current source name. Must begin with "f".			
node1	Positive terminal. Positive current flows into node1 .			
node2	Negative terminal. Positive current flows out of <i>node2</i> .			
κ	Current gain-the ratio of the output current to the control current.			
POLY	Keyword indicating that the output current is a polynomial function of the control currents.			
Ν	Number of control currents (valid values 1-6).			
vname1 vname2	Name(s) of the voltage source(s) supplying the control current(s).			
<i>P</i> ₀ <i>P</i> ₁ <i>P</i> ₂	Coefficients of the control polynomial.			

Options

[MAX=value] [MIN=value] [ABS =[0 | 1]] [TC1=value] [TC2=value] [SCALE=value]

MAX	Maximum output voltage value.
MIN	Minimum output voltage value.
ABS	Output is absolute value if ABS=1.
TC1, TC2,	First- and second-order temperature coefficients.
SCALE	Element value multiplier.

Current is reckoned positive if it enters a voltage source at its first terminal. A similar convention holds for the **current-controlled current source**.

The first statement creates a current source with a level equal to K multiplied by the current through voltage source **vname1**.

The second statement creates a current source whose level is a nonlinear polynomial function of the currents through up to three voltage sources. Let:

x = current through voltage source vname1;

- y = current through voltage source **vname2** (if **N** \ge 2);
- z = current through voltage source **vname3** (if **N** \ge 3).

Then the controlled current source's level is defined as follows:

If **N** = 1:

$$P_0 + P_1 x + P_2 x^2 + P_3 x^3 + \dots ag{6.12}$$

If **N** = 2:

$$P_0 + P_1 x + P_2 y + P_3 x^2 + P_4 x y + P_5 y^2 + P_6 x^3 + P_7 x^2 y + P_8 x y^2 + P_9 y^3 + \dots$$
(6.13)

If **N** = 3:

$$P_{0} + P_{1}x + P_{2}y + P_{3}z + P_{4}x^{2} + P_{5}xy + P_{6}xz + P_{7}y^{2} + P_{8}yz + P_{9}z^{2} + P_{10}x^{3} + P_{11}x^{2}y + P_{12}x^{2}z + P_{13}xy^{2} + P_{14}xyz + P_{15}xz^{2} + P_{16}y^{3} + P_{17}y^{2}z + P_{18}yz^{2} + P_{19}z^{3} + \dots$$
(6.14)

If N = 1 and only one polynomial coefficient is specified, it is assumed to be P_1 , to facilitate the specification of linearly-controlled sources.

Examples

```
ftest in gnd vin 1.0
```

Current-controlled current source **ftest** has a gain of 1 and is controlled by the current through **vin**.

f1 0 1 vcntrl 2.0

This defines a current source with a level equal to $2 \times i(ventrl)$, that is, twice the current through ventrl.

```
f2 0 1 POLY(1) vcntrl 1m 0 2
```

This defines a current source with a level equal to $10^{-3} + (2 \times i(\text{vcntrl})^2)$.

f3 0 1 POLY(2) v1 v2 0 1 2 3

This defines a current source with a level equal to $i(\mathbf{v1}) + (2 \times i(\mathbf{v2})) + (3 \times i(\mathbf{v1}) \times i(\mathbf{v2}))$.

f4 0 1 POLY(3) v1 v2 v3 0 1 0 3 0 4

This defines a current source with a level equal to $i(v1) + (3 \times i(v3)) + (4 \times i(v1) \times i(v2))$.

Current-Controlled Voltage Source (h)

A two-terminal ideal DC voltage supply with a level that is a function of one or more controlling currents.

Syntax

Linear

hname node1 node2 vname1 K [Options]

Polynomial

hname node1 node2 POLY(N) vname1 [vname2 [vname3]] P₀ P₁ P₂ ... [Options]

hname	Current-controlled voltage source name. Must begin with "h".
node1	Positive terminal.
node2	Negative terminal.
κ	Transresistance—the ratio of the output voltage to the control current.
POLY	Keyword indicating that the output voltage is a polynomial function of the control currents.
Ν	Number of control currents (valid values 1-6).
vname1 vname2	Name(s) of the voltage source(s) supplying the control current(s).
P ₀ P ₁ P ₂	Coefficients of the control polynomial. Current is reckoned positive if it enters a voltage source at its first terminal.

Options

[MAX=value] [MIN=value] [ABS =[0 | 1]] [TC1=value] [TC2=value] [SCALE=value]

MAX	Maximum output voltage value.
MIN	Minimum output voltage value.
ABS	Output is absolute value if ABS=1.
TC1, TC2,	First- and second-order temperature coefficients.
SCALE	Element value multiplier.

The first statement creates a voltage source with a level equal to K multiplied by the current through voltage source **vname1**.

The second statement creates a voltage source whose level is a nonlinear polynomial function of the currents through up to three voltage sources. Let

- x = current through voltage source vname1;
- y = current through voltage source **vname2** (if **N** \ge 2);

• z = current through voltage source **vname3** (if **N** \ge 3).

Then the controlled voltage source's level is defined as follows:

If **N** = 1:

$$P_0 + P_1 x + P_2 x^2 + P_3 x^3 + \dots ag{6.15}$$

If **N** = 2:

$$P_0 + P_1 x + P_2 y + P_3 x^2 + P_4 x y + P_5 y^2 + P_6 x^3 + P_7 x^2 y + P_8 x y^2 + P_9 y^3 + \dots$$
(6.16)

If **N** = 3:

$$P_{0} + P_{1}x + P_{2}y + P_{3}z + P_{4}x^{2} + P_{5}xy + P_{6}xz + P_{7}y^{2} + P_{8}yz + P_{9}z^{2} + P_{10}x^{3} + P_{11}x^{2}y + P_{12}x^{2}z + P_{13}xy^{2} + P_{14}xyz + P_{15}xz^{2} + P_{16}y^{3} + P_{17}y^{2}z + P_{18}yz^{2} + P_{19}z^{3} + \dots$$
(6.17)

If N = 1 and only one polynomial coefficient is specified, it is assumed to be P1, to facilitate the specification of linearly-controlled sources.

Examples

```
htest in gnd vin 1.23e4
```

Current-controlled voltage source **htest** has a transresistance of 12.3 kilohms and is controlled by the current through **vin**.

h1 0 1 vcntrl 2.0

This defines a voltage source with a level equal to $2 \times i(ventrl)$, that is, twice the current through ventrl.

```
h2 0 1 POLY(1) vcntrl 1m 0 2
```

This defines a voltage source with a level equal to $10^{-3} + (2 \times i(vcntrl)^2)$.

h3 0 1 POLY(2) v1 v2 0 1 2 3

This defines a voltage source with a level equal to $i(\mathbf{v1}) + (2 \times i(\mathbf{v2})) + (3 \times i(\mathbf{v1}) \times i(\mathbf{v2}))$.

h4 0 1 POLY(3) v1 v2 v3 0 1 0 3 0 4

This defines a voltage source with a level equal to $i(\mathbf{v1}) + (3 \times i(\mathbf{v3})) + (4 \times i(\mathbf{v1}) \times i(\mathbf{v2}))$.

Diode (d)

A two-terminal *p*-*n* junction diode.

Syntax

```
dname node1 node2 mode1 [[area=]A] [M=M] [L=length] [W=width] [PJ=PJ]
[LM=LM] [WM=WM] [LP=LP] [WP=WP]
```

name	Diode name.
node1	Positive terminal (p side).
node2	Negative terminal (<i>n</i> side).
model	Diode model name. This is specified elsewhere in the input file in the form .model name d [parameters] Schottky barrier diodes may be simulated using an appropriate model specification.
Α	Area of the diode. (Units: unitless for level 1, square meters for level 3. <i>Default:</i> 1.)
М	Multiplicity—the number of devices to be placed in parallel. (<i>Default:</i> 1.)
L	Length of the diode
W	Width of the diode
РЈ	Junction periphery. Overrides the model PJ value. (Units: Unitless for level 1, meters for level 3.)
LM	Length of metal capacitor. Overrides the model LM value. (Units: meters, for level 3 only)
WM	Width of metal capacitor. Overrides the model WM value. (Units: meters, for level 3 only)
LP	Length of polysilicon capacitor. Overrides the model LP value. (Units: meters, for level 3 only)
WP	Width of polysilicon capacitor. Overrides the model WP value. (Units: meters, for level 3 only)

Examples

dpn2 n1 n2 dmodel D3 n3 n4 dmodel 3

The **area** factor scales the diode current; thus, **D3** provides three times as much current as **dpn2**, given the same bias conditions.

Inductor (I)

A two-terminal inductor.

Coupled (mutual) inductors can be defined with the ${\bf k}$ statement.

Syntax

```
lname node1 node2 [L=] [M=M] [scale = scale] [tc1 = tc1] [tc2 = tc2] [dtemp
 = dtemp] [r=resistance]
```

or

```
lname node1 node2 L [tc1[tc2]] [M=M] [scale = scale] [dtemp = dtemp]
[r=resistance]
```

or

lname node1 node2 POLY C0 C1 ... [M=M]

Parameter Symbol Description	Description
------------------------------	-------------

name		Inductor name.
node1		Positive terminal.
node2		Negative terminal.
L	L_0	Inductance. (Unit: henries. Default: 0.)
POLY		Keyword indicating that the inductance is a polynomial function.
C0 C1	<i>c</i> ₀ , <i>c</i> ₁ , <i>c</i> ₂ 	Coefficients of the polynomial. The inductance is $C0 + (C1 \times i) + (C2 \times i^2)$, where <i>i</i> is the current through the inductor.
М	М	Multiplicity—the number of devices to be placed in parallel. (<i>Default:</i> 1.)
scale	S	Element scale factor. (Default: 1.)
Tc1	T_{cl}	First temperature coefficient for inductance. (<i>Unit:</i> (1/deg C) ²). (<i>Default:</i> 0.)
Tc2	T_{c2}	Second temperature coefficient for inductance. (<i>Unit:</i> (1/deg C)2). (<i>Default:</i> 0.)
Dtemp	D _{temp}	Difference between the inductor and the circuit temperatures. (<i>Unit:</i> Deg C). (<i>Default:</i> 0.)
R	<i>R</i> ₀	Parasitic resistance of the inductor. (<i>Unit:</i> ohm). (<i>Default:</i> 0.)

The formula for inductance is:

$$L = MS[1 + T_{c1}(\Delta T) + T_{c2}(\Delta T)^{2}]L_{0}$$
(6.18)

where

$$\Delta T = T_{circuit} + D_{temp} \angle T_{nom} \tag{6.19}$$

where $T_{circuit}$ is set in .temp and T_{nom} in .options *tnom*.

The formula for parasitic resistance is:

$$R_{parasitic} = R_0 / M. ag{6.20}$$

When the calculated inductance is greater than or equal to 0.1 H, T-Spice issues a warning message.

Examples

Note:

Ll na nb 10u

The example specifies an inductor with a value of 10 microhenries.

L1 a c 25 m=10scale=20R=10 dtemp=20 tc1=1.5e-2 tc2=5e-4

Instance (x)

An instantiation of a subcircuit definition, a Verilog-A device, or an external model device.

Subcircuit must be defined elsewhere in the input file with a .subckt/.ends block.

Nodes several levels deep within a subcircuit hierarchy are named using hierarchical notation in the form **xinstance.node**.

The \mathbf{x} key letter is also used to instance devices that are defined by Verilog-A modules and by external user-defined models.

Syntax

```
xname node1 [node2 ...] subcircuit | modulename | modelname [parameter=X
...] [M=M]
```

name	Subcircuit instance name.	
node1 node2	Specific instance nodes. The order of nodes named corresponds to the order specified by the .subckt command.	
parameter=X	Parameter(s) from the subcircuit definition or external model whose default value(s) are to be <i>overridden</i> by the assignment(s) made here. X can be a number or an expression. Subcircuit parameters have local scope. Parameters can be written in any order in both definition and instances. Parameters not specified here take their default values.	
subcircuit	Original subcircuit definition name.	
modulename	A Verilog-A module name	
modelname	External model name. T-Spice matches this device with a model defined using a .model command with a matching modelname an whose type is external .	
М	Multiplicity—the number of representations of parallel instances of the subcircuit. T-Spice multiplies the subcircuit terminal currents and charges by M . M can be any positive integer or decimal. (<i>Default:</i> 1.)	

Examples

```
.subckt inv in out Vdd length=1.25u nwidth=2u pwidth=3u
mt1 out in GND GND nmos l='length' w='nwidth'
mt2 out in Vdd Vdd pmos l='length' w='pwidth'
c2 out GND 800f
.ends inv
...
xinv1 a1 a2 Vdd inv nwidth=2.5u
```

The **.subckt**/.ends block creates a three-terminal subcircuit (an inverter) and names it inv. The subcircuit consists of two MOSFETs (one *n*-type and one *p*-type) and an 800-femtofarad capacitor. The instance statement defines an instance, named inv1, of the inverter subcircuit inv. Following the instance name are the three terminals of the instance (in order corresponding to that of the original

subcircuit definition); the name of the subcircuit to which it refers; and a new assignment for parameter **nwidth**, which overrides the default value assigned in the definition.

x1 1 0 resmodel res=1k

This statement instantiates a device with terminals attached to nodes 0 and 1 and matches it to a model defined using

```
.model resmodel external winfile="res.dll"
```

The parameter **res=1k** is passed to the external model.

JFET (j)

A transistor with drain, gate, and source terminals and an optional fourth terminal. (JFET stands for *junction field effect transistor*.)

Syntax

jname drain gate sourc	e model [[area=]A] [M= M]
name	JFET name.
drain	Drain terminal.
gate	Gate terminal.
source	Source terminal.
model	JFET model name. This is specified elsewhere in the input file in the form .model name njf pjf [parameters]
Α	Area scale factor. (Default: 1.)
М	Multiplicity—the number of devices to be placed in parallel. (<i>Default:</i> 1.)

Examples

```
jout 4 8 6 jfet2
j1 vdd in out jfet2 3
```

The **area** factor scales the generated currents; thus, the currents at the terminals of **j1** are three times those at the terminals of **jout**.

MESFET (z)

A transistor with three or four terminals: drain, gate, and source. (MESFET stands for *metal* semiconductor field effect transistor.)

Syntax

zname drain gate source [bulk] model [[area=]A] [l=L] [w=W] [M=M]

For HSPICE compatibility, you can create a MESFET device in T-Spice using a device name **jname** instead of **zname**. The syntax for these MESFET device statement is the same.]

name	MESFET name.
drain	Drain terminal.
gate	Gate terminal.
source	Source terminal.
bulk	Bulk terminal.
model	MESFET model name. This is specified elsewhere in the input file in the form .model name nmf pmf njf pjf [parameters]
Α	Area scale factor. (Default: 1.)
L	Device length. (Unit: meters.)
W	Device width. (Unit: meters.)
М	Multiplicity—the number of devices to be placed in parallel. (<i>Default:</i> 1.)

Examples

zout 4 8 6 mfet2 z1 vdd in out mfet2 3 ztest drain gate source vbg nmes1 w=20u l=2u

The **area** factor scales the generated current; thus, the currents at the terminals of **z1** are three times those at the terminals of **zout**. The third example shows specification of the bulk terminal and of width and length. The area is fixed by the given width and length; any **area** specification is overridden by this computed area.

MOSFET (m)

A transistor with four terminals: drain, gate, source, and bulk. (MOSFET stands for *metal oxide* semiconductor field effect transistor.)

Refer to **Additional Model Documentation** for complete documentation of the model parameter variations for each MOSFET level.

Unique T-Spice device model parameters can be found in "MOSFET Levels 8, 49 and 53 (BSIM3 Revision 3.3)" on page 416, "Variables for which equations are not given here are as follows." on page 424, "MOSFET Levels 44 and 55 (EKV Revision 2.6)" on page 445, and "MOSFET Level 57 / 70 (BSIM3SOI and BSIM4SOI)" on page 451.

Syntax

-	e bulk model [1 =L] [w =W] [ad =Ad] [pd =Pd] [as =As] [nrs= Nrs] [rdc =Rdc] [rsc =Rsc] [rsh =Rsh] [geo =Geo] [M =M]		
name	MOSFET name.		
drain	Drain terminal.		
gate	Gate terminal.		
source	Source terminal.		
bulk	Bulk terminal.		
model	MOSFET model name. The model is declared elsewhere in the input file in the form: .model name nmos pmos level=1 2 3 4 5 9 13 20 28 30 31 40 47 49 52 100 [parameters]		
L	Channel length. (<i>Unit:</i> meters. <i>Default:</i> set by the .options defl command.)		
W	Channel width. (<i>Unit:</i> meters. <i>Default:</i> set by the .options defw command.)		
Ad	Drain area. (<i>Unit:</i> square meters. <i>Default:</i> see "Drain area" on page 177.)		
Pd	Drain perimeter. (Unit: meters. Default: see "Drain perimeter" on page 178.)		
As	Source area. (Unit: square meters. Default: see "Source area" on page 177.)		
Ps	Source perimeter. (Unit: meters. Default: see "Source perimeter" on page 177.)		
Nrd	Number of squares of diffusion—drain. (<i>Default:</i> set by the .options defnrd command.)		
Nrs	Number of squares of diffusion—source. (<i>Default:</i> set by the .options defnrs command.)		

Rdc	Additional contact resistance, which overrides the rdc model parameter value—drain. (<i>Unit</i> : Ohms. <i>Default</i> : 0.0)
Rsc	Additional contact resistance, which overrides the rsc model parameter value—source. (<i>Unit</i> : Ohms. <i>Default</i> : 0.0)
Rsh	Source-Drain sheet resistance, which overrides the rsh model parameter. (<i>Unit</i> : Ohms/square. <i>Default</i> : 0.0)
Geo	Selector for source/drain sharing of stacked devices (Default: 0)
М	Multiplicity—the number of devices to be placed in parallel. (<i>Default:</i> 1.)
Delvto	Zero-bias threshold voltage shift. (Default: 0.0)

Default values for Ad, Pd, As, and Ps depend on the acm model parameter.

The parasitic diode characteristics are determined by the MOSFET device parameters **as**, **ad**, **pd**, **ps**, and **geo**, as well as the MOSFET model parameters **acm**, **cj**, **cjsw**, **cjgate**, **js**, **jsw**, **is**, **n**, **nds**, **vnds**, and **hdif**. The quantity **weff** also plays a role in determining default values for source and drain areas and perimeters for some values of **acm**.

The parasitic diode equations have been modified from the standard diode equations, in an effort to improve compatibility with other SPICE simulators and to improve simulator convergence. The diode charge/capacitance equations are unchanged; they are the same as for regular diodes. The DC current equations for MOSFET parasitic diodes are as follows.

If the MOSFET bulk-source voltage **vbs** is positive (the bulk-source diode is forward-biased), then the bulk-source diode's DC current is given by

$$ibs = isatbs \times (exp(vbs/(n \times vt) - 1))$$
(6.21)

where $\mathbf{vt} = kT/q$ (the thermal voltage), and the diode's saturation current isatbs is

$$isatbs = (js \times aseff) + (jsw \times pseff)$$
(6.22)

if that value is positive, or is zero otherwise. The effective source area **aseff** and perimeter **pseff** are computed as described below, depending on the value of the **acm** parameter.

Similarly, if the MOSFET bulk-drain voltage **vds** is positive (the bulk-drain diode is forward-biased), the bulk-drain diode's DC current is

$$ibd = isatbd \times (exp(vbd/(n \times vt) - 1))$$
(6.23)

where the diode saturation current isatbd is

$$isatbd = (js \times adeff) + (jsw \times pdeff)$$
(6.24)

if that value is positive, or is otherwise. The effective drain area **adeff** and perimeter **pdeff** are computed as described below.

The exponential function in both diodes is replaced by a linear extension when the current is larger than the value of the **expli** model parameter. The linear extension is chosen such that the diode current function is continuously differentiable at the transition point where the diode current equals **expli**.

The *n* parameter is now supported for MOSFET parasitic diodes.

When a MOSFET parasitic diode with saturation current **isat** is reverse-biased with a negative voltage **vdi**, then its current **idi** behaves as follows.

If 0 > vdi > vnds:

$$idi = isat \times vdi \tag{6.25}$$

If vdi < vnds:

$$idi = isat \times (vnds + (vdi - vnds)/nds)$$
(6.26)

The effective source and drain areas and perimeters are computed as in the chart below, depending on the value of the **acm** parameter. If **acm** = 3, the **geo** device parameter affects these calculations. The **geo** parameter is used to handle stacked MOSFET devices properly, and it can have the following values:

- **geo = 0** (default): the drain and the source are not shared by other devices.
- geo = 1: the drain is shared with another device.
- geo = 2: the source is shared with another device.
- geo = 3: the drain and the source are shared with other devices.

The **geo** parameter may be specified on the MOSFET device statement, at any point after the model name.

Each parasitic diode inherits its multiplicity factor **m** from its "parent" MOSFET. The values of **defas**, **defad**, and **moscap** are specified using **.options**.

	acm = 0	acm = 1	acm = 2	acm = 3
Source area				
with as	as $ imes$ wmlt ²	weff \times wmlt	as $ imes$ wmlt ²	as \times wmlt ²
without as	l × w (if moscap=1) defas (otherwise)	weff × wmlt	$2\times \text{hdifeff}\times \text{weff}$	$2 \times \text{hdifeff} \times \text{weff}$ (if geo = 0 or 1) hdifeff \times weff (otherwise)
Drain area				
with ad	$\text{ad}\times\text{wmlt}^2$	weff \times wmlt	$\text{ad}\times\text{wmlt}^2$	$\text{ad}\times\text{wmlt}^2$
without ad	l × w (if moscap = 1) defad (otherwise)	weff × wmlt	$2 \times \text{hdifeff} \times \text{weff}$	2 × hdifeff × weff (if geo = 0 or 2) hdifeff × weff (otherwise)
Source perimeter				
with ps	$\mathbf{ps} \times \mathbf{wmlt}$	weff	$\mathbf{ps} \times \mathbf{wmlt}$	$\textbf{ps} \times \textbf{wmlt}$

	acm = 0	acm = 1	acm = 2	acm = 3
without ps	2 × (I + w) (if moscap = 1) defps (otherwise)	weff	$4 \times hdifeff + 2 \times weff$	$4 \times$ hdifeff + weff (if geo = 0 or 1) $2 \times$ hdifeff (otherwise)
Drain perimeter				
with pd	pd imes wmlt	weff	$\mathbf{pd} \times \mathbf{wmlt}$	pd imes wmlt
without pd	2 × (I+w) (if moscap = 1) defpd (otherwise)	weff	$\begin{array}{l} 4 \times \text{hdifeff} + \\ 2 \times \text{weff} \end{array}$	$4 \times$ hdifeff + weff (if geo = 0 or 2) $2 \times$ hdifeff (otherwise)

The parasitic drain/source diodes' sidewall capacitance now makes use of the new **cjgate** parameter, which describes the sidewall capacitance per unit length along the gate edge. If **cjgate** is specified and the MOSFET's effective width **weff** is not greater than the diode's perimeter, then the total sidewall capacitance is given by:

$$csw = cjsw \times (p - weff) + (cjgate \times weff)$$
(6.27)

where **p** is **ps** for a source diode or **pd** for a drain diode. Otherwise, if **cjgate** is not specified or **weff** > **p**, the total sidewall capacitance is:

$$\mathbf{csw} = \mathbf{cjsw} \times \boldsymbol{p} \tag{6.28}$$

Examples

m12 n1 n2 GND GND ndep l=10u w=5u ad=100p as=100p pd=40u ps=40u

Mutual Inductor (k)

A coupled pair of inductors.

Syntax

kname inductor1 inductor2 K

name	Mutual inductor name.
inductor1	First inductor.
inductor2	Second inductor.
К	Coefficient of coupling $(0 < \mathbf{K} \le 1)$.

Examples

kl La Lb 10u

The example illustrates coupling between two inductors La and Lb, defined elsewhere in the input file:

La nodela nodela 10m Lb nodelb nodelb 20m

The *order* of node naming on the inductor statements determines the relative directions of current flow in the mutual inductor. The current flow from **node1a** to **node2a** (inductor **La**) is in the same direction as from **node1b** to **node2b** (inductor **Lb**). To reverse the current flow in either inductor, reverse the node order on the appropriate inductor statement.

Resistor (r)

A two-terminal resistor.

The resistance *R* is influenced by the temperature as follows:

 $R = \mathbf{N} \left(1 + \mathbf{A}T + \mathbf{B}T^2 \right)$ T = Ta - Tn

where N, A, B are device parameters described below; Ta (the "ambient" temperature) is set by the .temp command; and Tn (the "nominal" temperature) is set by the .options thom command.

Resistors can be specified using geometric and physical parameters such as l, w, and rsh. For a description of how resistance is calculated using these parameters, refer to the device model "Resistor" on page 461.

Optional capacitors may be included between the terminals and a bulk node (usually ground) to obtain a simple transmission line model.

Syntax

```
rname node1 node2 r=r [resistor parameters]
or
rname nodel node2 r [tc1[tc2]] [resistor parameters]
or
rname node1 node2 modelname + [[r=r] [resistor parameters]
or
rname node1 node2 modelname r [tc1[tc2]] [resistor_parameters]
name
                          Resistor name.
                          Positive terminal.
node1
node2
                          Negative terminal.
modelname
                          Name of resistor model. Must match .model name when type is r.
                          For additional information, see ".model" on page 99.
r=resistance
                          Nominal resistance. (Unit: ohms.)
```

In the first syntax and the third syntax, the *resistor_parameters* field is of the form:

[tcl=tc1] [tc2=tc2] [noise=noise] [m=mult] [scale=devscale] [ac=acres]
[dtemp=dtemp] [l=1] [w=w] [c=c]

In the second syntax and the fourth syntax, the **resistor_parameters** field is of the form:

<pre>[noise=noise] [m=mult] [c=c]</pre>	[scale =scale] [ac =acres] [dtemp =dtemp] [1 =1] [w =w]
Parameter	Description
tc1	First-order temperature coefficient. (Default: resistor model parameter <i>tc1r</i> ; 0 if no model is specified.)
tc2	Second-order temperature coefficient. (Default: resistor model parameter <i>tc2r</i> ; 0 if no model is specified.)
noise	Noise source multiplier. noise=0 eliminates resistor noise. (Default: resistor model parameter noise ; 1 if no model is specified.)
mult	Multiplicity—the number of devices to be placed in parallel. (<i>Default:</i> 1.)
devscale	Multiplies resistance and capacitance of device. (Default: 1.)
acres	Specifies device resistance during AC analysis. (<i>Default:</i> resistor model parameter rac ; if no model is specified, default is DC resistance.)
dtemp	Specifies the difference between the device temperature and the general circuit operating temperature. (<i>Default:</i> 0.)
I	Resistor length. Scaled length is obtained by multiplying <i>I</i> by .options scale (not the element parameter <i>devscale</i> , above) or the resistor model parameter <i>shrink</i> . (<i>Default:</i> resistor model parameter <i>I</i> .)
w	Resistor width. Scaled width is obtained by multiplying w by .options scale (not the element parameter <i>devscale</i> , above) or the resistor model parameter <i>shrink</i> . (<i>Default:</i> resistor model parameter w .)
c	Capacitance between node2 and a bulk node specified as a model parameter. Multiplied by .options scale . (<i>Default:</i> resistor model parameter <i>cap</i> .)

Note:

If T-Spice Pro calculates the effective resistance, R_{eff} , to be less than $10^{-5} \Omega$, then a warning message is issued and the effective resistance is automatically assigned a value of $10^{-5} \Omega$. See the model description "Resistor" on page 461 for calculation of R_{eff} .

Examples

r1 2 1 30K TC=1e-2,1e-4

This produces a resistor of resistance 30 kilohms at the nominal temperature tnom. If the temperature T is different from *tnom*, the resistance is 30,000*(1+0.01*(T-tnom)+0.0001*(T-tnom)*(T-tnom)). For example, if the circuit temperature is 127 degrees and *tnom* is 27 degrees, the resistance is 30,000*(1+0.01*100+0.0001*100*100) = 90,000 Ohms.

r1 n1 n2 rmod l=5u w=10u
.model rmod r rsh=1k cap=10pf cratio=0.5

This example creates a resistor between nodes **n1** and **n2** of size 500 Ohms (r = l*rsh/w) as well as two capacitors, 5 picofarads each, one between **n1** and **Gnd**, the other between **n2** and **Gnd**.

Voltage- or Current-Controlled Switch (s)

A switch is implemented as a resistor between **node1** and **node2**, whose resistance is controlled by the controlling voltage or current. (See also the device model "Switch" on page 464.)

Syntax

The general syntax for T-Spice's voltage-controlled switch element is:

sname node1 node2 control1 control2 modelname

The syntax for a current-controlled switch is:

sname nodel node2 vsourcename modelname

name	Switch name.
node1	Positive terminal.
node2	Negative terminal.
control1	Name of the voltage source supplying the control voltage.
control2	Name of the voltage source supplying the control voltage.
vsourcename	Controlling current for a current-controlled switch.
modelname	Name of resistor model. Must match .model modelname when type is sw or csw . For additional information, see " .model " on page 99.

Resistance is **roff** when the switch is off and **ron** when the switch is on. The switch is on when the control voltage or current for the switch is greater than its threshold voltage or current.

The **ron**, **roff**, and threshold values for the switch are specified in a **.model** statement whose model name matches the **modelname** on the device statement.

T-Spice switch elements can display hysteresis, so that the threshold value is different when the control voltage/current is increasing than when it is decreasing. For a voltage-controlled switch, the threshold voltage is **vt** when **v(control1, control2)** is increasing, and **vt-vh** when **v(control1, control2)** is decreasing. For a current-controlled switch the threshold current is **it** when **i(vsourcename)** is increasing, and **it-ih** when **i(vsourcename)** is decreasing. The switch is on when the control voltage or current is greater than the threshold value.

The **dv** and **di** parameters define a small interval around the threshold in which a smooth transition between **ron** and **roff** is made.

Examples

Voltage-Controlled Switch

The following two examples would both produce voltage-controlled switches:

s1 n1 n2 c1 c2 swmod
.model swmod sw ron=1 roff=1e12 vt=2.5

and

```
s1 out 0 0 in swmod
.model swmod sw vt=0 dv=0.2
```

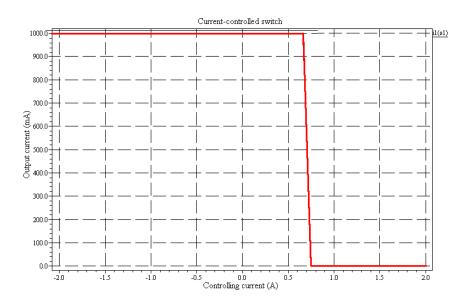
The waveform for this switch is illustrated in "Voltage-Controlled Resistor" on page 195.

Current-Controlled Switch

The following example demonstrates the modeling of a current-controlled switch:

s1 out 0 vin swmod
.model swmod csw it=0.7 di=0.1

This switch would produce the following waveform:



Transmission Line (t)

A mechanism for "lossless" or "lossy" signal propagation.

The "lossless" transmission line is described by characteristic impedance and delay; the "lossy" transmission line is described by RLCG parameters.

Syntax

"Lossless" Transmission Line

<pre>tname node1 node2 node3 node4 z0=Z [td=D] [f=F [nl=N]]</pre>	
name	Transmission line name.
node1 node4	Terminals. node1 (+) and node2 (-) are at one end of the transmission line, node3 (+) and node4 (-) at the opposite end.
Z	Impedance. (Unit: ohms.)
D	Transmission delay. The delay may instead be specified indirectly from F and N . (Unit: seconds.)
F	Line frequency. (Unit: Hertz. Default: 1×10^9 .)
Ν	Normalized number of wavelengths. The transmission delay is the ratio of the wavelength number N to the line frequency F . (<i>Default:</i> 0.25.)

"Lossy" Transmission Line

tname node1 node2 node3 node4 r=R l=L c=C g=G length=W [lumps=X] [lumptype=Y]

name	Transmission line name.
node1 node4	Terminals. <i>node1</i> (+) and <i>node2</i> (-) are at one end of the transmission line, <i>node3</i> (+) and <i>node4</i> (-) at the opposite end.
R	Distributed resistance. (Unit: ohms/meter.)
L	Distributed inductance. (Unit: henries/meter.)
С	Distributed capacitance. (Unit: farads/meter.)
G	Distributed conductance. (Unit: siemens/meter.)
W	Physical length. (Unit: meters.)
x	Number of lumps used for iterative ladder circuit (ILC) expansion. (<i>Default:</i> 1.)
Y	Type of lumps used for ILC expansion (see below). (Default: 3.)

Y is one of the following:

0	"Gamma" type lumps.
1	"Tee" type symmetric lumps.
2	"Pi" type symmetric lumps.
3	Hybrid RGT lumps (default).

Examples

tline2 pad2 GND pin2 GND z0=100 td=10ns
tline3 drive GND out GND z0=300 f=100meg nl=.1

Voltage Source (v)

A two-terminal ideal voltage supply.

Exponential, pulse, piecewise linear, frequency-modulated, sinusoidal, and customizable (vectorized) waveforms are available.

Voltage sources whose waveform is described using an expression can be created using the **e**-element with an expression and the **time()** function.

Syntax

vname nodel nodel [[**DC**] V] [**AC** M [P]] [waveform]

name	Voltage source name.
node1	Positive terminal—or bus named by an associated .vector command.
node2	Negative terminal.
V	DC level between <i>node1</i> and <i>node2</i> . (Unit: volts. Default: 0.)
waveform	Waveform identifier and parameters (see below).
М	AC magnitude. (Unit: volts.)
Ρ	AC phase. (Unit: degrees. Default: 0.)

DC, AC, and transient values can be specified independently and in any order.

waveform is one of the following:

Exponential Waveform

exp (Vi Vp [Dr [Tr [Df [Tf]]])

Vi	Initial voltage. (Unit: volts.)
Vp	Peak voltage. (Unit: volts.)
Dr	Rise time delay. (Unit: seconds. Default: 0.)
Tr	Rise time constant. (Unit: seconds. Default: 0.)
Df	Fall time delay. (Unit: seconds. Default: 0.)
Tf	Fall time constant. (Unit: seconds. Default: 0.)

Pulse Waveform

pulse (Vi Vp [D [Tr [Tf [Pw [Pp]]]]]) [ROUND=RND]

Vp	Peak voltage. (Unit: volts.)
D	Initial delay. (Unit: seconds. Default: 0.)
Tr	Rise time. (Unit: seconds. Default: time step from .tran.)
Tf	Fall time. (Unit: seconds. Default: time step from .tran.)
Pw	Pulse width. (Unit: seconds. Default: stop time from .tran.)
Рр	Pulse period. (Unit: seconds. Default: stop time from .tran.)
RND	Rounding half-interval. A corner at time <i>T</i> is replaced by a smoothly differentiable polynomial in the interval (T – <i>RND</i> , T + <i>RND</i>). The maximum <i>RND</i> is half the distance to the nearest neighboring corner. (<i>Default:</i> 0—no rounding.)

Note that rise time is not necessarily a "rise" time, but is the time to go from the initial voltage to the pulse voltage, regardless of whether it's smaller or larger.

Piecewise Linear Waveform

pwl (<i>T1 V1</i> [<i>T2 V2</i>]) [ROUND=RND] [REPEAT [=Tr]] [TD=DELAY]
T1 T2	Time at corner 1, 2, and so on. (Unit: seconds.)
V1 V2	Voltage at corner 1, 2, and so on. (Unit: volts.)
ROUND	Rounding half-interval. A corner at time <i>T</i> is replaced by a smoothly differentiable polynomial in the interval (T – <i>RND</i> , T + <i>RND</i>). The maximum <i>RND</i> is half the distance to the nearest neighboring corner. (<i>Default:</i> 0—no rounding.)
REPEAT	Starting time within the specified waveform for an infinite number of repetitions of the subwaveform. If Tr is not specified, the entire waveform repeats indefinitely (i.e., $Tr=0$). Tr must be less than or equal to the duration of the waveform. Waveforms can only repeat if the start and end points match. If they do not match, the repeat option is ignored. The REPEAT keyword can be abbreviated to R .
TD	Time delay added to the beginning of the waveform. If you specify corners <i>T1</i> , <i>T2</i> , <i>etc.</i> and TD=DELAY , then the defined voltage values will actually be applied at effective corner times <i>T1+DELAY</i> , <i>T2+DELAY</i> , <i>etc.</i>

Piecewise Linear Waveform File

pwlfile filename [ROUND=RND] [REPEAT[=Tr]] [TD=DELAY]

filename	Input file which contains the piecewise linear waveform definition in a series of time, voltage pairs, one per line.
ROUND	Same meaning as with pwl waveforms
REPEAT	Same meaning as with pwl waveforms
TD	Same meaning as with pwl waveforms

Frequency-Modulated Waveform

sffm (Vo Vp [Fc [Xm [Fs]]])

Vo	Offset voltage. (Unit: volts.)
Vp	Peak voltage. (Unit: volts.)
Fc	Carrier frequency (<i>Unit:</i> Hertz. <i>Default:</i> $1/T$, where T is the stop time from .tran .)
Хт	Modulation index. (Default: 0.)
Fs	Signal frequency. (<i>Unit:</i> Hertz. <i>Default:</i> 1/ <i>T</i> , where <i>T</i> is the stop time from .tran .)

Sinusoidal Waveform

sin (Vo Vp [Fr [De [Da [Ph]]])

Vo	Offset voltage. (Unit: volts.)
Vp	Peak voltage. (Unit: volts.)
Fr	Frequency. (<i>Unit:</i> Hertz. <i>Default:</i> $1/T$, where <i>T</i> is the stop time from .tran.)
De	Delay time. (Unit: seconds.)
Da	Damping factor. (Unit: 1/seconds.)
Ph	Phase advance. (Unit: degrees.)

Vectorized Waveform

bit bus	({pattern}	[on= A]	[off= <i>Z</i>]	[delay= D]	[pw= <i>P</i>]	[rt= <i>R</i>]	[ft= <i>F</i>]	[lt= <i>L</i>]
[ht=	H]) [ROUND=1	RND]						

pattern	An expression consisting of one or more string or string-multiplier combinations (see below).
Α	On voltage (Unit: volts. Default: 0.001.)
Z	Off voltage (Unit: volts. Default: 0.)
D	Delay time. (Unit: seconds. Default: 0.)
Ρ	Pulse width: $\mathbf{P} = \mathbf{R} + T_A = \mathbf{F} + T_Z$, where T_A is the time during a pulse where the voltage is "on" ($V = \mathbf{A}$) and $T\mathbf{Z}$ is the time during a pulse where the voltage is "off" ($V = \mathbf{Z}$). (<i>Unit:</i> seconds. <i>Default:</i> 10×10^{-9} .)
R	Rise time. (Unit: seconds. Default: 1×10^{-9} .)
F	Fall time. (Unit: seconds. Default: 1×10^{-9} .)
L	Low time: $\mathbf{L} = \mathbf{F} + T_{\mathbf{Z}}$, where $T_{\mathbf{Z}}$ is the time during a pulse where the voltage is "off" ($V = \mathbf{Z}$). (Unit: seconds. Default: 10×10^{-9} .)

Н	High time: $H = R + T_A$, where T_A is the time during a pulse where the voltage is "on" ($V = A$). (<i>Unit:</i> seconds. <i>Default:</i> 10×10^{-9} .)
RND	Rounding half-interval. A corner at time <i>T</i> is replaced by a smoothly differentiable polynomial in the interval (T – <i>RND</i> , T + <i>RND</i>). The maximum <i>RND</i> is half the distance to the nearest neighboring corner. (<i>Default:</i> 0—no rounding.)

A *bit* pattern consists of a set of numbers (possibly associated with multiplier factors) whose binary representations sequentially specify the "on"/"off" structure of the waveform. The pattern takes the form $a(b(x) c(y) \dots$), where a, b, and c are the optional multiplier factors and x and y are the numbers.

A *bus* pattern consists of a set of numbers (possibly associated with multiplier factors) whose binary representations—"bit strings"—are grouped together as a waveform bus and treated as a single input. The length of the bit strings is specified by the **.vector** command. If there are n nodes in a vector, then T-Spice assigns the first n bits of each bit string to those nodes. Extra bits are discarded. If there are not enough bits, the highest-order bits are set to zero. The leftmost node name in the **.vector** command takes the most significant bit.

Numbers are specified on the device statement in binary, hexadecimal (suffixed by \mathbf{h}), octal (suffixed by \mathbf{o}), or decimal (suffixed by \mathbf{d}) notation. (For decimal representations the number of lower-order bits to be collected is also given.)

Examples

v1 n1 GND sin (2.5 2.5 30MEG 100n)

v1 generates a **sin** (sinusoidal) input. It has an amplitude of 2.5 volts, a frequency of 30 MHz, an offset of 2.5 volts from system ground, and a time delay of 100 nanoseconds after the start of the simulation before the wave begins.

v2 n2 GND bit ({01010 11011} on=5.0 off=0.0 pw=50n rt=10n ft=30n)

v2 generates a **bit** input. Enclosed in braces { } are two binary-valued five-bit patterns specifying the waveform. The two patterns alternate in time. The **on** voltage value is 5.0 volts; the **off** voltage value is zero. The pulse width (**pw**), 50 nanoseconds, is the time the wave is either (ramping up and) on, or (dropping down and) off. The rise time (**rt**), 10 nanoseconds, is the time given for the wave to ramp from off to on; and the fall time (**ft**), 30 nanoseconds, the time given for the wave to drop from on to off.

v3 n3 GND bit ({5(01010 5(1))} pw=10n on=5.0 off=0.0)

v3 generates a *repeating* **bit** input. Two distinct patterns are given again, but now *multiplier factors* are included. The wave consists of two alternating patterns: the first pattern contains five bits, the second is a single bit. The five-bit pattern is followed by five successive repetitions of the single-bit pattern, and this combination is repeated five times. (The same pattern could be described by **{5(3(01) 4(1))}**.) The pulse width and on and off voltages are again specified, but the rise and fall times take default values.

```
.vector bb {n7 n6 n5 n4}
vb bb GND bus ({50(Ah) 30(7d4) 20(1000)} pw=5n on=5.0 off=0.0)
```

The **.vector** command defines the bus waveform generated by voltage source **vb**. The command assigns the bus a name (**bb**) and specifies by name the number of bits the bus waveform will have (four: **n7** through **n4**). The voltage source statement, which contains the **bus** keyword, specifies waveforms with one or more patterns, along with pulse width and level information.

- The first pattern is Ah (hex) = 1010 (binary). Thus, using the names given on the .vector command, n7=1, n6=0, n5=1, and n4=0. The pattern is repeated 50 times (that is, maintained for a time period equal to the pulse width multiplied by 50).
- The next pattern is 7d4—that is, 7 (decimal) = 111 (binary), or, to four lower-order bits, 0111. So n7=0, n6=1, n5=1, and n4=1. The pattern is repeated 30 times.
- The last pattern is **1000** (binary), so **n74**=1, **n6**=0, **n5**=0, and **n4**=0. The pattern is repeated 20 times.

Voltage-Controlled Current Source (g)

A two-terminal ideal DC current supply with a level that is a function of one or more controlling voltages. This device can be utilized to model a wide variety of elements, including voltage-controlled resistors, nonlinear capacitors, voltage-controlled capacitors, switch-level MOSFETs, and diodes. See "Examples" on page 194.

Syntax

Linear

gname nodel node2 nal nbl K [Options]

Polynomial

gname nodel node2 POLY(N) nal nb2 [na2 mb2 ...] P₀ P₁ P₂ ... [Options]

LaPlace Transform

gname nodel nodel LAPLACE nal nbl $a_1 a_2 \ldots a_m [/b_1 b_2 \ldots b_m]$ [Options]

Nonlinear | Behavioral

gname node1 node2 [cur='expression'] [chg='expression'] [Options]

gname	Voltage-controlled current source name. Must begin with "g".
node1	Positive terminal. Positive current flows into <i>node1</i> .
node2	Negative terminal. Positive current flows out of <i>node2</i> .
κ	Transconductance—the ratio of the output current to the control voltage.
POLY	Keyword indicating that the output current is a polynomial function of the control voltages.
Ν	Number of control voltages (valid values 1-6).
LAPLACE	Keyword indicating that the output current is described via a Laplace transform function
cur	Keyword indicating an expression expression that defines current flowing through the device.
chg	Keyword indicating an expression expression that defines terminal charges of the device. Used to define the capacitance of a nonlinear capacitor.
expression	Expression involving any node voltages and source currents.
na1 nb2	Node pairs whose voltages control the level of the g element.
$\boldsymbol{P}_{0} \boldsymbol{P}_{1} \boldsymbol{P}_{2} \dots$	Coefficients of the control polynomial.
$\mathbf{a}_0 \mathbf{a}_1 \mathbf{a}_2 \dots \mathbf{a}_m$	Numerator of Laplace transfer function.
$\mathbf{b}_0 \mathbf{b}_1 \mathbf{b}_2 \dots \mathbf{a}_n$	Denominator of Laplace transfer function.

Options

[MAX=value] [MIN=value] [ABS =[0 | 1]] [TC1=value] [TC2=value] [SCALE=value]

MAX	Maximum output voltage value.
MIN	Minimum output voltage value.
ABS	Output is absolute value if ABS=1.
TC1, TC2,	First- and second-order temperature coefficients.
SCALE	Element value multiplier.

Current is reckoned positive if it enters the **g** element at its first terminal.

Linear Functions

The first form of voltage-controlled current sources creates a current source with a level equal to *K* multiplied by the voltage across the node pair **na1 nb1**.

Polynomial Functions

The second form creates a current source whose level is a nonlinear polynomial function of the voltages across one or more node pairs. Let

- x = voltage across node pair na1 nb1;
- y = voltage across node pair *na2 nb2* (if *N* \ge 2);
- z =voltage across node pair **na3 nb3** (if **N** \ge 3).

Then the controlled voltage source's level is defined as follows:

If **N** = 1:

$$P_0 + P_1 x + P_2 x^2 + p_3 x^3 + \dots ag{6.29}$$

If **N** = 2:

$$P_0 + P_1 x + P_2 y + P_3 x^2 + P_4 xy + P_5 y^2 + P_6 x^3 + P_7 x^2 y + P_8 xy^2 + P_9 y^3 + \dots$$
(6.30)

If N = 3:

$$P_{0} + P_{1}x + P_{2}y + P_{3}z + P_{4}x^{2} + P_{5}xy + P_{6}xz + P_{7}y^{2} + P_{8}yz + P_{9}z^{2} + P_{10}x^{3} + P_{11}x^{2}y + P_{12}x^{2}z + P_{13}xy^{2} + P_{14}xyz + P_{15}xz^{2} + P_{16}y^{3} + P_{17}y^{2}z + P_{18}yz^{2} + P_{19}z^{3} + \dots$$
(6.31)

If N = 1 and only one polynomial coefficient is specified, it is assumed to be P1, to facilitate the specification of linearly-controlled sources.

Laplace Functions

With the Laplace keyword, the current source is implemented as a Laplace transfer function.

(6.32)

$$H(s) = \frac{a_0 + a_1 s + a_2 s^2 + \dots + a_m s^m}{b_0 + b_1 s + b_2 s^2 + \dots + b_n s^n}$$

Expression-Controlled Functions

The fourth form of voltage controlled current sources uses mathematical expressions ("**Expressions**" on page 56) to define the output current and charge functions. At least one of the keywords **cur** or **chg** must be specified.

Examples

Gtest in out n10 n17 -2.314

Gtest is a **g** element. Its terminals are connected to nodes in and **out**. The voltage across the node pair **n10** and **n17** control the level of **gtest**. The level of **gtest** equals $(-2.314)\{v(n10) - v(n17)\}$. If this is a positive number, current flows in this direction: node **in-gtest** -node **out**.

G1 0 1 poly(1) + n10 n17 + 1m 0 2

g1 is a **g** element. It terminals are connected to nodes **0** and **1**. The level of **g1** is a polynomial in one variable. The one variable is the voltage across the node pair **n10** and **n17**. The level of **g1** is computed as

$$g1 = 10^{23} + 2\{v(n10) \ge v(n17)\}^2$$
(6.33)

If this is a positive number, current flows in this direction: node **0–g1**–node **1**.

G3 01 poly(3) + nkingnkong + npingnpong + nsingnsong + 01 03 0 4

g3 is a **g** element. Its terminals are connected to nodes **0** and **1**. The level of **g3** is a polynomial in three variables. The three variables are the voltages across the three node pairs **nking** and **nkong**, **nping** and **npong**, **nsing** and **nsong**. The level of **g3** is computed as

$$g3 = \{v(nking) \angle v(nkong)\} + 3\{v(nsing) \angle v(nsong)\} + 4\{v(nking) \angle v(nkong)\}\{v(nping) \angle v(npong)\}$$
(6.34)

If this is a positive number, current flows in this direction: node **0–g3**–node **3**.

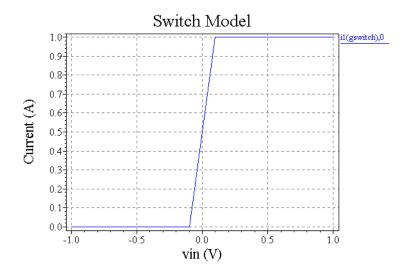
Laplace Transforms

For examples of Laplace transforms, please refer to the analogous examples of Laplace transforms in the voltage-controlled voltage source section (see "Voltage-Controlled Voltage Source (e)" on page 198).

Voltage-Controlled Resistor

```
gswitch out 0 cur='v(out)*table(v(in), -1,1e-12, -0.1,1e-12, 0.1,1, 1,1)'
```

The switch's resistance between nodes **out** and **ground** is controlled by the voltage at node **in**. The switch is off when **v(in)** is less than -0.1 V, and on when **v(in)** is greater than 0.1 V. The interval - 0.1V < v(in) < 0.1V serves as a smooth transition between the on and off states. Note the use of the table function to describe the conductance characteristics of the switch: the conductance is 10^{-12} (corresponding to a resistance of 10^{+12}) when the switch is off, while the conductance is 1 when the switch is on. The chart below shows the switch's output current as a function of input voltage (holding the voltage at node out fixed at 1V).



Nonlinear Capacitor

The following example models a nonlinear capacitor whose capacitance is a function of applied voltage. A capacitor is described by specifying a charge function that depends on the voltage across the device. The device's capacitance is the derivative of the charge function with respect to the voltage. For example, a CMOS capacitor might be modeled as follows:

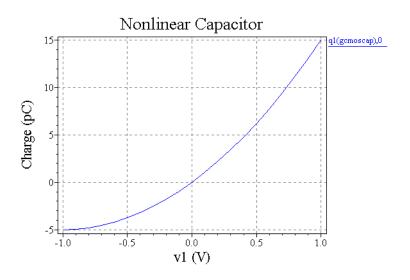
.param c0=10p vcc=1 gcmoscap n+ n- chg='c0*v(n+,n-) * (1 + 0.5*vcc*v(n+,n-))'

The capacitance of the device **gcmoscap** is then given by:

$$C = c0 * (1 + vcc * v(n+,n-))$$
(6.35)

where *c0* represents the capacitance at zero applied voltage, and *vcc* measures the sensitivity of the capacitance with respect to input voltage.

The capacitor's charge depends on applied voltage, as shown in the chart below.



Voltage-Controlled Capacitor

A voltage-controlled capacitor is a two-terminal device whose capacitance is a function of node voltages elsewhere in the circuit. Such an element can be modeled in T-Spice with the expression-controlled g-element, using the **chg** parameter.

For example, the capacitance of a vertically moving parallel plate capacitor, a device used in the design of microelectromechanical systems (MEMS) might be modeled as follows:

gvccap n+ n- chg='v(n+,n-)*k/v(gapdistance)'

where **gapdistance** refers to a state variable which represents the distance between the capacitor's plates and **k** is a proportionality constant defined using ".**param**" on page 116.

Switch-Level MOSFET

The T-Spice **stp()** and **table()** functions can be used to create a switch-level model for a MOSFET. An example of such a model for an N-type MOSFET is as follows:

```
gmos d s cur='v(d,s) * table(v(g,s)*stp(v(d,s)) + v(g,d)*(1-stp(v(d,s))),
+ 0,1e-12, 0.4,1e-12, 1,1e-7, 2,2e-5,
+ 3, 1e-4, 5, 4e-4)'
```

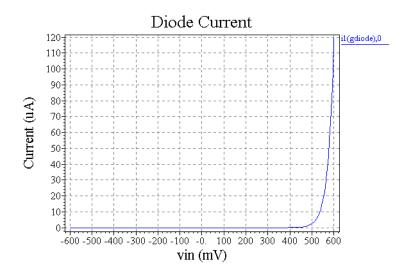
Note that the use of the **stp()** function allows for a model that is symmetric with respect to source and drain.

Diode

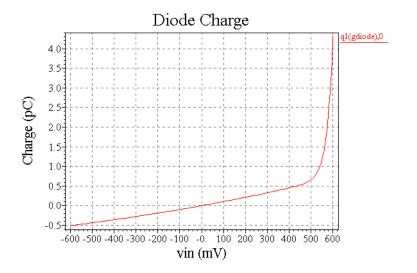
The T-Spice **g**-element can be used to model any device for which analytic equations are available. When the equations have different forms for different regions of operation, the T-Spice **stp()** function can be useful. The following example models the current and capacitance of a diode. Note that the capacitance equation has different forms for the forward and reverse bias regions, but the **stp()** function allows us to describe the entire model using a single charge expression.

.param vt=0.02586 is=1e-14 tt=30n cjo=1e-12 vj=1 m=0.5

This example would produce the following waveform for current:



and the following waveform for charge:



Voltage-Controlled Voltage Source (e)

A two-terminal ideal DC voltage supply with a level that is a function of one or more controlling voltages.

Syntax

Linear

ename nodel node2 nal nbl K [Options]

Polynomial

ename nodel node2 POLY(N) nal nbl [na2 nb2...] P₀ P₁ P₂ ... [Options]

LaPlace Transform

```
ename nodel nodel LAPLACE nal nbl a_1 a_2 \ldots a_m [/b_1 b_2 \ldots b_n] [Options]
```

Nonlinear | Behavioral

ename node1 node2 vol='expression' [Options]

Parameter	Description
ename	Voltage-controlled voltage source name. Must begin with "e".
node1	Positive terminal.
node2	Negative terminal.
κ	Voltage gain-the ratio of the output voltage to the control voltage.
POLY	Keyword indicating that the output voltage is a polynomial function of the control voltages.
Ν	Number of control voltages (valid values 1-6).
LAPLACE	Keyword indicating that the output current is described via a Laplace transform function
vol	Keyword indicating that the source voltage is specified by an expression.
expression	Expression specified by the vol keyword.
na1 nb2	Node pairs whose voltages control the level of the e element.
P ₀ P ₁ P ₂	Coefficients of the control polynomial.
$\mathbf{a}_0 \mathbf{a}_1 \mathbf{a}_2 \dots \mathbf{a}_m$	Numerator of Laplace transfer function.
$\mathbf{a}_0 \mathbf{a}_1 \mathbf{a}_2 \dots \mathbf{a}_m$ $\mathbf{b}_0 \mathbf{b}_1 \mathbf{b}_2 \dots \mathbf{a}_n$	Denominator of Laplace transfer function.

Options

[MAX=value] [MIN=value] [ABS =[0 | 1]] [TC1=value] [TC2=value] [SCALE=value]

MAX	Maximum output voltage value.
MIN	Minimum output voltage value.
ABS	Output is absolute value if ABS=1.
TC1, TC2,	First- and second-order temperature coefficients.
SCALE	Element value multiplier.

Linear Functions

The first statement creates a voltage source with a level equal to *K* multiplied by the voltage across node pair *na1 nb1*.

Polynomial Functions

The second statement creates a voltage source whose level is a nonlinear polynomial function of the voltages supplied by up to three voltage sources. Let

- x = voltage across node pair **na1 nb1**;
- $y = \text{voltage across node pair } na2 nb2 (if N \ge 2);$
- $z = \text{voltage across node pair } \textbf{na3 nb3} \text{ (if } \textbf{N} \ge 3\text{)}.$

Then the controlled voltage source's level is defined as follows:

If **N** = 1:

$$P_0 + P_1 x + P_2 x^2 + P_3 x^3 + \dots ag{6.36}$$

If **N** = 2:

$$P_0 + P_1 x + P_2 y + P_3 x^2 + P_4 x y + P_5 y^2 + P_6 x^3 + P_7 x^2 y + P_8 x y^2 + P_9 y^3 + \dots$$
(6.37)

If **N** = 3:

$$P_{0} + P_{1}x + P_{2}y + P_{3}z + P_{4}x^{2} + P_{5}xy + P_{6}xz + P_{7}y^{2} + P_{8}yz + P_{9}z^{2} + P_{10}x^{3} + P_{11}x^{2}y + P_{12}x^{2}z + P_{13}xy^{2} + P_{14}xyz + P_{15}xz^{2} + P_{16}y^{3} + P_{17}y^{2}z + P_{19}yz^{2} + P_{19}z^{3} + \dots$$
(6.38)

If N = 1 and only one polynomial coefficient is specified, it is assumed to be P1, to facilitate the specification of linearly-controlled sources.

Laplace Functions

With the Laplace keyword, the current source is implemented as a Laplace transfer function. The three transform equations supported by the Laplace transform source types in T-Spice are shown in the

equation below and several of the examples ("Integrator element" on page 201, "Differentiator element" on page 201, "Single Pole / Residue" on page 202).

(6.39)

$$H(s) = \frac{a_0 + a_1 s + a_2 s^2 + \dots + a_m s^m}{b_0 + b_1 s + b_2 s^2 + \dots + b_n s^n}$$

Expression-Controlled Functions

The fourth form of voltage controlled current sources uses mathematical expressions ("**Expressions**" on page 56) to define the output current and charge functions. At least one of the keywords **cur** or **chg** must be specified.

Examples

Etest in out n10 n17 -2.314

Etest is an **e** element. Its nodes are connected to nodes in and **out**. The voltage across the node pair **n10** and **n17** control the level of **etest**. The level of **etest** equals $(-2.314)\{v(n10) - v(n17)\}$.

E1	0	1	poly(1)				
+			n10	n17			
+					1m	0	2

e1 is an **e** element. It terminals are connected to nodes **0** and **1**. The level of **e1** is a polynomial in one variable. The one variable is the voltage across the node pair **n10** and **n17**. The level of **e1** is computed as

$$e1 = 10^{23} + 2\{v(n10) \angle v(n17)\}^2$$
(6.40)

E3	0	1	poly(3)					
+			nking	nkong				
+			nping	npong				
+			nsing	nsong				
+					0	1	0	304

e3 is an **e** element. Its terminals are connected to nodes **0** and **1**. The level of **e3** is a polynomial in three variables. The three variables are the voltages across the three node pairs **nking** and **nkong**, **nping** and **npong**, **nsing** and **nsong**. The level of **e3** is computed as

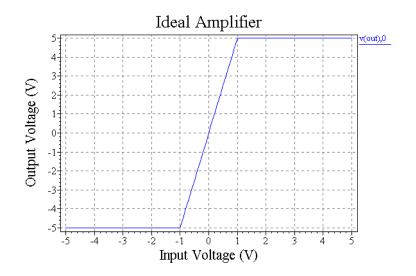
$$e3 = \{v(nking) \angle v(nkong)\} + 3\{v(nsing) \angle v(nsong)\} + 4\{v(nking) \angle v(nkong)\}\{v(nping) \angle v(npong)\}$$
(6.41)

Ideal OpAmp

The expression-controlled e-element (voltage-controlled voltage source) can be used with the table function to model an ideal voltage amplifier. The following circuit element implements a voltage amplifier with a gain of 5, and minimum and maximum output voltages of -5V and 5V, respectively.

eamp out 0 vol='table(v(in), -1, -5, 1, 5)'

This example would produce the following waveform:



Integrator element

You can model an integrator using the e element with the Laplace transformation function.

Consider the behavior of an integrator. In the frequency domain, the integrator is modeled as:

$$V_{out} = \frac{k}{s} V_{in} \tag{6.42}$$

And, in the time domain the integrator is modeled as:

$$V_{out} = k \int V_{in} dt \tag{6.43}$$

The transfer function for the voltage gain is:

$$H(s) = \frac{V_{out}}{V_{in}} = \frac{k}{s}$$
(6.44)

This is equivalent to the Laplace transfer function with the coefficient assignments: $a_0 = k, a_1 = 0, b_0 = 0, b_1 = 1$

The voltage-controlled voltage source element which implements this function is:

einteg out in laplace cpos cneg k 0.0 / 0.0 1.0 $\,$

Differentiator element

You can also use the e element with the Laplace transformation function to model a voltage differentiator.

Consider the behavior of a differentiator. In the frequency domain, the differentiator is defined by:

$$V_{out} = ksV_{in} \tag{6.45}$$

And, in the time domain the differentiator is defined by:

$$V_{out} = k \frac{\delta V_{in}}{\delta t}$$
(6.46)

The transfer function for the voltage gain is:

$$H(s) = \frac{V_{out}}{V_{in}} = ks \tag{6.47}$$

This is equivalent to the Laplace transfer function with the coefficient assignments: $a_0 = 0$, $a_1 = k$, $b_0 = 1$

The voltage-controlled voltage source element to implement this function is:

ediff out in laplace cpos cneg 0.0 k / 1.0

Single Pole / Residue

A single pole/residue element is modeled using a transfer function which is:

$$H(s) = \frac{a_0}{b_0 + b_1 s} \tag{6.48}$$

A representative single pole element is:

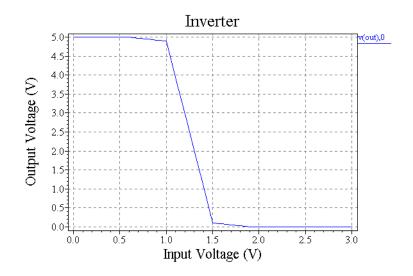
epole out in laplace cpos cneg 1.0 / 0.5 3.0

Zero-Delay Inverter Gate

The same technique used to produce the ideal amplifier, above, could be used to create a simple model of a zero-delay inverter:

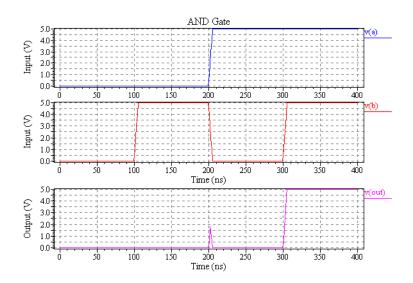
einvert out 0 vol='table(v(in), 0.6, 5, 1, 4.9, 1.5, 0.1, 1.9, 0)'

This example would produce the following waveform:



Zero-Delay AND Gate

The following example implements a simple model for a zero-delay digital AND gate: eand out 0 vol='table($\min(v(a), v(b))$, 0, 0, 1, 0.5, 4, 4.5, 5, 5)' This example would produce the following waveform:



Other logic gates can also be modeled using the same technique:

NAND gate:

enand nand 0 vol='table(min(v(a),v(b)), 0, 5, 1, 4.5, 4, 0.5, 5, 0)'

• OR gate:

```
eor or 0 vol='table( max(v(a),v(b)), 0, 0, 1, 0.5, 4, 4.5, 5, 5)'
```

NOR gate:

enor nor 0 vol='table(max(v(a),v(b)), 0, 5, 1, 4.5, 4, 0.5, 5, 0)'

Voltage-Controlled Oscillator (VCO)

A voltage-controlled oscillator model can be built using a combination of expression-controlled sources. The following example implements a VCO whose output voltage is a sine wave of frequency $f0+k0^*(vcontrol - vc)$, where vcontrol is the control voltage, and f0, k0, and vc are fixed parameters. The amplitude and offset of the VCO's output sine wave are controlled by the parameters **amp** and offset, respectively.

```
.param offset=2.5 amp=2.5 pi=3.141592654
.param f0=10k k0=3k vc=2.5
evco out 0 vol='offset+amp*sin(2*pi*(f0*time()+k0*v(theta)))'
gtheta theta 0 cur='vc-v(control)' chg='v(theta)'
.ic v(theta)=0
```

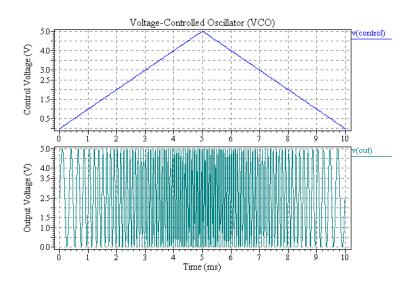
Note that a state variable called **theta** has been introduced to track the phase of the VCO. Without this additional state variable, the VCO might have been modeled using:

```
evco2 out 0 vol='offset+amp*sin(2*pi*(k0*(v(control)-vc)+f0)*time())'
```

but this would result in phase discontinuities of the VCO's output sine wave. The initial condition for **theta** is necessary to define a DC value for the phase, which would otherwise be arbitrary. The **gtheta** element implements the equation

$$\frac{d\theta}{dt} = v(control) \angle vc \tag{6.49}$$

The chart below shows the behavior of a VCO modeled as in the five SPICE lines above. The VCO's frequency ranges from 2.5kHz when the control voltage is zero to 17.5kHZ when the control voltage is 5V.



7 Simulation Options

This section provides a reference to the T-Spice simulation options that can be set with the ".options" (page 109) command.

Options are grouped in the following categories:

- "Accuracy and Convergence Options" (page 206)
- "Timestep and Integration Options" (page 237)
- "Model Evaluation Options" (page 256)
- "Linear Solver Options" (page 276)
- "General Options" (page 280)
- "Output Options" (page 291)
- "Probing Options" (page 316)

Accuracy and Convergence Options

"absi | abstol" (page 207)
"accurate" (page 209)
"bytol" (page 211)
"dchomotopy" (page 213)
"dcstep" (page 216)
"fast" (page 218)
"gmindc" (page 220)
"gshunt" (page 222)
"kvltest" (page 224)
"mindcratio" (page 226)
"numnd | itl1" (page 228)
"numns | itl6" (page 230)
"reli | reltol" (page 235)

"absv | vntol" (page 208)
"bypass" (page 210)
"cshunt" (page 212)
"dcmethod" (page 215)
"extraiter[ations] | newtol" (page 217)
"gmin" (page 219)
"gramp" (page 221)
"kcltest" (page 223)
"maxdcfailures" (page 225)
"minsrcstep" (page 227)
"numndset" (page 229)
"numnx | itl2" (page 231)
"precise" (page 233)
"relv" (page 236)

absi | abstol

.options absi = absi

where absi > 0

Default Value

 $1 \times 10^{-10} \,\mathrm{A}$

Description

Specifies a convergence criterion that limits the total RMS (root mean square) of residual branch currents at all nodes in the circuit. The current test for convergence is applied when **kcltest** = **true**.

When the current tolerance test is applied, the system of equations is determined to be converged if:

$$reli > \sqrt{\sum_{i=0}^{n} (\Delta I')^{2}} \qquad and \qquad absi > \sqrt{\sum_{i=0}^{n} I^{2}}$$

where I is the residual branch current at each node. The quantity $\Delta I'$ represents the change in relative residual branch current between two consecutive iterations:

$$\Delta I' = \left(\frac{I_j}{imax_j}\right) \angle \left(\frac{I_{j \ge 1}}{imax_{j \ge 1}}\right)$$

where *imax_j* is the largest branch current (in absolute value) flowing into the node in question in the j^{th} Newton iteration.

See Also

"reli | reltol" (page 235), "kcltest" (page 223)

absv | vntol

.options absv = absv

where absv > 0

Default Value

 $1 \times 10^{-6} \,\mathrm{V}$

Description

Specifies a convergence criterion limiting the absolute change in node voltage between two Newton iterations. The voltage test for convergence is applied when **kvitest** = **true**.

The voltage tolerance at each node is calculated as follows:

voltage tolerance = $max(absv, relv \times V)$,

where V is the node voltage value. If the voltage variation at each node is less than the calculated voltage tolerance for that node, then the iteration is considered to be converged.

See Also

"relv" (page 236), "kvltest" (page 224)

accurate

.options accurate = { true | false }

Default Value

false

Description

Triggers changes to other option settings to maximize simulation accuracy:

Option	Default	Accurate
" lvltim " (page 241)	1	3
"numnd itl1" (page 228)	250	500
"numndset" (page 229)	<i>numnd</i> / 10 (25)	<i>numnd</i> / 5 (100)
"numns itl6" (page 230)	50	100
"numnx itl2" (page 231)	100	200
"numnxramp" (page 232)	50	100
"reldv relvar" (page 251)	0.35	0.3
"reli reltol" (page 235)	5×10^{-4}	1×10^{-4}
" rmax " (page 253)	2	1

Specifying any of the above fields individually will override the value set by accurate.

See Also

"fast" (page 218), "precise" (page 233)

bypass

.options bypass = { true | false }

Default Value

true

Description

Enables or disables the diode and transistor evaluation bypass algorithm. If the terminal voltage values for a device have a relative change that is less than or equal to **bytol** since the previous evaluation, then this evaluation will be skipped, and the previous solutions used.

See Also

"**bytol**" (page 211)

bytol

.options bytol = bytol where $bytol \ge 0$

Default Value

1.0e-9

Description

Sets the relative tolerance for the bypass algorithm terminal voltage values.

See Also

"**bypass**" (page 210)

cshunt

.options cshunt = *cshunt*

where $cshunt \ge 0.0 \text{ F}$

Default Value

0.0 F

Description

Adds a capacitor with the specified capacitance from each node to ground. A small *cshunt* value will sometimes resolve transient analysis "timestep too small" values that are caused by small, high-frequency oscillations within the circuit.

See Also

"gmin" (page 219), "gshunt" (page 222)

dchomotopy

.options dchomotopy = { none | source | gmin | pseudo | all }

Default Value

all

Description

Specifies the algorithm used to correct DC operating point non-convergences. When a non-convergence occurs during DC operating point analysis, the selected form of homotpy will be used to try to obtain a valid, converged solution.

Options include:

none	Do not attempt any homotopy methods.
source	Source stepping. All voltage and current sources are ramped up from zero to their final values. The smallest source step that T-Spice will take is controlled by " minsrcstep " (page 227).
gmin	Gmin stepping. T-Spice uses the g_{min} stepping algorithm to find the minimum conductance value that yields a convergent solution. The options gmindc and gramp specify a search range for the minimum required conductance, g_{min} .
	$\mathbf{gmindc} \leq \mathbf{g}_{min} \leq \mathbf{gmindc} \times 10^{\mathbf{gramp}}$
pseudo	Pseudotransient solution. In the pseudotransient solution method, T-Spice uses homotopy methods to approximate a solution, then removes the homotopies for the final solution. T-Spice obtains a pseudotransient solution as follows:
	 T-Spice first enables pseudotransient simulation values for gmindc and cshunt, which are determined internally. The source values are then ramped up to their final values.
	 T-Spice then performs a time-stepping simulation. When this simulation converges, T-Spice removes the homotopy devices (<i>gmindc</i> and <i>cshunt</i>), one at a time, until the final solution is reached.
all	If a non-convergence occurs, T-Spice attempts homotopy methods in the following order:
	 source stepping
	 gmin stepping
	 pseudotransient solution
	As soon as a converged solution is achieved, the simulation

completes without attempting the next homotopy algorithm.

Note: If you know that a specific homotopy is required to reach a convergent solution, you can reduce simulation time by setting this as the default method with **dcmethod**. Using **dcmethod** automatically skips the standard solution (no homotopy) and only attempts to calculate the solution using the method specified.

See Also

"dcmethod" (page 215), "minsrcstep" (page 227), "gmindc" (page 220), "gramp" (page 221)

dcmethod

.options dcmethod = {standard | source | gmin | pseudo }

Default Value

standard

Description

Specifies the default method for solving a DC operating point problem. This option is useful when you have prior knowledge that the circuit can only reach a convergent solution when a particular homotopy is required. In this case, you can reduce simulation time by setting the **dcmethod** option to the appropriate method, thus skipping attempts to solve the problem using either the standard method or the other homotopy methods. The settings for **dcmethod** are:

standard	Default setting. If a non-convergence is reached using the standard method, T-Spice will then apply the homotopy methods specified by dchomotopy to try to reach a convergent solution.
source	Source stepping. All voltage and current sources are ramped up from zero to their final values. The smallest source step that T-Spice will take is controlled by the minsrcstep option.
gmin	Gmin stepping. T-Spice finds the minimum conductance value that yields a convergent solution. The options gmindc and gramp specify a search range for the minimum required conductance, g_{min} :
	$\mathbf{gmindc} \leq \mathbf{g}_{min} \leq (\mathbf{gmindc} \times 10^{\mathbf{gramp}})$
pseudo	Pseudotransient solution. In the pseudotransient solution method, T-Spice uses homotopy methods to approximate a solution, then removes the homotopies for the final solution. T-Spice obtains a pseudotransient solution as follows:
	 T-Spice first enables pseudotransient simulation values for gmindc and cshunt, which are determined internally. The source values are then ramped up to their final values.
	 T-Spice then performs a time-stepping simulation. When this simulation converges, T-Spice removes the homotopy devices (<i>gmindc</i> and <i>cshunt</i>), one at a time, until the final solution is reached.

Note:

If you do not know the best solution method for your circuit, then do not set dcmethod. Instead, set **dhomotopy** to the default value of **all**. In this case, T-Spice will automatically cycle through the homotopies as necessary to achieve convergence.

See Also

"dcstep" (page 216), "minsrcstep" (page 227), "gmindc" (page 220), "gramp" (page 221)

dcstep

.options dcstep = dcstep

where $dcstep \ge 0$

Default Value

0.0

Description

Adds a conductance across the terminals of each capacitor during DC operating point computation. If a non-zero value is specified, T-Spice computes the additional conductance for each capacitor as:

$$g = \frac{c}{dcstep}$$

where g is the applied conductance and c is the device capacitance.

See Also

"cshunt" (page 212), "gmindc" (page 220)

extraiter[ations] | newtol

.options extraiter = extraiter

where extraiter is a non-negative integer

Default Value

0

Description

Instructs T-Spice to compute the specified number of Newton solver iterative steps after convergence criteria have been met. This option is used to improve the accuracy of the solution, and is applicable to DC operating point, DC sweep, and AC simulations. For transient analysis, use the **trnewtol** option.

When **precise** = **true**, the default value of **extraiter** is 10.

See Also

"precise" (page 233), "trextraiter[ations] | trnewtol" (page 254)

fast

```
.options fast = { true | false }
```

Default Value

false

Description

Triggers changes to other options settings to maximum simulation speed:

Option	Default	Fast
"absi abstol" (page 207)	$1 \times 10^{-10} \mathrm{A}$	$5 \times 10^{-10} \mathrm{A}$
" bytol " (page 211)	0	1×10^{-13}
"reldv relvar" (page 251)	0.35	0.4
"reli reltol" (page 235)	5×10^{-4}	1 × 10 ⁻³
"relq relchgtol" (page 252)	<i>reli</i> (5×10^{-4})	<i>reli</i> (1×10^{-3})

Specifying any of the above fields individually will override the value set by fast.

See Also

"accurate" (page 209), "precise" (page 233)

gmin

.options gmin = gmin

where $gmin \ge 0$

Default Value

 $1 \times 10^{-12} \, \Omega^{-1}$

Description

Specifies a conductance added in parallel with all pn junctions during transient analaysis. When gmin > 0, T-Spice generates a gmin conductance across two terminals by adding a resistor with resistance R

$$R = \frac{1}{gmin}$$

T-Spice applies the **gmin** conductance to various elements as follows:

- diode—conductance is added across the positive/negative terminals.
- —conductance is added across the base/emitter and the base/collector terminals.
- MOSFET—conductance is added across the source/bulk, drain/bulk, and the source/drain terminals.
- MESFET—conductance is added across the source/gate, drain/gate, and source/drain terminals.
- JFET—conductance is added across the source/gate, drain/gate, and source/drain terminals.

See Also

"gmindc" (page 220), "gshunt" (page 222)

gmindc

.options gmindc = gmindc

where $gmindc \ge 0$

Default Value

 $1\times 10^{\text{-}12}\,\Omega^{\text{-}1}$

Description

Specifies a conductance that is added in parallel with all pn junctions during DC operating point analysis. When **gmindc** > 0, T-Spice generates a **gmindc** conductance across two terminals by adding a resistor with resistance R

$$R = \frac{1}{gmindc}$$

T-Spice applies the gmindc conductance to various elements as follows:

- diode—conductance is added across the positive/negative terminals.
- —conductance is added across the base/emitter and the base/collector terminals.
- MOSFET—conductance is added across the source/bulk, drain/bulk, and the source/drain terminals.
- MESFET—conductance is added across the source/gate, drain/gate, and source/drain terminals.
- JFET—conductance is added across the source/gate, drain/gate, and source/drain terminals.

Note: When a DC operating point non-convergence occurs, T-Spice can begin a g_{min} stepping algorithm to find the minimum conductance that yields a convergent solution. The g_{min} stepping algorithm is triggered when a non-convergence occurs and the **dchomotopy** option is set to **all** or **gmin**.

See Also

"gramp" (page 221), "dchomotopy" (page 213)

gramp

.options gramp = gramp

where 0 < *gramp* < (-log10 (100 × *gmindc*))

Default Value

4

Description

Specifies the range over which the **gmindc** value will be swept in g_{min} stepping for DC analysis. The g_{min} stepping algorithm is triggered when a non-convergence occurs and **dchomotopy** is set to **all** or **gmin**. Together, the options **gmindc** and **gramp** specify a search range for the minimum required conductance, g_{min} :

$gmindc \le g_{min} \le gmindc \cdot 10^{gramp}$

T-Spice's g_{min} stepping algorithm searches the specified conductance range in two steps. First, T-Spice performs a binary search between **gmindc** and **gmindc** $\cdot 10^{gramp}$. T-Spice searches for the smallest value of g_{min} that results in a converged solution. T-Spice automatically ends the binary search when it reaches a Δg_{min} that is less than or equal to a factor of 10.

Starting with binary search results, T-Spice then begins reducing the value of g_{min} by a factor of 10 in each iteration. Once a non-convergence occurs, the previous convergent iteration provides the final solution.

See Also

"gmindc" (page 220)

gshunt

.options gshunt = gshunt

where $gshunt \ge 0$

Default Value

 $0.0 \ \Omega^{-1}$

Description

Specifies a conductance to be added between every node and ground. When gshunt > 0, T-Spice generates a gshunt conductance from each node to ground by adding a resistor with resistance *R*

$$R = \frac{1}{gshunt}$$

See Also

"cshunt" (page 212), "gmin" (page 219)

kcltest

.options kcltest = {true | false }

Default Value

true

Description

Enables the current tolerance test for convergence. When the current tolerance test is applied, the system of equations is determined to be converged if:

$$reli > \sqrt{\sum_{i=0}^{n} (\Delta I')^2}$$
 and $absi > \sqrt{\sum_{i=0}^{n} I^2}$

where I is the residual branch current at each node. The quantity $\Delta I'$ represents the change in relative residual branch current between two consecutive iterations:

$$\Delta I' = \left(\frac{I_j}{imax_j}\right) \angle \left(\frac{I_{j \ge 1}}{imax_{j \ge 1}}\right)$$

where $imax_j$ is the largest branch current (in absolute value) flowing into the node in question in the j^{th} Newton iteration.

See Also

"absi | abstol" (page 207), "reli | reltol" (page 235), "kvltest" (page 224)

kvltest

.options kvltest = { true | false }

Default Value

false

Description

Enables the voltage tolerance test for convergence during transient analysis. The voltage tolerance test is always performed during DC, DC sweep, Transfer, and AC analysis. The **kvltest** option is used for enabling this test during transient analysis also.

The voltage tolerance is calculated as follows:

```
voltage tolerance = max(absv, relv \times V),
```

where V is the node voltage value. If the voltage variation at each node is less than the calculated voltage tolerance for that node, then the iteration is considered to be converged.

See Also

"absv | vntol" (page 208), "relv" (page 236), "kcltest" (page 223)

maxdcfailures

.options maxdcfailures = n

where \boldsymbol{n} is a non-negative integer

Default Value

4

Description

Maximum number of non-convergence failures allowed in a DC sweep simulation before T-Spice ends processing with a "too many nonconvergences" error.

See Also

"mindcratio" (page 226), "numnx | itl2" (page 231)

mindcratio

.options mindcratio = *mindcratio* where 0 < *mindcratio* < 1

Default Value

 1×10^{-4}

Description

Minimum fractional step size allowed in source ramping for DC sweep analysis:

 $\Delta dc_{min} = mindcratio \times \Delta dc$

where Δdc is the step size specified in the netlist **sweep** statement. If the step size falls below Δdc_{min} , T-Spice will declare a non-convergence error.

T-Spice applies source ramping when a fixed source step fails to converge. In source ramping, the source variable is gradually ramped up from the previous sweep value to the next sweep value.

See Also

"maxdcfailures" (page 225), "numnx | itl2" (page 231)

minsrcstep

.options minsrcstep = *minsrcstep* where *minsrcstep* > 0

Default Value

 1×10^{-8}

Description

Minimum fractional step size for source stepping:

min step size = *minsrcstep* × (*Source value*)

In source stepping, all voltage and current sources are ramped up from zero to their final values. This allows T-Spice to find the DC operating points of difficult-to-converge circuits. Source stepping is used only in non-converging cases of initial DC operating point computations when **dchomotopy** is set to **source** or **all**.

See Also

"numns | itl6" (page 230), "dchomotopy" (page 213)

numnd | itl1

.options numnd = numnd

where *numnd* is a positive integer

Default Value

250

Description

Newton iteration limit for DC operating point computation. If a solution does not converge within *numnd* iterations, T-Spice applies the homotopy method specified by **dchomotopy** to attempt to reach a convergent solution. If **dchomotopy** = **none**, T-Spice declares a non-convergence error.

See Also

"dchomotopy" (page 213)

numndset

.options numndset = *numndset*

where *numndset* is a positive integer

Default Value

 $\textbf{numnd} \ / \ 10$

Description

This option is used during DC operating point computations when the user has specified node voltage guesses using the **.nodeset** command. **Numndset** is the number of Newton iterations during which the **.nodeset** nodes will be held at their user-specified voltage values. After **numndset** iterations, or when the circuit convergence criteria have been met, these node voltages are allowed to vary for the remainder of the computation

See Also

".nodeset" (page 103)

numns | itl6

.options numns = *numns*

where *numns* is a positive integer

Default Value

50

Description

Newton iteration limit for each source stepping attempt in DC operating point analysis. In source stepping, all voltage and current sources are ramped up from zero to their final values. This allows T-Spice to find the DC operating points of difficult-to-converge circuits. Source stepping is used only in non-converging cases of initial DC operating point computations when **dchomotopy** is set to **source** or **all**.

See Also

"numnd | itl1" (page 228), "dchomotopy" (page 213)

numnx | itl2

.options numnx = *numnx*

where *numnx* is a positive integer

Default Value

100

Description

Newton iteration limit for DC sweep computation. If a convergent solution is not reached within **numnx** iterations, T-Spice begins source ramping. In source ramping, the source variable is gradually ramped up from the previous sweep value to the next sweep value. The Newton iteration limit for source ramping is specified by **numnxramp**.

See Also

"numnxramp" (page 232)

numnxramp

.options numnxramp = numnxramp where numnxramp is a positive integer

Default Value

50

Description

Newton iteration limit for DC sweep computation during source ramping. T-Spice applies source ramping when a fixed source step fails to converge within **numnx** iterations. In source ramping, the source variable is gradually ramped up from the previous sweep value to the next sweep value.

See Also

"numnx | itl2" (page 231), "minsrcstep" (page 227)

precise

.options precise = {true | false}

Default Value

false

Description

Triggers changes to other options for extreme simulation precision. This option should only be used for single transistor characterizations, or for very simple circuits.

The following option settings will be used:

Option	Default	Precise
"absdv absvar" (page 238)	0.5 V	0.3 V
"absi abstol" (page 207)	$1 \times 10^{-10} \mathrm{A}$	$5 \times 10^{-11} \text{ A}$
" absq chgtol chargetol " (page 239)	$1 \times 10^{-14} \text{ C}$	$1 \times 10^{-14} \text{ C}$
" absv vntol " (page 208)	$1 \times 10^{-6} \text{ V}$	$1 \times 10^{-7} \mathrm{V}$
" extraiter[ations] newtol " (page 217)	0	10
" gmin " (page 219)	$1\times 10^{\text{-}12}\Omega^{\text{-}1}$	$1 imes 10^{-14} \Omega^{-1}$
" gmindc " (page 220)	$1 \times 10^{-12} \Omega^{-1}$	$1 imes 10^{-14} \Omega^{-1}$
"kvltest" (page 224)	false	true
" lvltim " (page 241)	1	3
" extraiter[ations] newtol " (page 217)	0	10
"numnd itl1" (page 228)	250	500
"numndset" (page 229)	<i>numnd</i> / 10 (25)	<i>numnd</i> / 5 (100)
"numns itl6" (page 230)	50	100
"numnx itl2" (page 231)	100	200
"numnxramp" (page 232)	50	100
" pivtol " (page 278)	1×10^{-14}	1×10^{-16}
"reldv relvar" (page 251)	0.35	0.25
" reli reltol " (page 235)	5×10^{-4}	1×10^{-4}
"relq relchgtol" (page 252)	<i>reli (</i> 5 × 10 ⁻⁴⁾	<i>reli (</i> 1 × 10 ⁻⁴)
" relv " (page 236)	1×10^{-3}	1×10^{-4}
" rmax " (page 253)	2	1

Option	Default	Precise	
" trextraiter[ations] trnewtol " (page 254)	0	1	

Specifying any of the above fields individually will override the value set by **precise**.

See Also

"accurate" (page 209), "fast" (page 218)

reli | reltol

.options reli = reli

where *reli* > 0

Default Value

 5×10^{-4}

Description

Specifies a convergence criterion limiting the relative change in total RMS branch current for all nodes in the circuit between consecutive iterations. The current test for convergence is applied when **kcltest** = **true**.

When the current tolerance test is applied, the system of equations is determined to be converged if:

$$\textbf{reli} > \sqrt{\sum_{i=0}^{n} (\Delta I')^2} \quad and \quad \textbf{absi} > \sqrt{\sum_{i=0}^{n} I^2}$$

where I is the residual branch current at each node. The quantity $\Delta I'$ represents the change in relative residual branch current between two consecutive iterations:

$$\Delta I' = \left(\frac{I_j}{imax_j}\right) \angle \left(\frac{I_{j \ge 1}}{imax_{j \ge 1}}\right)$$

where $imax_j$ is the largest branch current (in absolute value) flowing into the node in question in the j^{th} Newton iteration.

See Also

"absi | abstol" (page 207), "kcltest" (page 223)

relv

.options relv = relv

where relv > 0

Default Value

 1×10^{-3}

Description

Specifies a convergence criterion limiting the relative change in node voltage at any node in the circuit between consecutive iterations. The voltage test for convergence is applied when **kvltest** = **true**.

The voltage tolerance test uses both the **absv** and **relv** options to calculate tolerance:

voltage tolerance = max (**absv**, $relv \times V$),

where V is node voltage. If the voltage change at each node is less than the voltage tolerance for that node, then the iteration is considered to be converged.

See Also

"absv | vntol" (page 208), "kvltest" (page 224)

Timestep and Integration Options

"absdv | absvar" (page 238)
"ft" (page 240)
"maxord" (page 244)
"mintimeratio | rmin" (page 246)
"numnt | itl4 | imax" (page 248)
"poweruplen" (page 250)
"relq | relchgtol" (page 252)
"trextraiter[ations] | trnewtol" (page 254)

"absq | chgtol | chargetol" (page 239)
"lvltim" (page 241)
"method" (page 245)
"mu | xmu" (page 247)
"numntreduce | itl3" (page 249)
"reldv | relvar" (page 251)
"trtol" (page 255)

absdv | absvar

.options absdv = absdv

where absdv > 0

Default Value

0.5 V

Description

For transient analysis, **absdv** specifies the threshold absolute voltage change between two consecutive time steps. This quantity is used with *reldv* to calculate the voltage variance error measurement:

variance =
$$\frac{V_{n+1} \angle V_n}{\text{reldv} \cdot max(absdv, V_n)}$$

Voltage variance is used to scale time step sizes when "IvItim" (page 241) is equal to 1, 3, or 4.

See Also

"**lvltim**" (page 241)

absq | chgtol | chargetol

.options absq = absq

where absq > 0

Default Value

 $1 \times 10^{-14} \,\mathrm{C}$

Description

Minimum capacitor charge or inductor flux used to predict a timestep in the Local Truncation Error timestep algorithm (IvItim = 2 or 4). The **absq** option sets a floor on charge values to prevent the time step size from becoming too small.

The value of **absq** is used to calculate Local Truncation Error (LTE) as follows:

 $LTE = \frac{Q \angle Q_{predicted}}{trtol \times max(absq, (relq \times Q))}$

When lvltim=2 or 4, and LTE > 1, T-Spice recalculates the solution at a smaller timestep. See "lvltim" (page 241) for a description of the LTE algorithm.

See Also

"lvltim" (page 241), "relq | relchgtol" (page 252)

ft

where $0 < \mathbf{ft} < 1$

Default Value

0.25

Description

Fraction by which the internal timestep is decreased if a transient analysis solution does not converge within *numnt* iterations. T-Spice recalculates the solution for a smaller timestep:

$$\Delta t_n = \Delta t_n' (1-ft)$$

where $\Delta t_n'$ is the size of the failed or non-converged nth timestep.

The **ft** option also determines the fraction by which the next timestep (Δt_{n+1}) is decreased if the nth timestep solution requires more than **numntreduce** iterations to converge:

$$\Delta t_{n+1} = \Delta t_n \left(1 - ft \right) \, .$$

For more information about timestep reduction algorithms, see "IvItim" (page 241).

See Also

"numnt | itl4 | imax" (page 248), "numntreduce | itl3" (page 249), "lvltim" (page 241)

lvltim

.options lvltim = {1 | 2 | 3 | 4}

Default Value

1

Description

Specifies the algorithm used to control timestep sizes in transient analysis simulation:

lvltim = 1	Iteration count algorithm with voltage variance test.
lvltim = 2	Local Truncation Error timestep control algorithm.
lvltim = 3	Modified iteration count with voltage variance test and timestep reversal.
lvltim = 4	Combines lvltim=1 voltage variance test, prior to the timestep, with lvltim=2 local truncation error control of timestep reversal

Iteration Count with Voltage Variance Test (IvItim = 1, 3, or 4)

All three algorithms require that the solution at each time step converge within *numnt* iterations. If a convergent solution is not found within *numnt* iterations, T-Spice recalculates the solution at a smaller timestep:

$$\Delta t_n' = \Delta t_n (1-ft)$$

where Δt_n is the original size of the nth timestep. When **lvItim** = 1, no further conditions are placed on the current timestep solution.

When **lvltim**=3, the timestep solution must also have an error value less than or equal to 1, where error is calculated as the voltage variance between time steps

$$error = \frac{V_{n+1} \angle V_n}{max(absdv, (reldv \cdot V_n))}$$

If **lvltim**=3 and the error is greater than 1, T-Spice recalculates the solution for a smaller timestep. The smaller timestep is obtained by scaling the current timestep by the error (voltage variance):

$$\Delta t_n' = \Delta t_n \cdot \left(\frac{0.9}{error}\right)$$

T-Spice continues the timestep reversal algorithm until it reaches a convergent solution within *numnt* iterations, such that *error* < 1.

Note:

Local Truncation Error Algorithm (Ivitim = 2 or 4)

The Local Truncation Error (LTE) algorithm adjusts the timestep size according to the discretization error generated by integration. The amount of truncation error introduced by integration increases with the rate-of-change in the circuit. Local truncation error is calculated as the ratio between the error in predicted charge and the charge tolerances **relq** and **absq**. The value of "**trtol**" (page 255) is included as a corrective factor in the LTE calculation::

$$error = \frac{Q \angle Q_{predicted}}{trtol \cdot max((relq \cdot Q), absq)}$$

If the calculated local truncation error (*LTE*) is greater than 1, then T-Spice recalculates the solution for a smaller time step:

$$\Delta t' = \Delta t \cdot \left(\frac{0.9}{error}\right)$$

The LTE algorithm is error-prone in high-current devices, because the rapidly changing charge values will generate large local truncation error values. This can cause T-Spice to use extremely small timesteps, leading to slow simulations and/or "timestep too small" errors. In high-current circuits, a voltage-based timestep algorithm (lvltim = 1 or 3) is often the preferred choice.

Determining the Next Timestep (IvItim = 1, 2, 3, or 4)

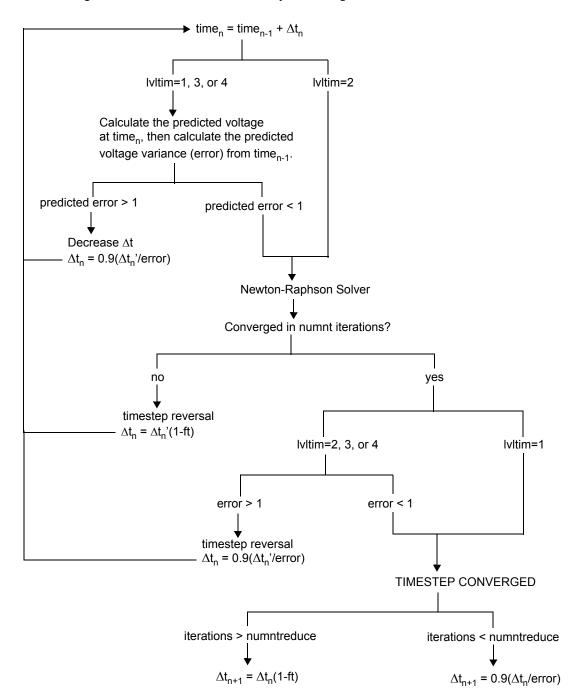
All three algorithms use both iteration count and an error measurement to determine the size of the next timestep. After a convergent solution is found at the current timestep, T-Spice applies the following rules to determine the next timestep size:

• If the solution required more than numntreduce iterations, T-Spice reduces the next timestep by the fraction ft:

$$\Delta t_{n+1} = \Delta t_n (1-ft)$$

If the solution converged in fewer than numntreduce iterations, T-Spice uses the appropriate error measurement to scale the next timestep. (Error is equal to voltage variance when lvltim = 1 or 3, and LTE when lvltim = 2 or 4.)

$$\Delta t_{n+1} = \Delta t_n \cdot \left(\frac{0.9}{error}\right)$$



The following chart summarizes the three timestep control algorithms:

See Also

"mintimeratio | rmin" (page 246), "numnt | itl4 | imax" (page 248), "numntreduce | itl3" (page 249), "absdv | absvar" (page 238), "reldv | relvar" (page 251), "ft" (page 240)

maxord

.options maxord = {1 | 2 | 3 | 4 }

Default Value

2

Description

Maximum time integration order for variable-order Gear's BDF calculation in transient analysis. Gear's BDF integration is used when **method** = **gear**.

See Also

"method" (page 245)

method

```
.options method = { gear | trap }
```

Default Value

trap

Description

Method of numerical integration for estimating the time derivative of the system's charge components during a **.tran** simulation. Possible settings are:

gear	Variable order Gear's backward differential formula (see "Gear's BDF Method" on page 32). The order of integration is controlled by the option maxord .
trap	Trapezoidal integration. This method is faster than gear but may introduce non-physical oscillations in nodal responses. (see "Trapezoidal Integration Method" on page 32).

See Also

"**maxord**" (page 244)

mintimeratio | rmin

.options mintimeratio = *mintimeratio* where *mintimeratio* > 0

Default Value

 1×10^{-9}

Description

Relative minimum timestep size for transient simulations. The minimum timestep for transient simulation is equal to *mintimeratio* \times *tstep*, where *tstep* is the timestep size listed on the *.tran* statement.

If the timestep size falls below *mintimeratio* \times *tstep*, T-Spice ends processing with a "timestep too small" error.

mu | xmu

.options mu = mu

where $0 \le mu \le 0.5$

Default Value

0.5

Description

Coefficient for varying the integration between the backward Euler formula and the Trapezoidal formula. Valid values of **mu** are between 0 and 0.5, with 0 yielding a backward Euler integration, 0.5 yielding Trapezoidal integration, and intermediate values producing a hybrid integration of the specified proportional weighting. Trapezoidal integration is used when **method** = **trap**.

See Also

"method" (page 245)

numnt | itl4 | imax

.options numnt = *numnt*

where *numnt* is a positive integer

Default Value

10

Description

Newton iteration limit for transient analysis solutions.

If a solution does not converge within *numnt* iterations, T-Spice recalculates the solution for a smaller time step. The fraction by which the time step is decreased after a non-convergence is specified by "ft" (page 240).

See Also

"**ft**" (page 240)

numntreduce | itl3

.options numntreduce = numntreduce where numntreduce is a positive integer

Default Value

3

Description

For transient analysis, the threshold number of Newton iterations that controls the next time step size.

If more than **numntreduce** iterations are needed to reach a convergent solution at the nth time step, then the next time step size is reduced by the fraction **ft**:

$$\Delta t_{n+1} = \Delta t_n (1-ft)$$

If the nth time step converges with fewer than *numntreduce* iterations, then T-Spice increases or decreases the next time step by scaling with a calculated error value:

$$\Delta t_{n+1} = \Delta t_n \cdot \left(\frac{0.9}{error}\right)$$

The error calculation is dependent on the algorithm specified by "lvltim" (page 241).

See Also

"ft" (page 240), "lvltim" (page 241)

poweruplen

.options poweruplen = poweruplen

Default Value

0.1% of the total transient simulation time.

Description

Length of the powerup ramp (seconds) during powerup transient analysis.

See Also

".tran" (page 148)

reldv | relvar

.options reldv = reldv

where reldv > 1

Default Value

0.35

Description

For transient analysis, **reldv** specifies the maximum relative voltage change between two consecutive time steps. This quantity is used with *absdv* to calculate the voltage variance error measurement:

variance =
$$\frac{V_{n+1} \angle V_n}{\text{reldv} \cdot max(\text{absdv}, V_n)}$$

Voltage variance is used to scale time step sizes when "IvItim" (page 241) is equal to 1, 3, or 4.

See Also

"absdv | absvar" (page 238), "lvltim" (page 241)

relq | relchgtol

.options relq = relq

where relq > 0

Default Value

 5×10^{-4}

Description

Maximum relative error in predicted capacitor charge or inductor flux. The error between predicted and actual charges is used to adjust timestep sizes in the Local Truncation Error timestep algorithm (IvItim = 2 or 4).

The value of **relq** is used to calculate Local Truncation Error (LTE) as follows:

$$LTE = \frac{Q \angle Q_{predicted}}{trtol \times max(absq, (relq \times Q))}$$

When lvltim=2 or 4, and LTE > 1, T-Spice recalculates the solution at a smaller timestep. See "lvltim" (page 241) for a description of the LTE algorithm.

See Also

"Ivltim" (page 241), "absq | chgtol | chargetol" (page 239)

rmax

.options rmax = *rmax*

where *rmax* ≥ 1

Default Value

2

Description

Defines the maximum allowed timestep in transient simulation, specified as a ratio. The maximum timestep is defined as:

$$\Delta t_{max} = \mathbf{rmax} \times \Delta t_{tran}$$

where Δt_{tran} is the timestep specified in the netlist **.tran** statement.

See Also

"fast" (page 218), "accurate" (page 209), "precise" (page 233)

trextraiter[ations] | trnewtol

.options trextraiter = trextraiter

```
where trextraiter \ge 0
```

Default Value

0

Description

Instructs T-Spice to compute the specified number of Newton solver iterative steps after convergence criteria have been met. This option is used to improve the accuracy of the solution, and is applicable to transient analysis only. For increasing the iterations of non-transient simulations use the **newtol** option.

When **precise** = **true**, the default value of *trextraiter* is 1.

See Also

"extraiter[ations] | newtol" (page 217), "precise" (page 233)

Timestep and Integration Options

trtol

.options trtol = trtol

Default Value

10

Description

Corrective factor for estimation of the local truncation error in the LTE algorithm:

$$LTE = \frac{Q \angle Q_{predicted}}{trtol \cdot max((relq \cdot Q), absq)}$$

See "Ivitim" (page 241) for a description of the LTE algorithm.

Note: The default value of **trtol** has been calculated to minimize error in the estimation of LTE. Changing the value of **trtol** is generally not recommended.

See Also

"absq | chgtol | chargetol" (page 239), "relq | relchgtol" (page 252), "trtol" (page 255)

Model Evaluation Options

"**dcap**" (page 257) "**dccap**" (page 258) "**defas**" (page 260) "defad" (page 259) "**defl**" (page 261) "**defnrd**" (page 262) "defnrs" (page 263) "defpd" (page 264) "defps" (page 265) "**defw**" (page 266) "**deriv**" (page 267) "minresistance | resmin" (page 268) "modmonte" (page 269) "moscap" (page 270) "mout" (page 271) "scale" (page 272) "scalm" (page 273) "tnom" (page 274) "wl" (page 275)

dcap

```
.options dcap = {1 | 2 }
```

Default Value

2

Description

Selects the model used to calculate depletion capacitance for BJTs, diodes, and MOS parasitic diodes. Possible settings are:

dcap = 1	Berkeley SPICE diode equations.
dcap = 2	Revised equations. See the device model documentation for "BJT Level 1 (Gummel-Poon)" (page 336) and "Diode" (page 366).

See Also

"BJT Level 1 (Gummel-Poon)" (page 336), "Diode" (page 366)

dccap

.options dccap = {true | false}

Default Value

false

Description

Controls the computation of charges and capacitances in DC simulations. Charge and capacitance values are not normally computed for DC operating point, DC sweep, and DC transfer analyses. Enabling this flag will permit the user to print out charge values for capacitors, diode, and transistors, without affecting the DC solutions.

defad

.options defad = defad

where $defad \ge 0.0$

Default Value

 $0.0 \ {\rm m}^2$

Description

Default MOSFET drain diode area.

See Also

defas

.options defas = defas

where *defas* ≥ 0.0

Default Value

 $0.0 \ {\rm m}^2$

Description

Default MOSFET source diode area.

See Also

defl

.options defl = defl

where $defl \ge 0.0$

Default Value

1e-4 m

Description

Default MOSFET channel length.

See Also

defnrd

.options defnrd = *defnrd*

where $defined \ge 0.0$

Default Value

0.0

Description

Default number of diffusion squares for a MOSFET drain resistor.

See Also

defnrs

.options defnrs = *defnrs*

where *defnrs* ≥ 0.0

Default Value

0.0

Description

Default number of diffusion squares for a MOSFET source resistor.

See Also

defpd

.options defpd = defpd

where $defpd \ge 0.0$

Default Value

0.0 m

Description

Default MOSFET drain diode perimeter.

See Also

defps

.options defps = defps

where $defps \ge 0.0$

Default Value

0.0 m

Description

Default MOSFET source diode perimeter.

See Also

defw

.options defw = defw

where $\textit{defw} \times 0.0$

Default Value

1e-4 m

Description

Default MOSFET channel width.

See Also

deriv

```
.options deriv = { 0 | 1 }
```

Default Value

0

Description

Selects the default method for computing all device dq/dv and di/dv derivatives:

0	Computes analytical derivatives where possible. (Available for most MOSFETs, diodes, and BJTs.)
1	Only uses numerical, finite-difference derivatives.

minresistance | resmin

.options minresistance = *minresistance*

Default Value

1e-5 Ω

Description

Minimum resistance value for all resistors, including parasitics and inductor values, as well as resistors defined in the netlist. Any resistance that is specified or computed to be less than *minresistance* is reset to *minresistance*.

modmonte

```
.options modmonte = {0 | 1}
```

Default Value

0

Description

Controls how model parameters are evaluated when they involve Monte Carlo variables.

If **modmonte** is 0, then lot variations of model parameters are performed, and each device that references the model will have the same model definition.

If **modmonte** is 1, then local (mismatch) variations of model parameters are performed, and each device that references the model will have a unique set of model parameters derived from a reevaluation of the Monte Carlo random variable(s). A new model is created for each device, and the model name will be the original model name with *#number* appended (e.g. nch#1, nch#2, ...).

Example

Example 1:

In this example of mismatch analysis, each Mosfet mn1-mn3 will have a unique threshold voltage value due to the dVthN Monte Carlo parameter variations

```
.option modmonte=1
.param dVthN = agauss(0.0, 0.07, 3)
.model NCH nmos level=49 VTH0='0.3703728+dVthN'
MN1 1 11 21 0 NCH W=2.5u L=.25u
MN2 2 12 22 0 NCH W=2.5u L=.25u
MN3 3 13 32 0 NCH W=2.5u L=.25u
```

Example 2:

In this example of process variation analysis, the 3 transistors mn1-mn3 will share the one NCH Mosfet model definition and will have equivalent performance for each Monte Carlo variation.

```
.option modmonte=0
.param dVthN = agauss(0.0, 0.07, 3)
.model NCH nmos level=49 VTH0='0.3703728+dVthN'
MN1 1 11 21 0 NCH W=2.5u L=.25u
MN2 2 12 22 0 NCH W=2.5u L=.25u
MN3 3 13 32 0 NCH W=2.5u L=.25u
```

See Also

"Monte Carlo Parameters" (page 117)

moscap

.options moscap = {true | false}

Default Value

false

Description

Enables automatic source/drain area/perimeter estimation for MOSFETs.

When the ACM model parameter is set to 0 (default) or 10, then: The default AD and AS values will be $\mathbf{I} \times \mathbf{w}$ The default PD and PS values will be $2 \times (\mathbf{I}+\mathbf{w})$

See Also

mout

```
.options mout = { 0 | 1 }
```

Default Value

0

Description

Selects whether output values should be scaled for all M parallel devices or should be single device values. This option affects AC small-signal parameter listings and terminal current, charge, and device detail plot outputs. Actual M scaling is unaffected but but listings and plots will display as either one device (mout=1) or the sum of all M parallel devices (mout=0).

Note that this option is not implemented for the Philips SiMKit models and devices.

Example

```
mnmos1 d g s b nmosmodel l=1u w=.15u M=4
.options mout=0
```

In this example, the AC small-signal listings and plots will be scaled to include the multiplier effects of all four mnmos1 parallel devices.

scale

.options scale = scale

where $scale \ge 0.0$

Default Value

1.0

Description

Scales the physical dimensions of capacitors, MESFETs, MOSFETs, and resistors. Lengths and widths are multiplied by *scale*, and areas are multiplied by *scale*^{2.}

See Also

"scalm" (page 273), "Capacitor (c)" (page 155), "MESFET (z)" (page 174), "MOSFET (m)" (page 175), "Resistor (r)" (page 180)

scalm

.options scalm = *scalm*

where $scalm \ge 0.0$

Default Value

1.0

Description

Default scaling factor for resistors and capacitors. The **scalm** option is overridden by setting the model parameter **scale**. The scaling factor affects lengths, widths, and drawn lengths and widths.

See Also

"scale" (page 272), "Capacitor" (page 363), "Resistor" (page 461)

tnom

.options tnom = tnom

Default Value

25 °C

Description

Nominal temperature in °C. This is the temperature at which all device and model parameters are assumed to be measured.

Note:

Differences in the nominal and the simulation temperatures may account for some variations in solutions when using different SPICE simulators. Many Berkeley SPICE derivatives use 27 °C as the baseline temperature.

wl

```
.options wl = { true | false }
```

Default Value

false

Description

Reverses MOSFET length and width specifications. If wl = true, then length specifications apply to width, and width specifications apply to length.

See Also

"defl" (page 261), "defw" (page 266)

"**pivtol**" (page 278)

Linear Solver Options

"linearsolver" (page 277)

"**zpivtol**" (page 279)

linearsolver

.options linearsolver = {best | klu | sparse }

Default Value

best

Description

Specifies how linear equations are solved. Possible settings are:

best	Allows T-Spice to select a solver based on the number of independent nodes in the system (sparse for less than 100, klu otherwise).
klu	A sparse solver for circuit simulators, developed by Tim Davis and the University of Florida. This is the default solver for systems with more than 100 independent nodes (equation unknowns).
sparse	The original Berkeley SPICE direct solver for a system with fewer than 100 independent nodes (equation unknowns).

pivtol

.options pivtol = *pivtol*

where *pivtol* > 0.0

Default Value

 1×10^{-14}

Description

Minimum pivoting tolerance for real matrices.

zpivtol

.options zpivtol = *zpivtol*

where *zpivtol* > 0.0

Default Value

 1×10^{-6}

Description

Minimum pivoting tolerance for complex matrices.

"tnom" (page 274)

General Options

"autostop" (page 281)
"compatibility" (page 283)
"parhier" (page 285)
"search" (page 288)
"threads" (page 290)

"casesensitive" (page 282) "conncheck" (page 284) "persist" (page 287) "spice" (page 289)

autostop

.options autostop = { true | false }

Default Value

false

Description

Instructs T-Spice to terminate transient analysis after all ".macro *l.eom*" (page 90) results have been found. The autostop option does not affect transient analyses run in preview mode.

See Also

".macro /.eom" (page 90), ".tran" (page 148)

casesensitive

.options casesensitive = { true | false }

Default Value

false

Description

Controls case sensitivity for names of models, subcircuits, library sections, parameters, and nodes.

Note: This option only controls case sensitivity for names that appear *after* the **.options casesensitive** command in the input file.

compatibility

.options compatibility = { spice | hspice | pspice }

Default Value

hspice

Description

Selects a compatibility mode for the input netlist syntax and for simulation settings.

T-Spice can natively read about 99% of Berkeley SPICE, HSPICE, and PSPICE input statements. There are, however, some incompatibilities and some irreconcilable syntax distinctions across the various simulators. By assigning a simulator cmpatibility mode, these input syntax ambiguities can be resolved and appropriately parsed.

In addition to providing syntax parsing support, the compatibility command sets certain simulator settings in order to mimic the behavior of the target simulator. The most notable of these settings is the default temperature, which is 25 °C in HSPICE, and 27 °C in other simulators. Other differences, such as the default MOSFET **nrd** and **nrs** values, and output format settings, may sometimes be the source of subtle or surprising differences in simulator solutions.

HSPICE compatibility mode settings:

• HSPICE compatibility mode is the default setting. Therefore, the default T-Spice settings are used.

SPICE compatibility mode settings:

 The command for assigning Berkeley SPICE compatibility, .options compat=spice, is equivalent to the .options spice command, described in "spice" (page 289).

PSPICE compatibility mode settings:

- The default temperature and **tnom** setting are 27 °C
- The "**acout**" (page 293) option is set to 0
- The **pwr()** function is evaluated as a signed power function in expressions

conncheck

.options conncheck = { true | false }

Default Value

true

Description

Toggles connectivity checking, which tests for common connectivity problems such as "No dc path to ground from node X" and "Node X is attached to only one device."

parhier

.options parhier={local | global}

Default value

global

Description

Establishes the scoping algorithm for selection of parameter values in a hierarchical design. Parameters can obtain their values in a number of different methods, and the varying methods must have an extablished precedence for resolving which value assignment to select when a parameter value is assigned in multiple ways or at multiple levels of hierarchy. The ways in which parameters can be set are:

- .param statements example:.param cap=600f
- subckt parameter declaration, which establish default values example:.subckt inverter in out v cap=800f
- subckt instances (calls) with parameter assignment example:xInverter n1 n2 vdd inverter cap=200f
- .step and DC sweep simulations example:.step cap 200f 1000f 200f

The **parhier** option controls whether global .**param** statements will override the local (subcircuit) parameter assignments. With global scoping the highest level (outermost) parameter assignment will be selected. With local scoping the lowest level (innermost) parameter assignment will be selected. The rules of scoping vary according to the parhier setting, as depicted in the following chart:

parhier=local	parhier=global	
sweep assignments	sweep assignments	
subckt call assignment	.param assignment	
subckt declaration assignment	subckt call assignment	
.param assignment	subckt declaration assignment	

The following example demonstrates how the parhier setting can effect the final parameter value.

```
.param cap=600f
.subckt inverter in out v cap=800f
...
cap1 n3 gnd C=cap
.ends
xinverter1 1 5 vdd cap=400f
```

If parhier is set to **local**, then xinverter.c1 will have a capacitance of 400f. If parhier is set to **global**, then xinverter.c1 will have a capacitance of 600f.

Note:

To get a listing of all parameter names, values, and the type of assignment, use the **xref** option: **.options xref=true**

persist

```
.options persist = { 0 | 1 | 2 | 3 }
```

Default Value

1

Description

Instructs T-Spice to continue simulation when the specified levels of warnings or errors are generated. In the default mode, a severe warning encountered during execution causes the simulation to exit with a terminal error message.

0	Stop simulation when a warning or error occurs.
1	Ignore warning messages.
2	Ignore severe warnings.
3	Ignore error messages.

Fatal error messages cannot be ignored; these always cause the simulation to exit.

Note:

The **persist** option should be used with discretion, as some warnings or errors may cause T-Spice to generate incorrect answers or to execute for a long period of time and ultimately fail.

search

.options search = *pathname*

where *pathname* specifies a valid directory path. If the path contains spaces, *pathname* must be enclosed in quotes.

Default Value

None

Description

Sets the search path for libraries and include files. T-Spice uses the search path as follows:

- If T-Spice encounters an undefined subcircuit, it automatically searches *pathname* for a file named *subckt.inc*, where *subckt* is the name of the subcircuit.
- If .include or .lib statements reference files that are not in the current directory, T-Spice automatically looks for these files in the *pathname* directory.

See Also

".if ... / .elseif ... / .else / .endif" (page 84), ".lib" (page 87)

spice

.options spice = { true | false }

Default Value

false

Description

Changes other option settings to be compatible with Berkeley SPICE:

Option	Default	spice	
" acout " (page 293)	1	0	
" dcap " (page 257)	2	1	
"defnrd" (page 262)	0.0	1.0	
"defnrs" (page 263)	0.0	1.0	
"ingold" (page 300)	0	2	
" tnom " (page 274)	25 °C	27 °C	

Specifying any of the above fields individually will override the value set by **spice**.

threads

.options threads = { 0 | 1 }

Default Value

0 on single processor computers

1 on multiprocessor and multicore computers.

Description

Controls parallel processing of model evaluation in T-Spice simulation. When the value is set to **1**, T-Spice will automatically decompose the workload into small tasks, and dynamically distribute these tasks to multiple threads for processing. The size of the tasks is controlled via internal variables, and is outside of user control.

0	Disables threading. This is the default on single processor computers.
1	Enables threading using a number of threads equal to the number of processor cores. This is the default on multiprocessor and multicore computers.
n	Enable threading using n threads, where n is a number greater than 1. It is not recommended to use a value of n which is greater than the number of processor cores available on the computer.

See Also

"Multi-Threaded Processing" on page 37

Output Options

"acct" (page 292)
"brief" (page 294)
"csdf" (page 296)
"echo" (page 298)
"ingold" (page 300)
"maxmsg" (page 302)
"nomod" (page 304)
"nutmeg" (page 304)
"outputall" (page 308)
"prtdel" (page 310)
"statdelay" (page 312)

"acout" (page 293)
"captab" (page 295)
"dnout" (page 297)
"expert" (page 299)
"list" (page 301)
"node" (page 303)
"numdgt" (page 303)
"opts" (page 307)
"pathnum" (page 309)
"prtinterp" (page 311)
"tabdelim" (page 313)

acct

.options acct = { true | false }

Default Value

false

Description

Tracks and reports simulation iteration counts and other accounting statistics. This information is written to the Simulation Window, and is also recorded in the output file.

acout

```
.options acout = { 0 | 1 }
```

Default Value

1

Description

Calculation method for AC magnitude or phase differences requested in .print and .probe statements (*e.g.*, vm(x,y)).

- If **acout** = 0, T-Spice performs subtraction first, then calculates the magnitude or phase of the difference, *e.g.*, vm(x,y) = vm(x-y).
- If acout = 1, T-Spice first calculates the magnitudes or phases and then takes the difference, e.g., vm(x,y) = vm(x) - vm(y).

Note: Use acout = 0 for compatibility with Berkeley SPICE, and acout = 1 for compatibility with H-Spice.

See Also

".print" (page 122), ".probe" (page 136)

brief

```
.options brief = { true | false }
```

Default Value

false

Description

Turns off most of the printout which is sent to the Simulation Status window.

The **brief** option is equivalent to the **verbose=0** setting.

captab

.options captab = { true | false }

Default Value

false

Description

Lists the capacitances for each node in the netlist, and identifies the node with the greatest capacitance.

csdf

.options csdf = { true | false }

Default Value

false

Description

Causes T-Spice to generate output in CSDF (Common Simulation Data Format) mode for compatibility with ViewLogic Tools.

If probing has been requested in the input T-Spice netlist (see ".probe" on page 136), then the output probe file will be written in CSDF binary file format. If probing has not been requested, then the standard T-Spice output file will be written in CSDF text format.

dnout

```
.options dnout = { 0 | 1 }
```

Default Value

0

Description

Selects the units that T-Spice uses to measure all input and output noise spectral density magnitudes.	
0	T-Spice reports noise spectral density contributions in units of Volts/sqrt(Hz).
1	T-Spice reports noise spectral density contributions in units of Volts ² /Hz.
Use dnout = 1 for compatibility with H-Spice computations.	

Note:

echo

.options echo = { true | false }

Default Value

false

Description

Causes T-Spice to print each line of input to the error log as it is read. The error log is the T-Spice GUI output window, or the specified file when the **-e** *filename* commandline option is used.

When **echo** = **true**, T-Spice lists each input next to the line number on which it occurs. For example:

```
Initializing parser with command line options
line 00001: .options verbose=2
End-of-input
line 00003: .param pres=100
line 00004: .param ptc1=0.1
line 00005: .param ptc2=0.4
line 00006:
line 00007: .options precise
line 00008:
line 00009: v1 1 0 0.01 sin(0.01 12 1e8)
...
```

expert

.options expert = { true | false }

Default Value

false

Description

Activates the printout of detailed information about non-convergent nodes and devices when a simulation, or a stage of a simulation, fails.

ingold

.options ingold = { 0 | 1 | 2 }

Default Value

0

Description

Controls the format of all real numeric data which is written to the AC Small-Signal output (".acmodel" (page 64)) and to the device listings ()..

ingold value	Format	Examples
0	engineering format	-2.875u
1	g format - combined fixed and exponential format	6.234
2	e format - constant width exponential format	-1.7428e-005

For the engineering format, exponents between the value of 1e-18 and 1e15 are expressed as a single character appended to the end of the real data. Numbers which are smaller then 1e-18 or greater than 1e15 are printed in the exponential format. The characters used to express the exponential value are:

Character suffix	Value
Т	10 ¹²
G	10 ⁹
X	10 ⁶
К	10 ³
m	10 ⁻³
u	10 ⁻⁶
n	10 ⁻⁹
р	10 ⁻¹²
f	10 ⁻¹⁵
a	10 ⁻¹⁸

list

```
.options list = { true | false }
```

Default Value

false

Description

Directs T-Spice to printout detailed information about every element in the netlist. The information will include nodal connectivity, the device values (resistance, capacitance, etc.), and other pertinent device parameter and device geometry settings.

maxmsg

.options maxmsg = maxmsg

where *maxmsg* is a non-negative integer

Default Value

4

Description

Sets the maximum number of times that a duplicate warning message will be printed. A value of 0 specifies that all warning messages should be printed an unlimited number of times.

node

.options node = { true | false }

Default Value

false

Description

Prints a node cross-reference table listing each node and all the elements connected to it. Each element is listed as **element:***term*, where *term* identifies the element terminal as follows.

Device Type	Terminal identifiers
Diode	+ = anode - = diode
	B = base C = collector E = emitter S = substrate
MOSFET or JFET	B = bulk D = drain S = source G = gate
All other devices	1 = terminal 1 2 = terminal 2 etc.

nomod

.options nomod = { true | false }

Default Value

true

Description

Suppresses printout of all model parameters.

numdgt

.options numdgt = *numdgt*

where *numdgt* is a non-negative integer

Default Value

4

Description

Minimum number of digits after the decimal point to be printed to the output file for each requested (.print) output value.

nutmeg

.options nutmeg = { true | false }

Default Value

false

Description

Generates output files in a format compatible with the Nutmeg graphics program.

opts

.options opts = { true | false }

Default Value

false

Description

Prints the current settings of all control options. The default behavior (**opts** = **false**) is to list only those option values that have been changed.

outputall

.options outputall = { true | false }

Default Value

false

Description

Causes all commands that list nodes, devices, or options to include internal listings. Internal nodes, devices, and options are normally hidden to the user.

The **outputall** option affects the following commands:

options node	Includes all internal nodes.
.options list	Includes all internal nodes and devices.
.options opts	Includes all hidden and undocumented options.
.print	Tests internal devces and nodes for wildcard matching. When .print is used without arguments, includes all internal nodes and devices in the output.
.probe	Tests internal nodes and devices for wildcard matching. When .probe is used without arguments, includes all internal nodes and devices in the output.

See Also

"node" (page 303), "xref" (page 315), "opts" (page 307), ".print" (page 122), ".probe" (page 136)

pathnum

options pathnum = { true | false }

Default Value

false

Description

The pathnum option converts all node and element names in the output listings so that the subcircuit pathname portion of each name is converted to a number. An accompanying cross-reference will be printed to show the correspondence of these numbers to the fully qualified subcircuit pathnames.

prtdel

.options prtdel = prtdel

where *prtdel* ≥ 0.0

Default Value

0.0 s

Description

Fixed time delay between output points in transient analysis. This does not affect the internal time step calculations needed to ensure solution accuracy.

.options prtdel affects both the .dat file output and the .out file output. If you want to decrease the number of data points in your .dat and .out files, you can use .options prtdel to set a larger timestep value for the output resolution which, in turn, will decrease the size of your .dat and .out files.

prtinterp

.options prtinterp = { true | false }

Default Value

true

Description

When the **prtdel** option is set, **prtinterp** determines how solutions are calculated at the output time intervals. When set to true, **prtdel** timepoints are interpolated rather than computed.

- prtinterp=0—In addition to the internal time steps, the T-Spice simulator takes time steps at the output intervals and calculates those solutions directly.
- prtinterp=1—Output solutions are computed using linear interpolation of the T-Spice engine's internal time step solutions.

The default value of option **prtinterp** to true, so that prtdel timepoints are interpolated. **prtdel** controls the frequency of printed output during a transient simulation. For example, a **prtdel** value of 1n should result in print statements being executed for each 1 nanosecond. But, prtdel specifically should not change the internal time-stepping algorithm. It should only change the printed timestep value, and use interpolation to get these values (unless **prtinterp** is set).

statdelay

.options statdelay = statdelay

Default Value

0.5 s

Description

Minimum delay in real time between updates of status display in the T-Spice user interface (GUI).

tabdelim

.options tabdelim = { true | false }

Default Value

false

Description

Toggles tab-delimited output columns.

verbose

```
.options verbose = { 0 | 1 | 2 | 3 | 4 }
```

Default Value

1

Description

Level of detail of circuit and simulation information printed to the Simulation Window.

0	Prints only the processing phase and final runtimes.
1	Prints node and device counts and major runtime statistics. Lists options whose values have been modified from the default.
2	Prints all option settings (equivalent to opts = true) and all runtime statistics (equivalent to acct = true).
3	Prints node connectivity (equivalent to node = true), lists devices (equivalent to list = true), and prints conditional statement, subcircuit, and parameter cross reference listings (equivalent to xref = true).
4	Lists hidden or internal devices, nodes, and options (equivalent to outputall = true), and lists convergence residual statistics (equivalent to expert = true). If the input file contains .alter statements, then all log (listing) printouts will be given for each alter section.

See Also

"opts" (page 307), "acct" (page 292), "node" (page 303), "outputall" (page 308)

xref

```
.options xref = { true | false }
```

Default Value

false

Description

Generates extensive cross-referencing information listings about the input circuit and simulation commands. The information includes:

- A list of all subcirctuit instances;
- A tree outline of all conditional statements (.if ()endif);
- A listing of all parameters (.param definitions or subcircuit parameters) that are defined and used in the circuit.

Probing Options

"binaryoutput" (page 317)
"probeq" (page 319)
"probefilename" (page 321)

"**probei**" (page 318) "**probev**" (page 320)

binaryoutput

.options binaryoutput = { 0 | 1 | 2 | 3 }

Default Value

3

Description

Specifies the form of binary output created with ".probe" (page 136).

0	Text format.
1	Binary format with no compression.
2	Binary format using constant waveform compression.
3	Binary format using linear extrapolation compression.

probei

.options probei = { true | false }

Default Value

false

Description

Instructs T-Spice to include device terminal current values in the output data generated by .probe and .print (when used without arguments).

probeq

.options probeq = { true | false }

Default Value

false

Description

Instructs T-Spice to include device terminal charge values in the output data generated by .probe and .print (when used without arguments).

probev

.options probev = { true | false }

Default Value

false

Description

Instructs T-Spice to include node voltage values in the output data generated by .probe and .print (when used without arguments).

probefilename

.options probefilename = filename

Default Value

fname.dat, where fname is the text output filename.

Description

Specifies the filename for binary output produced by the .probe command.

Verilog-A Options

"vaverbose" (page 323)
"vacache" (page 325)
"vaopts" (page 327)
"vaexprtol" (page 329)

"vasearch" (page 324) "vaalwayscompile" (page 326) "vatimetol" (page 328)

vaverbose

.option vaverbose [= { true | false | 1 | 0 }]

Default Value

0

Description

Enables or disables verbose printing of Verilog-A compiler settings, search paths, loaded modules, etc. This information is displayed in the Simulation Status window.

Possible settings are:

0 or false

1 or true

Print information.

Do not print information.

vasearch

.option vasearch = path1 [; path2 [; ...]]

Default Value

None

Description

Adds directories to the search path for Verilog-A files. Pathnames containing spaces must be enclosed in quotes.

T-Spice looks for Verilog-A files in the following default order:

1. Current working directory (directory containing the T-Spice input file)

2. Path(s) specified in the Simulation Settings dialog

- 3. Path(s) specified by the .option vasearch command
- 4. .\verilogA\models subdirectory of the local T-Spice installation

vacache

```
.option vacache [ = { true | false | 1 | 0 } ]
```

Default Value

0

Description

Enables or disables the Verilog-A CML (compiled model library) file-caching mechanism.

Possible settings are:

0 or falseDo not cache CML files.1 or trueCache CML files.

Verilog-A modules are automatically compiled when loaded, and the CML files resulting from compilation are cached for future use.

When **vacache** is set to **false** or **0**, CML files are placed in .**Nib.win32**, a subdirectory of the current working directory (directory containing the T-Spice input file).

When vacache is set to true or 1, CML files are placed in C:\Documents and Settings\ *username*\Application Data\Tanner EDA\.tanner-model-cache.

See Also

"vaalwayscompile" (page 326)

vaalwayscompile

.option vaalwayscompile [= { true | false | 1 | 0 }]

Default Value

0

Description

Enables or disables forced recompilation of each Verilog-A file, even when the CML (compiled model library) file is up-to-date.

Possible settings are:

0 or false	Do not recompile Verilog-A files when the CML file is up-to-date.
1 or true	Always recompile Verilog-A files.

When **vaalwayscompile** is set to **false** or **0**, a new simulation recompiles the Verilog-A module code only if (a) the code has changed, (b) the include files have changed, (c) the **vacomp** compiler version has changed, or (d) the CML cache directory or file has been deleted.

See Also

"vacache" (page 325)

vaopts

.option vaopts = "options"

Default Value

None

Description

Passes options to the vacomp compiler.

Note that the default **vacomp** options are adequate for almost all situations. The ability to set **vacomp** options with the **.option vaopts** command is provided for advanced users only, and should be used with caution.

Strings of multiple options must be enclosed in quotes. For example: .option vaopts="-strict -G".

The options are:

-f	Disable run-time floating point checking			
-o file	Specify compiled model library file name (defaults to inputfile.cml)			
-strict	Reject non-compliant language extensions			
-В	Force state variable creation for named branches			
-D <i>x</i>	Define preprocessor macro \boldsymbol{x} with value 1			
-D <i>x=y</i>	Define preprocessor macro x with value y			
-E	Run preprocessor; output to stdout			
-G	Make all variables available for output			
-I directory	Prepend <i>directory</i> to include search path			
-M	Generate dependency file			
-N	Suppress banner reporting			
-P file	Run preprocessor; output to <i>file</i>			
-U depth	Unroll genvar loops to level <i>depth</i> (0 no unrolling)			
-V level	Status message reporting level; $level = 02$ (default 1)			
-W level	Warning message reporting level; $level = 02$ (default 1)			

vatimetol

.option vatimetol = tolerance

Default Value

10 * mintimestep

Description

Sets the default time tolerance (time_tol) for the Verilog-A cross(), timer(), and above() functions.

See Also

mintimestep

vaexprtol

.option vaexprtol = tolerance

Default Value

absv

Description

Sets the default expression tolerance (*expr_tol*) for the Verilog-A cross() and above() functions.

See Also

"absv | vntol" (page 208)

Introduction

This chapter describes the predefined analytical device models. Original documentation from the developers of the models is provided with T-Spice for further reference in the **models** folder of the standard installation directory.

The T-Spice built-in device models are distributed as a collection of external dynamically linked libraries (DLLs) located in the **tspicemodels** subdirectory of the installation. This modularization improves the performance, quality and features of all built-in device models.

BIPOLAR Level/Model Cross Reference

T-Spice supports a number of different bipolar models, which are selectable using the **level** parameter in the **.model** statement. The association between model levels and the model type is shown in the following table.

Bipolar level	Model	Further Documentation
1	Gummel-Poon	BJT Level 1 (Gummel-Poon) (page 336)
6	Philips Mextram	BJT Level 6 (Mextram) (page 356)
9	VBIC	BJT Level 9 (VBIC) (page 357)
10	Philips Modella Lateral PNP	BJT Level 10 (Modella) (page 362)

Diode Level/Model Cross Reference

The diode models which are supported by T-Spice, together with their model **level** associations, are shown in the following table.

Diode level	Model	Further Documentation	
1	Non-geometric Junction Diode	Diode (page 366)	

Diode level	Model	Further Documentation	
2	Fowler-Nordheim	Diode (page 366)	
3	Geometric Junction Diode	Diode (page 366)	
4	Philips Juncap 2	Diode (page 366)	
200	Philips Advanced Diode	Diode (page 366)	

JFET & MESFET Level/Model Cross Reference

The diode models which are supported by T-Spice, together with their model **level** associations, are shown in the following table.

JFET/ MESFET level	Model	Further Documentation
0	Schichmann and Hodges JFET	JFET (page 380)
1	Curtice MESFET	MESFET (page 383)
2	Statz MESFET	MESFET (page 383)
3	Curtice GaAs MESFET	MESFET (page 383)

MOSFET Level/Model Cross Reference

Particular MOSFET models are selected by use of the **level** parameter in the **.model** statement. The association between model levels and the model type is shown in the following table.

Note: Some models can be referenced using more than one level number. This does not imply that the models are different. It is usually the case that the additional level is added for compatibility of input files from other simulators (Berkeley SPICE, HSPICE[®], PSPICE[®], etc.). For example, the EKV model can be selected as either MOSFET level 44, for SmartSpice compatibility, or as level 55, for HSPICE compatibility.

MOSFET Model level		Further documentation
1	SPICE level 1	MOSFET Levels 1/2/3 (Berkeley SPICE 2G6) (page 393)

MOSFET level	Model	Further documentation	
2	SPICE level 2	MOSFET Levels 1/2/3 (Berkeley SPICE 2G6) (page 393)	
3	SPICE level 3	MOSFET Levels 1/2/3 (Berkeley SPICE 2G6) (page 393)	
4	BSIM1	MOSFET Levels 4 and 13 (BSIM1) $(page 410)$	
5	proprietary Maher-Mead model	MOSFET Level 5 (Maher-Mead) $(page 414)$	
8	BSIM3 v3.3 — strict Berkeley implementation without extensions	MOSFET Levels 8, 49 and 53 (BSIM3 Revision 3.3) $\left(page 416 \right)$	
9	Philips MOS 9 (identical to level 50)	MOSFET Level 20 (Philips MOS 20) $(page 437)$	
11	Philips MOS 11 (identical to level 63)	MOSFET Levels 11 and 63 (Philips MOS 11) $(page \ 426)$	
13	BSIM1	MOSFET Levels 4 and 13 (BSIM1) $(page 410)$	
14	BSIM4 v4.5 (identical to level 54)	Variables for which equations are not given here are as follows. $\left(page \; 424\right)$	
15	RPI Amorphous-Si TFT Model	$\begin{array}{l} \textbf{MOSFET Levels 15 and 61 (RPI Amorphous-Si TFT Model)} \\ (page \ 430) \end{array}$	
16	RPI Poly-Si TFT Model (equivalent to AimSpice level 16 PSIA2)	MOSFET Levels 16 and 62 (RPI Poly-Si TFT Model, 1.0 and 2.0) $(page \ 433)$	
20	Philips MOS 20	MOSFET Level 20 (Philips MOS 20) (page 437)	
28	BSIM1 with extensions	MOSFET Level 28 (Extended BSIM1) (page 438)	
30	Philips MOS 30	MOSFET Level 40 (Philips MOS 40) $(page 444)$	
31	Philips MOS 31	MOSFET Level 31 (Philips MOS 31) $(page 443)$	
40	Philips MOS 40	MOSFET Level 40 (Philips MOS 40) (page 444)	
44	EKV v2.6 (identical to level 55)	.MOSFET Levels 44 and 55 (EKV Revision 2.6) $(page\ 445)$	
47	BSIM3 v2	MOSFET Level 47 (BSIM3 Revision 2) (page 446)	
49	BSIM3 v3.3 with HSPICE extensions	MOSFET Levels 8, 49 and 53 (BSIM3 Revision 3.3) $\left(page 416 \right)$	
53	BSIM3 v3.3 with limited HSPICE extension support (ACM, tnom, etc.)	MOSFET Levels 8, 49 and 53 (BSIM3 Revision 3.3) $\left(page 416 \right)$	
54	BSIM4 v4.5 (identical to level 14)	Variables for which equations are not given here are as follows. $\left(page \; 424\right)$	
55	EKV v2.6 (identical to level 44)	MOSFET Levels 44 and 55 (EKV Revision 2.6) $\left(page 445 \right)$	
57	BSIM3SOI v3.2	MOSFET Level 57 / 70 (BSIM3SOI and BSIM4SOI) (page $451)$	
100	PSP	MOSFET Level 100 (Penn State & Philips PSP Model) (page 454)	

Philips Model Cross Reference

T-Spice supports most of the models that are available in the Philips SiMKit compact transistor model library. The SiMKit library contains a variety of diode, bipolar, and MOSFET models, and has been made freely available to the circuit and model design community.

Note:

The Philips models do not support HSPICE extensions (ACM, HSPICE diodes, etc.)

In order to facilitate easy selection of Philips models, an additional parameter has been added to the **.model** statement: **model**=*modelname*. The *modelname* value will determine the Philips model which will be selected, and will override the **level** and **version** parameter values in the **.model** statement, if they are present. The possible values for *modelname* are listed in the following table. In this table, the e/ g column notes whether the model is electrical or geometrical; the **thermal** column states whether the model includes self-heating equations; and the **substrate** column states whether it is a bipolar model which includes the substrate current and charge terms.

Model	Туре	Level	Modelname	e/g	Therma	l Substrate
Juncap Level 1	d	1	juncap	e		
Juncap2 Level 200	d	200	juncap200	e		
Advanced Diode Level 500	d	500	dio500	e		
Modella	pnp	500	bjt500	e		yes
			bjt500t	e	yes	yes
Mextram Level 503	npn/pnp	503	bjt503	e		yes
			bjtd503	e		
Mextram Level 504	npn/pnp	504	bjt504	e		yes
			bjt504t	e	yes	yes
			bjtd504	e		
			bjtd504t	e	yes	
PSP Level 100.1	nmos/pmos	100	psp100 or psp100e	e		
		1000	psp1000 or psp100g	g		
Mos 11 Level 1100	nmos/pmos	1100	mos1100e	e		
			mos1100	g		
Mos 11 Level 1101	nmos/pmos	1101	mos1101e	e		
			mos1101et	e	yes	

Model	Type Lev	vel Modelname	e/g	Thermal Substrate
	110	10 mos11010	g	
		mos11010t	g	yes
	(binning) 110	11 mos11011	g	
		mos11011t	g	yes
Mos 11 Level 1102	nmos/pmos 110	2 mos1102e	e	
		mos1102et	e	yes
		mos11020	g	
		mos11020t	g	yes
	(binning) 110	21 mos11021	g	
		mos11021t	g	yes
Mos 20 Level 2001	nmos/pmos 200	1 mos2001e	e	
		mos2001et	e	yes
		mos2001	g	
		mos2001t	g	yes
Mos 31 Level 3100	nmos/pmos 310	0 mos3100	e	
		mos3100t	e	yes
Mos 40 Level 40	nmos/pmos 40	mos40	e	
		mos40t	e	yes
Mos 30 Level 3002	nmos/pmos 300	2 mos3002	e	
Mos 9 Level 902	nmos/pmos 902	mos902e	e	
		mos902	g	
Mos 9 Level 903	nmos/pmos 903	mos903e	e	
		mos903	g	

Model Descriptions

For each model class, the following information is typically given.

• The .model command to be used in the input file. The .model command initializes the model by specifying its name, type, level, and parameter values.

- The parameters that determine the model's characteristics. These are given in a table of parameter names (as used in the code), symbols (as used in the equations), descriptions, default values, and units.
- The circuit underlying the large-signal behavior of the model.
- The analytical equations that constitute the model.

The following abbreviations and conventions are employed.

I	(Vertical bar.) In syntax paradigms, separates alternative values. In parameter tables, separates alternative names (<i>aliases</i>).
Computed.	Indicates a parameter whose value is computed, not fixed or assigned.
[n]	Indicates the NMOS value of a parameter.
[p]	Indicates the PMOS value of a parameter.
	Symbol for <i>square</i> .
DIBL	Abbreviation for drain-induced barrier lowering.
LDD	Abbreviation for lightly-doped drain.

Constants

The following physical constants are used in parameter and equation evaluation.

Constant	Description	Value	Units
ε0	Dielectric permittivity of vacuum	8.85421×10^{-12}	F/m
εox	Relative dielectric permittivity of SiO_2	3.9	_
esi	Relative dielectric permittivity of silicon	11.7	_
ni	Intrinsic carrier concentration at 300 K	1.45×10^{16}	m ⁻³
q	Elementary electron charge	1.6021918 × 10 ⁻¹⁹	С
π	Pi	3.1415926	_
k	Boltzmann's constant	$1.3806226 \times 10^{-23}$	V·C/K
_	0 °C	273.15	Κ
Tnom	Default nominal model temperature	Specified by .options tnom (<i>default</i> : 25)	°C
e	Base of natural logarithms	2.7182818	

BJT Level 1 (Gummel-Poon)

The level 1 bipolar junction transistor model uses a modified version of the Gummel-Poon chargecontrol model that was implemented in the original SPICE. The model simplifies to the Ebers-Moll model when certain parameters are not specified. It also includes high-bias and temperature effects.

Note: Gummel-Poon is the default model which will be used for all bipolar models (type **npn** or **pnp**) which do not have the **level** model parameter set.

Parameters

The BJT model uses the following syntax.

```
.model name npn | pnp [level=1] [parameters]
```

The following tables describe all of the Gummel-Poon BJT parameters that T-Spice supports. Parameters that are not specified in the Ebers-Moll model are marked with an asterisk (*).

DC Current Parameters

Parameter (alias)	Symbol	Description	Default	Units
level		Model selector	1.0	
subs		Substrate connection selector	1 (npn); -1 (pnp)	_
update		Equation selector for base charge.	0	—
dcap		Equation selector for depletion capacitance.	2	—
bf	βf	Ideal forward maximum current gain.	100.0	—
br	β_r	Ideal reverse maximum current gain.	1.0	—
ibc	I _{bc}	Reverse saturation current between base and collector.	0.0	А
ibe	I _{be}	Reverse saturation current between base and emitter.	0.0	А
iss	I _{ss}	Reverse saturation current between bulk and collector for vertical geometry , or between bulk and base for lateral geometry	0.0	А
is	Is	Transport saturation current.	1.0×10 ⁻¹⁶	А
c2 (jle)	C ₂	Non-ideality factor for base-emitter leakage saturation current.*	0.0	—
c4	C ₄	Non-ideality factor for base-collector leakage saturation current.*		_
ise	I _{se}	Base-emitter leakage saturation current.*	c2×is	А
isc	I _{sc}	Base-collector leakage saturation current.*	c4×is	А
nf	$\eta_{\rm f}$	Forward current emission coefficient.*	1.0	_
nr	$\boldsymbol{\eta}_r$	Reverse current emission coefficient.*	1.0	—
ns	$\boldsymbol{\eta}_s$	Substrate current emission coefficient.	1.0	—
nc (nlc)	η_c	Base-collector leakage emission coefficient.*	2.0	
ne (nle)	η_e	Base-emitter leakage emission coefficient.*	1.5	
expli	EXPLI	Current explosion model parameter. The PN junction characteristics above the explosion current area are linear, with the slope at the explosion point.	1.0×10 ¹⁵	А

Base Charge Parameters

Parameter (alias)	Symbol	Description	Default	Units
vaf (vbf)	Vaf	Forward early voltage.*	0.0 (indicates infinite value)	V
var (vb, vbb)	V _{ar}	Reverse early voltage.*	0.0 (indicates infinite value)	V
ikf (ik, jbf)	I _{kf}	Corner for forward Beta high current roll-off.*	0.0 (indicates infinite value)	Α
ikr (jbr)	I _{kr}	Corner for reverse Beta high current roll-off.*	0.0 (indicates infinite value)	A
nkf	η_{kf}	Exponent for high current Beta roll-off.*	0.5	

Base charge parameters are not specified for the Ebers-Moll model.

Parasitic Resistor Parameters

Parameter (alias)	Symbol	Description	Default	Units
irb (jrb,iob)	Irb	Base current, where base resistance falls halfway between r_b and $rbm.*$	0.0 (indicates infinite value)	А
rb	r _b	Base resistance.*	0.0	Ω
rbm	r _{bm}	Minimum high current base resistance.*	rb	Ω
re	r _e	Emitter resistance.	0.0	Ω
rc	r _c	Collector resistance.	0.0	Ω

Parasitic Capacitance Parameters.

Parameter	Symbol	Description	Default	Units
сьср	CBCP	External base-collector constant capacitance.	0.0	F
cbep	CBEP	External base-emitter constant capacitance.	0.0	Φ
ccsp	CCSP	External collector-substrate (vertical) or base- substrate (lateral) constant capacitance.	0.0	Φ

Junction Capacitance Parameters

Parameter (alias)	Symbol	Description	Default	Units	
cjc	Cjc	Base-collector zero-bias depletion capacitance.	0.0	F	

Parameter (alias)	Symbol	Description	Default	Units
cje	C _{je}	Base-emitter zero-bias depletion capacitance.	0.0	Φ
cjs (ccs, csub)	C _{js}	Zero-bias collector-substrate capacitance.	0.0	Φ
fc	FC	Coefficient for forward bias depletion capacitance.	0.5	
mjc (mc)	m _{jc}	Base-collector junction exponent (grading factor).	0.33	
mje (me)	m _{je}	Base-emitter junction exponent (grading factor).	0.33	
mjs (esub)	m _{js}	Substrate junction exponent (grading factor).	0.5	
vjc (pc)	V _{jc}	Base-collector built-in potential.	0.75	V
vje (pe)	V _{je}	Base-emitter built-in potential.	0.75	V
vjs (psub)	V _{js}	Substrate junction built-in potential.	0.75	V
xcjc (cdis)	X _{cjc}	Internal base fraction of base-collector depletion capacitance.	1.0	

Transit Time parameters

Parameter (alias)	Symbol	Description	Default	Units
ptf	P _{tf}	Frequency multiplier to determine excess phase.	0.0	deg.
tf	$\tau_{\rm f}$	Base forward transit time.	0.0	S
tr	τ_{r}	Base reverse transit time.	0.0	S
vtf	V _{tf}	Voltage for V_{bc} dependence of τ_f	0.0 (indicates infinite value)	ς
xtf	X _{tf}	Coefficient for bias dependence of τf .	0.0	
itf (jtf)	Itf	Parameter for high-current effect on τ_{f} .	0.0	А

Noise Parameters

Parameter	Symbol	Description	Default
af	AF	Flick noise exponent.	1.0
kf	KF	Flick noise exponent.	0.0

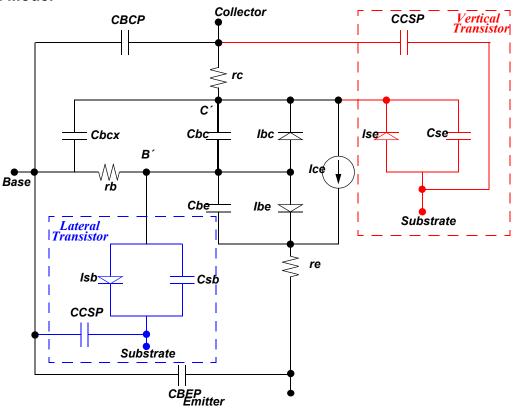
Temperature Effect Parameters

Parameter (alias)	Symbol	Description	Default	Units
tnom (tref)	T _{nom}	Nominal temperature	global tnom (25.0)	deg
tlev	tlev	Temperature equation selector	0	
tlevc	tlevc	Temperature equation selector for junction capacitances and potentials	0	
bex	Bex	V0 temperature exponent. (Level 2 only.)	2.42	
bexv	B _{exv}	<i>Rc</i> temperature exponent. (tlev=2 only.)	1.90	
ctc	C _{tc}	Temperature coefficient for zero-bias base- collector capacitance.	0.0	1/deg
cte	C _{te}	Temperature coefficient for zero-bias base- emitter capacitance.	0.0	1/deg
cts	C _{ts}	Temperature coefficient for zero-bias substrate capacitance.	0.0	1/δεγ
eg	E _g (0)	Energy gap at 0°K for tlev = 2 (default): for tlev = 0 , 1 , or 3:	1.16 1.11	eV
gap1	GAP1	Coefficient in energy gap temperature equation	7.02×10 ⁻⁴	eV/deg
gap2	GAP2	Coefficient in energy gap temperature equation	1108.0	deg
tbf1 tbf2	${ m TBF}_1 { m TBF}_2$	First order and second order temperature coefficients for β_{f}	0.0 0.0	1/deg 1/deg ²
tbr1 tbr2	TBR ₁ TBR ₂	First order and second order temperature coefficients for βr .	0.0 0.0	1/deg 1/deg ²
tikf1 tikf2	TIKF ₁ TIKF ₂	First order and second order temperature coefficients for <i>Ikf</i> .	0.0 0.0	1/deg 1/deg ²
tikr1 tikr2	TIKR ₁ TIKR ₂	First order and second order temperature coefficients for <i>Ikr</i> .	0.0 0.0	1/deg 1/deg ²
tirb1 tirb2	TIRB ₁ TIRB ₂	First order and second order temperature coefficients for <i>Irb</i> .	0.0 0.0	1/deg 1/deg ²

Parameter (alias)	Symbol	Description	Default	Units
tisc1 tisc2	$\frac{\text{TISC}_1}{\text{TISC}_2}$	First order and second order temperature coefficients for <i>Isc.</i> (tlev=3 only.)	0.0 0.0	1/deg 1/deg ²
tis1 tis2	$\begin{array}{c} \text{TIS}_1 \\ \text{TIS}_2 \end{array}$	First order and second order temperature coefficients for <i>Is</i> or <i>Ibe</i> and <i>Ibc</i> . (tlev=3 only).	0.0 0.0	1/deg 1/deg ²
tise1	TISE1	First order and second order temperature coefficients for <i>Ise</i> . (tlev=3 only)	0.0	1/deg
tise2	TISE2		0.0	1/deg ²
tiss1 tiss2	$\begin{array}{c} \text{TISS}_1 \\ \text{TISS}_2 \end{array}$	First order and second order temperature coefficients for <i>Iss</i> (tlev=3 only).	0.0 0.0	1/deg 1/deg ²
titf1	TITF ₁	First order and second order temperature coefficients for <i>Itf</i> .	0.0	1/deg
titf2	TITF ₂		0.0	1/deg ²
tmjc1	TMJC ₁	First order and second order temperature coefficients for <i>mjc</i> .	0.0	1/deg
tmjc2	TMJC ₂		0.0	1/deg ²
tmje1	TMJE ₁	First order and second order temperature coefficients for <i>mje</i> .	0.0	1/deg
tmje2	TMJE ₂		0.0	1/deg ²
tmjs1	$TMJS_1$	First order and second order temperature coefficient for <i>mjs</i> .	0.0	1/deg
tmjs2	$TMJS_2$		0.0	1/deg ²
tnc1	TNC ₁	First order and second order temperature coefficients for ηc .	0.0	1/deg
tnc2	TNC ₂		0.0	1/deg ²
tne1	TNE ₁	First order and second order temperature coefficients for ηe .	0.0	1/deg
tne2	TNE ₂		0.0	1/deg ²
tnf1	TNF ₁	First order and second order temperature coefficients for $\eta_{f^{t}}$	0.0	1/deg
tnf2	TNF ₂		0.0	1/deg ²
tnr1	TNR ₁	First order and second order temperature coefficients for ηr .	0.0	1/deg
tnr2	TNR ₂		0.0	1/deg ²
tns1	TNS ₁	First order and second order temperature coefficients for ηs .	0.0	1/deg
tns2	TNS ₂		0.0	1/deg ²
trb1	TRB ₁	First order and second order temperature coefficients for <i>rb</i> .	0.0	1/deg
trb2	TRB ₂		0.0	1/deg ²
trc1 trc2	$TRC_1 TRC_2$	First order and second order temperature coefficients for <i>rc</i> .	0.0 0.0	1/deg 1/deg ²
tre1	TRE ₁	First order and second order temperature coefficients for <i>re</i> .	0.0	1/deg
tre2	TRE ₂		0.0	1/deg ²
trm1	TRM ₁	First order and second order temperature coefficients for <i>rbm</i> .	trb1	1/deg
trm2	TRM ₂		trb2	1/deg ²
ttf1	TTF ₁	First order and second order temperature coefficients for τf .	0.0	1/deg
ttf2	TTF ₂		0.0	1/deg ²
ttr1	TTR ₁	First order and second order temperature coefficients for τr .	0.0	1/deg
ttr2	TTR ₂		0.0	1/deg ²

Parameter (alias)	Symbol	Description	Default	Units
tvaf1 tvaf2	TVF ₁ TVF ₂	First order and second order temperature coefficients for <i>Vaf</i> .	0.0 0.0	1/deg 1/deg ²
tvar1 tvar2	TVR ₁ TVR ₂	First order and second order temperature coefficients for <i>Var</i> .	0.0 0.0	1/deg 1/deg ²
tvjc	T _{vje}	Temperature coefficient for Vjc.	0.0	V/deg
tvje	T _{vje}	Temperature coefficient for V_{je} .	0.0	V/deg
tvjs	T _{vjs}	Temperature coefficient for Vjs.	0.0	V/deg
xtb (tb, tcb)	X _{tb}	Forward and reverse Beta temperature exponent.	0.0	
xti	X _{ti}	Saturation current temperature exponent. (Use <i>Xti</i> =3.0 for Silicon diffused junction, and <i>Xti</i> =2.0 for Schottky barrier diode.)	3.0	

Large-Signal Model



Equations

The Gummel-Poon model includes four "second-order" current effects:

• The low-current drop in current gain β is due to extra components of base current *IB*. The parameters I_{se} , η_e (the low current drop in β_f) and I_{sc} , η_c (the low current drop in β_r) describe this effect, and two non-ideal diodes are included in the Large-Signal Model, above as shown.

- Base-width modulation, affecting the BJT output conductance, is described by V_{ar} (reverse Early voltage) and V_{af} (forward Early voltage).
- High-level injection, modifying the slope of the log(IC) vs. V_{be} characteristic, is described by two "knee" currents, I_{kf} and I_{kr} , for the forward and reverse regions of operation.
- Base resistance is current dependent and is modeled by a combination of r_b , r_{bm} , and I_{rb} .

The Gummel-Poon large-signal model for transient simulations is topologically identical to the Ebers-Moll large-signal model except for the inclusion of the distributed base-collector capacitance. In addition, the effect of τ_f modulation (transit time) is handled.

Geometry Consideration

The BJT model has two geometric configurations based on physical layout: vertical and lateral. The geometric configuration is specified by the substrate connection selector parameter, **subs**. Set **subs** equal to 1 to specify vertical geometry or to -1 to specify lateral geometry. The default value of **subs** is 1 for **npn** transistors and -1 for **pnp** transistors.

The instance parameters **area**, **areab**, **areac**, and **M** specify geometric scaling for current and charge values in the Gummel-Poon BJT. (See "BJT (q)" on page 153 for more information about these parameters.)

Scaling: Both Vertical and Lateral Geometry

$$I_{s_{eff}} = area \cdot M \cdot I_{s}$$

$$I_{be_{eff}} = area \cdot M \cdot I_{be}$$

$$I_{se_{eff}} = area \cdot M \cdot I_{se}$$

$$I_{kf_{eff}} = area \cdot M \cdot I_{kf}$$

$$I_{kr_{eff}} = area \cdot M \cdot I_{kr}$$

$$I_{rb_{eff}} = area \cdot M \cdot I_{rb}$$

$$I_{ss_{eff}} = area \cdot M \cdot I_{ss} \quad if both I_{be} and I_{bc} are NOT specified$$

$$I_{tf_{eff}} = area \cdot M \cdot I_{tf}$$
(8.50)

$$EXPLI_{eff} = area \cdot M \cdot EXPLI \tag{8.51}$$

$$C_{bcp_{eff}} = area \cdot M \cdot C_{bcp}$$

$$C_{bep_{eff}} = area \cdot M \cdot C_{bep}$$

$$C_{csp_{eff}} = area \cdot M \cdot C_{csp}$$

$$C_{je_{eff}} = area \cdot M \cdot C_{je}$$
(8.52)

$$r_{b_{eff}} = \frac{r_b}{area \cdot M}$$

$$r_{bm_{eff}} = \frac{r_{bm}}{area \cdot M}$$

$$r_{e_{eff}} = \frac{r_e}{area \cdot M}$$

$$r_{c_{eff}} = \frac{r_c}{area \cdot M}$$
(8.53)

Scaling: Vertical Geometry (subs=1)

$$I_{bc_{eff}} = areab \cdot M \cdot I_{bc}$$

$$I_{sc_{eff}} = areab \cdot M \cdot I_{sc}$$

$$I_{ss_{eff}} = areab \cdot M \cdot I_{ss} \quad if both \ I_{be} \ and \ I_{bc} \ are \ specified$$

$$C_{js_{eff}} = areab \cdot M \cdot C_{js}$$

$$C_{jc_{eff}} = areab \cdot M \cdot C_{jc}$$
(8.54)

Scaling: Lateral Geometry (subs=-1)

$$I_{bc_{eff}} = areac \cdot M \cdot I_{bc}$$

$$I_{sc_{eff}} = areac \cdot M \cdot I_{sc}$$

$$I_{ss_{eff}} = areac \cdot M \cdot I_{ss} \quad if both \ I_{be} \ and \ I_{bc} \ are \ specified \qquad (8.55)$$

$$C_{js_{eff}} = areac \cdot M \cdot C_{js}$$

$$C_{jc_{eff}} = areac \cdot M \cdot C_{jc}$$

Current Equations (Level 1)

The following current equations are used when **level**=1, specifying that either the Gummel-Poon or Ebers-Moll model will be used. T-Spice chooses appropriate current equations according to which parameters were specified. The reverse saturation currents between base and collector and between base and emitter (I_{bc} and I_{be}) are optional parameters. If they are not specified, T-Spice uses the transport saturation current I_s in current equations.

There are no explicit switches between the different regions of device operation. Equations (8.56) through (8.68) describe currents in the normal active, inverse, saturation, and cut-off regions of operation. This means that the β roll-off at high collector current is slightly less pronounced in T-Spice.

Base Charge Equations

In order to determine BJT currents, T-Spice must first calculate base charge. There are two sets of base charge equations; you can specify which equations T-Spice will use by changing the model selector **update**.

The base charge q_b is calculated from the following equation:

$$q_b = \frac{q_1}{2} (1 + (1 + 4q_2)^{\eta_{kf}}), \qquad (8.56)$$

where q_2 and q_1 are calculated as follows.

$$q_2 = \frac{I_{se_{eff}}}{I_{kf_{eff}}} \left(e^{\frac{V_{be}}{\eta_f V_t}} \angle 1 \right) + \frac{I_{se_{eff}}}{I_{kr_{eff}}} \left(e^{\frac{V_{bc}}{\eta_r V_t}} \angle 1 \right)$$
(8.57)

The thermal voltage V_t is defined as:

$$V_t = kT/q, \tag{8.58}$$

where k is Boltzmann's constant, T is temperature, and q is the elementary electron charge.

If **update=1** and
$$\frac{V_{bc}}{V_{af}} + \frac{V_{be}}{V_{ar}} \ge 0$$
, then

$$q_1 = 1 + \frac{V_{bc}}{V_{af}} + \frac{V_{be}}{V_{ar}}.$$
(8.59)

If update=0 or
$$\frac{V_{bc}}{V_{af}} + \frac{V_{be}}{V_{ar}} < 0$$
, then

$$I_1 = \left(1 \angle \frac{V_{bc}}{V_{af}} \angle \frac{V_{be}}{V_{ar}}\right)^{\angle 1}.$$
(8.60)

Collector and Base Current Equations

If only the saturation current I_s is specified, T-Spice uses the following equations to calculate collector current (I_c) and base current (I_b) :

$$I_{s} = \frac{I_{s_{eff}}}{q_b} \left(e^{\frac{V_{BE}}{\eta_f V_t}} \right) \angle \frac{I_{s_{eff}}}{q_b} \left(e^{\frac{V_{BC}}{\eta_r V_t}} \right) \angle \frac{I_{s_{eff}}}{\beta_r} \left(e^{\frac{V_{bc}}{\eta_r V_t}} \angle 1 \right) \angle I_{sc_{eff}} \left(e^{\frac{V_{bc}}{\eta_c V_t}} \angle 1 \right)$$
(8.61)

$$_{,} = \frac{I_{s_{eff}}}{\beta_{f}} \left(e^{\frac{V_{be}}{\eta_{f}V_{t}}} \angle 1 \right) \angle \frac{I_{s_{eff}}}{\beta_{r}} \left(e^{\frac{V_{bc}}{\eta_{r}V_{t}}} \angle 1 \right) + I_{se_{eff}} \left(e^{\frac{V_{be}}{\eta_{e}V_{t}}} \angle 1 \right) + I_{sc_{eff}} \left(e^{\frac{V_{bc}}{\eta_{e}V_{t}}} \angle 1 \right) + (8.62)$$

If I_{be} and I_{bc} are both specified, T-Spice uses the following current equations:

$$=\frac{I_{be_{eff}}}{q_{b}}\left(e^{\frac{V_{be}}{\eta_{f}V_{t}}} \angle 1\right) \angle \frac{I_{bc_{eff}}}{q_{b}}\left(e^{\frac{V_{bc}}{\eta_{r}V_{t}}} \angle 1\right) \angle \frac{I_{bc_{eff}}}{\beta_{r}}\left(e^{\frac{V_{bc}}{\eta_{r}V_{t}}} \angle 1\right) \angle I_{sc_{eff}}\left(e^{\frac{V_{bc}}{\eta_{c}V_{t}}} \angle 1\right)$$
(8.63)

$$I_{b} = \frac{I_{be_{eff}}}{\beta_{f}} \left(e^{\frac{V_{be}}{\eta_{f}V_{t}}} \angle 1 \right) + \frac{I_{bc_{eff}}}{\beta_{r}} \left(e^{\frac{V_{bc}}{\eta_{r}V_{t}}} \angle 1 \right) + I_{se_{eff}} \left(e^{\frac{V_{be}}{\eta_{e}V_{t}}} \angle 1 \right) + I_{sc_{eff}} \left(e^{\frac{V_{bc}}{\eta_{c}V_{t}}} \angle 1 \right)$$
(8.64)

where q_b is the normalized base charge, β_r and β_f are the ideal maximum reverse and forward current gains, η_f and η_r are the forward and reverse current emission coefficients, and η_c and η_e are the base-collector and emitter-collector leakage emission coefficients.

The last two terms in the I_b expression represent recombination in the base-emitter and base-collector surfaces and depletion regions. The last term in the I_c expression represents recombination in the base-collector junction.

The emitter current, I_e , is simply the sum of base and collector currents:

$$I_e = I_b + I_c \,. \tag{8.65}$$

Excess Phase Equation

Excess phase represents the extra degrees of phase delay introduced by the BJT as a function of frequency, due to the distributed phenomena in the base region. T-Spice calculates excess phase in AC and transient analyses of the BJT. At any given frequency, the phase multiplier parameter **ptf** determines the relationship between excess phase and the base forward transit time, **tf**.

excess phase =
$$\left(2\pi \cdot P_{tf} \cdot \frac{\tau_f}{360}\right) \cdot 2\pi f$$
 (8.66)

In AC analysis, T-Spice applies excess phase as a linear phase delay in the transconductance generator, g_m . See the small-signal reference for "BJT Level 1 (Gummel-Poon)" on page 471 for a description of g_m .

In transient analysis, excess phase affects how T-Spice calculates collector current (I_c) . When excess phase is present (*i.e.*, **ptf** \neq **0**), T-Spice calculates the collector current as a cumulative function using time step dependent backward Euler integration. Otherwise, if **ptf** is not specified, collector current is simply a function of the current time step.

Substrate Current Equations

Substrate current is defined according to the geometric configuration of the BJT. The substrate current flows from substrate to collector for vertical BJTs (**subs=1**) and from substrate to base for lateral BJTs (**subs=-1**).

For vertical transistors (subs=1),

$$I_{sc} = I_{ss_{eff}} \left(e^{\frac{V_{sc}}{\eta_s V_t}} \angle 1 \right) \quad \text{when } V_{sc} > \angle 10 \cdot \eta_s \cdot V_t,$$

$$I_{sc} = \angle I_{ss_{eff}} \qquad \text{when } V_{sc} \le \angle 10 \cdot \eta_s \cdot V_t$$
(8.67)

where I_{sseff} is the effective reverse saturation current between bulk and collector.

For lateral transistors (**subs=**-**1**),

$$I_{bs} = I_{ss_{eff}} \left(e^{\frac{V_{bs}}{\eta_s V_t}} \angle 1 \right) \quad \text{when } V_{bs} > \angle 10 \cdot \eta_s \cdot V_t,$$

$$I_{bs} = \angle I_{ss_{eff}} \qquad \text{when } V_{bs} \le \angle 10 \cdot \eta_s \cdot V_t$$
(8.68)

where I_{sseff} is the effective reverse saturation current between bulk and base.

Variable Base Resistance Equations

The following equations describe the calculation of the base resistance, r_{bb} . Base resistance varies with current and depends on two parameters, the low-current maximum resistance (r_b) and the high-current minimum resistance (r_{bm}) . There are two ways that T-Spice can calculate r_{bb} , either with or without the parameter I_{rb} . I_{rb} is the base current that occurs when r_{bb} is equal to $0.5 \times (r_b - r_{bm})$, or the midpoint between minimum and maximum resistance values.

If Irb is not specified, T-Spice uses the following equation:

$$r_{bb} = r_{bm_{eff}} + \frac{r_{b_{eff}} \angle r_{bm_{eff}}}{q_b}$$

$$(8.69)$$

If I_{rb} is specified,

$$r_{bb} = r_{bm_{eff}} + 3(r_{b_{eff}} \angle r_{bm_{eff}}) \frac{\tan(z) \angle z}{z\tan(z)\tan(z)},$$
(8.70)

where

$$z = \frac{\angle 1 + \sqrt{1 + \frac{144 \cdot I_b}{\pi^2 \cdot I_{rb_{eff}}}}}{\frac{24}{\pi^2} \cdot \sqrt{\frac{I_b}{I_{rb_{eff}}}}}.$$
(8.71)

Capacitance Equations

Base-Emitter Capacitance

The total base-emitter capacitance consists of contributions from diffusion capacitance and depletion capacitance:

$$C_{be} = C_{be_{diff}} + C_{be_{dep}} \tag{8.72}$$

The diffusion capacitance is determined as follows:

$$C_{be_{diff}} = \frac{\partial}{\partial V_{beb}} \left(\tau_f \cdot \frac{i_{be}}{q_b} \right) \qquad \text{when} \quad i_{be} \le 0$$

$$C_{be_{diff}} = \frac{\partial}{\partial V_{be}} \left(\tau_f \cdot (1 + \arg \tau_f) \cdot \frac{i_{be}}{q_b} \right) \qquad \text{when} \quad i_{be} > 0$$
(8.73)

where

$$\arg \tau_f = X_{tf} \left(\frac{i_{be}}{i_{be} + I_{tf}} \right)^2 \cdot e^{\frac{V_{bc}}{1.44 \cdot V_{tf}}}$$
(8.74)

and

$$i_{be} = I_{s_{eff}} \left(e^{\frac{qV_{be}}{\eta_j kT}} \angle 1 \right).$$
(8.75)

T-Spice supports two different models for depletion capacitance. You can specify the depletion capacitance equations using the **dcap** model selector.

If dcap=1,

$$C_{be_{dep}} = C_{je_{eff}} \left(1 \angle \frac{V_{be}}{V_{je}} \right)^{\angle m_{je}} \qquad \text{when } V_{be} < FC \cdot V_{je}$$

$$C_{be_{dep}} = C_{je_{eff}} \cdot \frac{1 \angle FC(1 + m_{je}) + m_{je} \cdot \frac{V_{be}}{V_{je}}}{\left(1 \angle FC \right)^{1 + m_{je}}} \qquad \text{when } V_{be} \ge FC \cdot V_{je} \qquad (8.76)$$

If dcap=2 (default),

$$C_{be_{dep}} = C_{je_{eff}} \left(1 \angle \frac{V_{be}}{V_{je}} \right)^{\angle m_{je}} \qquad \text{when} \quad V_{be} < 0$$

$$C_{be_{dep}} = C_{je_{eff}} \left(1 + m_{je} \cdot \frac{V_{be}}{V_{je}} \right) \qquad \text{when} \quad V_{be} \ge 0$$

$$(8.77)$$

Base-Collector Capacitance

The total base-collector capacitance consists of contributions from diffusion capacitance and depletion capacitance:

$$C_{bc} = C_{bc_{diff}} + C_{bc_{dep}}$$
(8.78)

The base-collector diffusion capacitance is determined as follows:

$$C_{bc_{diff}} = \frac{\partial}{\partial V_{bc}} (\tau_r \cdot i_{bc})$$
(8.79)

where

$$i_{bc} = I_{s_{eff}} \left(e^{\frac{V_{bc}}{\eta_r V_t}} \angle 1 \right).$$
(8.80)

T-Spice offers two different models for base-collector depletion capacitance. Use **dcap** to select a set of equations.

For dcap=1:

$$C_{bc_{dep}} = X_{cjc} \cdot C_{jc_{eff}} \left(1 \angle \frac{V_{bc}}{V_{jc}} \right)^{\angle m_{jc}} \qquad \text{when } V_{bc} < FC \cdot V_{jc}$$

$$C_{bc_{dep}} = X_{cjc} \cdot C_{jc_{eff}} \cdot \frac{1 \angle FC(1 + m_{jc}) + m_{jc} \cdot \frac{V_{bc}}{V_{jc}}}{\left(1 \angle FC \right)^{1 + m_{jc}}} \qquad \text{when } V_{bc} \ge FC \cdot V_{jc} \qquad (8.81)$$

For dcap=2:

$$C_{bc_{dep}} = X_{cjc} \cdot C_{jc_{eff}} \left(1 \angle \frac{V_{bc}}{V_{jc}} \right)^{\angle m_{jc}} \qquad \text{when} \quad V_{bc} < 0$$

$$C_{bc_{dep}} = X_{cjc} \cdot C_{jc_{eff}} \left(1 + m_{jc} \cdot \frac{V_{bc}}{V_{jc}} \right) \qquad \text{when} \quad V_{bc} \ge 0$$

$$(8.82)$$

where *Xcjc* is the partition parameter specifying the ration of base-collector junction capacitance distribution between internal base-internal collector and external base-internal collector.

If *Xcjc*<1, the external base-internal collector capacitance has to be considered:

For dcap=1:

$$C_{bcx} = (1 \angle X_{cjc}) \cdot C_{jc_{eff}} \left(1 \angle \frac{V_{bcx}}{V_{jc}} \right)^{\angle m_{jc}} \qquad \text{when } V_{bcx} < FC \cdot V_{jc}$$

$$C_{bcx} = (1 \angle X_{cjc}) \cdot C_{jc_{eff}} \cdot \frac{1 \angle FC(1 + m_{jc}) + m_{jc} \cdot \frac{V_{bcx}}{V_{jc}}}{(1 \angle FC)^{1 + m_{jc}}} \qquad \text{when } V_{bcx} \ge FC \cdot V_{jc}$$

$$(8.83)$$

For dcap=2:

$$C_{bcx} = (1 \angle X_{cjc}) \cdot C_{jc_{eff}} \left(1 \angle \frac{V_{bcx}}{V_{jc}} \right)^{\angle m_{jc}} \quad \text{when } V_{bcx} < 0$$

$$C_{bcx} = (1 \angle X_{cjc}) \cdot C_{jc_{eff}} \left(1 + m_{jc} \cdot \frac{V_{bcx}}{V_{jc}} \right) \quad \text{when } V_{bcx} \ge 0$$

$$(8.84)$$

where *Vbcx* is the voltage between the external base node and the internal collector node.

Substrate Capacitance

The definition of substrate capacitance varies with BJT geometry. For vertical transistors (**subs=1**), substrate capacitance is defined for the base to substrate diode. For lateral transistors (**subs=-1**), it is defined as the capacitance of the substrate to collector diode.

For vertical BJTs,

$$C_{sc} = C_{js_{eff}} \left(1 \angle \frac{V_{sc}}{V_{js}} \right)^{\angle m_{js}} \qquad \text{when} \quad V_{sc} < 0$$

$$C_{sc} = C_{js_{eff}} \left(1 + m_{js} \cdot \frac{V_{sc}}{V_{js}} \right) \qquad \text{when} \quad V_{sc} \ge 0$$

$$(8.85)$$

For lateral BJTs,

$$C_{bs} = C_{js_{eff}} \left(1 \angle \frac{V_{bs}}{V_{js}} \right)^{\angle m_{js}} \qquad \text{when} \quad V_{bs} < 0$$

$$C_{bs} = C_{js_{eff}} \left(1 + m_{js} \cdot \frac{V_{bs}}{V_{js}} \right) \qquad \text{when} \quad V_{bs} \ge 0$$

$$(8.86)$$

Temperature Dependence

Below is a list of parameters that T-Spice modifies when one or more corresponding temperature coefficients are specified, regardless of **TLEV** values. When neither first nor second order coefficients

(8.87)

(8.88)

are specified for a given parameter, the **TLEV**-dependent equations in "Saturation Current and Beta" on page 352 take precedence.

Forward and reverse current gain

$$\begin{split} \beta_f(T) &= \beta_f \cdot (1 + TBF_1 \cdot \Delta T + TBF_2 \cdot \Delta T^2) \\ \beta_r(T) &= \beta_r \cdot (1 + TBR_1 \cdot \Delta T + TBR_2 \cdot \Delta T^2) \end{split}$$

Voltage and current parameters

 $V_{af}(T) = V_{af} \cdot (1 + TVAF_1 \cdot \Delta T + TVAF_2 \cdot \Delta T^2)$ $V_{ar}(T) = V_{ar} \cdot (1 + TVAR_1 \cdot \Delta T + TVAR_2 \cdot \Delta T^2)$ $I_{tf}(T) = I_{tf} \cdot (1 + TITF_1 \cdot \Delta T + TITF_2 \cdot \Delta T^2)$

Transit time parameters

(8.89)

(8.90)

$$\begin{aligned} \tau_f(T) &= \tau_f \cdot (1 + TTF_1 \cdot \Delta T + TTF_2 \cdot \Delta T^2) \\ \tau_r(T) &= \tau_r \cdot (1 + TTR_1 \cdot \Delta T + TTR_2 \cdot \Delta T^2) \end{aligned}$$

Emission coefficients

$$\begin{split} \eta_f(T) &= \eta_f \cdot (1 + TNF_1 \cdot \Delta T + TNF_2 \cdot \Delta T^2) \\ \eta_r(T) &= \eta_r \cdot (1 + TNR_1 \cdot \Delta T + TNR_2 \cdot \Delta T^2) \\ \eta_e(T) &= \eta_e \cdot (1 + TNE_1 \cdot \Delta T + TNE_2 \cdot \Delta T^2) \\ \eta_c(T) &= \eta_c \cdot (1 + TNC_1 \cdot \Delta T + TNC_2 \cdot \Delta T^2) \\ \eta_s(T) &= \eta_s \cdot (1 + TNS_1 \cdot \Delta T + TNS_2 \cdot \Delta T^2) \end{split}$$

Junction exponents

(8.91)

$$\begin{split} m_{je}(T) &= m_{je} \cdot (1 + TMJE_1 \cdot \Delta T + TMJE_2 \cdot \Delta T^2) \\ m_{jc}(T) &= m_{jc} \cdot (1 + TMJC_1 \cdot \Delta T + TMJC_2 \cdot \Delta T^2) \\ m_{js}(T) &= m_{js} \cdot (1 + TMJS_1 \cdot \Delta T + TMJS_2 \cdot \Delta T^2) \end{split}$$

Parasitic resistor parameters

(8.92)

$$r_{e}(T) = r_{e} \cdot (1 + TRE_{1} \cdot \Delta T + TRE_{2} \cdot \Delta T^{2})$$

$$r_{b}(T) = r_{b} \cdot (1 + TRB_{1} \cdot \Delta T + TRB_{2} \cdot \Delta T^{2})$$

$$r_{bm}(T) = r_{bm} \cdot (1 + TRM_{1} \cdot \Delta T + TRM_{2} \cdot \Delta T^{2})$$

$$r_{c}(T) = r_{c} \cdot (1 + TRC_{1} \cdot \Delta T + TRC_{2} \cdot \Delta T^{2})$$

Energy Gap

The calculation of energy gap is dependent on **TLEV**. For **TLEV=0**, **1**, or **3**, energy gap is always calculated as follows:

$$E_g(T_{nom}) = 1.16 \angle (7.02 \times 10^4) \frac{T_{nom}^2}{T_{nom} + 1108.0}.$$
 (8.93)

If **TLEV=2**, the energy gap is calculated as a function of model parameters $E_g(0)$, GAP1, and GAP2:

$$E_g(T_{nom}) = E_g(0) \angle GAP1 \cdot \frac{T_{nom}^2}{T_{nom} + GAP2}.$$
(8.94)

Saturation Current and Beta

The following equations show the temperature effects for transport saturation current, base-emitter reverse saturation current, and base-collector reverse saturation current.

	<i>TLEV</i> =0, 1, or 2	TLEV=3	
$I_s(T) =$	$I_s \cdot e^{facLN}$	$I_{s}^{(1+TIS_{1}\Delta T+TIS_{2}\Delta T^{2})}$	
$I_{be}(T) =$	$I_{be} \cdot e^{\frac{facLN}{\eta_f}}$	$I_{be}^{(1+TIS_1\Delta T+TIS_2\Delta T^2)}$	

	<i>TLEV=0, 1, or 2</i>	TLEV=3
$I_{bc}(T) =$	$I_{bc} \cdot e^{\frac{faclN}{\eta_r}}$	$I_{bc}^{(1+TIS_1\Delta T+TIS_2\Delta T^2)}$
$I_{kf}(T) =$	$I_{kf} \cdot (1 + TIKF_1 \Delta T + TIKF_2 \Delta T^2)$	$I_{kf}^{(1+TIKF_1\Delta T+TIKF_2\Delta T^2)}$
$I_{kr}(T) =$	$I_{kr} \cdot (1 + TIKR_1 \Delta T + TIKR_2 \Delta T^2)$	$I_{kr}^{(1 + TIKR_1\Delta T + TIKR_2\Delta T^2)}$
$I_{rb}(T) =$	$I_{rb} \cdot (1 + TIRB_1 \Delta T + TIRB_2 \Delta T^2)$	$I_{rb}^{(1 + TIRB_1 \Delta T + TIRB_2 \Delta T^2)}$

Temperature-effect equations for leakage saturation currents, bulk-to-collector (or base) saturation current, and beta parameters are shown below.

	TLEV=0 or 2	TLEV=1	TLEV=3
$\overline{I_{se}(T)} =$	$\frac{I_{se}}{\left(\frac{T}{T_{nom}}\right)^{X_{tb}}} \cdot e^{\frac{facLN}{\eta_e}}$	$\frac{I_{se}}{1+X_{tb}\Delta T} \cdot e^{\frac{facLN}{\eta_e}}$	$I_{se}^{(1+TISE_1\Delta T+TISE_2\Delta T^2)}$
$I_{sc}(T) =$ $I_{ss}(T) =$	$\frac{I_{sc}}{\left(\frac{T}{T_{nom}}\right)^{X_{tb}}} \cdot e^{\frac{facLN}{\eta_c}}$	$\frac{I_{sc}}{1+X_{lb}\Delta T} \cdot \frac{facLN}{e^{-\eta_c}}$	$I_{sc}^{(1 + TISC_1\Delta T + TISC_2\Delta T^2)}$
$\beta_{f}(T) =$	$\frac{I_{ss}}{\left(\frac{T}{T_{nom}}\right)^{X_{tb}}} \cdot e^{\frac{facLN}{\eta_s}}$	$\frac{I_{ss}}{1+X_{tb}\Delta T}\cdot \frac{facLN}{e^{-\eta_s}}$	$I_{ss}^{(1+TISS_1\Delta T+TISS_2\Delta T^2)}$
	$\beta_{f} \cdot \left(\frac{T}{T_{nom}}\right)^{X_{tb}}$ (if TBF_1, TBF_2	$\beta_f \cdot (1 + X_{tb} \Delta T)$ F_2 are not specified)	$\beta_f \cdot \left(\frac{T}{T_{nom}}\right)^{X_{ib}}$
$\beta_r(T) =$	$\beta_r \cdot \left(\frac{T}{T_{nom}}\right)^{X_{tb}}$	$\beta_r \cdot (1 + X_{tb} \Delta T)$	$\beta_r \cdot \left(\frac{T}{T_{nom}}\right)^{X_{tb}}$

(if TBR_1 , TBR_2 are not specified)

For TLEV=0 and 1

$$facln = \frac{E_g(0)}{V_t(T_{nom})} \angle \frac{E_g(0)}{V_t(T)} + XTI \cdot ln\left(\frac{T}{T_{nom}}\right)$$
(8.95)

For *TLEV*=2

$$facln = \frac{E_g(T_{nom})}{V_t(T_{nom})} \angle \frac{E_g(T)}{Vt(T)} + XTI \cdot ln\left(\frac{T}{T_{nom}}\right)$$
(8.96)

For *TLEV*=3

$$facln = \frac{V_{SB}}{V_t(T_{nom})} \angle \frac{V_{SB}}{Vt(T)} + XTI \cdot ln\left(\frac{T}{T_{nom}}\right)$$
(8.97)

Note:

If TBF_1 or TBF_2 is specified, then β_f will be calculated using the equation for **tlev=3**, regardless of the actual value of **tlev**. Similarly, the **tlev=3** equation for β_r will always take precedence if either TBR_1 or TBR_2 is specified.

Capacitance

Capacitance equations are selected by the parameter **TLEVC**.

The following capacitance equations are used when **TLEVC=0**:

$$C_{je}(T) = C_{je} \cdot \left\{ 1 + m_{je} \cdot \left(4.0 \times 10^{24} \cdot \Delta T \angle \frac{V_{je}(T)}{V_{je}} + 1 \right) \right\}$$

$$C_{jc}(T) = C_{jc} \cdot \left\{ 1 + m_{jc} \cdot \left(4.0 \times 10^{24} \cdot \Delta T \angle \frac{V_{jc}(T)}{V_{jc}} + 1 \right) \right\},$$

$$C_{js}(T) = C_{js} \cdot \left\{ 1 + m_{js} \cdot \left(4.0 \times 10^{24} \cdot \Delta T \angle \frac{V_{js}(T)}{V_{js}} + 1 \right) \right\}$$
(8.98)

where contact voltages are determined by

$$V_{je}(T) = V_{je} \cdot \left(\frac{T}{T_{nom}}\right) \angle V_{t}(T) \cdot \left\{ 3\ln\left(\frac{T}{T_{nom}}\right) + \frac{E_{g}(T_{nom})}{V_{t}(T_{nom})} \angle \frac{E_{g}(T)}{V_{t}(T)} \right\}$$

$$V_{jc}(T) = V_{jc} \cdot \left(\frac{T}{T_{nom}}\right) \angle V_{t}(T) \cdot \left\{ 3\ln\left(\frac{T}{T_{nom}}\right) + \frac{E_{g}(T_{nom})}{V_{t}(T_{nom})} \angle \frac{E_{g}(T)}{V_{t}(T)} \right\}$$

$$V_{js}(T) = V_{js} \cdot \left(\frac{T}{T_{nom}}\right) \angle V_{t}(T) \cdot \left\{ 3\ln\left(\frac{T}{T_{nom}}\right) + \frac{E_{g}(T_{nom})}{V_{t}(T_{nom})} \angle \frac{E_{g}(T)}{V_{t}(T)} \right\}$$
(8.99)

If TLEVC=1,

$$C_{je}(T) = C_{je} \cdot (1 + C_{te} \cdot \Delta T)$$

$$C_{jc}(T) = C_{jc} \cdot (1 + C_{tc} \cdot \Delta T)$$

$$C_{js}(T) = C_{js} \cdot (1 + C_{ts} \cdot \Delta T)$$
(8.100)

and contact voltages are determined by

$$V_{je}(T) = V_{je} \angle T_{vje} \cdot \Delta T$$

$$V_{jc}(T) = V_{jc} \angle T_{vjc} \cdot \Delta T$$

$$V_{js}(T) = V_{js} \angle T_{vjs} \cdot \Delta T$$
(8.101)

If TLEVC=2,

$$C_{je}(T) = C_{je} \cdot \left(\frac{V_{je}}{V_{je}(T)}\right)^{m_{je}}$$

$$C_{jc}(T) = C_{jc} \cdot \left(\frac{V_{jc}}{V_{jc}(T)}\right)^{m_{jc}}$$

$$C_{js}(T) = C_{js} \cdot \left(\frac{V_{js}}{V_{js}(T)}\right)^{m_{js}}$$
(8.102)

where

$$V_{je}(T) = V_{je} \angle T_{vje} \cdot \Delta T$$

$$V_{jc}(T) = V_{jc} \angle T_{vjc} \cdot \Delta T$$

$$V_{js}(T) = V_{js} \angle T_{vjs} \cdot \Delta T$$
(8.103)

Note:

Use *mje*, *mjc*, and *mjs* instead of mje(T), mjc(T), and mjs(T) in the above equations.

When **TLEVC=3**:

$$C_{je}(T) = C_{je} \cdot \left(1 \angle 0.5 \cdot dvjedt \cdot \frac{\Delta T}{V_{je}} \right)$$

$$C_{jc}(T) = C_{jc} \cdot \left(1 \angle 0.5 \cdot dvjcdt \cdot \frac{\Delta T}{V_{jc}} \right)$$

$$C_{js}(T) = C_{js} \cdot \left(1 \angle 0.5 \cdot dvjsdt \cdot \frac{\Delta T}{V_{js}} \right)$$
(8.104)

and

$$V_{je}(T) = V_{je} + dvjedt \cdot \Delta T$$

$$V_{jc}(T) = V_{jc} + dvjcdt \cdot \Delta T$$

$$V_{js}(T) = V_{js} + dvjsdt \cdot \Delta T$$
(8.105)

where

$$\begin{aligned} v_{j}edt &= \angle \frac{E_{g}(T_{nom}) + 3 \cdot V_{t}(T_{nom}) + [E_{g}(0) \angle E_{g}(T_{nom})] \cdot \left(2 \angle \frac{T_{nom}}{T_{nom} + GAP2}\right) \angle V_{j}}{T_{nom}} \\ v_{j}edt &= \angle \frac{E_{g}(T_{nom}) + 3 \cdot V_{t}(T_{nom}) + [E_{g}(0) \angle E_{g}(T_{nom})] \cdot \left(2 \angle \frac{T_{nom}}{T_{nom} + GAP2}\right) \angle V_{j}}{T_{nom}} \\ v_{j}sdt &= \angle \frac{E_{g}(T_{nom}) + 3 \cdot V_{t}(T_{nom}) + [E_{g}(0) \angle E_{g}(T_{nom})] \cdot \left(2 \angle \frac{T_{nom}}{T_{nom} + GAP2}\right) \angle V_{j}}{T_{nom}} \end{aligned}$$
(8.106)

BJT Level 6 (Mextram)

The level 6 bipolar junction transistor model is the Philips Mextram model.

Parameters

The Mextram model uses the following syntax.

.model name npn | pnp level=[6|503|504] | model=modelname [parameters]

The Mextram model is fully described in the document Bipolar Transistor Level 504.

For additional detailed information about the Mextram model, please refer to the Philips Compact Model Webpage:

<u>http://www.semiconductors.philips.com/Philips_Models/bipolar/mextram</u>

T-Spice includes support for Mextram versions 503 and 504. The version 504 model provides optional support for modeling the extrinsic substrate and the self-heating effects. Selection of an appropriate model is accomplished by using the **model=***modelname* parameter. If no specific model is specified via the **model** parameter, the **bjt503** model will be selected when level=503 or version=503, otherwise the **bjt504** model will be used.

The available modelname values for the Mextram model selection are:

Modelname	Description
bjt503	Mextram version 503 with substrate
bjtd503	Mextram version 503 without substrate
bjt504 (default)	Mextram version 504 with substrate
bjtd504	Mextram version 504 without substrate
bjt504t	Mextram version 504 with substrate, self-heating
bjtd504t	Mextram version 504 without substrate, self-heating

BJT Level 9 (VBIC)

In addition to the standard Gummel-Poon BJT model, T-Spice supports the Vertical Bipolar Inter-Company model (VBIC) as the level 9 BJT.

Note: If you specify VBIC Level 4 in T-Spice it will use the VBIC 1999 version 1.2 model.

Parameters

The VBIC model uses the following syntax.

```
.model name npn | pnp level=9 [parameters]
```

The T-Spice VBIC model is based upon release 1.2 of the VBIC code, and includes certain enhancements for improved convergence and stability.

The following tables describe all of the VBIC BJT parameter.

Parameter (alias)	VBIC Model Parameters Description	Default	Units
afn	base-emitter flicker noise exponent	1.0	
ajc	base-collector capacitance smoothing factor	5	
aje	base-emitter capacitance smoothing factor	5	
ajs	substrate-collector capacitance smoothing factor	5	
art	base-collector reach-through limiting voltage (0 means infinity)	0.1	V
avc1	base-collector weak avalanche parameter 1	0.0	1/V
avc2	base-collector weak avalanche parameter 2	0.0	1/V
bfn	base-emitter flicker noise 1/f dependence	1.0	
cbco (cbc0)	extrinsic base-collector overlap capacitance	0.0	С
cbeo (cbe0)	extrinsic base-emitter overlap capacitance	0.0	С
ccso	Fixed collector-substrate capacitance	0	С
cjc	base-collector intrinsic zero bias capacitance	0.0	С
cjcp	substrate-collector zero bias capacitance	0.0	С
cje	base-emitter zero bias capacitance	0.0	С
cjep	base-collector extrinsic zero bias capacitance	0.0	С
cth	thermal capacitance	0.0	А
dear	Activation energy shift for ISRR (HBTs)	0	V

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Parameter (alias)	VBIC Model Parameters <i>Description</i>	Default	Units
dtemp (dtmp)	local temperature rise	0	deg C
ea	activation energy for IS	1.12	eV
eaic	activation energy for IBCI/IBEIP	1.12	eV
eaie	activation energy for IBEI	1.12	eV
eais	activation energy for IBCIP	1.12	eV
eanc	activation energy for IBCN/IBENP	1.12	eV
eane	activation energy for IBEN	1.12	eV
eans	activation energy for IBCNP	1.12	eV
eap	Activation energy for ISP	1.12	V
fc	forward bias depletion capacitance limit	0.9	
gamm (gamma)	epi doping parameter	0.0	
hrcf	high current RC factor	0.0	
ibbe	Base-Emitter breakdown current	1e-6	
ibci	ideal base-collector saturation current	1.0E-16	А
ibcip	ideal parasitic base-collector saturation current	0.0	А
ibcn	non-ideal base-collector saturation current	0.0	А
ibcnp	non-ideal parasitic base-collector saturation current	0.0	А
ibei	ideal base-emitter saturation current	1.0E-18	А
ibeip	ideal parasitic base-emitter saturation current	0.0	А
iben	non-ideal base-emitter saturation current	0.0	
ibenp	non-ideal parasitic base-emitter saturation current	0.0	А
ikf	forward knee current (zero means infinity)	0.0	А
ikp	parasitic knee current (zero means infinity)	0.0	А
ikr	reverse knee current (zero means infinity)	0.0	А
is	transport saturation current	1.0E-16	Amps
isp	parasitic transport saturation current	0.0	А
isrr	Reverse saturation current factor (HBTs)	1.0	
itf	coefficient of TF dependence in Ic	0.0	
kfn	base-emitter flicker noise constant	0.0	
mc	base-collector grading coefficient	0.33	
me	base-emitter grading coefficient	0.33	

Parameter (alias)	VBIC Model Parameters Description	Default	Units
ms	substrate-collector grading coefficient	0.33	
nbbe	Base-Emitter breakdown emission coefficient	1.0	
nci	ideal base-collector emission coefficient	1.0	
псір	ideal parasitic base-collector emission coefficient	1.0	А
ncn	non-ideal base-collector emission coefficient	2.0	
пспр	non-ideal parasitic base-collector emission coefficient	2.0	
nei	ideal base-emitter emission coefficient	1.0	
nen	non-ideal base-emitter emission coefficient	2.0	
nf	forward emission coefficient	1.0	
nfp	parasitic fwd emission coefficient	1.0	
nkf	High current roll-off coefficient	0.5	
nr	reverse emission coefficient	1.0	
рс	base-collector built-in potential	0.75	V
ре	base-emitter built-in potential	0.75	V
ps	substrate-collector built-in potential	0.75	V
qbm	Selector for SGP qb formulation	0	
qco (qc0)	epi charge parameter	0.0	С
qtf	variation of TF with base-width modulation	0.0	S
rbi	intrinsic base resistance	0.0	Ω
rbp	parasitic base resistance	0.0	Ω
rbx	extrinsic base resistance	0.0	Ω
rci	intrinsic collector resistance	0.0	Ω
rcx	extrinsic collector resistance	0.0	Ω
re	emitter resistance	0.0	Ω
rs	substrate resistance	0.0	Ω
rth	thermal resistance	0.0	Ω
tavc	temperature coefficient of AVC2	0.0	
td	forward excess-phase delay time	0.0	S
tf	forward transit time	0.0	S
tnbbe	Temperature coefficient of NBBE	0	
tnf	temperature coefficient of NF	0.0	

Parameter (alias)	VBIC Model Parameters Description	Default	Units
tnom (tref)	nominal measurement temperature of parameters	global tnom (25.0)	deg. C
tr	reverse transit time	0.0	S
tvbbe1	First temperature coefficient of VBBE	0	
tvbbe2	Second temperature coefficient of VBBE	0	
vbbe	Base-Emitter breakdown voltage (zero means infinity)	0	V
vef	forward Early voltage (zero means infinity)	0.0	V
ver	reverse Early voltage (zero means infinity)	0.0	V
vers (version)	Version	1.2	
vo (v0)	epi drift saturation voltage	0.0	V
vrev	Revision	0	
vrt	base-collector reach-through limiting voltage (0 means infinity)	0	V
vtf	coefficient of TF dependence on Vbc	0.0	
wbe	portion of IBEI from Vbei (1-WBE from Vbex)	1.0	
wsp	portion of ICCP from Vbep (1-WSP from Vbci)	1.0	
xii	temperature exponent of IBEI/IBCI/IBEIP/ IBCIP	3.0	
xikf	Temperature exponent of IKF	0	
xin	temperature exponent of IBEN/IBCN/IBENP/ IBCNP	3.0	
xis	temperature exponent of IS	3.0	
xisr	Temperature exponent of ISRR (HBTs)	0	
xrb (xrbi)	temperature exponent of base resistance	0.0	
xrbp	Temperature exponent of extrinsic resistance RBP	0	
xrbx	Temperature exponent of extrinsic resistance RBX	0	
xrc (xrci)	temperature exponent of collector resistance	0.0	
xrcx	Temperature exponent of extrinsic resistance RCX	0	
xre	temperature exponent of emitter resistance	0.0	
xrs	temperature exponent of substrate resistance	0.0	
xtf	coefficient of TF bias dependence	0.0	
xvo (xv0)	temperature exponent of VO	0.0	

The following VBIC model parameters are T-Spice extensions to the standard model.

level	model selector	4	V
ismin	Minimum permissible value of IS	1e-19	А
ispmin	Minimum permissible value of ISP	1e-19	А
mcmin	Minimum permissible value of MC	.01	
memin	Minimum permissible value of ME	.01	
msmin	Minimum permissible value of MS	.01	
rbpmin	Minimum permissible value of RBP	.001	Ω

Equations

For a thorough description of the VBIC model and equations, please refer to the following website:

http://www.designers-guide.org/VBIC/index.html

Note:

Please keep in mind that the default operating temperature and model reference temperature in T-Spice is 25 degrees Celsius, whereas many simulaters use 27 degrees. When performing simulation comparisons against these simulators, you may want to set the default reference temperature option, "tnom" (page 274), and the operating temperature, ".temp" (page 146), to 27.

BJT Level 10 (Modella)

The level 10 bipolar junction transistor model is the Philips Modella model, a lateral PNP bipolar model.

Parameters

The Modella model uses the following syntax.

.model name pnp level=[10|500] | model=modelname [parameters]

The complete user manual for the Modella model is located at **Bipolar PNP Transistor Level 500**.

For additional detailed information about the Modella model, please refer to the Philips Compact Model Webpage:

http://www.semiconductors.philips.com/Philips Models/bipolar/modella

T-Spice includes support for the Modella model version 500 with and without self-heating effects. When the self-heating model is used, the device statement should include an additional temperature node following the substrate node name.

The available *modelname* values for the Modella model selection are:

Modelname	Description
bjt500 (default)	Modella version 500 with substrate
bjt500t	Mextram version 500 with substrate, self-heating

Capacitor

Indicates the capacitance of a planar diffused region from geometric and process information.

Parameters

Parameter	Symbol	Description	Value	Unit
Сар	С0	Capacitance	0	F
Capsw	Csw	Sidewall capacitance	0	F/m
Cox	Cox	Bottomwall capacitance	0	F/m ²
Del	δ	Difference between drawn and actual widths or lengths	0	m
Di	к	Dielectric constant or relative permittivity	0	-
L	L	Length of the capacitor	0	m
Shrink	Sshrink	Shrink factor	1	-
Tc1	Tcl	The first temperature coefficient for capacitance	0	1/deg C
Tc2	Tc2	The second temperature coefficient for capacitance	0	1/(deg C) ²
Thick	τ	Insulator thickness	0	m
Tnom Tref	tref	Reference temperature	global tnom (25.0)	Deg C
W	W	Width of capacitor	0	m

Equations

The statement ".model" (page 99) must be associated with an element statement; see the third syntax example in "Capacitor (c)" (page 155).

$$C = MS_{scale} [1 + T_{c1}\Delta T + T_{c2}(\Delta T)^{2}]C_{0}$$
(8.107)

Note:

When the calculated capacitance is greater than 0.1 F, T-Spice issues a warning message.

The user supplies the multiplicity factor M and the scale factor *Scale* in the element statement. See "**Capacitor**" (page 363). The user can supply *Tc1*, *Tc2*, and *Dtemp* in the element statement, model statement, or both. In the last case, element values override model values. *C0* will be determined in one of three ways, which are listed in order of selection:

i) C0 in the element statement.

ii) C0x in the model statement; C0 will be computed using equation 0.111. *iii)* C0 in the model statement. When C0x is supplied in the model description, T-Spice would then compute C0 as follows:

$$C_0 = L_{eff} W_{eff} C_{ox} + 2(L_{eff} + W_{eff}) C_{sw}$$
(8.108)

where

$$L_{eff} = L_{scaled} \angle 2\Delta_{eff} \tag{8.109}$$

$$W_{eff} = W_{scaled} \angle 2\Delta_{eff} \tag{8.110}$$

If *L* is supplied in the element statement:
$$L_{scaled} = LS_{shrink}S'_{scale}$$
 (8.111)

- If *L* is supplied in the model statement: $L_{scaled} = LS_{shrink}S'_{scalm}$ (8.112)
- If W is supplied in the element statement: $W_{scaled} = WS_{shrink}S'_{scale}$ (8.113)

If W is supplied in the model statement:
$$W_{scaled} = wS_{shrink}S'_{scale}$$
 (8.114)

The user supplies S'_{scale} and S'_{scalm} using **.options scale** or **.options scalm**. For further information, see "**.options**" (page 109).

$$\Delta = \delta S'_{scalm} \tag{8.115}$$

If τ is supplied, T-Spice would compute *Cox* from

If
$$\kappa \neq 0$$
: $C_{ox} = \kappa(\varepsilon_0/\tau)$ (8.116)

If
$$\kappa = 0$$
: $C_{ox} = \varepsilon_{0x} / \tau$ (8.117)

The quantities ε_0 , $\varepsilon_0 x$ are 8.8542149e-12 and 3.453148e-11, respectively. After this, T-Spice would compute *C0* using the formulas above. If τ is not supplied, T-Spice sets *C0* = 0.

Examples

V1 a d AC 150) ()			
R1 a b 10				
L1 b c 50				
.model	сархх	С		
+				cox=0.25
+				capsw=1/3.0
+				del=0.1
+				shrink=0.5
C1	С	d	capxx	
+				scale= 0.02/2.5
				$1 = 2 \times 1.2 / 27.7$
				w = 2 * 2.2 / 27.7
.options scal	e = 27.7			
.AC LIN 1 0.5	5/3.14159 0.5/	3.14159)	
.PRINT AC IM((V1) IP(V1)			

Coupled Transmission Line (Level 1)

The coupled transmission line model employs variable electrical parameters.

Parameters

.model name cpl level=1 [[r]={matrix}] [l]={matrix} [c]={matrix}
[[g]={matrix}]

Matrices are entered as follows.

```
[r]={r11, r12, r13, ...
+ {r21, r22, r23, ...
+ {r31, r32, r33, ...
...}
```

Parameter	Description	Default	Units
[r]	Optional per unit length resistance matrix. Must be positive definite.	[Zero matrix]	Ω/m
[1]	Per unit length inductance matrix. Must be positive definite. Off-diagonal elements must be non-negative. n and p metric prefixes may be used.	[Zero matrix]	H ∕m
[c]	Per unit length capacitance matrix. Must be positive definite. Off-diagonal elements must be zero or negative. n and p metric prefixes may be used.	[Zero matrix]	F/m
[9]	Optional per unit length conductance matrix. Must be positive definite.	[Zero matrix]	S/m

Example

An example using lossless symmetrical coupled lines:

.model exCPL CPL level=1
+ [1]={494.6n, 63,3n,
+ 63.3n, 494.6n }
+ [c]={62.8p, -4.94p,
+ -4.94p, 62.8p }

Diode

There are five types of diode models in T-Spice.

- Level 1 describes the Non-Geometric Junction diode model. It is used to model discrete diode devices such as standard and Zener diodes.
- Level 2 describes the Fowler-Nordheim model that is generally used to characterize the tunneling current flow through thin insulator in nonvolatile memory devices.
- Level 3 describes the Geometric Junction diode model. It is used to model IC-based standard silicone-diffused diodes, Schottky barrier diodes and Zener diodes.
- Level 4 describes the Philips Juncap version 2 diode. Note level 200 and level 9 are also the Juncap model, with different level numbers provided for compatibility with various simulators.
- Level 500 describes the Philips Advanced diode.

Parameters

The Philips Juncap2 model is fully described in the document Philips Juncap.

The Philips Advanced Diode is fully described in the document Philips Diode 500.

The following model parameter and equation descriptions pertain to Diode levels 1-3.

.model name d [parameters]

Model Selectors

Parameter	Symbol	Description	Default	Unit
level	level	Diode model selector	1	_
dcap	dcap	Capacitance model selector	2	_
tlev	tlev	Temperature equation selector (<i>tlev</i> =3 for Schottky barrier diode)	0	_
tlevc	tlevc	Temperature equation selector for junction capacitance and contact potential (<i>tlevc</i> =1 and 2 for Schottky barrier diode)	0	_

Geometric and Scaling Parameters

Parameter	Symbol	Description	Default	Unit
area	area	Junction area (unitless in level=1)	1.0	m ²
PJ	PJ	Junction periphery (unitless in level=1)	0.0	m
М	М	Multiplier factor to simulate multiple diode in parallel	1	
SCALE	SCALE	Scaling factor for geometric parameters	1	
SCALM	SCALM	Scaling factor for model parameters	1	

Parameter	Symbol	Description	Default	Unit
SHRINK	SHRIN K	Shrink factor	1	
L	L	Length of diode	0.0	m
W	W	Width of diode	0.0	m
XW	XW	Masking and etching effects	0.0	m
LM	LM	Length of metal capacitor	0.0	m
WM	WM	Width of metal capacitor	0.0	m
ХМ	XM	Masking and etching effects for LM and WM	0.0	m
LP	LP	Length of polysilicon capacitor	0.0	m
WP	WP	Width of polysilicon capacitor	0.0	m
ХР	XP	Masking and etching effects for LP and WP	0.0	m

DC Parameters

Parameter	Symbol	Description	Default	Unit
IS JS	IS	Saturation current (per unit area). Use calculated <i>IS</i> value for Schottky barrier diode if <i>IS</i> is not specified; see "Application Notes— Schottky Barrier Diodes" on page 378.	1.0×10 ⁻¹⁴	A
JSW	JSW	Side wall saturation current (per unit length)	0.0	А
RS	RS	Ohmic resistance	0.0	Ω
Ν	Ν	Emission coefficient (<i>N</i> ≡1 for Schottky barrier diode)	1.0	
BV VB VA R VRB	BV	Breakdown voltage	∞	V
IBV IB	IBV	Current at breakdown voltage	1.0×10 ⁻³	А
IK IKF IBF	IKF	Forward knee current (per unit area)	0.0	А
IKB IKR IBR	IKB	Reverse knee current (per unit area)	0.0	А
EXPLI	EXPLI	Current explosion model parameter. The PN junction characteristics above the explosion current area are linear, with the slope at the explosion point.	1.0×10 ⁻¹⁵	A

Capacitance Parameters

Parameter	Symbol	Description	Default	Unit
CJ0 CJ CJA	Cj0	Zero-bias bottom wall junction capacitance (per unit area)	0.0	F

Parameter	Symbol	Description	Default	Unit
CJP CJSW	Сјр0	Zero-bias side wall/periphery junction capacitance (per unit length)	0.0	F
FC	FC	Coefficient for forward-bias depletion area capacitance	0.5	
FCS	FCS	Coefficient for forward-bias depletion periphery capacitance	0.5	
MJ M EXA	mj	Area junction grading coefficient $(mj=0.5 \text{ for Schottky barrier diode})$	0.5	
MJSW EXP	mjsw	Periphery junction grading coefficient	0.33	
pb phi vj Pha	PB	Area junction contact potential. Use Schottky barrier height as default <i>PB</i> value for Schottky barrier diode if PB is not specified.	0.8	V
PHP VJSW	PHP	Periphery junction contact potential	PB	V
π	τ	Transit time (minority carrier storage time) (τ =0 for Schottky barrier diode)	0.0	S
XOI	XOP	Thickness of oxide contacted on polysilicon	1.0×10 ⁴	Å
хом	ХОМ	Thickness of oxide contacted on metal	1.0×10 ⁴	Å

Noise Parameters

Parameter	Symbol	Description	Default	Unit
AF	AF	Flick noise exponent	1.0	
KF	KF	Flick noise exponent	0.0	

Temperature Parameters

Parameter	Symbol	Description	Default	Unit
TNOM TREF	Tnom	Reference temperature	global tnom (25.0)	deg
EG	Eg(0)	Energy gap at 0°K for tlev = 2 : for tlev = 0, 1, 3 :	1.16 1.11	eV
VSB	VSB	Schottky barrier height (tlev=3 only)	0.8	V
GAP1	GAP1	Coefficient in energy gap temperature equation (Si: 4.73×10^{-4} , Ge: 4.77×10^{-4} , and GaAs: 5.41×10^{-4})	7.02×10 ⁻⁴	eV/deg
GAP2	GAP2	Coefficient in energy gap temperature equation (Si: 636, Ge: 235, and GaAs: 204)	1108	deg
тсу	TCV	Breakdown voltage temperature coefficient	0.0	1/deg

Parameter	Symbol	Description	Default	Unit
TTT1	τ <i>t1</i>	First-order temperature coefficient for $\boldsymbol{\tau}$	0.0	1/deg
TTT2	τ <i>t2</i>	Second-order temperature coefficient for $\boldsymbol{\tau}$	0.0	$1/deg^2$
ТРВ	TPB	Temperature coefficient for PB	0.0	1/deg
ТРНР	TPHP	Temperature coefficient for PHP	0.0	1/deg
СТА СТС	CTA	Temperature coefficient for CJ	0.0	1/deg
СТР	CTP	Temperature coefficient for CJP	0.0	1/deg
TM1	TM1	First order temperature coefficient for mj ($TM \equiv 1$ for Schottky barrier diode)	0.0	1/deg
TM2	TM2	Second order temperature coefficient for $mjsw$ ($TM=2$ for Schottky barrier diode)	0.0	1/deg ²
TRS	TRS	Resistance temperature coefficient	0.0	1/deg
ХТІ	XTI	Saturation current temperature exponent (for Schottky barrier diode)	3.0	

Fowler-Nordheim Model Parameters (level=2)

Parameter	Symbol	Description	Default	Unit
EF	EF	Forward critical electric field	1.0×10 ⁸	V/cm
ER	ER	Reverse critical electric field	EF	V/cm
JF	JF	Forward Fowler-Nordheim current coefficient	1.0×10 ⁻¹⁰	A/V^2
JR	JR	Reverse Fowler-Nordheim current coefficient	JF	A/V^2
тох	τοχ	Thickness of oxide layer	100.0	Å
L	L	Length of diode	0.0	m
w	W	Width of diode	0.0	m
XW	XW	Masking and etching effects	0.0	m

Current Equations

Level 1 and Level 3

In levels 1 and 3, the diodes are modeled in forward bias, reverse bias, and breakdown regions.

In forward and reverse bias regions: Vd > -BVeff,

$$I_d = I_{seff} \cdot \left(\exp\left(\frac{V_d}{N \cdot V_t} \angle 1\right) \right)$$
(8.118)

Diode

where where Vt is thermal voltage, Vt = kTnom/q, Vd is the voltage across the diode, Vd = Vnode1-*Vnode2*, *BVeff* is the adjusted breakdown voltage, and N is emission coefficient (N=1 for Schottky barrier diode).

BVeff can be determined by

$$BV_{eff} = BV \angle (N \cdot V_t \cdot In) \left(\frac{IBV_{eff}}{I_{break}}\right)$$
(8.119)

when IBVeff>Ibreak.

and

$$IBVeff = BV$$
, when $IBVeff \le Ibreak$. (8.120)

where

$$I_{break} = \angle I_{seff} \cdot \left(\exp\left(\frac{BV}{N \cdot V_t} \angle 1\right) \right)$$
(8.121)

In breakdown region: *BV* <- *BVeff*

$$I_d = I_{seff} \cdot \left(\exp\left(\frac{V_d + BV_{eff}}{N \cdot V_t}\right) \right)$$
(8.122)

In all the above equations we assume that the diode has a finite breakdown voltage, that is $BV \neq \infty$. When BV is not given, or the diode has an infinite breakdown voltage,

$$I_d = I_{seff} \cdot \left(\exp\left(\frac{V_d}{N \cdot V_t} \angle 1\right) \right)$$
(8.123)

Vd>0 is the forward-bias region and Vd<0 is the reverse-bias region. There is no breakdown region in this case.

If the high-level injection effects are considered, the current equations are

in forward-bias region (Vd>0):

$$I^{*}{}_{d} = \frac{I_{d}}{1 + \left(\frac{I_{d}}{I_{KF}}\right)^{\frac{1}{2}}}$$
(8.124)

when $IKF \neq 0$.

$$I*D=ID$$
 (8.125)

when IKF=0.

and in reverse-bias region (
$$Vd < 0$$
)

$$I^{*}{}_{d} = \frac{I_{d}}{1 + \left(\frac{I_{d}}{I_{KR}}\right)^{\frac{1}{2}}}$$
(8.126)

when *IKR* \neq 0.

$$I^*D = ID$$
 (8.127)

when IKR=0.

Diode Capacitance Equations

The diode capacitance CD consists of the contributions from diffusion capacitance Cd, junction capacitance (depletion capacitance) Cj, metal (contact electrode) capacitance Cm, and polysilicon (contact electrode) capacitance Cp.

Diffusion Capacitance

$$C_d = \pi \cdot \frac{\partial I_d}{\partial V_d} \tag{8.128}$$

Note:

For Schottky barrier diodes, Cd=0 ($\pi=0$) because the Schottky barrier diode is a majority carrier device and minority carrier effect can be ignored.

Junction Capacitance (Depletion Capacitance)

The junction capacitance has two components: the junction bottom area capacitance *Cja* and the junction periphery capacitance *Cjp*.

Cj = Cja + Cjp.

There are two sets of junction capacitance equations selected by the parameter dcap.

For dcap=1, the junction bottom area capacitance is given by

$$C_{ja} = C_{j0eff} \cdot \left(1 \angle \frac{V_d}{PB}\right)^{\angle m_j}$$
(8.129)

when $Vd > FC \times PB$

$$C_{ja} = C_{j0eff} \cdot \frac{1 \angle FC \times (1+m_j) + m_j \times \frac{V_d}{PB}}{(1 \angle FC)^{1+m_j}}$$
(8.130)

when $Vd > FC \times PB$

The junction periphery capacitance is given by

$$C_{jp} = C_{jp0eff} \cdot \left(1 \angle \frac{V_d}{PHP}\right)^{\angle m_{jsw}}$$
(8.131)

when $Vd > FCS \times PHP$

$$C_{ja} = C_{j0eff} \cdot \frac{1 \angle FCS \times (1 + m_{jsw}) + m_{jsw} \times \frac{V_d}{PB}}{(1 \angle FCS)^{1 + m_{jsw}}}$$
(8.132)

when $Vd > FCS \times PHP$

The total junction capacitance is

$$C_j = C_{ja} + C_{jp} \tag{8.133}$$

For dcap=2 (default), the total junction capacitance is given by

$$C_j = C_{j0eff} \cdot \left(1 \angle \frac{V_d}{PB}\right)^{\angle m_j} + C_{jp0eff} \cdot \left(1 \angle \frac{V_d}{PHP}\right)^{\angle m_{jss}}$$
(8.134)

when Vd < 0.

$$C_{j} = C_{j0eff} \cdot \left(1 + m_{j} \cdot \frac{V_{d}}{PB}\right) + C_{jp0eff} \cdot \left(1 + m_{sjw} \cdot \frac{V_{d}}{PHP}\right)$$
(8.135)

when Vd > 0.

Metal (Contact Electrode) Capacitance

For level=3 only

$$C_m = \frac{\varepsilon_{ox}}{X_{OM}} \cdot (W_{Meff} + X_{Meff}) \cdot (L_{Meff} + X_{Meff})$$
(8.136)

Polysilicon (Contact Electrode) Capacitance

For level=3 only

$$C_p = \frac{\varepsilon_{ox}}{X_{OP}} \cdot (W_{Peff} + X_{Peff}) \cdot (L_{Peff} + X_{Peff})$$
(8.137)

Geometric Scaling Effect

Level 1

Scaling for **level=1** involves the use of the junction area (area), junction periphery (*PJ*), and the dimensionless multiplier factor (M) to simulate multiple diodes.

Geometric parameters include

$$area_{eff} = area \cdot M$$
 (8.138)

$$PJ_{eff} = PJ \cdot M \tag{8.139}$$

Element and model parameters include:

$$I_{KEeff} = I_{KF} \cdot area_{eff} \tag{8.140}$$

$$I_{KREeff} = I_{KR} \cdot area_{eff} \tag{8.141}$$

$$IBV_{eff} = IBV \cdot area_{eff} \tag{8.142}$$

$$I_{Seff} = I_S \cdot area_{eff} + JSW \cdot PJ_{eff}$$
(8.143)

$$JSW_{eff} = JSW \cdot PJ_{eff} \tag{8.144}$$

$$EXPLI = EXPLI \cdot area_{eff} \tag{8.145}$$

$$C_{j0eff} = C_{j0} \cdot area_{eff} \tag{8.146}$$

$$C_{jp0eff} = C_{jp0} \cdot PJ_{eff} \tag{8.147}$$

$$R_{Seff} = R_s / (area_{eff})$$
(8.148)

Level 3

Level 3 model scaling is affected by the parameters SCALE, SCALM, SHRINK, and M.

When both L and W are specified, geometric parameters include

$$area_{eff} = W_{eff} \cdot L_{eff} \cdot M \tag{8.149}$$

$$PJ_{eff} = (2 \cdot W_{eff} + 2 \cdot L_{eff}) \cdot M$$
(8.150)

where

$$Weff = W \times SCALE \times SHRINK + XWeff$$

 $Leff = L \times SCALE \times SHRINK + XWeff$

and

 $XWeff = XW \times SCALM$

otherwise

 $areaeff = area \times M \times SCALE2 \times SHRINK2$

 $PJeff = PJ \times M \times SCALE \times SHRINK$

Geometric parameters for polysilicon and metal capacitance include

$$LMeff = LM SCALE \times SHRINK$$

WMeff = *WM SCALE* × *SHRINK*

 $XMeff = XM \times SCALM$

 $LPeff = LP \ SCALE \times SHRINK$

WPeff = *WP SCALE* × *SHRINK*

 $XPeff = XP \times SCALM$

Element and model parameters include

$$I_{KEeff} = I_{KF} \cdot area_{eff} \tag{8.151}$$

$$I_{KREeff} = I_{KR} \cdot area_{eff} \tag{8.152}$$

$$IBV_{eff} = (IBV \cdot area_{eff}) / (SCALM^2)$$
(8.153)

$$I_{Seff} = I_S \cdot area_{eff} / SCALM^2 + JSW \cdot PJ_{eff} / SCALM$$
(8.154)

$$JSW_{eff} = (JSW \cdot PJ_{eff}) / (SCALM)$$
(8.155)

$$EXPLI = EXPLI \cdot area_{eff} \tag{8.156}$$

$$R_{Seff} = R_s / (area_{eff} \cdot SCALM^2)$$
(8.157)

$$C_{j0eff} = C_{j0} \cdot area_{eff} / SCALM^2$$
(8.158)

$$C_{jp0eff} = C_{jp0} \cdot PJ_{eff} / (SCALM)$$
(8.159)

Temperature Effects

Energy Gap

The calculation of energy gap is dependent on **TLEV**. For **TLEV=0**, **1**, or **3**, energy gap is always calculated as follows:

$$E_g(T_{nom}) = 1.16 \angle (7.02 \times 10^4) \frac{T_{nom}^2}{T_{nom} + 1108.0}.$$
(8.160)

If **TLEV=2**, the energy gap is calculated as a function of model parameters $E_g(0)$, GAP1, and GAP2:

$$E_g(T_{nom}) = E_g(0) \angle GAP1 \cdot \frac{T_{nom}^2}{T_{nom} + GAP2}.$$
(8.161)

Saturation Current

$$I_{S}(T) = I_{S} \cdot e^{\frac{facln}{N}}$$
(8.162)

$$JSW(T) = JSW \cdot e^{\frac{facln}{N}}$$
(8.163)

For TLEV=0 and 1

$$facln = \frac{E_g(0)}{V_t(T_{nom})} \angle \frac{E_g(0)}{Vt(T)} + XTI \cdot ln\left(\frac{T}{T_{nom}}\right)$$
(8.164)

For *TLEV*=2

$$facln = \frac{E_g(T_{nom})}{V_t(T_{nom})} \angle \frac{E_g(T)}{Vt(T)} + XTI \cdot ln\left(\frac{T}{T_{nom}}\right)$$
(8.165)

For *TLEV*=3

$$facln = \frac{V_{SB}}{V_t(T_{nom})} \angle \frac{V_{SB}}{Vt(T)} + XTI \cdot ln\left(\frac{T}{T_{nom}}\right)$$
(8.166)

Breakdown Voltage

For *TLEV*=0

$$BV(T) = BV \angle TCV \cdot \Delta T \tag{8.167}$$

For *TLEV*=1, 2, or 3

$$BV(T) = BV \cdot (1 \angle TCV \cdot \Delta T)$$
(8.168)

where $\Delta T = T - Tnom$

Transit Time

$$\tau(T) = \tau \cdot (1 + \tau_{t1} \cdot \Delta T + \tau_{t2} \cdot \Delta T^2)$$
(8.169)

Contact Potential

For *TLEV*=0

$$PB(T) = PB \cdot \left(\frac{T}{T_{nom}}\right) \angle V_t(T) \cdot \left\{3 \cdot \ln\left(\frac{T}{T_{nom}}\right) + \frac{E_g(T_{nom})}{V_t(T_{nom})} \angle \frac{E_g(T)}{V_t(T)}\right\}$$
(8.170)

$$PHP(T) = PHP \cdot \left(\frac{T}{T_{nom}}\right) \angle V_t(T) \cdot \left\{3 \cdot \ln\left(\frac{T}{T_{nom}}\right) + \frac{E_g(T_{nom})}{V_t(T_{nom})} \angle \frac{E_g(T)}{V_t(T)}\right\}$$
(8.171)

For *TLEV*=1 or 2

$$PB(T) = PB - TPB \times \Delta T \tag{8.172}$$

$$PHP(T) = PHP - TPHP \times \Delta T \tag{8.173}$$

For *TLEV*=3

$$PB(T) = PB + dpbdt \times \Delta T \tag{8.174}$$

$$PHP(T) = PHP - dphpdt \times \Delta T \tag{8.175}$$

where

TLEV=2

$$Pbdt = (8.176)$$

$$\frac{E_g(T_{nom}) + 3 \cdot V_t(T_{nom}) + [E_g(0) \angle E_g(T_{nom})] \cdot \left(2 \angle \frac{T_{nom}}{T_{nom} + GAP2}\right) \angle PB$$

$$\frac{Z_{nom}}{T_{nom}}$$

$$Phpdt = (8.177)$$

$$\frac{E_g(T_{nom}) + 3 \cdot V_t(T_{nom}) + [E_g(0) \angle E_g(T_{nom})] \cdot \left(2 \angle \frac{T_{nom}}{T_{nom} + GAP2}\right) \angle PHP$$

$$\frac{Z_{nom}}{T_{nom}}$$

and

TLEV=0 or 1

Eg(0) and GAP2 take their default values in the above equations:

Eg(0) = 1.16

GAP2 = 1108.0

Junction Capacitance

TLEV=0

$$C_{j}(T) = C_{j0} \cdot \left\{ 1 + m_{j} \cdot \left(4.0 \times 10^{24} \cdot \Delta T \angle \frac{PB(T)}{PB} + 1 \right) \right\}$$
(8.178)

$$C_{jsw}(T) = C_{jsw0} \cdot \left\{ 1 + m_j \cdot \left(4.0 \times 10^{\angle 4} \cdot \Delta T \angle \frac{PHP(T)}{PHP} + 1 \right) \right\}$$
(8.179)

TLEV=1

$$C_{i}(T) = C_{i0} \cdot (1 + CTA \cdot \Delta T) \tag{8.180}$$

$$C_{isw}(T) = C_{isw0} \cdot (1 + CTP \cdot \Delta T)$$
(8.181)

TLEV=2

$$C_j(T) = C_{j0} \cdot \left(\frac{PB}{PB(T)}\right)^{m_j}$$
(8.182)

$$C_{j_{SW}}(T) = C_{j_{SW0}} \cdot \left(\frac{PHP}{PHP(T)}\right)^{m_{j_{SW}}}$$
(8.183)

Note:

Use mj instead of mj(T) in the above equation.

TLEV=3

$$C_j(T) = C_{j0} \cdot 1 \angle 0.5 \cdot dpbdt \cdot \frac{\Delta T}{PB}$$
(8.184)

$$C_{jsw}(T) = C_{jsw0} \cdot \left(1 \angle 0.5 \cdot dphpdt \cdot \frac{\Delta T}{PHP} \right)$$
(8.185)

Grading Coefficient

$$m_j(T) = m_j \cdot (1 + TM1 \cdot \Delta T + TM2 \cdot \Delta T^2)$$
(8.186)

Resistance

$$R_{S}(T) = R_{S} \cdot (1 + TRS \cdot \Delta T) \tag{8.187}$$

_

Fowler-Nordheim Model (Level 2)

The Fowler-Nordheim model is used to characterize the tunneling current flow through thin insulators in nonvolatile memory devices such as the floating gate devices and the MIOS (metal-insulator-oxide-

semiconductor) devices. The insulators in these devices are sufficiently thin (about 100 Å) to permit tunneling of carriers.

Current Equations

 $I_d = area_{eff} \cdot J_F \cdot \left(\frac{v_d}{t_{ox}}\right)^2 \cdot e^{\frac{\sum E_F \cdot t_{ox}}{V_d}}$ (8.188)

when $Vd \ge 0$

$$I_d = \angle area_{eff} \cdot J_R \cdot \left(\frac{v_d}{t_{ox}}\right)^2 \cdot e^{\angle \frac{E_R \cdot t_{ox}}{V_d}}$$
(8.189)

when Vd < 0

where

 $areaeff = Weff \times Leff \times M$

and

 $Weff = W \times SCALM \times SHRINK + XWeff$

 $Leff = L \times SCALM \times SHRINK + XWeff$

 $XWeff = XW \times SCALM$

Capacitance

$$C_D = area_{eff} \cdot \frac{\varepsilon_{ox}}{t_{ox}}$$
(8.190)

Application Notes—Schottky Barrier Diodes

The Schottky barrier diode is not explicitly modeled in T-Spice, but it can be simulated using the PN junction diode model provided extra attention is paid to the differences between the PN junction diode and Schottky barrier diode.

Schottky barrier diodes and PN junction diodes have a similar I-V relation, but their saturation current expressions are quite different. For Schottky barrier diode, the saturation current is given by

$$I_{S} = A_{RC} \cdot K_{RC} \cdot T_{nom}^{2} \cdot \exp\left(\angle \frac{V_{sb}}{V_{t}}\right)$$
(8.191)

where $A_{RC} = 1.2 \times 10^6 (A \cdot m^{2} \cdot K^{2})$ is the Richardson constant, *KRC* is the ratio of the effective Richardson constant to the Richardson constant, *VSB* is the Schottky barrier height, and $V_t = (kT_{nom})/q$ is the thermal voltage. Use this calculated *IS* value for Schottky barrier diode if *IS* is not specified.

Some typical *KRC* values are:

Туре	Si	Ge	GaAs
p-type	0.66	0.34	0.62
n-type	• (111): 2.2	• (111): 1.11	0.068
	• (100): 2.1	• (100): 1.19	

Some other parameter values intended for Schottky barrier diodes are indicated in the diode parameter list. Use these values instead of default in the simulation of Schottky barrier diode if these parameters are not specified.

JFET

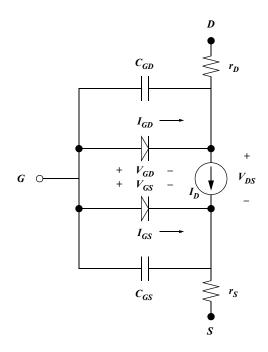
The junction field-effect transistor model uses the basic FET model of Schichmann and Hodges. The DC characteristics are modeled by the threshold voltage and the gain factor, and charge storage is modeled by two reverse-biased PN junctions. Source and drain series resistances are included. JFET models are always level 0.

Parameters

Parameter	Symbol	Description	Default	Units
vto	Vt0	Threshold voltage	-2.0	V
beta	β	Transconductance parameter	1.0×10^{-4}	A/V^2
lambda	λ	Channel length modulation parameter	0.0	1N
rd	Rd	Drain series resistance	0.0	Ω
rs	Rs	Source series resistance	0.0	Ω
cgs	Cgs	Zero-bias gate-source junction capacitance	0.0	F
cgd	Cgd	Zero-bias gate-drain junction capacitance	0.0	F
pb	PB	Gate junction potential	1.0	V
is	IS	Gate junction saturation current	$1.0 imes 10^{-14}$	А
fc	FC	Forward-bias depletion capacitance coefficient	0.5	

.model name njf|pjf [parameters]

Large-Signal Model



Equations

Currents

In the normal or forward region of operation, the DC currents are described by the following equations, based on the quadratic FET model of Shichmann and Hodges.

For $(VGS - VTO) \le 0$,

$$I_{DS} = 0$$
 (8.192)

For $0 < (VGS - VTO) \le VDS$,

$$I_{DS} = \beta (V_{GS} \angle V_{TO})^2 (1 + \lambda V_{DS})$$

$$(8.193)$$

For 0 < VDS < (VGS - VTO),

$$I_{DS} = \beta V_{DS} [2(V_{GS} \angle V_{TO}) \angle V_{DS}] (1 + \lambda V_{DS})$$

$$(8.194)$$

For the inverse or reverse region of operation where VDS < 0, the same set of equations is used, with VGS replaced by VGD and the signs on the VDS terms reversed.

For $(VGD - VTO) \le 0$,

$$I_{DS} = 0 \tag{8.195}$$

For $0 < (VGD - VTO) \le VDS$,

$$I_{DS} = \beta (V_{GD} \angle V_{TO})^2 (1 \angle \lambda V_{DS})$$
(8.196)

For 0 < VDS < (VGD - VTO),

$$V_{DS} = \beta V_{DS} [2(V_{GD} \angle V_{TO}) \angle V_{DS}] (1 \angle \lambda V_{DS})$$

$$(8.197)$$

The gate-to-drain and gate-to-source leakage currents are:

$$I_{GD} = I_S \cdot \left(e^{\frac{qV_{GD}}{kT}} \angle 1 \right)$$
(8.198)

$$I_{GS} = I_S \cdot \left(e^{\frac{qV_{GS}}{kT}} \angle 1 \right)$$
(8.199)

The total currents are then:

$$I_D = I_{DS} \angle I_{GD} \tag{8.200}$$

$$I_G = I_{GD} + I_{GS} \tag{8.201}$$

$$I_S = \angle (I_{DS} + I_{GS}) \tag{8.202}$$

Charges

The charge equations corresponding to *CGD* and *CGS* are based on reverse-biased P-N step junctions. For $VGX < FC \cdot PB$,

$$Q_{GX} = 2C_{GX} \cdot PB\left(1 \angle \sqrt{1 \angle \frac{V_{GX}}{PB}}\right)$$
(8.203)

For $VGX \ge FC \cdot PB$,

$$Q_{GX} = \frac{C_{GX} \left[\left(1 \le \frac{3}{2} FC \right) (V_{GX} \le FC \cdot PB) + \frac{1}{4PB} (V_{GX}^2 \le (FC \cdot PB)^2) \right]}{(1 \le FC) \sqrt{1 \le FC}} +$$
(8.204)

$$C_{GX} \cdot PB \cdot (1 \angle \sqrt{1 \angle FC})$$

X denotes either source (S) or drain (D). The junction charge equations are identical to those used by the BJT and MOSFET models, except that the grading coefficient has been fixed at 0.5.

MESFET

Parameters

.model name nmf | pmf | njf | pjf [parameters]

For HSPICE compatibility, you can create a MESFET device in T-Spice using a name which begins with the letter j. The syntax for the MESFET device statement is exactly as documented in "MESFET (z)" on page 174, except that the device name is **jname** instead of **zname**.

Additionally, the MESFET model can use either the .model name [nmf | pmf] naming convention or .model name [njf | pjf].

Submodel Selectors

Parameter	Symbol	Description	Default	Units
level	LEVEL	Level selector (1, 2 or 3)	1	
sat	SAT	Model selector	0	_
сарор	CAPOP	Capacitance model selector	0	—
dcap	DCAP	Forward-biased diode equation selector (<i>CAPOP</i> =0)	2	—
tlev	TLEV	Temperature model selector	0	_
tlevc	TLEVC	Junction capacitance temperature model selector	0	
nlev	NLEV	Channel thermal noise equation selector	2	

DC Parameters

Parameter	Symbol	Description	Default	Units
alpha	α	Saturation voltage factor	2.0	V^{-1}
b	b	Doping tail extending parameter	0.3	V^{-1}
beta	β	Transconductance parameter	$2.5 imes 10^{-3}$	AN^2
d	D	Channel dielectric constant	11.7 (Si)	_
gamma ∣ gamds	γds	Drain-induced VT0 lowering	0.0	А
is	Isat	Gate saturation current	1.0×10^{-14}	А
k1	k1	Body effect on VTO	0.0	V^{-1}
lambda	λ	Channel length modulation parameter	0.0	V^{-1}
nchan	ND	Channel doping concentration	1.552×10^{16}	cm ⁻³
rd	Rd	Drain ohmic resistance	0.0	Ω
rg	Rg	Gate resistance	0.0	Ω

Parameter	Symbol	Description	Default	Units
rs	Rs	Source ohmic resistance	0.0	Ω
rsh	Rsh	Source/drain sheet resistance	0.0	Ω/m^2
rshg	Rshg	Gate sheet resistance	0.0	Ω/m^2
rshl	Rshl	Channel sheet resistance	0.0	Ω/m^2
satexp	nvds	Drain voltage exponent for sat =3	3.0	
ucrit	Ec	Critical mobility degradation field	0.0	V/cm
vbi	Vbi	Gate diode built-in voltage	1.0	V
vgexp	nvgst	Gate voltage exponent for sat =3	2.0	
vp	Vp	Channel pinch-off voltage	Computed.	V
vto	VT0	Threshold voltage	Computed.	V

Capacitance Parameters

Parameter	Symbol	Description	Default	Units
cgs	Cgs	Zero bias G-S capacitance	0.0	F
cgd	Cgd	Zero bias G-D capacitance	0.0	F
crat	CRAT	Source fraction of GCAP	0.666	
fc	FC	Forward bias depletion capacitance coefficient	0.5	
gcap	GCAP	Total zero bias gate capacitance		F
interr	Eint	Integration error bound (CAPOP=1)	0.01	—
m	m	Junction grading coefficient (CAPOP=0)	0.5	—
pb	φ <i>s0</i>	Gate junction potential	0.8	V
tt	τ	Transit time (CAPOP=0)	0.0	S
vdel	δ	Transition width for Vgs (CAPOP=1)	0.2	V
vmax	Vmax	<i>Vn</i> limiting value (<i>CAPOP</i> =1)	0.5	V

Noise Parameters

Parameter	Symbol	Description	Default	Units
af	Af	Flicker noise exponent	1.0	_
gdsnoi	GDSNO I	Thermal channel noise coefficient (NLEV=3)	1.0	_
kf	Kf	Flicker noise coefficient	0.0	_

Parameter	Symbol	Description	Default	Units
acm	ACM	Area calculation method selector	0	_
align	ALIGN	Misalignment of gate	0.0	m
hdif	Hdif	Space between S/D contacts and junction	0.0	m
I	L	Default gate length	0.0	m
ldel	Ldel	Delta between drawn and optical gate length	0.0	m
ldif	Ldif	Distance from junction to gate edge	0.0	m
w	W	Default gate width	0.0	m
wdel	Wdel	Delta between drawn and optical gate width	0.0	m

Area Calculation Method (ACM) Parameters

	ACM=0	ACM=1
AREAeff	$\frac{Weff}{Leff} \cdot M$	$Weff \cdot Leff \cdot M$
RDeff	RD AREAeff	If RD \neq 0: $\frac{RD}{M}$ If RD=0:
		r
		$\frac{DIF}{eff \cdot M} + RSHL \cdot \frac{LDIF + ALIGN}{Weff \cdot M}$
RSeff	$\frac{RS}{AREAeff}$	If RS \neq 0: $\frac{RS}{M}$ If RS=0:
		$RSH \cdot \frac{HDIF}{Weff \cdot M} + RSHL \cdot \frac{LDIF \angle ALIGN}{Weff \cdot M}$
		w ejj · M
RGeff	$RG \cdot \frac{AREA eff}{M^2}$	If RG \neq 0: $\frac{RG}{M}$ If RG=0:
		$RSHG \cdot \frac{Weff}{Leff \cdot M}$

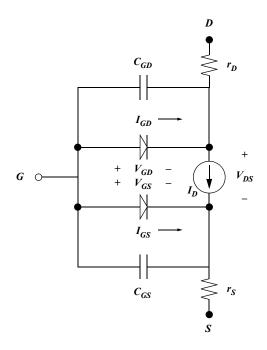
	ACM=0	ACM=1
ISeff	IS · AREAeff	IS · AREAeff
CGSeff	$CGS \cdot AREA eff$	$CGS \cdot AREA eff$
CGDeff	$CGD \cdot AREA eff$	$CGD \cdot AREA eff$
BETAeff	$BETA \cdot \frac{Weff}{Leff} \cdot M$	$BETA \cdot \frac{Weff}{Leff} \cdot M$

Note that the model parameters *IS*, *CGS*, and *CGD* are unitless when **ACM=0** and per square meter when **ACM=1**. For example, when **ACM=0**, $CGS = 5 \times 10^{212}$, $CGD = 1.4 \times 10^{211}$, and $IS = 1 \times 10^{214}$; for **ACM=1**, however, CGS = 5, CGD = 14, and $IS = 1 \times 10^{22}$.

Temperature Dependence Parameters

Parameter	Symbol	Description	Default	Units
bex	BEX	Mobility temperature exponent	0.0	_
ctd	CTD	Temperature coefficient for Cgd	0.0	deg ⁻¹
cts	CTS	Temperature coefficient for Cgs	0.0	deg ⁻¹
eg	Eg	Energy gap for G-D and G-S diodes	1.16	eV
gap1	GAP1	First-order bandgap correction	7.02e-4	eV/deg
gap2	GAP2	Second-order bandgap correction	1108	deg
n	N	G-S and G-D diode emission coefficient	1.0	
tcv	TCV	Temperature coefficient for VT0	0.0	deg ⁻¹
tpb	TPB	Temperature coefficient for pb	0.0	deg^{-1}
trd	TRD	Temperature coefficient for Rd	0.0	deg ⁻¹
trg	TRG	Temperature coefficient for Rg	0.0	deg ⁻¹
trs	TRS	Temperature coefficient for Rs	0.0	deg ⁻¹
xti	XTI	Isat temperature exponent	0.0	—

Large-Signal Model



Equations

There are three levels of the T-Spice MESFET model.

- Level 1. The Curtice model—a diode-based capacitance model and a simplified Ids calculation.
- Level 2. The Statz model (Statz et al. 1987)—a revision of the Curtice model, with an improved capacitance model and a more sophisticated *Ids* calculation.
- Level 3. An HSPICE-compatible model—highly customizable.

Currents

For all three levels,

$$I_{ds} = \beta \cdot \frac{(V_{gst})^{VGEXP}}{A} \cdot B \cdot (1 + \lambda V_{ds})$$
(8.205)

where

$$V_{gst} = V_{gs} \angle V_{T0} \angle \gamma_{ds} \cdot V_{ds}$$
(8.206)

A is the doping profile extension factor. At level 1, A = 0; otherwise:

$$A = 1 + bV_{gst} \tag{8.207}$$

VGEXP can be varied only at level 3; at levels 1 and 2, it is fixed at 2.0.

B is the saturation term; its form depends on the value of *SAT*.

When SAT = 0:

$$B = \tanh(\alpha V_{ds}) \tag{8.208}$$

This form is fixed (that is, *SAT* can only take a value of 0) at level 1.

When SAT = 1:

$$B = \tanh\left(\alpha \cdot \frac{V_{ds}}{V_{gst}}\right) \tag{8.209}$$

When SAT = 2:

$$B = 1 \angle \left(1 \angle \alpha \cdot \frac{V_{ds}}{3}\right)^3 \tag{8.210}$$

When $Vds > 3/\alpha$, B = 1. This form is fixed (that is, *SAT* can only take a value of 2) at level 2.

When SAT = 3 and $Vds < SATEXP/\alpha$:

$$B = 1 \angle \left(1 \angle \alpha \cdot \frac{V_{ds}}{SATEXP} \right)^{SATEXP}$$
(8.211)

Otherwise, B = 1.

Capacitances

There are two capacitance models, one at level 1 (a "diode-like" model) and one at level 2 (the Statz model). The *CAPOP* parameter selects between the models.

When CAPOP = 0:

When the junctions are reverse-biased ($Vgd < FC \cdot \phi s\theta$):

$$C_{gd} = C_{gd}(0) \cdot \left(1 \angle \frac{V_{gd}}{\phi_{s0}}\right)^{\angle m}$$
(8.212)

$$C_{gs} = C_{gs}(0) \cdot \left(1 \angle \frac{V_{gs}}{\phi_{s0}}\right)^{\angle m}$$
(8.213)

$$C_{gd} = \tau \cdot \frac{\partial I_{gd}}{\partial V_{gd}} + C_{gd}(0) \cdot \frac{1 \angle FC(1+m) + m \frac{V_{gd}}{\phi_{s0}}}{(1 \angle FC)^{m+1}}$$
(8.214)

$$C_{gs} = \tau \cdot \frac{\partial I_{gs}}{\partial V_{gs}} + C_{gs}(0) \cdot \frac{1 \angle FC(1+m) + m \frac{V_{gs}}{\phi_{s0}}}{(1 \angle FC)^{m+1}}$$
(8.215)

When DCAP = 2 (default):

$$C_{gd} = \tau \cdot \frac{\partial I_{gd}}{\partial V_{gd}} + C_{gd}(0) \cdot \left(1 + m \frac{V_{gd}}{\phi_{s0}}\right)$$
(8.216)

$$C_{gs} = \tau \cdot \frac{\partial I_{gs}}{\partial V_{gs}} + C_{gs}(0) \cdot \left(1 + m \frac{V_{gs}}{\phi_{s0}}\right)$$
(8.217)

When CAPOP = 1:

The basic Statz capacitance equations are:

$$C_{gs,gd} = \frac{1}{4} \frac{C_{gs}(0)}{\sqrt{1 \le \frac{V_n}{\phi_{s0}}}} \times \left[1 + \frac{V_{eff} \le V_{T0}}{\sqrt{(V_{eff} \le V_{T0})^2 + \delta^2}} \right] \left[1 \pm \frac{V_{gs} \le V_{gd}}{\sqrt{(V_{gs} \le V_{gd})^2 + (\alpha)^{\le 2}}} \right]$$
(8.218)
+ $\frac{1}{2} \times C_{gd}(0) \left[1 \mp \frac{V_{gs} \le V_{gd}}{\sqrt{(V_{gs} \le V_{gd})^2 + (\alpha)^{\le 2}}} \right]$

where

$$V_{eff} = \frac{1}{2} [V_{gs} + V_{gd} + \sqrt{(V_{gs} \angle V_{gd})^2 + (\alpha)^{2}}]$$
(8.219)

$$V_n = \frac{1}{2} [V_{eff} + V_{T0} + \sqrt{(V_{eff} \angle V_{T0})^2 + (\delta)^2}]$$
(8.220)

If $V_n > V_{max}$, then Vn is limited to Vmax. In the plus/minus signs (±) above, the top signs hold for Cgs, the bottom ones for Cgd.

Temperature Dependence Equations

In the following, $\Delta T = T \angle T_{ref}$. T_{ref} is the temperature at which the user-supplied parameters are valid, which defaults to 25° C. All temperatures in the following equations are assumed to be in Kelvin.

 E_g temperature dependence. For all values of TLEV, the energy gap E_g at the reference and simulation temperatures is calculated using

$$E_g(T) = EG \angle GAP1 \times \frac{T}{T + GAP2}$$
(8.221)

For *TLEV* 0 and 1, *EG*, *GAP1*, and *GAP2* are held fixed at 1.16, 7.02×10^{4} , and 1108.0, respectively, regardless of what values the user specifies for these parameters.

Saturation current temperature dependence. The saturation current temperature extrapolation is calculated by the following general equation:

$$I_{s}(T) = IS \cdot \exp\left\{\frac{e}{k_{B}N}\left(\frac{E_{g}(T_{ref})}{T_{ref}} \ge \frac{E_{g}(T)}{T} + XTI \cdot In\left(\frac{T}{T_{ref}}\right)\right)\right\}$$
(8.222)

For TLEV 0 and 1, the user-supplied EG is used in place of $E_g(T)$ for all T. For TLEV=2, $E_g(T) = E_g(T)$, as calculated above.

Capacitance parameters temperature dependence. A separate selection parameter, TLEVC, is used to choose one of four methods of temperature-adjusting the gate capacitance values. This parameter also influences the temperature compensation of ϕ_{s0} .

For TLEVC=0, the gate junction potential (θ_{s0}) is temperature-adjusted as follows:

$$\phi_{s0}(T) = \Phi_{s0} \cdot \frac{T}{T_{ref}} \angle \frac{3k_B}{e} T \ln\left(\frac{T}{T_{ref}}\right) \angle E_g(T_{ref}) \cdot \frac{T}{T_{ref}} + E_g(T)$$
(8.223)

The gate capacitances are calculated by

$$C_{gs}(T) = C_{gs} \cdot \left[1 + m \cdot \left(4.0 \times 10^{24} \cdot \Delta T \angle \frac{\phi_{s0(T)}}{\phi_{s0(T_{ref})}} + 1 \right) \right]$$
(8.224)

$$C_{gd}(T) = C_{gs} \cdot \left[1 + m \cdot \left(4.0 \times 10^{24} \cdot \Delta T \angle \frac{\phi_{s0(T)}}{\phi_{s0(T_{ref})}} + 1 \right) \right]$$
(8.225)

For TLEVC=1, the junction potential is temperature-adjusted with

$$\phi_{s0}(T) = \phi_{s0} \angle TPB \cdot \Delta T \tag{8.226}$$

The gate capacitances are calculated by

$$C_{gs}(T) = C_{gs} \cdot (1 + CTS + \Delta T)$$
(8.227)

$$C_{gd}(T) = C_{gd} \cdot (1 + CTS \cdot \Delta T)$$
(8.228)

For TLEVC=2, the junction potential is calculated as it is for TLEVC=1. The gate capacitances are calculated by

$$C_{gs}(T) = C_{gs} \cdot \left(\frac{\phi_{s0}}{\phi_{s0^{T}}}\right)^{m}$$
(8.229)

$$C_{gs}(T) = C_{gd} \cdot \left(\frac{\phi_{s0}}{\phi_{s0}^{T}}\right)^m$$
(8.230)

For TLEVC=3, the junction potential calculation attempts to estimate the term $d\phi_{s0}/(dT)$ (*dpbdt*) using the following equations, depending on TLEV.

For TLEV=0 or 1,

$$dpbdt = \angle \left(\frac{1}{T_{ref}}E_g(T_{ref}) + \frac{3k_B}{e}T_{ref} + (1.16 \angle E_g(T_{ref})) \cdot \left(2 \angle \frac{T_{ref}}{T_{ref} + 1108}\right)(\angle \phi_{s0})\right)$$
(8.231)

For TLEV=2,

$$dpbdt (8.232)$$

The gate capacitances are then calculated by

$$C_{gs}(T) = C_{gs} \cdot \left(1 \angle 0.5 \cdot dpbdt \times \frac{\Delta T}{\phi_{s0}} \right)$$
(8.233)

$$C_{gc}(T) = C_{gd} \cdot \left(1 \angle 0.5 \cdot dpbdt \times \frac{\Delta T}{\phi_{s0}} \right)$$
(8.234)

Note that $C_{gs, gd}$ becomes what is referred to elsewhere as $C_{gs, gd}(0)$, the zero-bias gate capacitances.

 V_{TO} temperature dependence. The threshold voltage is temperature-compensated with a simple linear model

$$V_{TO}(T) = V_{TO} \angle TCV \times \Delta T$$
(8.235)

Transconductance temperature dependence. The temperature compensation of the transconductance factor (β) is calculated as follows

$$\beta(T) = \beta \cdot \left(\frac{T}{T_{ref}}\right)^{BEX}$$
(8.236)

Parasitic resistance temperature dependence. The source, drain, and gate parasitic resistances are temperature-compensated by the following equations

$$R_d(T) = R_d \cdot (1 + TRD \times \Delta T) \tag{8.237}$$

$$R_s(T) = R_s \cdot (1 + TRS \times \Delta T) \tag{8.238}$$

$$R_g(T) = R_g \cdot (1 + TRG \times \Delta T)$$
(8.239)

MOSFET Levels 1/2/3 (Berkeley SPICE 2G6)

Parameters

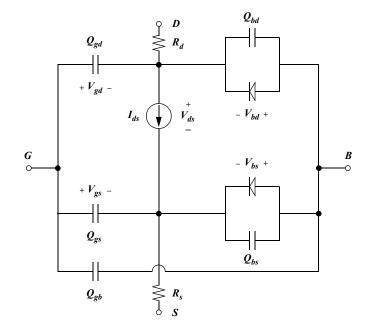
.model name nmos | pmos level=1 | 2 | 3 [parameters]

Also see "Additional MOSFET Parameters" on page 455.

Parameter	Symbol	Description	Default	Units	
level	LEVEL	Model selector	1		000
vto	Vt0	Zero-bias threshold voltage	Computed	V	000
kp	KP	MOSFET transconductance	Computed	A/V^2	000
gamma	γ	Bulk threshold parameter	Computed	V ^{1/2}	000
phi	φ	Surface potential	Computed	V	000
lambda	λ	Channel length modulation	Computed	V^{-1}	00
tox	Tox	Gate oxide thickness	Computed.	If < 1, m; if > 1, Å	000
nsub dnb nb	Nsub	Bulk doping concentration	0.0	cm ⁻³	000
nss	NSS	Surface state density	0.0	cm ⁻²	00
nfs dnf nf dfs	NFS	Fast surface state density	Computed	cm ⁻²	000
xj	Xj	Junction depth	0.0	m	000
ld	LD	Lateral diffusion	$0.75 \times xj$	m	000
wd	WD	Width diffusion	0.0	m	000
xl dl Idel	Xl	Mask and etching length change	0.0	m	000
xw dw wdel	Xw	Mask and etching width change	0.0	m	006
uo	μ <i>0</i>	Electron or hole mobility	600.0	$cm^2/V \cdot s$	000
ucrit	UCRIT	Critical field mobility degradation coefficient	1.0×10^{-4}	V/cm	0
uexp	UEXP	Critical field mobility degradation exponent	0.0	_	0
vmax	VMAX	Maximum carrier drift velocity	0.0	m/s	00
neff	NEFF	Total channel charge coefficient	1.0	—	0
delta	δ	Width effect on threshold voltage	0.0	_	00
tpg	TPG	Type of gate material:	1	—	000
		• Doping type same as source-drain (tpg=1)			000
		 Doping type reverse of source-drain (tpg=- 1) 			006

Parameter	Symbol	Description	Default	Units	
		• Aluminum gate (tpg=0)			000
theta	θ	Mobility modulation	0.0	V-1	₿
eta	η	Static feedback	0.0	—	6
kappa	κ	Saturation field factor	0.2	—	₿
del		Channel length reduction per side	0.0	m	000

Large-Signal Model



This schematic represents the Level 2 model. The Level 1 model has the same configuration, without the junction diodes.

The terminals (G, D, S, B) represent the gate, drain, source, and bulk connections, respectively, of the MOSFET. *Id* is the current flowing from the drain to the source as a function of (Vgs, Vds, Vbs). The ohmic resistance of the drain and source diffusion junctions are represented by *Rd* and *Rs*. A P-channel MOSFET can be modeled by reversing the polarity of (Vgs, Vds, Vbs), the current source *Id*, and the junction diodes.

When **nrs** and **nrd** are not given as options on the MOSFET device statement, T-Spice computes them by calculating the number of squares from the geometry of the junction and then multiplying them by **RSH** to obtain the drain and source resistors *Rd* and *Rs*.

Level 1 Equations

The Level 1 model is included for SPICE compatibility, but it is inaccurate when simulating circuits with analog characteristics. The original intent of the model was to provide an approximation for digital circuits that could be evaluated quickly, reducing the simulation time by as much as a factor of two. However, due to the inherent inaccuracies of the level 1 equations in analog simulations, this model should generally be avoided.

Current

Current behavior is modeled by three equations, representing the three regions of MOSFET operation: *cutoff, linear*, and *saturation*.

Cutoff region: Vgs ð Vth

$$I_{ds} = 0$$
 (8.240)

Linear region: Vgs > Vth and (Vgs - Vth) > Vds

$$I_{ds} = \frac{\beta}{2} V_{ds} (2(V_{gs} \angle V_{th}) \angle V_{ds}) (1 + \lambda V_{ds})$$
(8.241)

Saturation region: Vgs > Vth and $(Vgs - Vth) \le Vds$

$$I_{ds} = \frac{\beta}{2} (V_{gs} \angle V_{th})^2 (1 + \lambda V_{ds})$$
(8.242)

In equations (8.241) and (8.242),

$$\beta = \frac{W \angle (2 \cdot WD)}{L \angle (2 \cdot LD)} \cdot KP$$
(8.243)

Charge

$$Q_{g} = C_{gb}V_{gb} + C_{gd}V_{gd} + C_{gs}V_{gs}$$
(8.244)

$$Q_d = C_{gd} V_{gd} + \int C_{db}(v) dv \tag{8.245}$$

$$Q_{s} = C_{gs}V_{gs} + \int C_{sb}(v)dv$$
 (8.246)

$$Q_b = \angle (Q_g + Q_d + Q_s) \tag{8.247}$$

Capacitance

The Meyer gate capacitance model was replaced by a simplified model that provides conservation of charge.

$$C_{gb} = C_{gs} = C_{gd} = \frac{1}{3}WL\frac{\varepsilon_{ox}}{T_{ox}}$$
(8.248)

The junction capacitance for the drain and source is dependent on the drain-bulk and drain-source voltages.

$$C_{db} = C_{pn}(V_{bd}, AD, PD)$$
(8.249)

$$C_{sb} = C_{pn}(V_{bs}, AS, PS)$$
(8.250)

For reverse bias $Vpn < FC \cdot PB$,

$$C_{pn}(V_{pn}, A, P) = \left(CJ \cdot \frac{A}{\left(1 \angle \frac{V_{pn}}{PB}\right)^{MJ}}\right) + \left(CJSW \cdot \frac{P}{\left(1 \angle \frac{V_{pn}}{PB}\right)^{MJSW}}\right)$$
(8.251)

For forward bias $Vpn \ge FC \cdot PB$,

$$C_{pn}(V_{pn}, A, P) = CJ\left(\frac{A}{(1 \angle FC)^{(1+MJ)}}\right)\left(1 \angle FC1 + MJ + \frac{V_{pn}}{PB}MJ\right) + CJ\left(\frac{P}{(1 \angle FC)^{(1+MJSW)}}\right)\left(1 \angle FC1 + MJSW + \frac{V_{pn}}{PB}MJSW\right)$$
(8.252)

In equations (8.251) and (8.252), A denotes area and P denotes perimeter.

The charge can be calculated using

$$Q = \int C(V)dv \tag{8.253}$$

Threshold Voltage

An increase in the threshold voltage is due to a reverse bias from the gate to the substrate called the *body effect*, which causes degradation in the current drive of a transistor.

$$V_{to} = V_{FB} + (\gamma \sqrt{\phi} + \phi)$$
(8.254)

$$\gamma = \frac{\sqrt{2\varepsilon_0 \varepsilon_{si} q N_{sub}}}{C_{ox}}$$
(8.255)

$$C_{ox} = \frac{\varepsilon_0 \varepsilon_{ox}}{T_{ox}}$$
(8.256)

$$KP = \mu_0 C_{ox} \tag{8.257}$$

$$V_{FB} = \left(\angle TPG \cdot \frac{E_q}{2} \right) \angle \frac{\phi}{2} \angle \frac{qN_{st}}{C_{ox}}$$
(8.258)

Equation (8.254) is dependent on Vbs and is implemented as follows:

$$V_{th} = V_{to} + \gamma(bodyterm \angle \sqrt{2\phi_F})$$
(8.259)

When $Vbs \leq 0.0$,

$$bodyterm = \sqrt{2\phi_F \angle V_{bs}}$$
(8.260)

When Vbs > 0.0,

$$bodyterm = \max\left(\left(\sqrt{2\phi_F} \angle \frac{V_{bs}}{2\sqrt{2\phi_F}}\right), 0\right)$$
(8.261)

In Equations (8.259) through (8.261),

$$2\phi_F = \phi = 2\frac{kT}{q}ln\left(\frac{N_{sub}}{n_i}\right)$$
(8.262)

Level 2 Equations

The Level 2 model uses two current equations. Since the MOSFET is not an ideal switch, the current begins to flow before the transistor reaches the turn-on voltage. This region is called *weak* inversion. As the voltage on the gate approaches the threshold voltage, it conducts current much more vigorously. At this point the channel is in the *strong* inversion region. The strong inversion region includes the linear and saturation regions. Many second-order effects that control the amount of current are calculated in the Level 2 model, including backgate bias and short and narrow channel effects. The Level 2 current equations are similar to the Grove equation for a MOSFET. These equations insure the continuity of current at *Von* (threshold point) through the transistor regions.

Subthreshold Region

The weak inversion current equation is used when the transistor is in the subthreshold region, Vgs < Von.

$$d_{s} = \beta \left(\left(V_{on} \angle V_{bin} \angle \frac{\eta V_{on}}{2} \right) V_{on} \angle \right)$$

$$\frac{2}{3} \gamma_{s} \left((2\phi_{F} \angle V_{bs} + V_{on})^{3/2} \angle (2\phi_{F} \angle V_{bs})^{3/2} \right) e^{\frac{q}{nkT} (V_{gs} \angle V_{on})}$$

$$(8.263)$$

The strong inversion current equation is used to calculate the current when $Vgs \ge Von$:

$$_{ds} = \beta \left(\left(V_{gs} \angle V_{bin} \angle \frac{\eta V_{ds}}{2} \right) V_{ds} \angle \frac{2}{3} \gamma_s ((2\phi_F \angle V_{bs} + V_{ds})^{3/2} \angle (2\phi_F \angle V_{bs})^{3/2}) \right)$$

$$(8.264)$$

where Vds = Vdsat for Vds > Vdsat.

The voltages calculated to determined the second order effects of the transistor currents are defined as:

$$V_{th} = V_{bin} + \gamma_s \sqrt{2\phi_F \angle V_{bs}}$$
(8.265)

$$V_{bin} = V_{bi} + \delta \left(\frac{\pi \varepsilon_0 \varepsilon_{si}}{4 C_{ox} W_{eff}}\right) (2\phi_F \angle V_{bs})$$
(8.266)

$$V_{bi} = V_{fb} + 2\phi_F \tag{8.267}$$

$$2\phi_F = \phi = 2\frac{kT}{q}\ln\left(\frac{N_{sub}}{n_i}\right)$$
(8.268)

$$V_{fb} = \phi_{ms} \angle \frac{q \cdot NSS}{C_{ox}}$$
(8.269)

The voltage *Von* is used to switch between the weak and strong inversion model regions. When *NFS* is not specified,

$$V_{on} = V_{th} \tag{8.270}$$

$$n = \infty \tag{8.271}$$

However, a more accurate cut-on point can be modeled by using a curve fitting parameter *NFS* in the evaluation of *Von*:

$$V_{on} = V_{th} + \frac{nkT}{q}$$
(8.272)

where

$$n = 1 + \frac{C_{FS}}{C_{ox}} + \frac{C_D}{C_{ox}}$$
(8.273)

$$C_{FS} = q \cdot NFS \tag{8.274}$$

$$C_{D} = \frac{\partial Q_{B}}{\partial V_{bs}} = C_{ox} \left(\angle \gamma_{s} \left(\frac{d \sqrt{2\phi_{F} \angle V_{bs}}}{dV_{bs}} \right) \right)$$

$$\left(\frac{\partial \gamma_{s}}{\partial V_{bs}} \right) \sqrt{2\phi_{F} \angle V_{bs}} + \delta \frac{\pi \varepsilon_{0} \varepsilon_{si}}{4 C_{ox} W_{eff}}$$

$$(8.275)$$

Taking the partial derivatives and applying the chain rule yields

$$C_{D} = C_{ox} \left[\frac{1}{2} \gamma_{s} \frac{1}{\sqrt{2\phi_{F} \angle V_{bs}}} \angle \gamma_{s} \sqrt{2\phi_{F} \angle V_{bs}} \left[\frac{X_{D}}{4L} \cdot \frac{1}{\left(1 + \frac{2X_{D}\sqrt{2\phi_{F} \angle V_{bs}}}{X_{j}}\right)^{1/2}} \cdot \frac{1}{\sqrt{2\phi_{F} \angle V_{bs}}} \right] \right] \quad (8.276)$$

$$+ \left[\frac{X_{D}}{4L} \cdot \frac{1}{\left(1 + \frac{2X_{D}\sqrt{2\phi_{F} \angle V_{bs} + V_{ds}}}{X_{j}}\right)^{1/2}} \cdot \frac{1}{\sqrt{2\phi_{F} \angle V_{bs} + V_{ds}}} \right] + \delta \frac{\pi\varepsilon_{0}\varepsilon_{si}}{4C_{ox}W_{eff}}$$

Equation (8.276) assumes that Vbs is negative. When Vbs is positive, $\sqrt{2\phi_F} \angle V_{bs}$ should be replaced with

$$\frac{\sqrt{2\phi_F}}{1 + \frac{V_{bs}}{4\phi_F}}$$
(8.277)

Linear and Saturation Regions

The saturation voltage *Vdsat* can be computed with either of two methods. Which method is chosen depends on whether the input parameter *VMAX* has been defined.

Method 1. When *VMAX* is *not* defined, the model computes *Vdsat* assuming that the channel is pinched off at the drain:

$$V_{dsat} = \frac{V_{gs} \angle V_{bin}}{\eta}$$

$$+ \frac{1}{2} \left(\frac{\gamma_s}{\eta}\right)^2 \left(1 \angle \sqrt{1 + 4\left(\frac{\eta}{\gamma_s}\right)^2 \left(\frac{V_{gs} \angle V_{bin}}{\eta} + 2\phi_F \angle V_{bs}\right)}\right)$$
(8.278)

If the parameter λ is not defined while using the pinch-off method, then it can be computed as

$$\lambda = \frac{X_D}{L_l V_{ds}} \sqrt{\frac{V_{ds} \angle V_{dsat}}{4} + \sqrt{1 + \left(\frac{V_{ds} \angle V_{dsat}}{4}\right)^2}}$$
(8.279)

The channel length becomes smaller due to the pinch-off of the channel. The effective channel length is

$$L_{eff} = L_l (1 \angle \lambda V_{ds}) \tag{8.280}$$

Method 2. When VMAX is defined as Vdsat and the channel length modulation is calculated using the carrier scattering limited velocity model, this method appropriately models saturation current for short-

channel MOSFETs as charge carriers reaching their maximum scattering limited velocity before the pinch-off effect comes into play.

$$VMAX = \frac{\mu_s \left(\left(V_{gs} \angle V_{bin} \angle \frac{\eta V_{dsat}}{2} \right) V_{dsat} \angle \frac{2\gamma_s}{3} ((V_{dsat} + 2\phi_F \angle V_{bs})^{3/2} \angle (2\phi_F \angle V_{bs})^{3/2}) \right)}{L_{eff} (V_{gs} \angle V_{bin} \angle \eta V_{dsat} \angle \gamma \sqrt{V_{dsat} + 2\phi_F \angle V_{bs}})}$$
(8.281)

The effective channel length is dependent on VMAX and Vdsat and computed as

$$L_{eff} = L_{I} \angle X_{D} \left(\left(\frac{X_{D} V M A X}{2 \mu_{s}} \right)^{2} + \left(V_{ds} \angle V_{dsat} \right)^{1/2} + \frac{(X_{D})^{2} V M A X}{2 \mu_{s}}$$
(8.282)

Solving for *Vdsat* is difficult because it requires the simultaneous solution of the nonlinear equations (8.281) and (8.282). A less computationally expensive approach is desirable:

Assume that *Leff* and *L1* in equation (8.282) are equal. Then by selecting parameter *NEFF*, adjust the value of *XD* to obtain a good fit to the I-V characteristics of the MOSFET.

$$X_D = \sqrt{\frac{2\varepsilon_0 \varepsilon_{si}}{q N_{sub} NEFF}}$$
(8.283)

Equation (8.282) can be solved using Ferrari's method. There will be 2 or 4 real roots. The smallest positive real root is the correct value of *Vdsat*.

If λ is not defined, then it can be computed using *Vdsat* and equations (8.281) and (8.284):

$$\lambda = \frac{X_D}{L_l V_{ds}} \left(\left(\left(\frac{X_D V M A X}{2\mu_s} \right)^2 + \left(V_{ds} \angle V_{dsat} \right) \right)^{1/2} + \frac{X_D V M A X}{2\mu_s} \right)$$
(8.284)

Then Leff can be computed as

$$L_{eff} = L_l(1 \angle \lambda V_{ds}) \tag{8.285}$$

Thus the value of *Leff* is available from either of the two current saturation methods—channel pinch-off or carrier scattering limited velocity. If *Leff* is smaller than the zero-bias depletion layer width $WB = XD\sqrt{PB}$, then *Leff* must be recomputed as

$$L_{eff} = \frac{W_B}{1 + \frac{\Delta L \angle L_{max}}{W_B}}$$
(8.286)

where

$$\Delta L = \lambda V_{ds} L_{l} \tag{8.287}$$

$$L_{max} = L_1 \angle W_B \tag{8.288}$$

Equation (8.286) prevents numerical non-convergence, but does not model the punch-through effect.

The voltage *Vdsat* is compared with *Vds*. If *Vds* is greater than *Vdsat*, then *Vds* is set equal to *Vdsat*, thus clamping the drain-to-source voltage to *Vdsat* in the saturation region.

The result is a potential drop (*Vds*) across the saturated transistor and a smaller effective transistor gate length that increases the gain (β).

$$\beta = \frac{W_{eff}}{L_{eff}} KP \tag{8.289}$$

$$KP = \mu_s C_{ox} \tag{8.290}$$

KP is the transconductance of the MOSFET. If it is not specified, it will take the calculated value.

Second-Order Effects

Other variables, coefficients, and modified input parameters that are used in the model are defined as follows:

$$\phi_{ms} = \angle \left(\frac{2\phi_F}{2} + \frac{E_g}{2}\right) \tag{8.291}$$

$$C_{ox} = \frac{\varepsilon_0 \varepsilon_{ox}}{T_{ox}}$$
(8.292)

$$L_l = L \angle (2 \cdot LD) \tag{8.293}$$

$$W_{eff} = W \angle (2 \cdot WD) \tag{8.294}$$

$$\eta = 1 + \delta \left(\frac{\pi \varepsilon_0 \varepsilon_{si}}{4 C_{ox} W_{eff}} \right)$$
(8.295)

$$\mu_{s} = U_{\theta} \left(\frac{UCRIT\varepsilon_{\theta}\varepsilon_{si}}{C_{ox}(V_{gs} \angle V_{on})} \right)^{UEXP}$$
(8.296)

$$\gamma_s = \gamma(1 \angle \alpha_s \angle \alpha_d) \tag{8.297}$$

$$\gamma = \frac{\sqrt{2q\varepsilon_0 \varepsilon_{si} N_{sub}}}{C_{ox}}$$
(8.298)

$$\alpha_S = \frac{1}{2} \cdot \frac{X_j}{L_l} \cdot \left(\sqrt{1 + 2\frac{W_S}{X_J}} \angle 1 \right)$$
(8.299)

$$\alpha_D = \frac{1}{2} \cdot \frac{X_j}{L_l} \cdot \left(\sqrt{1 + 2\frac{W_D}{X_J}} \angle 1 \right)$$
(8.300)

$$W_S = X_D \sqrt{2\phi_F \angle V_{bs}} \tag{8.301}$$

$$W_D = X_D \sqrt{2\phi_F \angle V_{bs} + V_{ds}}$$
(8.302)

$$X_D = \sqrt{\frac{2\varepsilon_0 \varepsilon_{si}}{q N_{sub}}}$$
(8.303)

Ward-Dutton Charge Model

The Ward-Dutton charge model was used to replace the shortcomings of the Meyer capacitance model. It has been shown that assuming capacitance reciprocity leads to non-conservation of charge. This non-conservation of bogus charge can cause various charge-dependent circuits to be simulated incorrectly.

The Ward-Dutton model derives equations based on charge instead of capacitance and conserves charge through all regions of the transistor. This model applies to Level 2 and Level 3 MOSFET models only.

The following table lists the parameters used by the equations describing the Ward-Dutton charge model (see "MOSFET Levels 4 and 13 (BSIM1)" on page 410).

Symbol	Description	Unit	
Idc	DC drain current	А	
Vd	Drain voltage	V	
Vg	Gate voltage	V	
Vs	Source voltage	V	
Vdsat	Saturation voltage	V	
Qb	Total bulk charge	С	
Qg	Total gate charge	С	
Qs	Total source charge	С	
Qd	Total drain charge	С	
Qgi	Intrinsic gate charge	С	
Qsi	Intrinsic source charge	С	
Qdi	Intrinsic drain charge	С	
Qgo	Overlap gate charge	С	
Qso	Overlap source charge	С	
Qdo	Overlap drain charge	С	
Qsj	Junction source charge	С	
Qdj	Junction drain charge	С	

The Ward-Dutton model defines these normalized voltages as:

$$V_g = V_{gs} \angle V_{bs} \angle V_{fb} \tag{8.304}$$

$$V_d = V_{ds} \angle V_{bs} + 2\phi_F \tag{8.305}$$

$$V_s = \angle V_{bs} + 2\phi_F \tag{8.306}$$

The charge on the gate, drain, and source of a transistor is the total charge due to the overlap, junction, and intrinsic channel charge.

$$Q_g = Q_{gi} + Q_{go} \tag{8.307}$$

$$Q_d = Q_{di} + Q_{do} + Q_{dj} (8.308)$$

$$Q_s = Q_{si} + Q_{so} + Q_{sj}$$
(8.309)

The overlap capacitors are due to the gate edges overlapping the substrate and diffusion junctions.

$$Q_{go} = C_{gso} W_{eff} V_{gs} + C_{gso} W_{eff} (V_{gs} \angle V_{ds}) + 2C_{gbo} L_l (V_{gs} \angle V_{bs})$$

$$(8.310)$$

$$Q_{do} = C_{gdo} W_{eff} (V_{ds} \angle V_{gs})$$
(8.311)

$$Q_{so} = \angle C_{gso} W_{eff} V_{gs}$$
(8.312)

The Ward-Dutton model addresses only the intrinsic channel charge. Two sets of equations model the regions of transistor charge.

Cut-off region. The charge model is in the cut-off region when the gate voltage is less than the threshold voltage.

When Vgs < Vth and (Vgs - Vbs) < Vfb,

$$Q_{di} = 0 \tag{8.313}$$

$$Q_{si} = 0 \tag{8.314}$$

$$Q_{gi} = C_{ox} W_{eff} L_l V_g \tag{8.315}$$

When Vgs < Vth and (Vgs - Vbs) > Vfb,

$$Q_{di} = 0$$
 (8.316)

$$Q_{si} = 0 \tag{8.317}$$

$$Q_{gi} = C_{ox} W L_l \cdot \frac{1}{2} \gamma_s \sqrt{\gamma_s^2 + 4V_g}$$
(8.318)

Linear and saturation regions. The model uses the same equation for the linear and saturation regions. In the saturation region the voltage Vd is clamped at the saturation voltage Vdsat when the following condition is true:

$$V_d + \gamma_s \sqrt{V_d} \ge V_g \tag{8.319}$$

Then

$$2\sqrt{V_{dsat}} = \angle \gamma_s + \sqrt{\gamma_s^2 + 4V_g}$$
(8.320)

$$V_d = (\sqrt{V_{dsat}})^2 \tag{8.321}$$

The intrinsic charge for the linear or saturation region is computed as

$$Q_{si} = \frac{3}{5}Q_{CSAT} + \frac{3}{10}(Q_C \angle Q_{CSAT})$$
(8.322)

$$Q_{di} = \frac{23}{5}Q_{CSAT} + \frac{7}{10}(Q_C \angle Q_{CSAT})$$
(8.323)

$$Q_C = \angle (Q_{gi} + Q_{bi}) \tag{8.324}$$

$$Q_{CSAT} = \angle \frac{2}{3} C_{ox} W_{eff} L_1 (V_g \angle V_s \angle \gamma_s \sqrt{V_s})$$
(8.325)

$$V_{gi} = C_{ox} W_{eff} L_I \left[V_g \angle \frac{1}{I_{dc}} \left(V_g \frac{1}{2} (V_d^2 \angle V_s^2) \angle \frac{2}{5} \gamma_s (V_d^{5/2} \angle V_s^{5/2}) \angle \frac{1}{3} (V_d^3 \angle V_s^3) \right)$$
(8.326)

$$Y_{bi} = \angle \frac{C_{ox} W_{eff} L_1}{I_{dc}} \Big[V_g \frac{2}{3} \gamma_s (V_d^{3/2} \angle V_s^{3/2}) \angle \gamma_s^2 \frac{1}{2} (V_d^2 \angle V_s^2) \angle \frac{2}{5} \gamma_s (V_d^{5/2} \angle V_s^{5/2})$$
(8.327)

$$_{lc} = V_g(V_d \angle V_s) \angle \frac{2}{3} \gamma_s(V_d^{3/2} \angle V_s^{3/2}) \angle \frac{1}{2} (V_d^2 \angle V_s^2)$$
(8.328)

The diffusion junction capacitance equations for the drain and source are the same as in the Level 1 model. The capacitance is dependent on the drain to bulk or drain to source voltage.

For reverse bias $Vbs < FC \cdot PB$,

$$C_{bd} = CJ \left(\frac{AS}{\left(1 \angle \frac{V_{bs}}{PB}\right)^{MJ}} + CJSW \left(\frac{PS}{\left(1 \angle \frac{V_{bs}}{PB}\right)^{MJSW}} \right)$$
(8.329)

For forward bias $Vbs > FC \cdot PB$,

$$C_{bd} = CJ \left(\frac{AS}{(1 \angle FC)^{(1 + MJSW)}}\right) \left[1 \angle FC(1 + MJ) + \frac{V_{bs}}{PB}MJ\right] +$$

$$CJSW \left(\frac{PS}{(1 \angle FC)^{(1 + MJSW)}}\right) \left[1 \angle FC(1 + MJSW) + \frac{V_{bs}}{PB}MJSW\right]$$
(8.330)

To obtain the charge function at the junction of the drain or source, integrate the junction capacitance over the range of *Vbs*:

$$Q = \int C(v)dv \tag{8.331}$$

Now integrate the reverse bias region from *Vbs* to $(FC \cdot PB)$.

For reverse bias $Vbs < FC \cdot PB$,

$$Q_{Dj} = \int_{V_{bs}}^{FC \cdot PB} C_{bd} V_{bs} dv$$
(8.332)

$$Q_{Dj} = (CJ \cdot AS \cdot PB) \left(\left(\frac{1.0 \angle V_{bs}}{PB} \right)^{(1 \angle MJ)} \angle \frac{(1.0 \angle FC)^{(1 \angle MJ)}}{(1 \angle MJ)} \right) +$$

$$(CJSW \cdot PS \cdot PB) \left(\left(\frac{1.0 \angle V_{bs}}{PB} \right)^{(1 \angle MJSW)} \angle \frac{(1.0 \angle FC)^{(1 \angle MJSW)}}{(1 \angle MJSW)} \right)$$

$$(8.333)$$

For forward bias $Vbs > FC \cdot PB$,

$$Q_{Dj} = \int_{FC \cdot PB}^{V_{bs}} C_{bd} V_{bs} dv \tag{8.334}$$

$$\mathcal{P}_{Dj} = \frac{CJ \cdot AS \cdot PB}{(10 \angle FC)^{2 \angle MJ}} \cdot \left[(V_{bs} \angle (FC \cdot PB))(1.0 \angle FC(2 \angle MJ)) + \frac{1}{2} \left(\frac{V_{bs}^2}{PB} \angle FC^2 PB \right) (1 \angle MJ) \right] \angle \frac{CJ \cdot SW \cdot PS \cdot PB}{(1.0 \angle FC)^{2 + MJSW}} \cdot \left[(V_{bs} \angle (FC \cdot PB))(1.0 \angle FC(2 \angle MJSW)) + \frac{1}{2} \left(\frac{V_{bs}^2}{PB} \angle FC^2 PB \right) (1 \angle MJ) \right]$$

$$(8.335)$$

Level 3 Equations

The Level 3 MOSFET model is a semi-empirical model developed to handle small-geometry devices.

The drain current in the linear and saturation regions (for Vgs > Vth) is calculated using

$$I'_{ds} = \beta \cdot \left[\frac{1}{1 + V_{ds}\left(\frac{\mu_s V_{max}}{L_1}\right)}\right] \cdot \left[V_{gs} \angle V_{th} \angle \left(\frac{1 + F_B}{2}\right) V_{ds}\right] \cdot V_{ds}$$
(8.336)

where Vds = Vdsat for Vds > Vdsat and Vdsat is defined as follows:

If $Vmax \leq 0.0$,

$$V_{dsat} = \frac{V_{gs} \angle V_{th}}{1 + F_B} \tag{8.337}$$

If Vmax > 0.0,

$$V_{dsat} = \frac{V_{gs} \angle V_{th}}{1 + F_B} + \frac{V_{max} \cdot L_I}{\mu_s} \angle \sqrt{\left(\frac{V_{gs} \angle V_{th}}{1 + F_B}\right)^2 + \left(\frac{V_{max} \cdot L_I}{\mu_s}\right)^2}$$
(8.338)

and

$$\mu_{s} = \frac{\mu_{0}}{1 + \theta(V_{gs} \angle V_{th})}$$
(8.339)

$$\beta = \frac{W_{eff}}{L_I} \mu_s C_{ox} \tag{8.340}$$

$$F_B = \frac{\gamma F_s}{4\sqrt{2\phi_F \angle V_{bs}}} \angle F_n \tag{8.341}$$

$$\mathcal{F}_{s} = 1 \angle \frac{X_{j}}{L_{1}} \left(\frac{LD + W_{c}}{X_{j}} \sqrt{1 \angle \left(\frac{W_{p}}{X_{j} + W_{p}} \right)^{2}} \angle \frac{LD}{X_{j}} \right)$$
(8.342)

$$W_p = X_d \sqrt{2\phi_F \angle V_{bs}} \tag{8.343}$$

$$X_d = \sqrt{\frac{2\varepsilon_{si}\varepsilon_0}{qN_A}}$$
(8.344)

$$\frac{W_c}{X_j} = 0.0631353 + 0.8013292 \frac{W_p}{X_j} \angle 0.01110777 \left(\frac{W_p}{X_j}\right)^2$$
(8.345)

$$F_n = \frac{\varepsilon_{si}\varepsilon_0 \delta \pi}{2C_{ox} W_{eff}}$$
(8.346)

$$V_{th} = V_{FB} + 2\phi_F \angle \sigma V_{ds} + \gamma F_s \sqrt{2\phi_F \angle V_{bs}} + F_n(2\phi_F \angle V_{bs})$$
(8.347)

$$\sigma = \eta \cdot \frac{8.15 \times 10^{222}}{C_{ox}L_I}$$
(8.348)

Channel length modulation is calculated for *Vds* > *Vdsat* as follows:

$$I_{dsat} = I'_{ds} \left(V_{ds} = V_{dsat} \right) \tag{8.349}$$

$$G_{dsat} = \frac{\partial I'_{ds}}{\partial V_{ds}} (V_{ds} = V_{dsat})$$
(8.350)

$$I_{ds} = \frac{I_{dsat}}{1 \angle \left(\frac{L_{I} \angle L'}{L_{I}}\right)}$$
(8.351)

where

$$L_{I} \angle L' = \sqrt{\left(\frac{E_{p}X_{D}^{2}}{2}\right)^{2} + KX_{D}^{2}(V_{ds} \angle V_{dsat})} \angle \left(\frac{E_{p}X_{D}^{2}}{2}\right)$$

$$(8.352)$$

$$E_p = \frac{I_{dsat}}{G_{dsat}L_I}$$
(8.353)

For Vgs < Von, Ids is modified to included the weak inversion component of the drain current.

$$V_{on} = V_{th} + \frac{kT}{q} \cdot N \tag{8.354}$$

$$N = 1 + \frac{q}{C_{ox}} + \frac{\gamma F_s \sqrt{2\phi_F \angle V_{bs}} + F_n(2\phi_F \angle V_{bs})}{2(2\phi_F \angle V_{bs})}$$
(8.355)

$$I'_{ds} = I_{ds} \cdot e^{\frac{q}{NkT} \cdot (V_{gs} \angle V_{on})}$$
(8.356)

Temperature Dependence

The MOSFET model at Levels 1, 2, and 3 contains temperature-dependent model parameters. If a new temperature is specified with the **.temp** command, then these parameters must be modified before they are used in the current equations. The default temperature is 25 °C, which is equivalent to 300.15 K. The parameters affected by temperature changes are: ϕF (Fermi potential), *Eg* (energy gap), *PB* (built-in potential of the drain and source), $\mu \theta$ (mobility), and *Is* (reverse current of the diffused junctions).

The energy gap between the conduction band and the valence band for polysilicon at Tref = 300.15 K and at the new temperature *Tnew* is:

$$E_{g,ref} = 1.16 \angle \left(\frac{7.02 \times 10^{24} \cdot (T_{ref})^2}{1108 + T_{ref}}\right)$$
(8.357)

$$E_{g,new} = 1.16 \angle \left(\frac{7.02 \times 10^{\angle 4} \cdot (T_{new})^2}{1108 + T_{new}}\right)$$
(8.358)

The intrinsic doping is adjusted by different equations depending whether the parameter *PHI* is defined. When *PHI* is *not* defined,

$$n_{i,new} = n_i \left(\frac{T_{new}}{T_{ref}}\right)^{3/2} \left(e^{\frac{q}{k}\left(\frac{E_{g,ref}}{T_{ref}} \ge \frac{E_{g,new}}{T_{new}}\right)}\right)^{1/2}$$
(8.359)

When PHI is defined,

$$n_{i,new} = N_{sub} \left(\frac{T_{new}}{T_{ref}}\right)^{3/2} \left(e^{\frac{q}{k} \left(\frac{E_{g,ref}}{T_{ref}} \le \frac{E_{g,new}}{T_{new}} \le \frac{2\Phi_F}{T_{ref}}\right)}\right)^{1/2}$$
(8.360)

PHI for the new temperature is computed using *ni,new*:

$$\phi_{new} = 2\phi_{F,new} = \left(\frac{2kT_{new}}{q}\right) \ln\left(\frac{N_{sub}}{n_{i,new}}\right)$$
(8.361)

The conduction factor KP and the mobility vary with temperature as

$$\frac{\mu_{0,new}}{\mu_{0,ref}} = \left(\frac{T_{new}}{T_{ref}}\right)^{\angle 3/2}$$
(8.362)

The parameter *KP* or β contains the temperature adjustment when computed from $\mu 0$; however, when *KP* is entered from the model statement, the value is modified as

$$\frac{\beta_{new}}{\beta_{ref}} = \left(\frac{T_{new}}{T_{ref}}\right)^{\angle 3/2}$$
(8.363)

The MOSFET substrate junction diode saturation current varies as

$$\frac{I_{s,new}}{I_{s,ref}} = \left(\frac{T_{new}}{T_{ref}}\right)^3 \left(e^{\frac{q}{k}\left(\frac{E_{g,ref}}{T_{ref}} \le \frac{E_{g,new}}{T_{new}}\right)}\right)$$
(8.364)

The built-in potential PB is adjusted as

$$PB = PB\left(\frac{T_{new}}{T_{ref}}\right) \angle \left(\frac{2kT_{new}}{q}\right) \ln\left(\frac{T_{new}}{T_{ref}}\right)^{3/2} + \left[\left(\frac{T_{new}}{T_{ref}}\right)E_{g,ref} \angle E_{g,new}\right]$$
(8.365)

MOSFET Levels 4 and 13 (BSIM1)

Parameters

.model name nmos | pmos level= 4 | 13 [parameters]

Based on the Berkeley short-channel IGFET model, ©1990 Regents of the University of California. Also see "Additional MOSFET Parameters" on page 455.

Parameter	Description	Default	Units
vfb	Flat band voltage	-0.3	V
lvfb	Length sensitivity of vfb	0.0	$\mu m\cdot V$
wvfb	Width sensitivity of vfb	0.0	$\mu m\cdot V$
pvfb	WL-product sensitivity of vfb	0.0	$\mu m^2 \cdot V$
phi	Surface potential (double the Fermi potential)	0.7	V
lphi	Length sensitivity of phi	0.0	$\mu m\cdot V$
wphi	Width sensitivity of phi	0.0	$\mu m\cdot V$
pphi	WL-product sensitivity of phi	0.0	$\mu m^2 \cdot V$
k1	$\sqrt{V_{sb}}$ threshold coefficient	0.5	V ^{1/2}
lk1	Length sensitivity of k1	0.0	$\mu m \cdot V^{1/2}$
wk1	Width sensitivity of k1	0.0	$\mu m\cdot V^{1/2}$
pk1	WL-product sensitivity of k1	0.0	$\mu m^2 \cdot V^{1/2}$
k2	Linear Vsb threshold coefficient	0.0	_
lk2	Length sensitivity of k2	0.0	μm
wk2	Width sensitivity of k2	0.0	μm
pk2	<i>WL</i> -product sensitivity of k2	0.0	μm^2
eta	Linear Vds threshold coefficient	0.0	_
leta	Length sensitivity of eta	0.0	μm
weta	Width sensitivity of eta	0.0	μm
peta	WL-product sensitivity of eta	0.0	μm^2
muz	Low drain field first-order mobility	600	cm ² / (V·s)
lmuz	Length sensitivity of muz	0.0	$\begin{array}{l} \mu m \cdot cm^2 \\ / (V \cdot s) \end{array}$
wmuz	Width sensitivity of muz	0.0	$\begin{array}{l} \mu m \cdot cm^2 \\ /(V \cdot s) \end{array}$
pmuz	WL-product sensitivity of muz	0.0	$\mu m^2 \cdot cm^2$ /(V · s)

Parameter	Description	Default	Units
dl	Channel length reduction	0.0	μm
dw	Channel width reduction	0.0	μm
u0	Gate field mobility reduction	0.0	1/V
lu0	Length sensitivity of u0	0.0	$\mu m/V$
wu0	Width sensitivity of u0	0.0	$\mu m / V$
pu0	WL-product sensitivity of u0	0.0	$\mu m^2 / V$
u1	Drain field mobility reduction	0.0	1/V
lu1	Length sensitivity of u1	0.0	μm/V
wu1	Width sensitivity of u1	0.0	μm/V
pu1	WL-product sensitivity of u1	0.0	$\mu m^2 / V$
x2mz	Vsb correction to low-field 1st-order mobility	0.0	$cm^2/(V^2 \cdot s)$
lx2mz	Length sensitivity of x2mz	0.0	$\mu m \cdot cm^2$ /(V ² · s)
wx2mz	Width sensitivity of x2mz	0.0	$\mu m \cdot cm$ /(V ² · s)
px2mz	<i>WL</i> -product sensitivity of x2mz	0.0	$\mu m^2 \cdot cm$ /(V ² · s)
x2e	<i>Vsb</i> correction to linear <i>Vds</i> threshold coefficient	0.0	1/V
lx2e	Length sensitivity of x2e	0.0	$\mu m N$
wx2e	Width sensitivity of x2e	0.0	$\mu m / V$
px2e	<i>WL</i> -product sensitivity of x2e	0.0	$\mu m^2 N$
x3e	<i>Vds</i> correction to linear <i>Vds</i> threshold coefficient	0.0	1/V
x3e	Length sensitivity of x3e	0.0	μm/V
wx3e	Width sensitivity of x3e	0.0	μm/V
px3e	<i>WL</i> -product sensitivity of x3e	0.0	$\mu m^2 / V$
x2u0	Vsb reduction to gate field mobility reduction	0.0	$1/V^2$
x2u0	Length sensitivity of x2u0	0.0	$\mu m/V^2$
wx2u0	Width sensitivity of x2u0	0.0	$\mu m/V^2$
px2u0	<i>WL</i> -product sensitivity of x2u0	0.0	$\mu m^2/V^2$
x2u1	Vsb reduction to drain field mobility reduction	0.0	$1/V^2$
x2u1	Length sensitivity of x2u1	0.0	$\mu m/V^2$
wx2u1	Width sensitivity of x2u1	0.0	$\mu m/V^2$
px2u1	<i>WL</i> -product sensitivity of x2u1	0.0	$\mu m^2/V^2$

Parameter	Description	Default	Units
mus	High drain field mobility	600	cm ² / (V·s)
Imus	Length sensitivity of mus	0.0	$\mu m \cdot cm^2$ (V · s)
wmus	Width sensitivity of mus	0.0	μm∙cm², (V∙s)
pmus	WL-product sensitivity of mus	0.0	μm∙cm², (V∙s)
x2ms	Vbs reduction to high drain field mobility	0.0	$cm^2/(V^2 \cdot s)$
lx2ms	Length sensitivity of x2ms	0.0	$\mu m \cdot cm^2$ (V ² ·s)
wx2ms	Width sensitivity of x2ms	0.0	$\mu m \cdot cm^2$ (V ² ·s)
px2ms	<i>WL</i> -product sensitivity of x2ms	0.0	µm · cm², (V · s)
x3ms	<i>Vds</i> reduction to high drain field mobility	5.0	$cm^2/(V^2 \cdot s)$
lx3ms	Length sensitivity of x3ms	0.0	$\mu m \cdot cm^2$ (V ² ·s)
wx3ms	Width sensitivity of x3ms	0.0	$\mu m \cdot cm^2$ (V ² ·s)
px3ms	<i>WL</i> -product sensitivity of x3ms	0.0	$\mu m^2 \cdot cm^2/(V^2 \cdot s)$
x3u1	Vds reduction to drain field mobility reduction	0.0	$1/N^{2}$
lx3u1	Length sensitivity of x3u1	0.0	$\mu m/V^2$
wx3u1	Width sensitivity of x3u1	0.0	$\mu m/V^2$
px3u1	WL-product sensitivity of x3u1	0.0	$\mu m^2 N^2$
tox	Gate oxide thickness	0.02	μm; Å if >1
temp	Temperature	25.0	°C
vdd	Critical voltage for high drain field mobility reduction	5.0	V
cgdo	Gate/drain parasitic capacitance per unit channel width	1.5×10^{-9}	F/m
cgso	Gate/source parasitic capacitance per unit channel width	1.5×10^{-9}	F/m
cgbo	Gate/bulk parasitic capacitance per unit channel length	2.0×10^{-10}	F/m
xpart	Flag for channel charge partitioning	1	

Parameter	Description	Default	Units
n0	Low-field weak inversion gate drive coefficient. A value $\Box \ge 200$ disables weak inversion calculation.	0.5	
In0	Length sensitivity of n0	0.0	μm
wn0	Width sensitivity of n0	0.0	μm
pn0	WL-product sensitivity of n0	0.0	μm^2
nb	Vsb reduction to n0	0.0	_
Inb	Length sensitivity of nb	0.0	μm
wnb	Width sensitivity of nb	0.0	μm
pnb	WL-product sensitivity of nb	0.0	μm^2
nd	Vds reduction to n0	0.0	_
Ind	Length sensitivity of nd	0.0	μm
wnd	Width sensitivity of nd	0.0	μm
pnd	WL-product sensitivity of nd	0.0	μm^2
xl dl Idel	Mask and etching length change	0.0	m
xw dw wdel	Mask and etching width change	0.0	m

MOSFET Level 5 (Maher-Mead)

The Maher-Mead MOSFET model is accurate, physically based, continuous over all transistor regions of operation, including subthreshold, and scales to submicron channel lengths.

Parameters

.model name nmos | pmos level=5 [parameters]

Also see "Additional MOSFET Parameters" on page 455.

Parameter	Symbol	Description	Default	Unit
solver	solver	Nonlinear system solver selector: bisection: solver =0 secant: solver =1	1	—
tox	Tox	Oxide thickness	1.0e-7	m
vmax	Vmax	Saturated velocity of electrons or holes	0	m/s
mu0	μ <i>0</i>	Zero gate field mobility	Computed.	$cm^2/V \cdot s$
nsub	Nsub	Substrate doping	_	cm ⁻³
vfb	Vfb	Flat band voltage	0.0	V
eghalf	Eghalf	Electric field where mobility = mu0	1.0×10^{10}	V/m
ld	Ld	Length adjustment parameter	$0.75 \times xj$	m
wd	Wd	Width adjustment parameter	0.0	m
xl dl Idel	Xl	Mask and etching length change	0.0	m
xw dw wdel	Xw	Mask and etching width change	0.0	m
xj	Xj	Junction depth	0.0	m
del	del	Channel length reduction per side	0.0	m
tnom tref	Tref	Reference temperature	global tnom (25.0)	°C
qstol	qstol	Tolerance for nonlinear solution of source charge	1.0 × 10 ⁻⁸	
qdtol	qdtol	Tolerance for nonlinear solution of drain charge	$1.0 imes 10^{-8}$	
qdmindydx		Lower bound on derivative in nonlinear solution of drain charge	0.01	

Characteristics

The Maher-Mead model is a physically based, charge-controlled model for the DC current, the intrinsic terminal charges, and the transcapacitances in the MOSFET.

The model expresses the current in the MOSFET in terms of the mobile charge per unit area in the channel, and uses a complete set of natural units for velocity, voltage, length, charge, and current. The

current-flow equation for the transistor includes both a drift term and a diffusion term, so that the formulation applies equally over the subthreshold, saturation, and "ohmic" regions of transistor operation and includes the effect of velocity saturation.

The model uses physical parameters derived from the fabrication process by direct measurement and from the dimensions of the device. The model agrees closely with measurements on the scaling of current with channel length down to submicron channel lengths.

MOSFET Levels 8, 49 and 53 (BSIM3 Revision 3.3)

Parameters

```
.model name nmos | pmos level=8|49|53 [parameters]
```

Levels 49 and 53 are based upon the 3.3 version of Berkeley SPICE. They contain the most commonly used HSPICE ACM, parasitic resistor, and parasitic diode extensions. These extensions are described in "Additional MOSFET Parameters" on page 455.

Level 8 is a strict Berkeley v3.30 implementation with the addition of the HSPICE Effective area and Perimeter calculations and parasitic resistor equations, but not the diode equations.

Refer to the Berkeley manual BSIM3v330.pdf for further model parameters and equations.

Model Selectors

Parameter	Symbol	Description	Default
binflag	binflag	Flag for use of xwref and xIref parameters	0 (Off)
capmod	capmod	Flag for short channel capacitance model	1 [v3.0] 0 [v3.1] 3 [≥v3.2]
mobmod	mobmo d	Mobility model selector.	1
nqsmod	nqsmod	Flag for NQS model. This turns the non- quasistatic model equations on or off, and overrides the model parameter value.	0
		<i>Note:</i> This option applies to BSIM3 v3.2 and v3.3 only.	
		nqsmod is a device parameter as well as a device statement.	
version	version	Select version of Berkeley BSIM3: 3.0, 3.1. 3.2, or 3.3.	3.3

Basic Model Parameters

Parameter	Symbol	Description	Default	Units
a1	AI	Non-saturation factor 1	0.0 [n] 0.23 ¹ [p]	V-1
a2	A2	Non-saturation factor 2	1.0 [n] 0.08 [p]	
ags	Ags	Gate bias coefficient of Abulk	0.0	V ⁻¹
alpha0	αθ	1st parameter of impact ionization current	0	m⁄V

Parameter	Symbol	Description	Default	Units
b0	<i>B0</i>	Bulk charge effect coefficient for channel width	0.0	m
b1	B1	Bulk charge effect width offset	0.0	m
beta0	β <i>0</i>	2nd parameter of impact ionization current	30	V
cdsc	Cdsc	Drain/source and channel coupling capacitance	2.4×10^{-4}	F/m ²
cdscb	Cdscb	Body effect coefficient of cdsc	0.0	$F/V \cdot m^2$
cdscd	Cdscd	Drain-bias sensitivity of cdsc	0.0	$F/V \cdot m^2$
cit	Cit	Interface state capacitance	0.0	F/m ²
delta	δ	Effective Vds parameter	0.01	_
drout	DRout	DIBL effect on Rout coefficient	0.56	_
dsub	Dsub	DIBL effect coefficient in subthreshold region	drout	
dvt0	Dvt0	Short channel effect coefficient 0	2.2	
dvt0w	Dvt0w	1 st coefficient of narrow width effect on vth at small L	0	
dvt1	Dvtl	Short channel effect coefficient 1	0.53	
dvt1w	Dvtlw	2nd coefficient of narrow width effect on vth at small L	5.3×10^6	m ⁻¹
dvt2	Dvt2	Short channel effect coefficient 2	-0.032	V ⁻¹
dvt2w	Dvt2w	Body-bias coefficient of narrow width effect on vth at small L	-0.032	V ⁻¹
eta0	η <i>0</i>	Subthreshold region DIBL coefficient	0.08	
etab	η <i>b</i>	Subthreshold region DIBL coefficient	-0.07 V ⁻¹	V ⁻¹
is	Is	Bulk saturation current	$1.0 imes 10^{-14}$	А
k1	K1	1 st order bulk effect coefficient	0.53	V ^{1/2}
k2	K2	2 nd order bulk effect coefficient	-0.0186	
k3	K3	Narrow width effect coefficient	80.0	
k3b	K3b	Body effect coefficient of k3	0.0	V ⁻¹
keta	K _η	Body bias coefficient of non-uniform depletion width effect	-0.047	V ⁻¹

Parameter	Symbol	Description	Default	Units
nch npeak	Nch	Peak doping concentration	1.7 × 10 ¹⁷	cm ⁻³ Note: T-Spice assigns units of m ⁻³ to values > 10 ²³ .
nfactor	Nfactor	Subthreshold swing coefficient	1	
ngate	Ngate	Poly gate doping concentration	0	cm ⁻³
nlx	Nlx	Lateral non-uniform doping effect	1.74×10^{-7}	m
nsub	Nsub	Doping concentration	6.0 × 10 ¹⁶	cm^{-3} Note: T-Spice assigns units of m^{-3} to values > 10^{23} .
oclm	Pclm	Channel-length modulation effect coefficient	1.3	
odiblc1	Pdiblc1	1st output resistance DIBL effect correction parameter	0.39	—
pdiblc2	Pdiblc2	2nd output resistance DIBL effect correction parameter	0.0086	—
pdiblcb	Pdiblcb	Body effect coefficient of DIBL correction parameters	0.0	V ⁻¹
prwb	Prwb	Body effect coefficient of rdsw	0	V ^{1/2}
prwg	Prwg	Gate bias coefficient of rdsw	0	V-1
pscbe1	Pscbel	Substrate current body effect coefficient 1	4.24×10^8	V/m
pscbe2	Pscbe2	Substrate current body effect coefficient 2	$1.0 imes 10^{-5}$	V/m
pvag	Pvag	Vg dependence of Rout coefficient	0.0	V
rdsw	Rdsw	Source/drain resistance per unit width	0.0	Ω⁄µm
tox	Tox	Gate oxide thickness	1.50×10^{-8}	m
u0	μ <i>0</i>	Low-field mobility at tnom	670 [n] 250 [p]	$cm^{2}/V \cdot s$ (≥ 1) $m^{2}/V \cdot s$ (<1)

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Parameter	Symbol	Description	Default	Units
ua	Ua	Linear Vgs dependence of mobility	2.25×10^{-9}	m⁄V
ub	Ub	Quadratic Vgs dependence of mobility	5.87×10^{-18}	m²/V ²
uc	Uc	Body-bias dependence of mobility	-4.65× 10 ⁻¹¹	V ⁻¹
vbm	Vbm	Maximum body voltage	v3.0: −5.0 ≥v3.1: −3.0	V
vfb	vfb	DC flatband voltage.	-1	V
vfbcv	vfbcv	Flatband voltage used in charge/capacitance equations when vfbflag=1 and capmod=0 .	-1	V
vfbflag	vfbflag	Selects vfb for capmod=0. (Vers. 3.2+)	0	
voff	Voff	Threshold voltage offset	-0.08	V
voffcv	Voffcv	C-V parameter for weak to strong inversion transition	0	—
vsat	vsat	Saturation velocity at tnom	8.0×10^4	m⁄s
vtho vth0	Vth0	Threshold voltage.	0.7 [n] -0.7 [p]	V
w0	WO	Narrow width effect coefficient	2.5×10^{-6}	m
wr	Wr	Width offset from <i>Weff</i> for <i>Rds</i> calculation	1.0	
xj	Xj	Junction depth	$1.5 imes 10^{-7}$	m

AC and Capacitance Parameters

Parameter	Symbol	Description	Default	Units
cf	Cf	Fringing field capacitance	Computed,	F⁄m
cgbo	Cgbo	Gate/bulk overlap capacitance per unit channel length	0.0	F⁄m
cgdl	Cgdl	Light doped drain-gate region overlap capacitance	0.0	F/m
cgdo	Cgdo	Gate/drain overlap capacitance per unit channel width	0.0	F⁄m
cgsl	Cgsl	Light doped source-gate region overlap capacitance	0.0	F/m
cgso	Cgso	Gate/source overlap capacitance per unit channel width	0.0	F⁄m
скарра	C _K	Coefficient for lightly doped region overlap capacitance	0.6	F⁄m
clc	CLC	Constant term for short-channel model	0.1 ×10 ⁻⁶	m
cle	CLE	Exponential term for short-channel model	0.6	
xpart	Xpart	Flag for channel charge partitioning	0	—

Length and Width Parameters

Parameter	Symbol	Description	Default	
dic	DLC	Length offset fitting parameter from C-V	lint	m
dwb	dWb	Coefficient of <i>Weff</i> substrate body bias dependence	0.0	$(m/V)^{1/2}$
dwc	DWC	Width offset fitting parameter from C-V	wint	m
dwg	dWg	Coefficient of Weff gate dependence	0.0	m⁄V
lint	Lint	Length offset fitting parameter from I-V without bias	0.0	m
II	Ll	Coefficient of length dependence for length offset	0.0	m ^{lln}
llc	Llc	Coefficient of length dependence for C-V channel width offset	II	m ^{lln}
lln	Lln	Power of length dependence for length offset	1.0	_
lw	Lw	Coefficient of width dependence for length offset	0.0	m ^{lwn}

Parameter	Symbol	Description	Default	
lwc	Lwc	Coefficient of width dependence for C-V channel length offset	lw	m ^{lwn}
lwi	Lwl	Coefficient of length and width cross terms for length offset	0.0	m ^{lln+lwn}
lwlc	Lwlc	Coefficient of length and width cross terms for C-V channel length offset	lwic	m ^{lln+lwn}
lwn	Lwn	Power of width dependence for length offset	1.0	—
wint	Wint	Width offset fitting parameter from I-V without bias	0.0	m
wl	Wl	Coefficient of length dependence for width offset	0.0	m ^{wln}
wic	Wlc	Coefficient of length dependence for C-V channel width offset	wl	m ^{wln}
wIn	Wln	Power of length dependence for width offset	1.0	
ww	Ww	Coefficient of width dependence for width offset	0.0	m ^{wwn}
wwc	Wwc	Coefficient of width dependence for C-V channel width offset	ww	m ^{wwn}
wwl	Wwl	Coefficient of length and width cross terms for width offset	0.0	m ^{wwn+wln}
wwlc	Wwlc	Coefficient of length and width cross terms for C-V channel width offset	wwl	m ^{wwn+wln}
wwn	Wwn	Power of width dependence for width offset	1.0	_
xl dl Idel	Xl	Mask and etching length change	0.0	m
xw dw wdel I	Xw	Mask and etching width change	0.0	m

Temperature Parameters.

Parameter	Symbol	Description	Default	
at	At	Temperature coefficient of vsat	3.3×10^{4}	m⁄s
СТА СТС	CTA CTC	Temperature coefficient for Cj	0.0	deg ⁻¹
СТР	CTP	Temperature coefficient for Cjsw	0.0	deg ⁻¹
EG	Eg(0)	Energy gap at 0° K (Si: 1.166, Ge: 0.74, and GaAs: 1.52)	1.16	eV
GAP1	GAP1	Coefficient in energy gap temperature equation (Si: 4.73×10^{-4} , Ge: 4.77×10^{-4} , and GaAs: 5.41 $\times 10^{-4}$)	7.02×10^{-4}	eV/deg

Parameter	Symbol	Description	Default	
GAP2	GAP2	Coefficient in energy gap temperature equation (Si: 636, Ge: 235, and GaAs: 204	1108	deg
kt1	Ktl	Temperature coefficient of Vth	-0.11	V
kt1l	Ktll	Channel length sensitivity of kt1	0.0	V·m
kt2	Kt2	Body bias coefficient of kt1	0.022	_
prt	Prt	Temperature coefficient for rdsw	0.0	$\Omega\!\cdot\!\mu m$
ΡΤΑ	PTA	Temperature coefficient for Pb	0.0	deg ⁻¹
РТР	PTP	Temperature coefficient for Pbsw	0.0	deg ⁻¹
tlev	tlev	Temperature equation selector	0	_
tlevc	tlevc	Temperature equation selector for junction capacitance and contact potential	0	
tnom tref	T _{ref}	Reference temperature	global tnom (25.0)	deg
TRD	TRD	Temperature coefficient for Rd	0.0	deg ⁻¹
TRS	TRS	Temperature coefficient for Rs	0.0	deg ⁻¹
ua1	Ual	Temperature coefficient of ua	4.31 × 10 ⁻⁹	m⁄V
ub1	Ub1	Temperature coefficient of ub	-7.61×10^{-18}	m^2/V^2
uc1	Ucl	Temperature coefficient of uc	-5.6e-11	V-1
ute	μte	Temperature coefficient of mobility	-1.5	_
ХТІ	XTI	Saturation current temperature exponent	0.0	_

Bin Description Parameters.

Parameter	Symbol	Description	Default	
binunit	binunit	Bin unit selector	1	
Process Parameters				
Parameter	Symbol	Description	Default	Units
em	Em	Maximum electric field	4.1×10^7	V/m

Parameter	Symbol	Description	Default	Units
gamma1	γ1	Vth coefficient 1	Computed	V ^{1/2}
gamma2	γ2	Vth coefficient 2	0.0	V ^{1/2}
vbx	Vbx	Vth transition body voltage	Computed	V
xt	Xt	Doping depth	1.55×10^{-7}	m

NonQuasi-Static Parameters

Parameter	Symbol	Description	Default
elm	elm	Elmore constant	5

Equations

For the complete set of equations describing the Level 49 model, see the *BSIM3v3 Manual* (Ko et al. 1995).

Drain Current

$$I_{ds} = \frac{I_{dso(V_{ds,eff})}}{1 + \frac{R_{ds}I_{dso(V_{ds,eff})}}{V_{ds,eff}}} \left(1 + \frac{V_{ds} \angle V_{ds,eff}}{V_A}\right) \left(1 + \frac{V_{ds} \angle V_{ds,eff}}{V_{ASCBE}}\right)$$
(8.366)

where

$$I_{dso} = \frac{W_{eff} \mu_{eff} C_{ox} V_{gst, eff} \left(1 \angle A_{bulk} \frac{V_{ds, eff}}{2(V_{gst, eff} + 2\nu_t)} \right) V_{ds, eff}}{L_{eff} \left(1 + \frac{V_{ds, eff}}{E_{sat} L_{eff}} \right)}$$
(8.367)

$$Y_{ds,eff} = V_{dsat} \angle \frac{1}{2} (V_{dsat} \angle V_{ds} \angle \delta + \sqrt{(V_{dsat} \angle V_{ds} \angle \delta)^2 + 4\delta V_{dsat}}$$
(8.368)

$$E_{sat} = \frac{2v_{sat}}{\mu_{eff}}$$
(8.369)

$$v_t = \frac{kT}{q} \tag{8.370}$$

Variables for which equations are not given here are as follows.

 V_A

Early voltage

V _{ASCBE}	Early voltage due to substrate current-induced body effect
V _{gst,eff}	Effective Vgs – Vth (Vth: effective threshold voltage)
$\mu_{e\!f\!f}$	Effective mobility
A_{bulk}	Bulk charge effect factor
V _{dsat}	Drain saturation voltage

Gate Charge

$$Q_g = \angle (Q_{acc} + Q_{sub0} + \delta Q_{sub} + Q_{inv})$$
(8.371)

Variables for which equations are not given here are as follows.

Q_{acc}	Channel majority or accumulation charge
Q_{sub0}	Substrate charge at $Vds = 0$
Q_{sub}	Non-uniform substrate charge in presence of drain bias
Q_{inv}	Qs + Qd = channel minority or inversion charge

MOSFET Levels 9 and 50 (Philips MOS 9)

Philips MOS Model 9 is a compact MOS-transistor model, intended for the simulation of circuit behaviour with emphasis on analog applications. The model gives a complete description of all transistor-action related quantities: nodal currents and charges, noise-power spectral densities and weak-avalanche currents. The equations describing these quantities are based on the gradual-channel approximation with a number of first-order corrections for small-size effects. The consistency is maintained by using the same carrier-density and electrical-field expressions in the calculation of all model quantities. MOS Model 9 only provides a model for the intrinsic transistor. Junction charges and leakage currents are not included. They are covered by the separate **Juncap** model.

The MOS 9 model is fully documented in Philips MOS 9.

For further detailed information about the MOS 9 model, please refer to the Philips Compact Model Webpage:

<u>http://www.semiconductors.philips.com/Philips_Models/model9</u>

Parameters

The MOS 9 model uses the following syntax.

.model name nmos | pmos level=[9|50] | model=modelname [parameters]

T-Spice includes support for MOS 9 versions 902 and 903, and for both geometrical and electrical based model parameter sets.

The available modelname values for the MOS 9 model selection are:

Modelname	Description
mos902	Mos 9 level 902, geometrical
mos902e	Mos 9 level 902, electrical
mos903 (default)	Mos 9 level 903, geometrical
mos903e	Mos 9 level 903, electrical

MOSFET Levels 11 and 63 (Philips MOS 11)

MOS Model 11 has been developed as the successor of MOS Model 9. It is a symmetrical, surfacepotential-based model, giving an accurate physical description of the transition from weak to strong inversion. MOS 11 includes an accurate description of all physical effects important for modern and future CMOS technologies, such as:

mobility reduction bias-dependent series resistance velocity saturation conductance effects (CLM, DIBL, etc.) gate leakage current gate-induced drain leakage gate depletion quantum-mechanical effects bias-dependent overlap capacitances

The description of the source-bulk and drain-bulk junction diode is not included in MOS Model 11. The behaviour of these junction diodes is modelled by the Juncap model. This model has to be added between the source and bulk node and between the drain and bulk node. The MOS 11 model is fully documented in Philips MOS 11.

The MOS 11 model is fully documented in **Philips MOS 11**.

For further detailed information about the MOS 11 model, please refer to the Philips Compact Model Webpage:

http://www.semiconductors.philips.com/Philips Models/model11

Parameters

The MOS 11 model uses the following syntax.

.model name nmos | pmos level=[11|63] | model=modelname [parameters]

T-Spice includes support for Mos 11 versions 1100, 1101, and 1102. Each of these versions, in turn, offers a selection of electrical or geometrical based parameterization, modeling of self-heating effects, and model binning

The available *modelname* values for the Mos 11 model are:

Modelname	Description
mos1100	Mos 11 level 1100, geometrical
mos1100e	Mos 11 level 1100, electrical
mos1101	Mos 11 level 1101, electrical
mos1101t	Mos 11 level 1101, electrical, self-heating
mos11010	Mos 11 level 1101, geometrical
mos11010t	Mos 11 level 1101, geometrical, self-heating
mos11011	Mos 11 level 1101, geometrical, binning

mos11011t	Mos 11 level 1101, geometrical, binning, self-heating
mos1102	Mos 11 level 1102, electrical
mos1102t	Mos 11 level 1102, electrical, self-heating
mos11020 (default)	Mos 11 level 1102, geometrical
mos11020t	Mos 11 level 1102, geometrical, self-heating
mos11021	Mos 11 level 1102, geometrical, binning
mos11021t	Mos 11 level 1102, geometrical, binning, self-heating

MOSFET Levels 14 and 54 (BSIM4 Revision 5)

Parameters

```
.model name nmos | pmos level=14 | 54 [parameters]
```

Levels 14 and 54 are fully compliant with the original UC Berkeley release of BSIM4 Revision 5. For standard model parameters and equations, refer to the Berkeley manual **BSIM450.pdf**. Specific device instance statements and their parameters are shown in the following section.

Syntax

General MOSFET device parameters (length, width, drain, source, etc.) are described in the device statement chapter under "MOSFET (m)" on page 175. In the case of device values which have corresponding model values, the device settings override the model settings.

Device instance parameters for BSIM4 are as follows:

```
mname drain gate source bulk model [l=L] [w=W] [ad=Ad] [pd=Pd] [as=As]
[ps=Ps] [nrd=Nrd] [nrs=Nrs] [M=M] [acnqsmod=acnqsmod] [geomod=geomod]
[min=min] [nrd=nrd] [nrs=nrs] [rbdb=rbdb] [rbodymod=rbodymod] [rbpb=rbpb]
[rbpd=rbpd] [rbps=rbps] [rbsb=rbsb] [rgatemod=rgatemod] [rgeomod=rgeomod]
[trnqsmod=trnqsmod] [sa=sa] [sb=sb] [sd=sd]
```

acnqsmod	AC small-signal NQS model selector
geomod	Geometry-dependent parasitics model selector - specifying how the end S/D diffusions are connected
min	Wheter to minimize the number of drain or source diffusions for even-number finger devices
nf	Number of device fingers
nrd	Number of drain diffusion squares
nrs	Number of source diffusion squares
rbdb	Resistance connected between dbNode and bNode
rbodymod	Substrate resistance network model selector
rbpb	Resistance connected between bNodePrime and bNode
rbpd	Resistance connected between bNodePrime and dbNode
rbps	Resistance connected between bNodePrime and sbNode
rbsb	Resistance connected between sbNode and bNode
rgatemod	Gate resistance model selector
rgeomod	Source/drain diffusion resistance and contact model selector - specifying the end S/D contact type: point, wide or merged, and how S/D parasitics resistance is computed
trnqsmod	Transient NQS model selector
sa	Distance between OD edge to Poly from one side

sb	Distance between OD edge to Poly from other side
sd	Distance between neighboring fingers

MOSFET Levels 15 and 61 (RPI Amorphous-Si TFT Model)

Level 15 is a thin-film transistor (TFT) amorphous silicon (a-Si) model developed at Rensselaer Polytechnic Institute (RPI).

This model is based on the universal charge control concept, which allows for currents and the large and small-signal parameters to be written as continuous functions of the applied bias, providing smooth transitions between the different operating regimes. Interpolation techniques are applied to the equations to unify the model.

Note that contrary to devices such as SOI MOSFETs, self-heating in a-Si TFT leads to an increase in current, since the carrier mobility increases with the temperature.

Physical effects included in MOS Model 15 include: Above threshold: Modified charge control model; induced charge trapped in localized states Field effect mobility becoming a function of gate bias Band mobility dominated by lattice scattering

Below threshold:

Fermi level located in deep localized states

Relate position of Fermi level, including the deep DOS back to the gate bias Empirical expression for current at large negative gate biases for hole-induced leakage current. Interpolation techniques are applied to the equations to unify the model.

Note:

The T-Spice implementation of the RPI a-Si TFT model supports model binning. The additional model parameters for this are **Imin**, **Imax**, **wmin**, **wmax**, **xl**, **xlref**, **xw**, and **xwref**, described in the section "Additional MOSFET Parameters" on page 455.

Parameters

This is a 3-terminal model. Because no bulk node exists, no parasitic drain-bulk or source-build diodes are appended to the model. You can specify a fourth node but it will not affect simulation results. The drain and source areas and perimeters are not used either, since the model equation is based solely upon the width and length.

Device instance parameters for MOS level 15 are as follows:

mname drain gate source model [L=1] [W=w] [M=m][TEMP=t]

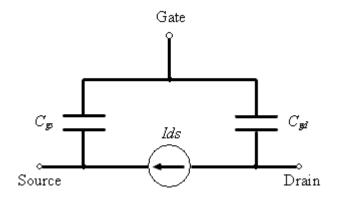
The parameter definitions (L, W, and M) are the MOSFET standards (see "MOSFET (m)" on page 175), and TEMP is the device temperature (C).

For further detailed information please refer to the Rensselaer Polytechnic Institute research papers in the T-Spice models folder.

Parameter	Description	Default	Units
ALPHASAT	Saturation modulation parameter	0.6	_
CGDO	Gate-drain overlap capacitance per meter channel width	0.0	F/m

Parameter	Description	Default	Units
CGSO	Gate-source overlap capacitance per meter channel width	0.0	F/m
DEFO	Dark Fermi level position	0.6	eV
DELTA	Transition width parameter	5	-
EL	Activation energy of the hole leakage current	.35	eV
EMU	Field effect mobility activation energy	0.06	eV
EPS	Relative dielectric constant of substrate	11	-
EPSI	Relative dielectric constant of gate insulator	7.4	-
GAMMA	Power law mobility parameter	0.4	-
GMIN (GO, G0)	Minimum density of deep states	1E23	m ⁻³ eV ⁻¹
IOL	Zero bias leakage current parameter	3E-14	А
KASAT	Temperature coefficient of ALPHASAT	0.006	1/° C
кут	Threshold voltage temperature coefficient	-0.036	V/° C
LAMBDA	Output conductance parameter	0.0008	1/V
M (MSAT)	Knee shape parameter	2.5	-
MUBAND	Conduction band mobility	0.001	m²/Vs
RD	Drain resistance	0.0	μ
RS	Source resistance	0.0	μ
SIGMA0 (sigma0)	Minimum leakage current parameter	1E-14	А
TNOM (TREF)	Parameter measurement temperature	global Tnom	oC
тох	Thin-oxide thickness	1E-7	m
V0	Characteristic voltage for deep states	0.12	V
VAA	Characteristic voltage for field effect mobility	7.5E3	V
VDSL	Hole leakage current drain voltage parameter	7	V
VFB	Flat band voltage	-3	V
VGSL (VGL)	Hole leakage current gate voltage parameter	7	V
VMIN	Convergence parameter	0.3	V
VTO (VT0)	Zero-bias threshold voltage	0.0	V

Equivalent Circuit



MOSFET Levels 16 and 62 (RPI Poly-Si TFT Model, 1.0 and 2.0)

Level 16 is a thin-film transistor (TFT) poly-silicon (Poly-Si) model developed at Rensselaer Polytechnic Institute (RPI).

MOS level 16 improves on existing devices models by including the necessary dependencies to make it scalable from long-channel to short-channel devices.

This model accounts for some effects that are specific to poly-Si TFTs, including the kink effect, the increase of the field-effect mobility as the gate voltage is increased in moderate inversion, the offcurrent, the DIBL (Drain Induced Barrier Lowering) and velocity saturation effects, as well as series resistances. The DIBL effect is more pronounced in poly-Si TFTs than in crystalline MOSFETs and cannot be neglected even for long-channel devices.

More specifically,

- Field effect mobility becomes a function of gate bias
- Effective mobility that accounts for trap states, for low V gs using a power law, for high V gs a constant.
- A unified DC model that includes all four regimes for channel lengths down to 4 m—leakage (thermionic emission), subthreshold (diffusion-like model), above threshold (c-Si-like, with mFet) and kink (impact ionization with feedback).
- An AC model that accurately reproduces C_{gc} frequency dispersion
- An automatic scaling of model parameters to accurately model a wide range of device geometries

Note:

The T-Spice implementation of the RPI Poly-Si TFT model supports model binning. The additional model parameters for this are **Imin**, **Imax**, **wmin**, **wmax**, **xl**, **xlref**, **xw**, and **xwref**, described in the section "Additional MOSFET Parameters" on page 455.

Parameters

This is a 3-terminal model. MOS level 16 does not use a bulk node; there are no corresponding drainbulk or source-bulk diodes to be modeled. You can specify a fourth node but it does it not affect simulation results.

Device instance parameters for MOS level 16 are as follows:

```
mname drain gate source model [L=1] [W=w] [NRS=nrs] [NRD=nrd] [M=m] [TEMP=t]
```

The parameter definitions (L, W, NRS, NRD, M, etc.) are the MOSFET standard ones (see "MOSFET (m)" on page 175). TEMP is the device temperature (C).

For further detailed information please refer to the Rensselaer Polytechnic Institute papers in the T-Spice models folder.

Parameter	Description	Default	Units
ASAT	Proportionality constant of Vsat	1	-
AT	DIBL parameter 1	3E-8	m/V

Parameter	Description	Default	Units
BLK	Leakage barrier lowering constant	0.001	-
BT	DIBL parameter 2	1.9E-6	m·V
CAPMOD	Capacitance model selector	0	-
CGDO	Gate-drain overlap capacitance per meter channel width	0.0	F/m
CGSO	Gate-source overlap capacitance per meter channel width	0.0	F/m
DASAT	Temperature coefficient of ASAT	0	1/°C
DD	Vds field constant	1400 Å	m
DELTA	Transition width parameter	4.0	-
DG	Vgs field constant	2000 Å	m
DMU1	Temperature coefficient of MU1	0	cm ² /Vs° C
DVT	The difference between VON and the threshold voltage	0	V
DVTO	Temperature coefficient of VTO	0	V/°C
EB	Barrier height of diode	0.68	EV
ETA (ETAI)	Subthreshold ideality factor	7	-
ETAC0	Capacitance subthreshold ideality factor at zero drain bias	ETA	-
ETAC00	Capacitance subthreshold coefficient of drain bias	0	1/V
10 (CLK)	Leakage scaling constant	6.0	A/m
100	Reverse diode saturation current	150	A/m
LASAT	Coefficient for length dependence of ASAT	0	М
LKINK	Kink effect constant	19E-6	М
мс	Capacitance knee shape parameter	3.0	-
MK (MKINK)	Kink effect exponent	1.3	-
MMU (M)	Low field mobility exponent	1.7	-
MU0	High field mobility	100	cm ² /Vs
MU1	Low field mobility parameter	0.0022	cm ² /Vs
MUS	Subthreshold mobility	1.0	cm ² /Vs
RD	Drain resistance	0.0	W
RDX	Resistance in series with Cgd (RF)	0	W
RS	Source resistance	0.0	W
RSH	Sheet resistance	0	Ω/sq
RSX (RI)	Resistance in series with Cgs	0	W

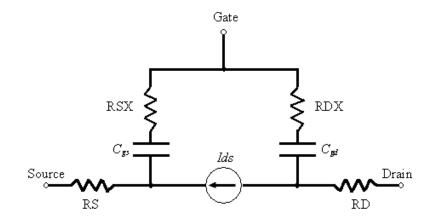
Parameter	Description	Default	Units
TNOM (TREF)	Parameter measurement temperature	27	°C
тох	Thin-oxide thickness	1.0e-7	m
VFB	Flat band voltage	-0.1	V
VKINK	Kink effect voltage	9.1	V
VON	On-voltage	0	V
ντο	Zero-bias threshold voltage	0.0	V

Version 2.0 Parameters

Version 1.0 is the standard release of the Poly-Si model, equivalent to the AimSpice level 16 PSIA2 model. Version 2.0 (selected using the model parameter VERSION=2.0) is a newer release, and includes an intrinsic resistance model, alternate channel length modulation equations, and DIBL (drain induced barrier lowering) equations.

Parameter	Description	Default	Units
INTDSNOD	Extrinsic resistance mode selector	0	-
ISUBMOD	Channel length modulation equation selector	0	-
LAMBDA	Channel length modulation parameter	.048	m/V
LS	Channel length modulation parameter	35e-9	m/V
ME (MS)	Long channel saturation transition parameter	2.5	-
META	Eta floating body parameter	1.0	-
MSS	Vdse transition parameter	1.5	-
THETA	Mobility degradation parameter	0	1/V
VMAX	Saturation velocity	4e4	m/s
VP	Channel length modulation parameter	0.2	V
VSIGMA	Above threshold DIBL parameter	0.2	V
VSIGMAT	Above threshold DIBL parameter	1.7	V

Equivalent Circuit



MOSFET Level 20 (Philips MOS 20)

MOS Model 20 is a compact LDMOS model, which combines the MOSFET operation of the channel region with that of the drift region under the thin gate oxide. As such, it is aimed as a successor of MOS Model 9 in series with MOS Model 31. MOS Model 20 has especially been developed to improve the convergence behaviour during simulation, by having the voltage at the transition from the channel region to the drift region calculated inside the model itself.

The MOS 20 model is fully documented in Philips MOS 20.

For further detailed information about the MOS 20model, please refer to the Philips Compact Model Webpage:

http://www.semiconductors.philips.com/Philips Models/high voltage/model20

Parameters

The MOS 20 model uses the following syntax.

.model name nmos | pmos level=20 | model=modelname [parameters]

T-Spice includes support for MOS 20 version 2001 with geometrical and electrical model parameterization, and self-heating effects.

The available modelname values for the MOS 20 model selection are:

Modelname	Description
mos2001 (default)	Mos 20 level 2001, geometrical
mos2001e	Mos 20 level 2001, electrical
mos2001et	Mos 20 level 2001, electrical, self-heating

MOSFET Level 28 (Extended BSIM1)

.model	name	nmos	pmos	level=28	[parameters]

T-Spice supports MOSFET model level 28, based on the Berkeley short-channel IGFET models. The Extended BSIM1 level 28 model is a proprietary Tanner Research extension to the core BSIM1 model developed at Berkeley. The extensions attempt to fix many of the problems in the original model equations, including:

- Negative output conductance in the saturation region of operation.
- Discontinuities in the output conductance at the transition between the linear and saturation regions of operation.
- Discontinuities in the subthreshold current and transconductance characteristics near threshold.

In addition, the core equations have been enhanced to correct deficiencies in the original model equations:

- Temperature compensation equations have been added for proper handling of temperature effects.
- Effective length-width product scaling factors have been added for use with the BSIM3 revision 3 scaling equations.

Note: T-Spice accepts BSIM1 model parameters entered in the level 13 and level 28 conventions used by HSPICETM1.

Level 13 model parameters are translated to standard BSIM1 model (see "MOSFET Levels 4 and 13 (BSIM1)" on page 410.)

Level 28 model parameters are automatically translated to the extended BSIM1 model as shown below.

Parameters

Following are the Tanner Extended BSIM1 MOSFET model parameters.

Parameter	Description	Default	Units
tempmod	Temperature model selector. tempmod=0 disables the temperature compensation equation. tempmod>0 enables the temperature compensation equation.	0	
ute	Temperature exponent for mobility	1.5	—
lute	Length sensitivity of ute	0.0	_
wute	Width sensitivity of ute	0.0	_
pute	<i>WL</i> -product sensitivity of ute	0.0	—
kt1	Temperature coefficient for flat band voltage	0.0	V
lkt1	Length sensitivity of kti	0.0	$\mu m \cdot V$
wkt1	Width sensitivity of kti	0.0	$\mu m \cdot V$
pkt1	WL-product sensitivity of kti	0.0	$\mu m^2 \!\cdot\! V$

1 HSPICE(®) is a registered trademark of Synopsys, Inc.

Parameter	Description	Default	Units
submod	Subthreshold current model selector	0	—
voffset	Subthreshold offset voltage above threshold	0.0	V
lvoffset	Length sensitivity of voffset	0.0	$\mu m \cdot V$
wvoffset	Width sensitivity of voffset	0.0	$\mu m \!\cdot\! V$
pvoffset	WL-product sensitivity of voffset	0.0	$\mu m^2 \cdot V$
iratio	Subthreshold current factor	e ⁻²	
liratio	Length sensitivity of iratio	0.0	—
wiratio	Width sensitivity of iratio	0.0	—
piratio	WL-product sensitivity of iratio	0.0	—
satmod	Saturated drain current model selector	0	—
alpha	Saturated drain current knee parameter	1.0	
lalpha	Length sensitivity of alpha	0.0	—
walpha	Width sensitivity of alpha	0.0	—
palpha	WL-product sensitivity of alpha	0.0	
gamma	Saturated drain current output conductance parameter	0.0	_
Igamma	Length sensitivity of gamma	0.0	
wgamma	Width sensitivity of gamma	0.0	
pgamma	WL-product sensitivity of gamma	0.0	
xj	Junction depth	0.0	m
wmlt	Width shrink factor	1.0	_

Equations

Process Parameters

Process parameters express the sensitivity of the BSIM1 electrical parameters to device length, width, and the product of length and width (*WL*-product). The SPICE names of process parameters are derived from the related electrical parameter names by prefixing the letters I, w, and p.

The actual value of an electrical parameter P is

$$P = P_0 + \frac{P_L}{L_i \angle \Delta L} + \frac{P_W}{W_i \angle \Delta W} + \frac{P_P}{(L_i \angle \Delta L)(W_i \angle \Delta W)}$$
(8.372)

where PL, PW, and PP denote P's length, width, and product sensitivity parameters, respectively.

Drain Current

Drain current is modeled by three equations, representing the three regions of MOSFET operation: *cutoff, linear*, and *saturation*.

Cutoff region: $Vgs \le Vth$

$$I_{ds} = 0$$
 (8.373)

Linear region: Vgs > *Vth* and 0 < *Vds* < *Vd,sat*

$$Y_{ds} = \frac{\mu_0}{1 + U_0(V_{gs} \angle V_{th})} \cdot \frac{C'_{ox} \frac{W_{eff}}{L_{eff}}}{\left(1 + \frac{U_l}{L_{eff}} V_{ds}\right)} \cdot \left[(V_{gs} \angle V_{th}) V_{ds} \angle \frac{a}{2} V_{ds}^2 \right]$$
(8.374)

where

$$a = \frac{1 + gK_I}{2\sqrt{\phi_s \, \angle \, V_{bs}}} > 1 \tag{8.375}$$

and

$$g = 1 \angle \frac{1}{1.744 + 0.8364(\phi_s \angle V_{bs})}$$
(8.376)

Saturation region: Vgs > Vth and $Vds \ge Vd, sat$

$$I_{ds} = \frac{\mu_0}{1 + U_0(V_{gs} \angle V_{th})} \cdot \frac{C'_{ox} \frac{W_{eff}}{L_{eff}}}{2aK} \cdot (V_{gs} \angle V_{th})^2$$
(8.377)

where

$$K = \frac{1 + v_c + \sqrt{1 + 2v_c}}{2} \tag{8.378}$$

and

$$v_c = \frac{U_l}{L_{eff}} \cdot \frac{(V_{gs} \angle V_{th})}{a}$$
(8.379)

In the linear and saturation regions,

$$V_{d,sat} = \frac{V_{gs} \angle V_{th}}{a \sqrt{K}}$$
(8.380)

$$U_0(V_{ds}, V_{bs}) = U_{0z} + U_{0b}V_{bs}$$
(8.381)

$$U_{I}(V_{ds}, V_{bs}) = U_{1z} + U_{1b}V_{bs} + U_{1d}(V_{ds} \angle V_{dd})$$
(8.382)

 $\mu \theta$ is computed by quadratic interpolation given three conditions:

$$\mu_0(V_{ds} = 0) = \mu_z + \mu_{zb}V_{bs} \tag{8.383}$$

$$\mu_0(V_{ds} = V_{dd}) = \mu_s + \mu_{sb}V_{bs}$$
(8.384)

and the sensitivity of $\mu \theta$ to the drain bias at Vds = Vdd.

Subthreshold Current

The total drain current is modeled as the sum of two components: the *strong inversion* component Ids,s, equivalent to the drain current modeled in equations (8.373) through (8.384), and the weak inversion component Ids,w:

$$I_{ds,w} = \frac{I_{exp}I_{limit}}{I_{exp} + I_{limit}}$$
(8.385)

where

$$I_{exp} = \mu_0 C'_{ox} \frac{W_{eff}}{L_{eff}} \left(\frac{kT}{q}\right)^2 e^{1.8} e^{q(V_{gs} \angle V_{th})/nkT} (1 \angle e^{\angle qV_{ds}/kT})$$
(8.386)

and

$$I_{limit} = \frac{\mu_0 C'_{ox}}{2} \frac{W_{eff}}{L_{eff}} \left(\frac{3kT}{q}\right)^2$$
(8.387)

The subthreshold parameter n is modeled as

$$n(V_{ds}, V_{bs}) = n_0 + n_b V_{bs} + n_d V_{ds} > 0.5$$
(8.388)

MOSFET Level 30 (Philips MOS 30)

MOS Model 30 is a long channel JFET/MOSFET model developed to describe the drift region of LDMOS, EPMOS and VDMOS devices.

Note: MOS Model 30 has been replaced with the MOS 31 model, and is provided for historical and compatibility purposes only. It's use is not recommended.

The MOS 30 model is fully documented in Philips MOS 30.

Parameters

The MOS 30 model uses the following syntax.

.model name nmos | pmos level=30 | model=mos3002 [parameters]

T-Spice includes support for MOS 30 version 3002 with electrical model parameterization.

MOSFET Level 31 (Philips MOS 31)

MOS Model 31 is a physics based transistor model to be used in circuit simulation and IC-design of analog high-voltage applications. The model describes the electrical behaviour of a junction-isolated accumulation/depletion-type MOSFET. The model is used as the drain extension of high-voltage MOS devices, like the Lateral Double-diffused MOS (LDMOS), the Vertical Double-diffused MOS (VDMOS), and the Extended MOS transistors. Physical effects included in MOS Model 31:

Both accumulation and depletion underneath the gate oxide; Depletion from the substrate (a pn-junction); Pinch-off effects; Velocity saturation; and Temperature scaling.

The MOS 31 model is fully documented in Philips MOS 31.

For further detailed information about the MOS 31 model, please refer to the Philips Compact Model Webpage:

<u>http://www.semiconductors.philips.com/Philips_Models/high_voltage/model31</u>

Parameters

The MOS 31 model uses the following syntax.

.model name nmos | pmos level=31 | model=modelname [parameters]

T-Spice includes support for MOS 31 version 3100 with and without self-heating effects.

The available modelname values for the MOS 31 model selection are:

Modelname	Description
mos3100 (default)	Mos 31 level 3100, electrical
mos3100t	Mos 31 level 3100, electrical, self-heating

MOSFET Level 40 (Philips MOS 40)

MOS Model 40 is a physics based transistor model to be used in circuit simulation and IC-design of analogue high-voltage applications processed in Silicon-on-Insulator (SOI). The model describes the electrical behavior of an accumulation/depletion-type MOSFET in SOI. The model is used as drain extension of high-voltage MOS devices, like the Lateral Double-diffused MOS (LDMOS), the Vertical Double-diffused MOS (VDMOS), and the Extended MOS transistors. Physical effects in MOS Model 40 include:

Both accumulation and depletion underneath the gate oxide; Both accumulation and depletion from the substrate (an oxide layer); Pinch-off effects; Velocity saturation; and Temperature scaling.

The MOS 40 model is fully documented in Philips MOS 40.

For further detailed information about the MOS 40 model, please refer to the Philips Compact Model Webpage:

<u>http://www.semiconductors.philips.com/Philips_Models/high_voltage/model40</u>

Parameters

The MOS 40 model uses the following syntax.

.model name nmos | pmos level=40 | model=modelname [parameters]

T-Spice includes support for MOS 40 version 40 with and without self-heating effects.

The available *modelname* values for the MOS 40 model selection are:

Modelname	Description
mos40 (default)	Mos 40 level 40, electrical
mos40t	Mos 40 level 40, electrical, self-heating

MOSFET Levels 44 and 55 (EKV Revision 2.6)

Parameters

.model name nmos | pmos level=44 | 55 [parameters]

For model parameters, model equations and device instance statements and their parameters, refer to the Swiss Federal Institute of Technology manual **EKV_v262.pdf**.

MOSFET Level 47 (BSIM3 Revision 2)

Parameters

.model name nmos | pmos level=47 [parameters]

Based on the Berkeley short-channel IGFET model, ©1990 Regents of the University of California.]

Also see "Additional MOSFET Parameters" on page 455.

Parameter	Symbol	Description	Default	Units
subthmod	subthmo d	Subthreshold model selector	2	_
satmod	satmod	Saturation model selector	2	—
bulkmod	bulkmo d	Bulk charge effect model selector	1 [n] 2 [p]	—
mobmod	mobmo d	Mobility model selector	1	_
tox	Tox	Gate oxide thickness	1.50×10^{-8}	m
cdsc	Cdsc	Drain/source and channel coupling capacitance	2.4×10^{-4}	F/m^2
cdscb	Cdscb	Body effect coefficient of cdsc	0.0	$F/V \cdot m^2$
cit	Cit	Interface state capacitance	0.0	F/m ²
nfactor	Nfactor	Swing coefficient	1	—
xj	Xj	Junction depth	1.50e-7	m
vsat	vsat	Saturation velocity at tnom	8.0×10^{-6}	cm/s
at	At	Temperature coefficient of vsat	3.3×10^{-4}	m/s
a0	AO	Non-uniform depletion width effect coefficient	1.0 [bulkmod=1] 4.4 [bulkmod=2]	_
a1	Al	Non-saturation factor 1	0.0 [n] 0.23 [p]	1/V
a2	A2	Non-saturation factor 2	1.0 [n] 0.08 [p]	
keta	Keta	Body bias coefficient of non-uniform depletion width effect	-0.047	1/V
vghigh	Vghigh	High bound of transition region	0.12	V
vglow	Vglow	Low bound of transition region	-0.12	V
nsub	Nsub	Doping concentration	6.0×10^{16}	cm^{-3} ($\leq 10^{20}$) m^{-3} (>10^{20})

Parameter	Symbol	Description	Default	Units
nch ∣ npeak	Npeak	Peak doping concentration	1.7×10^{17}	$\begin{array}{c} cm^{-3} \\ (\leq 10^{23}) \\ m^{-3} \\ (> 10^{23}) \end{array}$
ngate	Ngate	Gate doping concentration	0.0	cm ⁻³
gamma1	γ1	Vth coefficient	0.0	V ^{1/2}
gamma2	γ <i>2</i>	Vth coefficient 2	0.0	V ^{1/2}
/bx	Vbx	Vth transition body voltage	0.0	V
/bi	Vbi	Drain/source junction built-in potential	0.0	V
/bm	Vbm	Maximum body voltage	-5.0	V
ct	Xt	Doping depth	1.55×10^{-7}	m
ohi	φ	Strong inversion surface potential	Computed	V
itl	Litl	Depth of current path	0.0	m
em	Em	Maximum electric field	$4.1 imes 10^7$	V/m
c1	Kl	Bulk effect coefficient 1	0.0	V ^{1/2}
xt1	Ktl	Temperature coefficient of Vth	-0.11	V
ct1l	Ktll	Channel length sensitivity of kt1	0.0	$V\!\cdot\!m$
xt2	Kt2	Body bias coefficient of kt1	0.022	
(2	K2	Bulk effect coefficient 2	0.0	—
(3	K3	Narrow width effect coefficient	80.0	—
(3b	K3b	Body effect coefficient of k3	0.0	1/V
v0	WO	Narrow width effect coefficient	$2.5 imes 10^{-6}$	m
nlx	Nlx	Lateral non-uniform doping effect	1.74×10^{-7}	m
lvt0	Dvt0	Short channel effect coefficient 0	2.2	_
dvt1	Dvtl	Short channel effect coefficient 1	0.53	
lvt2	Dvt2	Short channel effect coefficient 2	-0.032	1/V
lrout	DRout	DIBL effect on Rout coefficient	0.56	
lsub	Dsub	DIBL effect coefficient in subthreshold region	drout	
∕tho ∣ vth0	Vth	Threshold voltage	0.7 [n] –0.7 [p]	V
Ja	Ua	Linear Vgs dependence of mobility	2.25×10^{-9}	m/V
la1	Ual	Temperature coefficient of ua	4.31×10^{-9}	m/V
dı	Ub	Quadratic Vgs dependence of mobility	$5.87 imes 10^{-19}$	m^2/V^2
ub1	Ubl	Temperature coefficient of ub	-7.61×10^{-18}	m^2/V^2
uc	Uc	Body-bias dependence of mobility	0.0465	1/V
uc0	Uc0	Mobility coefficient	0.0	V^2/m^2

Parameter	Symbol	Description	Default	Units
uc1	Ucl	Temperature coefficient of uc	-0.056	1/V
u0	μ <i>0</i>	Low-field mobility at tnom	670.0 [n] 250.0 [p]	$cm^2/V \cdot s$ (≥ 1) $m^2/V \cdot s$ (< 1)
ute	μte	Temperature coefficient of mobility	-1.5	—
voff	Voff	Threshold voltage offset	-0.11	V
vfb	Vfb	Flat band voltage	-1.0	V
dl ld	Dl	Channel length reduction	0.0	m
dw wd	Dw	Channel width reduction	0.0	m
Imit	Lmlt	Length shrink factor	1.0	_
wmlt	Wmlt	Width shrink factor	1.0	_
xl dl Idel	Xl	Mask and etching length reduction factor	0.0	
xw dw wdel	Xw	Mask and etching width reduction factor	0.0	—
tnom tref	Tnom	Temperature	25.0	°C
cgso ∣ cgsom	Cgso	Gate/source overlap capacitance per unit channel width	0.0	F/m
cgdo ∣ cgdom	Cgdo	Gate/drain overlap capacitance per unit channel width	0.0	F/m
cgbo∣ cgbom	Cgbo	Gate/bulk overlap capacitance per unit channel length	0.0	F/m
xpart	Xpart	Flag for channel charge partitioning	0.0	
rdsw	Rdsw	Source/drain resistance per unit width	0.0	$\Omega \cdot \mu m$
rds0	Rds0	Source/drain contact resistance	0.0	Ω
ldd	LDD	Total source/drain LDD region length	0.0	m
eta	Eta	Effective drain voltage coefficient	0.3	
eta0	Eta0	Subthreshold region DIBL coefficient	0.08	
etab	Etab	Subthreshold region DIBL coefficient	-0.07	1/V
pcIm	Pclm	Channel-length modulation effect coefficient	1.3	—
pdibl1	Pdibl1	DIBL effect coefficient 1	0.39	—
pdibl2	Pdibl2	DIBL effect coefficient 2	0.0086	
pscbe1	Pscbel	Substrate current body effect coefficient 1	4.24×10^8	V/m
pscbe2	Pscbe2	Substrate current body effect coefficient 2	$1.0 imes 10^{-5}$	m/V
pvag	Pvag	Vg dependence of Rout coefficient	0.0	_

Equations

For the complete equations describing the Level 47 model, refer to J. H. Huang, Z. H. Liu, M. C. Jeng, K. Hui, M. Chan, P. K. Ko, and C. Hu, BSIM3 Manual (Version 2.0). Berkeley, CA: University of California, 1994.).

Drain Current

In the linear region:

$$I_{ds} = \frac{I_{dslin0}}{1 + \frac{R_{ds}I_{dslin0}}{V_{ds}}}$$
(8.389)

where

$$I_{dslin0} = \mu_{eff} C_{ox} \left(\frac{W}{L}\right) \left(\frac{1}{1 + \frac{V_{ds}}{E_{sat}L}}\right) \left(V_{gst} \angle A_{bulk} \frac{V_{ds}}{2}\right) V_{ds}$$
(8.390)

In the saturation region:

$$I_{ds} = I_{dsat} \left(1 + \frac{V_{ds} \angle V_{dsat}}{V_A} \right) \left(1 + \frac{V_{ds} \angle V_{dsat}}{V_{ASCBE}} \right)$$
(8.391)

where

$$I_{dsat} = W v_{sat} C_{ox} (V_{gst} \angle A_{bulk} V_{dsat})$$
(8.392)

In the subthreshold region:

If subthmod = 0:

$$I_{ds} = 0 \tag{8.393}$$

If subthmod = 1:

$$I_{ds} = \frac{I_{limit}I_{exp}}{I_{limit} + I_{exp}} (1 \angle e^{\angle V_{ds}/V_{tm}})$$
(8.394)

where

$$I_{limit} = \frac{9}{2}\mu_0 C_{dep} \left(\frac{W}{L}\right) V_{tm}^2 \cdot e^{\left(\frac{(E_{ta0} + E_{tab} \cdot V_{bs})\theta_{dibl}V_{ds}}{nV_{tm}}\right)}$$
(8.395)

$$I_{exp} = \mu_0 C_{dep} \left(\frac{W}{L}\right) V_{tm}^2 \cdot e^{\left(\frac{V_{gs} \angle V_{th} \angle V_{off} + (E_{tab} + E_{tab} \cdot V_{bs})\theta_{dibl}V_{ds}\right)}{nV_{tm}}}$$
(8.396)

If subthmod = 2:

$$V_{ds} = I_{s0}(1 \angle e^{\angle V_{ds} / V_{tm}}) \cdot e^{\left(\frac{V_{gst} \angle V_{off} + (E_{ta0} + E_{tab} \cdot V_{bs})\theta_{dibl}V_{ds}}{nV_{tm}}\right)}$$
(8.397)

where

$$I_{s0} = \mu_0 \frac{W}{L} \sqrt{\frac{q \varepsilon_{si} N_{peak}}{2 \phi_s}} \cdot V_{tm}^2$$
(8.398)

In the transition region:

$$I_{ds} = (1 \angle t)^2 I_{dslow} + 2(1 \angle t) t I_p + t^2 I_{dshigh}$$
(8.399)

where

$$= \left(\frac{V_p \angle V_{gslow}}{V_{gslow} \angle 2V_p + V_{gshigh}}\right) \times$$

$$\left(\sqrt{1 + \frac{(V_{gslow} \angle 2V_p + V_{gshigh})(V_{gst} \angle V_{gslow})}{(V_p \angle V_{gslow})^2}} \angle 1\right)$$
(8.400)

Variables for which equations are not given here are as follows.

VA	Early voltage
VASCBE	Early voltage due to substrate current-induced body effect
μ <i>eff</i>	Effective mobility
Abulk	Bulk charge effect factor
Vdsat	Drain saturation voltage

MOSFET Level 57 / 70 (BSIM3SOI and BSIM4SOI)

BSIMSOI is an international standard model for silicon-on-insulator (SOI) circuit design, adjunct to the BSIM3v3 framework.

Parameters

.model name nmos | pmos level=57 [parameters]

For standard model parameters and equations, please refer to the Berkeley manuals included with the Tanner T-Spice documentation. Specific device instance statements and their parameters are listed in the following section.

Syntax

General MOSFET device parameters (length, width, drain, source, etc.) are described in the device statement chapter under "MOSFET (m)" on page 175. In the case of device values which have corresponding model values, the device settings override the model settings.

Device instance parameters for the BSIMSOI MOSFET model are as follows:

```
mname d g s e [p] [b] [t] model [L=1] [W=w] [P=p] [B=b] [T=t] [AD=ad]
[AS=as] [PD=pd] [PS=ps] [NRS=nrs] [NRD=nrd] [NRB=nrb] [M=M]
[OFF][BJTOFF=bjtoff] [IC=ds gs bs es ps initial voltages] [RTH0=rth0]
[CTH0=cth0] [NBC=nbc] [NSEG=nseg] [PDBCP=pdbcp] [PSBCP=psbcp]
[AGBCP=agbcp] [AEBCP=aebcp] [VBSUSR=vbsusr] [TNODEOUT]
[RGATEMOD=rgatemod] [SOIMOD=soimod] [FRBODY=frbody]
```

d	Drain node
g	Front gate node
S	Source node
e	Back gate or substrate node
р	Optional external body contact node
b	Optional internal body node
t	Optional temperature node
ad	Drain diffusion area
aebcp	Parasitic gate-to-body overlap area for body contact
agbcp	Parasitic perimeter length for body contact at drain side
as	Source diffusion area
bjtoff	Turn off BJT current if equal to 1
cth0	Thermal capacitance per unit width:
	• if not specified, CTH0 is extracted from model card
	• f specified, it will override the one in model card
frbody	Layout-dependent body resistance coefficient

ic	Initial guess in the order of (Vds, Vgs, Vbs, Ves, Vps). (Vps will be ignored in the case of a 4-terminal device.)
I	Channel length
nbc	Number of body contact isolation edge
nrb	Number of squares in body series resistance
nrd	Number of squares in drain series resistance
nrs	Number of squares in source series resistance
nseg	Number of segments for channel width partitioning. (The effective channel width may change due to the body contact, please refer to the equations in BSIMSOI3p1.pdf and BSIMSOI3p2.pdf .
off	Device initial conditions off in DC operating point calculations
pd	Drain diffusion perimeter area
pdbcp	Parasitic perimeter length for body contact at drain side
ps	Drain diffusion perimeter length
psbcp	Parasitic perimeter length for body contact at source side
rgatemod	Gate resistance model selector
rsh	Number of squares in drain series resistance
rth0	Thermal resistance per unit width: if not specified, RTH0 is extracted from model card if specified, it will override the one in model card
soimod	SOI model selector for PD/FD operation
	 Soimod=0: BSIMPD (partially depleted)
	 Soimod=1: unified model for PD&FD
	• Soimod=2: ideal FD (fully depleted)
tnodeout	Flag indicating external temperature node
vbsusr	Optional initial value of Vbs specified by user for transient analysis
w	Channel width

SOI Modes

There are three modes in BSIMSOI, soimod = 0, 1 or 2. BSIMPD (soimod = 0) can be used to model the PD SOI device, where the body potential is independent of DVbi (VBS > DVbi). Therefore the calculation of DVbi is skipped in this mode. On the other hand, the ideal FD model (soimod = 2) is for the FD device with body potential equal to DVbi. Hence the calculation of body current/charge, which is essential to the PD model, is skipped. For the unified SOI model (soimod = 1), however, both DVbi and body current/charge are calculated to capture the floating-body behavior exhibited in FD devices. This unified model covers both BSIMPD and the ideal FD model.

Body and Temperature Nodes

There are three optional nodes, P, B and T nodes. Nodes P and B are used for body contact devices. If the TNODEOUT flag is not set, when you specify four nodes, this element is a four terminal device, i.e., floating body. If you specify five nodes, the fifth node represents the external body contact node (P). There is a body resistance between the internal body node and the P node. In both these cases, an internal body node is created, but it is not accessible in the circuit deck. However, if you specify six nodes, the fifth node will represent the P node and the sixth node will represent the internal body node (B). This configuration is useful for distributed body resistance simulation.

If the TNODEOUT flag is set, the last node is interpreted as the temperature node. In this case, when you specify five nodes, it is a floating body. If you specify six nodes, it is a body-contacted case. Finally, if you specify seven nodes, it is a body-contacted case with an accessible internal body node. The temperature node is useful for thermal coupling simulation.

MOSFET Level 100 (Penn State & Philips PSP Model)

The PSP model is a new compact MOSFET model, which has been jointly developed by Philips Research and Penn State University, and is able to accurately model present-day and upcoming deep-submicron bulk CMOS technologies.

The PSP model is a symmetrical, surface-potential-based model, giving an accurate physical description of the transition from weak to strong inversion. The PSP model includes an accurate description of all physical effects important for modern and future CMOS technologies, such as:

mobility reduction bias-dependent series resistance velocity saturation conductance effects (CLM, DIBL, etc.) lateral doping gradient effect mechanical stress related to STI gate leakage current gate-induced drain leakage gate depletion quantum-mechanical effects bias-dependent overlap capacitances

In addition, it gives an accurate description of charges and currents and their first-order derivatives (transconductance, conductance, capacitances), but also of their higher-order derivatives. In other words, it gives an accurate description of MOSFET distortion behaviour, and as such the PSP model is suitable for digital, analog as well as RF circuit design.

The PSP model is fully documented in Penn State & Philips PSP Model.

For further detailed information about the PSP model, please refer to the Philips Compact Model Webpage:

http://www.semiconductors.philips.com/Philips Models/high voltage/model40

Parameters

The PSP model uses the following syntax.

```
.model name nmos | pmos level=100 | 1000 | model=modelname [parameters]
```

T-Spice includes support for PSP version 100.1 with both electrical and geometrical model parameterization.

The available *modelname* values for the PSP model selection are:

Modelname	Description
psp100 or psp100e (default)	PSP model version 100.1, electrical
psp1000 or psp100g	PSP model version 100.1, geometrical

Additional MOSFET Parameters

This section describes additional parameters, including parasitics, used by the equations describing MOSFET levels 1-3 and BSIM (levels 1, 2, 3, 14, 28, 47, 49, 53, and 54).

Parameters

Parameter	Symbol	Description	Default	Units
acm	ACM	Source/drain area calculation method	0	_
cj ∣ cjm	Cj	Source/drain bottom junction capacitance	5.7911×10 ⁻⁴ [level 49] 5.0×10 ⁻⁴ [else]	F/m ²
cjgate	Cj,gate	Zero-bias gate edge sidewall junction capacitance	0.0	F⁄m
cjsw∣cjw	Cjsw	Source/drain sidewall junction capacitance	0.0	F⁄m
expli	EXPLI	Current limit	1.0×10 ¹⁵	А
hdif	Hdif	Length of heavily doped diffusion from contact to lightly doped region	0.0	m
is	Is	Bulk saturation current	0.0 [level 49] 1.0×10 ⁻¹⁴ [else]	А
js ijs	J_S	Source/drain junction reverse saturation current density	0.0	A/m ²
jsw jssw	Jsw	Source/drain sidewall junction reverse saturation current density	0.0	A/m
ld dlat latd	Ld	Lateral diffusion into channel from source/drain diffusion	0.75 · xj	
ldif	Ldif	Length of lightly doped diffusion adjacent to gate	0.0	m
lmax	Lmax	Maximum channel length	0.0	m
lmin	Lmin	Minimum channel length	0.0	m
meto	Meto	Fringing field factor for overlap capacitance calculation	0.0	m
mj ∣ mj0	Mj	Source/drain bottom junction capacitance grading coefficient	0.5	
mjsw ∣ mjw	Mjsw	Source/drain sidewall junction capacitance grading coefficient	0.33	_
n	Ν	Emission coefficient	1.0	_

Parameter	Symbol	Description	Default	Units
nds	Nds	Reverse bias slope coefficient	1.0	
pb pj	Pb	Source/drain junction built-in potential	0.8 [level 49] 1.0 [else]	V
pbsw pjw php	Pbsw	Source/drain sidewall junction capacitance built-in potential	pb	V
prdt	Prdt	Drain resistance temperature coefficient	0.0	
prst	Prst	Source resistance temperature coefficient	0.0	
rd	Rd	Drain resistance (rsh override)	0.0	Ω
rdc	Rdc	Drain contact resistance	0.0	Ω
rs	Rs	Source resistance (rsh override)	0.0	Ω
rsc	Rsc	Source contact resistance	0.0	Ω
rsh ∣ rshm	Rsh	Source/drain sheet resistance	0.0	Ω⁄□
vnds	Vn,ds	Reverse diode current transition point	-1	V
wmax	Wmax	Maximum channel width	1.0	m
wmin	Wmin	Minimum channel width	0.0	m
wmlt	Wmlt	Width diffusion layer shrink reduction factor	1.0	_
×I	Xl	Difference between the drawn and the actual length	0.0	m
xlref	Xlref	Difference between physical and drawn reference channel length	0.0	m
xw	Xw	Difference between the drawn and the actual width	0.0	m
xwref	Xwref	Difference between physical and drawn reference channel width	0.0	m

Equations

Parasitic Resistances

MOSFET parasitics are simulated as resistances in series with the source $(R_{s_{eff}})$ and drain $(R_{d_{eff}})$. How these resistances are computed depends on the area calculation method (**acm**) specified.

acm	rseff	rdeff
0, 10		
	$R_{s} = N_{rs} \cdot R_{sh} + R_{sc} if \ N_{rs} \cdot R_{sh} \neq 0$	$R_{d_{-\alpha}} = N_{rd} \cdot R_{sh} + R_{dc} if \ N_{rd} \cdot R_{sh} \neq 0$

$$\begin{split} R_{s_{eff}} &= N_{rs} \cdot R_{sh} + R_{sc} \quad if \quad N_{rs} \cdot R_{sh} \neq 0 \qquad R_{d_{eff}} = N_{rd} \cdot R_{sh} + R_{dc} \quad if \quad N_{rd} \cdot R_{sh} \neq \\ R_{s_{eff}} &= R_s + R_{sc} \qquad otherwise \qquad R_{d_{eff}} = R_s + R_{dc} \qquad otherwise \end{split}$$

1, 11

$$R_{s_{eff}} = \frac{(L_d + L_{dif}) \cdot R_s}{W_{eff}} + N_{rs} \cdot R_{sh} + R_{sc} \qquad R_{d_{eff}} = \frac{(L_d + L_{dif}) \cdot R_d}{W_{eff}} + N_{rd} \cdot R_{sh} + R_{dc}$$

2, **3**, **12**, **13** If N_{rs} is specified:

If N_{rd} is specified:

$$R_{s_{eff}} = \frac{(L_d + L_{dif}) \cdot R_s}{W_{eff}} + N_{rs} \cdot R_{sh} + R_{sc} \quad R_{d_{eff}} = \frac{(L_d + L_{dif}) \cdot R_d}{W_{eff}} + N_{rd} \cdot R_{sh} + R_{dc} \cdot R_{sh} + R_{sc} \cdot$$

Otherwise:

Otherwise:

$$R_{s_{eff}} = \frac{(L_d + L_{dif}) \cdot R_s + R_{sh} \cdot H_{dif_{eff}}}{W_{eff}} \qquad R_{d_{eff}} = \frac{(L_d + L_{dif}) \cdot R_d + R_{sh} \cdot H_{dif_{eff}}}{W_{eff}}$$

Parasitic Diodes

Parasitic diodes are added for each MOSFET. One diode is placed between the MOSFET's bulk and source terminals, and the other between the bulk and drain.

Diode characteristics are determined by the device parameters **as**, **ad**, **pd**, **ps**, and **geo**, as well as the model parameters **acm**, **cj**, **cjsw**, **cjgate**, **js**, **jsw**, **is**, **n**, **nds**, **vnds**, and **hdif**. The quantity **weff** also plays a role in determining default values for source and drain areas and perimeters for some values of **acm**.

If the MOSFET bulk-source voltage **vbs** is positive (the bulk-source diode is forward biased), then the bulk-source DC current **ibs** is

$$ibs = isatbs \cdot exp(vbs/(n \cdot vt) - 1)$$
(8.401)

where vt = kT/q (the thermal voltage), and **isatbs** is the saturation current:

$$isatbs = js \cdot aseff + jsw \cdot pseff$$
 (8.402)

aseff and pseff are described below.

If this computed value of isatbs is zero, then isatbs will be set to the is parameter value.

If the MOSFET bulk-drain voltage vds is positive (the bulk-drain diode is forward biased), then the bulk-drain DC current is

$$ibd = isatbd \cdot exp(vbd/(n \cdot vt) - 1)$$
(8.403)

where isatbd is the saturation current:

$$isatbd = js \cdot adeff + jsw \cdot pdeff$$
 (8.404)

adeff and pdeff are described below.

If this computed value of isatbd is zero, then isatbd will be set to the **is** parameter value.

The exponential function in both diodes is replaced by a linear extension when the current is larger than the value of **expli**. The linear extension is chosen such that the diode current function is continuously differentiable at the transition point where the diode current equals **expli**.

When a MOSFET parasitic diode with saturation current **isat** is reverse-biased with a negative voltage **vdi**, then its current **idi** behaves as follows.

If 0 > vdi > vnds, then

$$idi = isat \cdot vdi \tag{8.405}$$

If vdi < vnds, then

$$idi = isat \cdot (vnds + (vdi - vnds) / nds)$$

$$(8.406)$$

Effective Areas and Perimeters

Effective source and drain areas and perimeters depend on the value of parameter **acm** (and, if **acm** = 3, on parameter **geo**). The parameter names are:

aseff	Effective source area
adeff	Effective drain area
pseff	Effective source perimeter
pdeff	Effective drain perimeter

The values of geo are:

0	Drain and source not shared by other devices (default)
1	Drain shared with another device
2	Source shared with another device
3	Drain and source shared with other devices

The area and perimeter values are computed as follows. The first table lists the equations used when **acm=0**, **1**, **2**, or **3**. The second table lists equations for **acm=10**, **11**, **12**, or **13**. The parameter **CALCACM** can only be invoked when **acm=12**. The values of **defas**, **defad**, and **moscap** are specified with the **.options** command.

	acm=0 or 10 with as	acm=0 without as	acm=10 without as
$A_{s_{e\!f\!f}}$	$A_s \cdot (W_{mlt})^2$	l·w if moscap=1 defas otherwise	0
$A_{d_{e\!f\!f}}$	$A_d \cdot (W_{mlt})^2$	$l \cdot w$ if moscap=1 defad otherwise	0
$P_{s_{eff}}$	$P_s \cdot W_{mlt}$	$2 \cdot (l+w)$ if moscap=1 0 otherwise	0
$P_{d_{eff}}$	$P_d \cdot W_{mlt}$	$2 \cdot (l+w)$ if moscap=1 0 otherwise	0

For acm=1 or 11:

	acm=1 or 11 with as	acm=1 without as	acm=11 without as	
$A_{s_{eff}}$	W _{eff} ·W _{mlt}	W_{eff} , W_{mlt}	$W_{eff}W_{mlt}$	
$A_{d_{eff}}$	$W_{eff} W_{mlt}$	W_{eff} . W_{mlt}	W_{eff} , W_{mlt}	
$P_{s_{eff}}$	W _{eff}	W _{eff}	W _{eff}	
$P_{d_{eff}}$	W _{eff}	W _{eff}	W _{eff}	

For acm=2 or 12:

	acm=2 or 12 with as	acm=2 without as	acm=12 without as	
$A_{s_{eff}}$	$A_s \cdot (W_{mlt})^2$	$2 \cdot H_{dif_{eff}} \cdot W_{eff}$	$\begin{array}{c} 2 \cdot H_{dif_{eff}} \cdot W_{eff} \\ 0 \end{array}$	if calcacm=1 otherwise
$A_{d_{e\!f\!f}}$	$A_{d} \cdot (W_{mlt})^2$	$2 \cdot H_{dif_{eff}} \cdot W_{eff}$	$\begin{array}{c} 2 \cdot H_{dif_{eff}} \cdot W_{eff} \\ 0 \end{array}$	if calcacm=1 otherwise
$P_{s_{eff}}$	$P_s \cdot W_{mlt}$	$4 \cdot H_{dif_{eff}} + 2 \cdot W_{eff}$	$\begin{array}{c} 4 \cdot H_{dif_{eff}} + 2 \cdot W_{eff} \\ 0 \end{array}$	if calcacm=1 otherwise

	acm=2 or 12 with as	acm=2 without as	acm=12 without as	
$P_{d_{eff}}$	$P_d \cdot W_{mlt}$	$4 \cdot H_{dif_{eff}} + 2 \cdot W_{eff}$	$\begin{array}{c} 4 \cdot H_{dif_{eff}} + 2 \cdot W_{eff} \\ 0 \end{array}$	if calcacm=1 otherwise

For acm=3 or 13:

	acm=3 or 13 with as	acm=3 without as		acm=13 without as
$A_{s_{e\!f\!f}}$	$A_s \cdot (W_{mlt})^2$	$\begin{array}{l} 2 \cdot H_{dif_{eff}} \cdot W_{eff} \\ H_{dif_{eff}} \cdot W_{eff} \end{array}$	if geo=0 or 1 otherwise	0
$A_{d_{eff}}$	$A_d \cdot (W_{mlt})^2$	$\begin{array}{l} 2 \cdot H_{dif_{eff}} \cdot W_{eff} \\ H_{dif_{eff}} \cdot W_{eff} \end{array}$	if geo=0 or 1 otherwise	0
$P_{s_{eff}}$	$P_s \cdot W_{mlt}$	$\begin{array}{l} 4 \cdot H_{dif_{eff}} + W_{eff} \\ 2 \cdot H_{dif_{eff}} + W_{eff} \end{array}$	if geo=0 or 1 otherwise	0
$P_{d_{eff}}$	$P_d \cdot W_{mlt}$	$\begin{array}{l} 4 \cdot H_{dif_{eff}} + W_{eff} \\ 2 \cdot H_{dif_{eff}} + W_{eff} \end{array}$	if geo=0 or 1 otherwise	0

Resistor

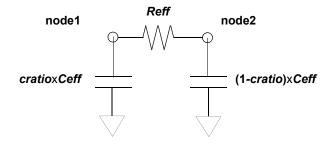
Parameters

.model name r [parameter=X]

Parameter	Description	Default	Units
bulk	Name of the node used as the bulk node for capacitance.	Gnd	
сар	Default capacitance.	0	F
capsw	Sidewall fringing capacitance.	0	F/m
cratio	Specifies how capacitance is distributed between input and output nodes. The capacitor between node1 and the bulk node has the value cratio × Ceff , while the capacitor between node2 and the bulk node has the value (1- cratio)× Ceff . Ceff is the effective capacitance as described below.	0.5	
сох	Bottomwall capacitance.	0	F/m
di	Relative dielectric constant.	0	
dir	Difference between the drawn resistor length and its actual length. Multiplied by .options scalm . For further information, see " .options " (page 109).	0	m
dw	Difference between the drawn resistor width and its actual width. Multiplied by .options scalm . For further information, see " .options " (page 109).	0	m
I	Default length. Multiplied by shrink and .options scalm to obtain the scaled length. For further information, see " .options " (page 109).	0	m
level	Model selector—not used.		
noise	Default noise multiplier.	1	
rac	Default AC resistance.	DC resistance	Ohm
res	Default resistance.	0	Ohm
rsh	Sheet resistance per square.	0	
shrink	Shrink factor.	1	
tc1c	First-order temperature coefficient for capacitance.	0	$deg^{\angle 1}$
tc2c	Second-order temperature coefficient for capacitance.	0	$deg^{\angle 2}$
tc1r	First-order temperature coefficient for resistance.	0	$deg^{\angle 1}$

Parameter	Description	Default	Units
tc2r	Second-order temperature coefficient for resistance.	0	deg^{2}
thick	Dielectric thickness.	0	m
tnom tref	Reference temperature for temperature compensation.	global tnom (25.0)	deg
w	Default width. Multiplied by shrink and .options scalm to obtain the scaled width. For further information, see " .options " (page 109).	0	m

Large-Signal Model



Equations

Resistance

Effective length is calculated as

$$L_{eff} = L_{scaled} \angle (2 \cdot dlr \cdot scalm) \tag{8.407}$$

Effective width is calculated as

$$W_{eff} = W_{scaled} \angle (2 \cdot dw \cdot scalm) \tag{8.408}$$

If element resistance is specified, the effective resistance is

$$R_{eff} = resistance \times devscale \tag{8.409}$$

Otherwise, if $W_{eff} \cdot L_{eff} \cdot rsh = 0$, then $R_{eff} = res \cdot devscale$.

Or if $W_{eff} \cdot L_{eff} \cdot rsh \neq 0$, then $R_{eff} = L_{eff} \cdot rsh \cdot (devscale) / W_{eff}$.

In AC analysis, the device's resistance is

$$RAC_{eff} = acres \cdot devscale \tag{8.410}$$

if acres is given.

$$RAC_{eff} = rac \cdot devscale \tag{8.411}$$

if acres is not given and model parameter rac is given.

$$RAC_{eff} = R_{eff} \tag{8.412}$$

if neither acres nor rac is given.

Note:

If T-Spice calculates the effective resistance $(R_{eff} \text{ or } RAC_{eff})$ to be less than 10⁻⁵ Ω , then a warning message is issued and the effective resistance is automatically assigned a value of 10⁻⁵ Ω .

For additional information on *devscale*, see the device statement "Resistor (r)" on page 180.

Capacitance

Effective length is calculated as

$$L_{eff} = L_{scaled} \angle (2 \cdot dlr \cdot scalm)$$
(8.413)

Effective width is calculated as

$$W_{eff} = W_{scaled} \angle (2 \cdot dw \cdot scalm) \tag{8.414}$$

If element capacitance is specified, the effective capacitance is

$$C_{eff} = c \times devscale \tag{8.415}$$

If cap is the only model parameter specified

$$C_{eff} = cap \cdot devscale \tag{8.416}$$

Otherwise,

$$C_{eff} = devscale \cdot (Leff \cdot Weff \cdot cox + 2(L_{eff} + W_{eff}) \times capsw)$$
(8.417)

If **cox** is not specified, it is computed in one of two ways.

If **di** is specified:
$$cox = di \cdot \frac{8.8542149 \cdot 10^{-12}}{thick}$$
 (8.418)

If If **di** is not specified:
$$cox = \frac{3.453148 \cdot 10^{\angle 11}}{thick}$$
 (8.419)

Note:

If c, cap, cox, and thick are not specified, no capacitor is created.

Switch

A current- or voltage-controlled switch.

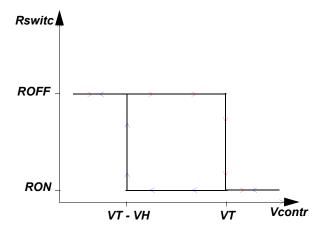
Syntax

.model modelname sw|csw [parameter=value [parameter=value [...]]]

Name	Model	Description	Default	Unit
vt	sw	Threshold voltage	0	V
it	csw	Threshold current	0	А
vh	sw	Hysteresis voltage	0	V
ih	csw	Hysteresis current	0	А
ron	sw, csw	ON resistance	1	Ohm
roff	sw, csw	OFF resistance	1e12	Ohm
dv	sw	Threshold transition width	0.01	V
di	csw	Threshold transition width	1e-8	А
hdt	sw, csw	Threshold transition time	1e-10	S

The T-Spice switch is essentially a controlled resistor. The resistance is **ron** when the switch is on, and **roff** when the switch is off. The switch changes state between on and off when the controlling voltage or current is at its threshold value.

The following figure shows the resistance of the switch as a function of the controlling variable:



The T-Spice switch elements can display hysteresis, so that the threshold value is different when the control voltage/current is increasing than when it is decreasing. For a voltage-controlled switch, the threshold voltage is **vt** when v(control1, control2) is increasing, and **vt-vh** when v(control1, control2) is decreasing. For a current-controlled switch, the threshold current is **it** when i(vsource_name) is increasing, and **it-ih** when i(vsource_name) is decreasing. The switch is on when the control voltage or current is greater than the threshold value.

The **dv** and **di** parameters define a small interval around the threshold in which a smooth transition between **ron** and **roff** is made.

Examples

The following example creates a voltage-controlled switch:

.model swmod sw vt=0.7 dv=0.1

The following example creates a current-controlled switch:

```
.model swmod csw it=0.7 di=0.1
```

Transmission Line

T-Spice supports two transmission line models:

- Lossless line, defined by characteristic impedance and delay. This model is described by Branin 1967.
- Lossy line, defined by RLCG parameters. This model is described here.

Equations

The lossy transmission line is modeled with equivalent circuits consisting of cascaded cells or *lumps*, typically comprising discrete resistors, inductors, and capacitors. Lumps essentially discretize the transmission line wave equations over the length of the line. Distributed RLCG values are converted to non-distributed (lumped element) values:

$$Rlump = R \cdot l/n \tag{8.420}$$

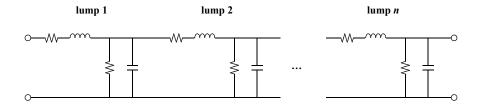
$$Llump = L \cdot l/n \tag{8.421}$$

$$Clump = C \cdot l/n \tag{8.422}$$

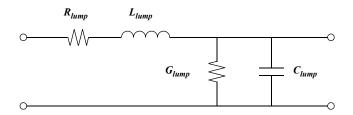
$$Glump = G \cdot l/n \tag{8.423}$$

where *l* is the physical length of the transmission line and *n* is the number of lumps.

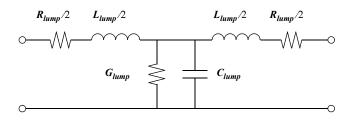
Typically, many lumps are needed to model a transmission line accurately. The number of lumps is specified by the **lumps** parameter on the device statement. A cascade ladder network—the *iterative ladder circuit*—is constructed with the specified number of lumps.



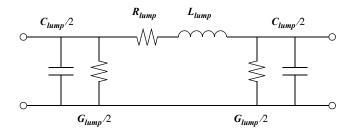
The "gamma" lump type is the most common implementation.



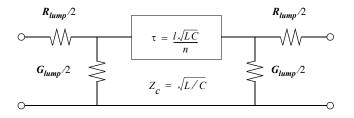
The "tee" lump type is a symmetrical alternative that includes an additional series resistance and inductance per lump.



The "pi" lump type is formed by adding identical shunt elements at the input and output of each lump.



Low-loss transmission lines need not be modeled with RLCG lumps. An alternative approach is to use lossless transmission line sections separated by lumped resistances and conductances. The "hybrid RGT" lump type consists of an ideal transmission line section with series resistances and shunt conductances at input and output. This equivalent circuit defaults to the lossless transmission line when R and G values are zero, and is therefore the default **lumptype** option.



Small-Signal and Noise Models

Introduction

9

Small-Signal Models

The linear small-signal models for diodes, BJTs, JFETs, MESFETs, and MOSFETs described in this chapter are derived from T-Spice's nonlinear device representations.

Instead of using simplified equations to compute the small-signal model parameters, which can introduce errors at low and high frequencies, T-Spice generates linearized small-signal models directly from the device equations, with the most accurate small-signal results available.

Small-signal parameters are evaluated at the DC operating point. The currents and voltages appearing in the equations in this chapter are all DC values. In addition, the voltages are measured at the "intrinsic" terminals, *inside* the parasitic resistances connected to the external terminals.

Small-signal data are available with the ".acmodel" (page 64) command.

Noise Models

The following parameters are used by many of T-Spice's noise models.

Parameter	Symbol	Description	Default	Unit
noiselevel nlev	_	Noise equation selector (JFET, MESFET, MOSFET only)	2	_
gdsnoise gdsnoi	GDSn	Channel noise coefficient (JFET, MESFET, MOSFET only)	1.0	_
af	Af	Flicker noise exponent	1.0	_
kf	Kf	Flicker noise coefficient	0.0	_

Noise models add RMS noise current sources to small signal models in order to simulate noise power densities (NPDs) in the device. The NPDs are calculated from model parameter values and DC operating point conditions.

For example, each of the resistors in a circuit, including the parasitic resistances in models, generates thermal noise, whose NPD is inversely proportional to the resistance:

$$\overline{|i_{th}|^2} = \frac{4kT}{R} \cdot \Delta f \tag{9.1}$$

where k is Boltzmann's constant, T is the temperature in Kelvins, R is the resistance, and Δf is the width of the frequency band over which the noise is measured (1 Hz in T-Spice). The corresponding noise current source has a magnitude of $\sqrt{|i_{th}|^2}$ and units of A/\sqrt{Hz} , and is placed in parallel with the resistor.

The following sections show the NPD calculation for intrinsic noise sources in the models. These sources represent shot and/or flicker noise.

Shot noise is typically computed as

$$\overline{|i_{shot}|^2} = 2q|I_x| \cdot \Delta f \tag{9.2}$$

where q is the electron charge and Ix is the DC current into terminal x at the operating point of the device.

Flicker noise is usually modeled by

$$\overline{\left|i_{flicker}\right|^{2}} = \frac{K_{f}\left|I_{x}\right|^{A_{f}}}{f} \cdot \Delta f$$
(9.3)

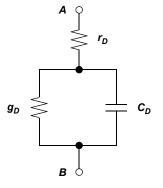
where f is the center frequency of the band over which the noise is being measured.

Where appropriate, alternate formulations for shot and flicker noise are presented for individual models.

The noise source corresponding to the NPD, $\sqrt{|i_{XY_n}|^2}$, is connected between the intrinsic X and Y nodes in the noise model.

Diode

Small-Signal Model



The conductance gD is the partial derivative of the forward current ID with respect to the voltage VD across the intrinsic diode.

$$g_D = \frac{\partial I_D}{\partial V_D}\Big|_{\text{op}} \tag{9.4}$$

The small-signal capacitance CD across the diode is

$$C_D = \frac{\partial Q_D}{\partial V_D} \bigg|_{\text{op}}$$
(9.5)

rD models the diode's linear parasitic resistance.

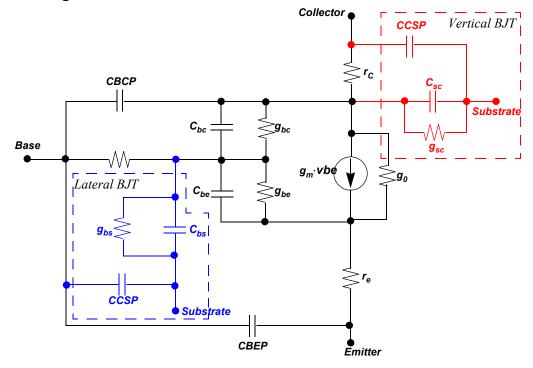
Noise Model

In addition to the thermal noise associated with rD, this model includes a PN junction noise source that includes shot and flicker noise:

$$\overline{\left|i_{AB_{n}}\right|^{2}} = 2qI_{A} \cdot \Delta f + \frac{K_{f}|I_{A}|^{A_{f}}}{f} \cdot \Delta f$$
(9.6)

BJT Level 1 (Gummel-Poon)

Small-Signal Model



The bipolar conductances are denoted by gm, go, g_{π} , and g_{μ} .

$$g_m = \frac{\partial I_C}{\partial V_{BE}}\Big|_{\rm op} \tag{9.7}$$

$$g_o = \frac{1}{r_o} = \frac{\partial I_C}{\partial V_{CE}}\Big|_{\text{op}}$$
(9.8)

$$g_{\pi} = \frac{1}{r_{\pi}} = \frac{\partial I_B}{\partial V_{BE}} \Big|_{\text{op}}$$
(9.9)

$$g_{\mu} = \frac{1}{r_{\mu}} = \frac{\partial I_B}{\partial V_{BC}}\Big|_{\text{op}}$$
(9.10)

The capacitances CBE and CBC are denoted by C_{π} and C_{μ} respectively.

$$C_{\pi} = \frac{\partial Q_B}{\partial V_{BE}} |_{\text{op}}$$
(9.11)

$$C_{\mu} = \frac{\partial Q_B}{\partial V_{BC}}\Big|_{\text{op}}$$
(9.12)

Other parameters computed are the transistor gain at DC operating point βDC , the AC signal gain βAC , and the gain-band-width product fT.

$$\beta_{DC} = \frac{I_C}{I_B}\Big|_{\text{op}} \tag{9.13}$$

$$\beta_{AC} = \frac{\partial I_C}{\partial I_B}\Big|_{\text{op}} = g_m r_\pi$$
(9.14)

$$f_T = \left. \frac{g_m}{2\pi (C_\pi + C_\mu)} \right|_{\rm op} \tag{9.15}$$

Gummel-Poon Noise Model

T-Spice uses the equations in this section to simulate thermal, shot, and flicker noise power densities in the BJT Gummel-Poon device model.

Thermal Noise

T-Spice uses the following equations to calculate thermal noise power density (nd_{therm}) of the base resistor (r_b) , collector resistor (r_c) , and emitter resistor (r_e) noise currents, respectively:

$$nd_{therm}(r_{b}) = \frac{4kT}{r_{bb}}$$

$$nd_{therm}(r_{c}) = \frac{4kT}{r_{c_{eff}}},$$

$$nd_{therm}(r_{e}) = \frac{4kT}{r_{e_{eff}}}$$
(9.16)

where k is Boltzmann's constant, T is temperature, and r_{bb} , r_{ceff} , and r_{eeff} are the effective base, collector, and emitter resistances.

Shot Noise

The following equations give the shot noise density (nd_{shot}) of the base current (I_b) and collector current (I_c) , respectively:

$$nd_{shot}(I_b) = 2qI_b$$

$$nd_{shot}(I_c) = 2qI_c$$
(9.17)

where q is the elementary electron charge.

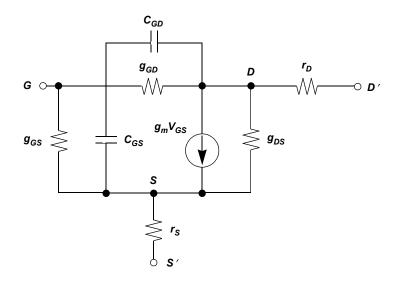
Flicker Noise

The flicker noise density (nd_{flick}) of the base current (I_b) is:

$$nd_{flick}(I_b) = \frac{KF \cdot (I_b)^{AF}}{f}, \qquad (9.18)$$

JFET/MESFET

Small-Signal Model



The transconductance is denoted by gm and the output conductance by gDS.

$$g_m = \frac{\partial I_D}{\partial V_{GS}}\Big|_{\text{op}}$$
(9.19)

$$g_{DS} = \frac{\partial I_D}{\partial V_{DS}}\Big|_{\rm op} \tag{9.20}$$

The gate junction conductances are denoted by gGS and gGD. These are usually very small, since the junctions are reverse-biased in normal operation.

$$g_{GS} = \frac{\partial I_{GS}}{\partial V_{GS}}\Big|_{\rm op} \tag{9.21}$$

$$g_{GD} = \frac{\partial I_{GD}}{\partial V_{GD}}\Big|_{\rm op} \tag{9.22}$$

The gate junction capacitances are denoted by CGS and CGD.

$$C_{GS} = \frac{\partial Q_G}{\partial V_{GS}}\Big|_{\text{op}}$$
(9.23)

$$C_{GD} = \frac{\partial Q_G}{\partial V_{GD}}\Big|_{\text{op}}$$
(9.24)

rD and rS are constant linear resistances.

JFET/MESFET

Noise Model

In addition to the thermal noise associated with rD, rS, and rG, this model includes the intrinsic noise source

$$\overline{\left|i_{DS_{n}}\right|^{2}} = \overline{\left|i_{ch}\right|^{2}} + \frac{K_{f}|I_{D}|^{A_{f}}}{f} \cdot \Delta f$$
(9.25)

where ID is the DC operating point drain current.

Channel noise is modeled in two ways, depending on the parameter **noiselevel**. When **noiselevel** < 3,

$$\overline{|i_{ch}|^2} = \frac{8}{3}kTg_m \cdot \Delta f \tag{9.26}$$

When **noiselevel** = 3,

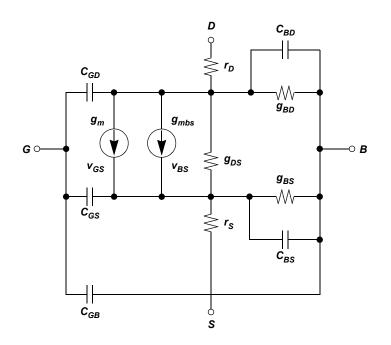
$$\overline{|i_{ch}|^2} = \frac{8}{3}kT\beta \cdot (V_{GS} \angle V_{t0}) \cdot G_{DS_n} \cdot \left(\frac{1+\alpha+\alpha^2}{1+\alpha}\right) \cdot \Delta f$$
(9.27)

where k is Boltzmann's constant, T is the current temperature in Kelvins, gm is the transconductance, β is the gain at the operating point, and

$$\alpha = \begin{cases} 1 \angle \frac{V_{DS}}{V_{GS} \angle V_{t0}} & (linear region) \\ 0 & (saturation region) \end{cases}$$
(9.28)

MOSFET

Small-Signal Model



The MOSFET conductances are denoted by gm, gDS, and gmbs.

$$g_m = \frac{\partial I_{DS}}{\partial V_{GS}} \bigg|_{\text{op}}$$
(9.29)

$$g_{DS} = \frac{\partial I_{DS}}{\partial V_{DS}}\Big|_{\rm op} \tag{9.30}$$

$$g_{mbs} = \frac{\partial I_{DS}}{\partial V_{BS}}\Big|_{\text{op}}$$
(9.31)

The gate junction conductances are denoted by gBD and gBS. These are usually very small, since the junctions are reverse-biased in normal operation.

.

$$g_{BD} = \frac{\partial I_{BD}}{\partial V_{BD}} \bigg|_{\text{op}}$$
(9.32)

$$g_{BS} = \frac{\partial I_{BS}}{\partial V_{BS}}\Big|_{\rm op} \tag{9.33}$$

The bulk junction capacitances are denoted by CBS and CBD.

$$C_{BD} = \frac{\partial Q_B}{\partial V_{BD}} \bigg|_{\text{op}}$$
(9.34)

$$C_{BS} = \frac{\partial Q_B}{\partial V_{BS}} \bigg|_{\text{op}}$$
(9.35)

The gate-to-junction and gate-to-bulk capacitances are denoted by CGS, CGD, and CGB.

$$C_{GS} = \frac{\partial Q_G}{\partial V_{GS}}\Big|_{\text{op}}$$
(9.36)

$$C_{GD} = \frac{\partial Q_G}{\partial V_{GD}} \bigg|_{\text{op}}$$
(9.37)

$$C_{GB} = \frac{\partial Q_G}{\partial V_{GB}} \bigg|_{\text{op}}$$
(9.38)

The AC small-signal capacitances are denoted by CDtot, CGtot, and CStot, and CBtot.

$$CD_{tot} = \frac{\partial Q_D}{\partial V_D}\Big|_{\text{tot}}$$
(9.39)

$$CG_{tot} = \frac{\partial Q_G}{\partial V_G}\Big|_{tot}$$
(9.40)

$$CS_{tot} = \frac{\partial Q_S}{\partial V_S}\Big|_{\text{tot}}$$
(9.41)

$$CB_{tot} = \frac{\partial Q_B}{\partial V_B} \bigg|_{\text{tot}}$$
(9.42)

Since these parameters are computed directly from the MOSFET equations, the model is valid for lowand high-frequency simulations.

Noise Model

In addition to the thermal noise associated with *rD* and *rS*, this model includes *channel* and *flicker* noise sources.

$$\overline{\left|i_{DS_n}\right|^2} = \overline{\left|i_{ch}\right|^2} + \overline{\left|i_{flicker}\right|^2}$$
(9.43)

$$\overline{|i_{ch}|^2} = \frac{8}{3}kTg_m \cdot \Delta f \tag{9.44}$$

When **noiselevel** = 3,

$$\overline{|i_{ch}|^2} = \frac{8}{3}kT\beta \cdot (V_{GS} \angle V_{th}) \cdot G_{DS_n} \cdot \left(\frac{1+\alpha+\alpha^2}{1+\alpha}\right) \cdot \Delta f$$
(9.45)

where β is the gain at the operating point and

$$\alpha = \begin{cases} 1 \ge \frac{V_{DS}}{V_{Dsat}} & (linear region) \\ 0 & (saturation region) \end{cases}$$
(9.46)

Flicker noise is modeled in three ways, depending on **noiselevel**. When **noiselevel** = 0,

$$\overline{\left|i_{flicker}\right|^{2}} = \frac{K_{f} \cdot (i_{DS})^{A_{f}}}{C_{ox}L_{eff}^{2}f} \cdot \Delta f$$
(9.47)

When **noiselevel** = 1,

$$\overline{\left|i_{flicker}\right|^{2}} = \frac{K_{f} \cdot (i_{DS})^{A_{f}}}{fC_{ox}L_{eff}W_{eff}} \cdot \Delta f$$
(9.48)

When **noiselevel** = 2 or **noiselevel** = 3,

$$\overline{|i_{flicker}|^2} = \frac{K_f \cdot g_m^2}{f^{4_f} C_{ox} L_{eff} W_{eff}} \cdot \Delta f$$
(9.49)

References

L. W. Nagel, *SPICE2: A Computer Program to Simulate Semiconductor Circuits*. Electronics Research Laboratory Memorandum ERL-M520. Berkeley, CA: University of California, 1975.

P. Antognetti and G. Massobrio (eds.), *Semiconductor Device Modeling with SPICE*, 2nd ed. New York: McGraw-Hill, 1993.

Y. P. Tsivids, Operation and Modeling of the MOS Transistor. New York: McGraw-Hill, 1987.

10 User-Defined External Models

Introduction

The devices that are components of circuits simulated by T-Spice are described by *device models*. In essence, models are mathematical functions that evaluate a device's terminal currents and charges, given its terminal voltages (and in some cases other state variables).

While many "hard-coded" models are included with T-Spice, representing a wide range of devices commonly used in circuit design, the need may arise for special models not already available. Such models may represent improvements over existing models for standard devices (such as transistors), or they may describe devices not included in T-Spice (such as mechanical devices used by MEMS designers, or macro-devices to be described in a behavioral way).

The *user-defined external model* feature allows users to code custom-designed device models using C or C++. The code can be compiled into DLLs (Windows) or shared objects (Unix) and then dynamically linked to T-Spice simulations. Alternatively, the raw code can be interpreted by T-Spice *during* simulation, eliminating the compilation step with faster turnaround time for writing and debugging, at the expense of slower performance.

Creating External Models

Templates

T-Spice simulates user-defined external models with information from either of two sources:

- DLL (dynamically linked library) or shared object files, generated *before* T-Spice is run by compiling C program files. (See "Compiling External Models" on page 481.)
- Uncompiled C program files, interpreted by T-Spice at runtime.

The original C code must be written in any case. A basic framework for this code can be found in the file **template.c**. This file contains comment lines describing the functions and actions required of the code for a typical external model.

The heart of the code is the **ExternalModelMain()** function. This function is called whenever information about the external model is required during simulation—both for initializing and instancing a model and for evaluating devices that are instances of the model. (See "Initializing the Definition" on page 483 and "Instancing a Device" on page 483.)

ExternalModelMain() typically consists of a call to the **GetModelInfo()** function—to specify the device and/or model and the information required—and a **switch(action)** statement—to call other functions based on the value of **action** (see "External Model Actions" on page 488).

Examples

Five example external models are provided. Each example consists of three commented files: a C program (.c) file, a DLL (.dll) file, and a T-Spice input (.sp) file illustrating the use of the model (see "Using External Models" on page 482).

File base name	Model description
diode	A model incorporating most of the features of the standard SPICE diode model, with parameters analogous to those of T-Spice's internal diode model.
mos1	An implementation of the level 1 MOSFET model, with parasitic diodes and resistors and noise models.
resist	A simple linear resistor model.
switch	A switch model implemented as a voltage-controlled resistor with a hysteresis loop. This model is an extension of the SPICE3 voltage-controlled switch.
vco	A voltage-controlled oscillator (VCO) model.

Compiling External Models

To be used in DLL or shared object form, external models must be compiled from the original C code.

The (required) C compiler and (provided) make file, make script, and object file names for each supported platform are as follows.

Platform	Compiler	Make file	Make script	Object file
Windows	Visual C++ 4.0 or later	model.mak	makemodl.bat	tspmodel.lib
Solaris	gcc	Makefile	makemodel_sol	tspmodel_sol.o

Example files and instructions for these platforms are also provided.

To compile from a DOS command line, you must first configure your DOS environment for Microsoft Visual C++. Visual C++ includes a batch file that you can execute from autoexec.bat. This will establish the environment variables needed to run the C tools from the DOS command prompt. Generally, you can set up this environment by adding the following line to your autoexec.bat file:

C:\Progra~1\Micros~1\VC98\Bin\vcvars32.bat

To compile from the command line (Unix or DOS), type the following at the prompt:

script model

where *script* is the name of the appropriate make script (e.g., *mademodel.bat* on Windows) and *model* is the base name of the C file that contains the external model (for example, *resistor* for a model contained in *resistor.c*).

Using Microsoft Developer

To compile an external model using Microsoft Visual C++ Developer:

- With Visual C++ Developer launched, use the File > New command to create a new project: in the dialog, select Projects. Select Win32 Dynamic Link Library. Give the project a name and choose a location: use the file browser to navigate to the directory if it already exists; if not, then a new directory will be created. Click OK.
- When asked What kind of DLL would you like to create?, choose An empty DLL project. Click Finish. When the New Project Information dialog displays, click OK.
- Use the File > New command to create a program file: in the dialog, select C++ Source File. Choose a file name and click OK.

Note:

The file name you choose must be either a C file (*.c) or a C++ file (*.cpp). If you choose a C++ file, you will have to wrap all T-Spice interface declarations with **extern "C"{...}**.

- Copy the text of program template.c and paste it into the editing space. Save the file.
- Use the Tools > Options command to add search paths to the T-Spice external C header and library files: in the dialog, click the Directories tab.
- In the Show directories for pull-down menu, select Include files. In the Directories: list, enter the fully qualified path to the extmod/win32 directory. (If you used the default installation of T-Spice Pro, this will be C:\Tanner\TSpice70\extmod/win32.)
- In the Show directories for pull-down menu, select Library files. In the Directories: list, enter the same path as in the previous step.
- Use the Project > Settings command and perform the following actions:
- Set Settings for to All Configurations.
- Click the Debug tab. In the field Executable for debug session, enter the fully qualified path to tspice.exe. (C:\Tanner\TSpice91\tspice.exe by default.)
- In the Working directory field, enter the path to your T-Spice netlist.
- In the Program arguments field, enter the name of your T-Spice netlist. You can now compile and debug your external C model.
- Click the C/C++ tab. From the Category pull-down menu, select Code Generation. Set processor to Blend. Set Calling convention to __cdecl. Set Struct member alignment to 8 bytes.
- From the Category pull-down menu, select Preprocessor. Add MAKE_DLL to the Preprocessor definitions list. Set Setting for to both the Win32 Debug and Win32 Release versions.
- Click the Link tab. Make sure that Object/library modules includes tspmodel.lib.
- Click OK.
- Use the Build >project.dll command to compile the DLL.

Using External Models

After a user-defined external model has been created and compiled (if it is to be used in DLL or shared object form), it can be used in a simulation. This involves two procedures: initializing the model definition and instancing a device using the model.

Initializing the Definition

An external model definition is initialized from within a T-Spice input file by means of the ".model" (page 99) command with the external keyword:

.model name external ([parameter=value [...]])

name is the string by which the model will be identified in the input file.

Within the parentheses, predefined *parameters* are assigned *values* (as many as necessary) to tune the model's characteristics. Values may be numbers or strings; string values are enclosed in double quotes. Parameter/value pairs are separated by spaces, and are passed to the external model as *model parameters*.

One of the parameter assignments must indicate the name of the file containing the model code (in either raw or compiled form). The *name* of this parameter depends on the platform:

Platform	Parameter	
Windows	winfile	
Solaris	solfile	

The *value* of this parameter is the name of the file containing the model code. T-Spice will attempt to interpret (that is, treat as raw C code) any file whose name has a **.c** extension. Any other file will be assumed to be already compiled. Compiled files (DLLs or shared objects) typically have extension **.dll** or **.sl**.

Instancing a Device

An actual *instance* of a device using an external model is created within a T-Spice input file using the "Instance (x)" (page 171) statement, in the same way that subcircuit instances are created:

xname node1 [node2 [...]]] modelname [parameter=value [parameter=value
[...]]]

Here, **modelname** must match the **modelname** specified by the corresponding ".model" (page 99) command. Because the **x** key letter is also used for subcircuit instances, **modelname** should not conflict with any subcircuit definition name.

As with model initialization, parameters can be assigned values to tune the instantiated device's characteristics. Values may be numbers or strings; string values are enclosed in double quotes. Parameter/value pairs are separated by spaces, and are passed to the external model as *device parameters*.

When interpreted (C) files are used, a path must be set to the directory containing the header files. This is done in either of two ways:

- At the operating system level, set the environment variable LUPI_INCLUDE to the appropriate path.
- Include the following command in the input file: ".options" (page 109) cpath=path, where path is the appropriate path.

External Model Features

Simple external models may only require the "EVALUATE_DEVICE" (page 492) and "EVALUATE_DERIVATIVES" (page 492) actions. More complex models may need to take advantage of advanced features, a number of which are described in this section:

- "User-Defined Model and Device Parameters," below
- "Error Handling" on page 484
- "Automatic Model Selection" on page 485
- "Parasitic Effects and Internal Nodes" on page 485
- "Noise Analysis" on page 486
- "Current-Controlled Devices" on page 487
- "Voltage Sources" on page 487

User-Defined Model and Device Parameters

When T-Spice parses a ".model" (page 99) command of type **external**, or a device statement instancing an external model, the model and device parameter names and values are stored for later interpretation.

The model's **"PARSE_MODEL_PARAMETERS"** (page 489) and **"PRECOMPUTE_DEVICE_PARAMETERS"** (page 491) actions may use the **LookupParameter** functions to find specific parameter names and their associated values. These are then typically stored in a model-specific structure.

For example, a resistor model may contain the following type declaration:

```
typedef struct ResistorDevice
{
     double resistance;
     double mult;
} ResistorDevice;
```

The code for the "**PRECOMPUTE_DEVICE_PARAMETERS**" (page 491) action might be as follows:

No error handling is performed in this code: if malloc() returns NULL, then disaster follows.

Error Handling

If an error occurs in the user-defined model code, T-Spice must be informed of this so that the simulation can be stopped. This is done by setting the **error** field in the **ExternalModel** or **ExternalModelDevice** structures to 1. Whenever an external model action returns to T-Spice, those **error** fields are checked, and the simulation is stopped if an **error** field is nonzero. For example, the following code might be inserted in the resistor example above, immediately below the call to **malloc()**:

if (r==NULL)

```
{
      device->error = 1;
      return;
```

Automatic Model Selection

}

T-Spice allows multiple ".model" (page 99) commands in one input file with the same model name and different extensions, such as nch.1, nch.2, etc., all of which match devices with the model name nch. The particular .model command actually used with a device is determined by the automatic model selector.

The automatic model selector compares certain device parameter values with model parameter values to determine which model matches the device. For example, T-Spice MOSFET model parameter sets can contain parameters wmin and wmax which specify a range of transistor widths over which the parameter set is valid. The automatic model selector selects a .model command for each device that ensures that the device width **w** falls within the model's width range.

The "MODEL_MATCHES_DEVICE" (page 490) action implements automatic model selection. This action is executed after the "PARSE_MODEL_PARAMETERS" (page 489) action, but before any device parameter parsing. It sets the model->model_matches_device flag to False if the model cannot be matched with the device.

If no model parameter set matches a device, then T-Spice exits with an error message. If multiple model parameters match, then T-Spice selects one of the matching sets.

The following example implements automatic model selection in the case of a MOSFET:

```
MosfetModel *m;
TspBoolean pf;
double w;
m = (MosfetModel *)model->info;
w = LookupParameterDouble(device->parameter list, "w", "0.0", &pf);
model->model matches device = True;
if (m->wmax specified && pf)
       if (w > m - > wmax)
             model->model matches device = False;
if (m->wmin specified && pf)
      if (w < m - > wmin)
             model->model matches device = False;
```

Parasitic Effects and Internal Nodes

Many device models contain parasitic effects-effects that account for various phenomena inherent in the physical medium in which devices are used.

The "PARASITIC SETUP" (page 491) action adds parasitic effects. Several predefined functions ("AddSeriesResistor()" (page 492), "AddParasiticDiode()" (page 492)) add simple standard parasitics. The "AddInternalNode()" (page 492) function adds custom parasitic elements by generating internal state variables. The "EVALUATE DEVICE" (page 492) action adds the contributions of these elements.

For example, a 100 Ω parasitic resistor could be added in series with terminal 0 of a device with the "AddSeriesResistor()" (page 492) function:

device->rs id = AddSeriesResistor(device, 0, 100.0, "RS");

Alternatively, the "AddInternalNode()" (page 492) function could be used:

d->rs terminal = AddInternalNode(device, "rs");

Using **"AddSeriesResistor()**" (page 492) is more convenient. However, **"AddInternalNode()**" (page 492) allows for the addition of arbitrary series parasitic devices.

In the case of the internal node method, the resistor's current would have to be accounted for by the "EVALUATE_DEVICE" (page 492) action as follows:

```
double irs = (device->voltage[0] - device->voltage[d->rs_terminal]) / 100.0;
device->current[0] += irs;
device->current[d->rs terminal] -= irs;
```

In addition, the **"EVALUATE_DERIVATIVES**" (page 492) action would need to add the parasitic resistor's derivative (unless numerical derivatives were used):

```
device->current_deriv[0][0] += 1.0/100.0;
device->current_deriv[0][d->rs_terminal] -= 1.0/100.0;
device->current_deriv[d->rs_terminal][0] -= 1.0/100.0;
device->current_deriv[d->rs_terminal] [d->rs_terminal] += 1.0/100.0;
```

If thermal noise modeling for the resistor were desired, then the "NOISE_SETUP" (page 493) action would set up a noise source:

```
AddNoiseSource(device, "RS", 0, d->rs_terminal, 4.0*BOLTZMANN_CONSTANT*(1.0/
100.0)*(model->sim data[SIM TEMPERATURE]+KELVIN));
```

Noise Analysis

Noise analysis is performed in conjunction with an AC analysis frequency sweep. T-Spice's noise analysis computes the effect of "random" phenomena on the circuit output. Examples of such phenomena are resistor thermal noise and semiconductor shot and flicker noise.

Noise generators are modeled as current sources characterized by mean-square values in A^2 / Hz . Instantaneous noise source values are not available, since the effects are considered random.

The "NOISE_SETUP" (page 493) action calls the "AddNoiseSource()" (page 493) function to add a noise current source of specified mean-square value between two device terminals.

The ".print" (page 122) command with the **noise** parameter can be used (in the T-Spice input file) with the noise source name to plot the effects of such noise sources on the circuit output.

The following example adds a typical thermal noise source for a resistor:

AddNoiseSource(device, "RS", 0, d->rs_terminal, 4.0*BOLTZMANN_CONSTANT*(1.0/ 100.0)*(model->sim data[SIM TEMPERATURE]+KELVIN));

The following T-Spice command outputs the effect of this noise source (assuming the input file contains ".noise" (page 104) and ".ac" (page 61) commands, and a device called **x1** which uses the external model):

.print noise dn(x1, RS)

If all noise sources are frequency independent, no more code needs to be written in the external model. Otherwise, the "**NOISE_EVALUATE**" (page 493) action can be used to set a noise source's mean-square value at each frequency point. This is done by calling the "**SetNoiseSourceValue()**" (page 493) function. The noise source is identified by the name given to it by the "**AddNoiseSource()**" (page 493) function.

The following example sets the flicker noise source value for a diode:

Current-Controlled Devices

While most T-Spice models set terminal currents and charges as functions of terminal voltages, it is sometimes desirable to use devices which use a current (instead of a voltage) as an input state variable. An example of this is the standard SPICE current-controlled current source.

T-Spice's external models allow for current-controlled devices. The \mathbf{x} device statement syntax allows on its pin list either node names or voltage source currents of the form **i**(*vsource*). For example, the declarations

```
x1 n1 n2 i(v1) mymodel
v1 n2 n3 0
```

generate a three-terminal device x1, with the third terminal representing the current through the voltage source v1.

The voltage source current can be accessed by device->voltage[2].

The device->terminal_type array can be examined to differentiate between node voltage and voltage source current type terminals. If terminal *i* is a node voltage, then device->terminal_type[*i*] equals TERMINAL_NODE_VOLTAGE; if it is a voltage source current, then device->terminal_type[*i*] equals TERMINAL_VSOURCE_CURRENT.

It is illegal to set the **device->current** and **device->charge** values of a **TERMINAL_VSOURCE_CURRENT** terminal.

Voltage Sources

Voltage sources, instead of setting terminal currents and charges, specify the potential difference between two terminal nodes. The current through the device is computed internally. This requires the addition of an internal node which represents the voltage source current.

Voltage sources can be inserted between any two terminals. To set up such a voltage source, either of the "**PRECOMPUTE_DEVICE_PARAMETERS**" (page 491) or "**PARASITIC_SETUP**" (page 491) actions can call the "**VoltageSource()**" (page 491) function. This declares a voltage source, and internally creates the extra terminal needed to represent the voltage source current.

The following example creates a voltage source between the first two terminals:

d->vsid = VoltageSource(device,0,1);

The return value is an identification number which is later used when setting the voltage source value. The first terminal is considered the positive terminal; that is, the voltage source value is defined to be the second terminal's voltage subtracted from the first terminal's voltage.

The **"EVALUATE_DEVICE**" (page 492) action sets the voltage source's value by calling the **"SetVoltageSourceValue()**" (page 492) function.

The following example sets a constant 5 V voltage source:

```
SetVoltageSourceValue(device, d->vsid, 5);
```

A voltage source may be controlled by other terminals' voltage (or current) values. The following example generates a linear voltage-controlled voltage source (VCVS):

Unless numerical differentiation is used, the "EVALUATE_DERIVATIVES" (page 492) action must calculate and set a voltage source's derivatives. For independent voltage sources, that derivative is always zero, so that no model code needs to be written. But for controlled voltage sources, such as the VCVS above, the derivatives must be set. For the VCVS example above, the derivatives would be set by:

```
SetVoltageSourceDerivative(device, d->vsid, 2, d->k);
SetVoltageSourceDerivative(device, d->vsid, 3, -d->k);
```

External Model Actions

Short descriptions of the predefined actions executed by **ExternalModelMain()** are given below. Each action is treated in more detail following. The actions are listed in the order in which they are executed. The actual *code* implementing each relevant action must, of course, be developed by the user.

"PARSE_MODEL_PARAMETERS" (page 489)

Read model parameter names and values and allocate memory.

```
"MODEL_MATCHES_DEVICE" (page 490)
```

Decide whether or not a requested model/device pair matches. Used in automatic model selection. (See "Automatic Model Selection" on page 485.)

"PRECOMPUTE_MODEL_PARAMETERS" (page 491)

Check model parameter names and values, precompute constant quantities to speed up model evaluations, and allocate memory.

"PRECOMPUTE_DEVICE_PARAMETERS" (page 491)

Check device parameter names and values, precompute constant quantities to speed up device evaluations, and allocate memory.

"PARASITIC_SETUP" (page 491)

Add parasitics (typically series resistors, parallel diodes, or internal nodes).

"EVALUATE_DEVICE" (page 492)

Given node voltages and state information, compute terminal currents and charges. *This action is required*.

"EVALUATE_DERIVATIVES" (page 492)

Compute all partial derivatives of the terminal currents and charges with respect to the terminal voltages. *This action is required.*

"NOISE_SETUP" (page 493)

Set up noise sources and make frequency-independent computations.

"NOISE_EVALUATE" (page 493)

Evaluate frequency-dependent noise sources at a particular frequency.

"PRINT_SMALL_SIGNAL_PARAMS" (page 493)

Compute and print small-signal parameter values.

"CLEANUP_DEVICE" (page 494)

Free memory associated with a device.

"CLEANUP_MODEL" (page 494)

Free memory associated with a model.

PARSE_MODEL_PARAMETERS

The **PARSE_MODEL_PARAMETERS** action processes the parameter list specified by ".model" (page 99) in the input file.

The purpose of the **.model** command is to introduce a model into the simulation. At the code level, this means initializing a data structure of type **ExternalModel**.

Most parameter names and values from the **.model** command are stored in a linked list. The pointer to this list is the **parameter_list** member of the **ExternalModel** structure.

The values from **parameter_list** must be stored as separate items of data; they are typically placed in fields of a user-defined structure whose pointer is stored by the **info** member of the **ExternalModel** structure.

Thus, the code for **PARSE_MODEL_PARAMETERS** generally involves:

- Allocating the memory needed to store specific parameter values in the particular ExternalModel structure being initialized. This is typically done with malloc().
- Looking through (parsing) the parameter list to identify and store the specified parameter values in the appropriate locations. This is done with the LookupParameter...() functions.

LookupParameterDouble()	Look up parameters of type double . The return value is a double .
LookupParameterInt()	Look up parameters of type int. The return value is an int.
LookupParameterString()	Look up parameters of type char . The return value is a char *, a pointer to the string array.

The LookupParameter...() functions all have the same arguments:

Туре	Argument	
TspParamListElem *	paramlist	
	The pointer to the model's parameter list (the parameter_list member of the ExternalModel structure).	
char *	parameter_name	
	The name(s) of the parameter to be extracted from the parameter list, enclosed in double quotes. The search is case-insensitive. Multiple names for the same parameter may be searched simultaneously by separating them with a vertical bar in the parameter_name string.	
char *	default_value	
	The value assigned to the requested parameter if it is not found in parameter_list , enclosed in double quotes. If necessary, this string is converted to the appropriate numeric type using atoi() or atof() . The result becomes the function's return value.	
TspBoolean *	parameter_found	
	This Boolean, passed by reference, is set to True if the parameter was found, and False otherwise.	

PARSE_MODEL_PARAMETERS is executed for each **.model** command in the input file, whether the model referred to is instanced as a device or not. This is to support automatic model selection, which requires that model parameter values be known before models and devices are matched. (See "Automatic Model Selection" on page 485.)

PARSE_MODEL_PARAMETERS acts on model parameter sets *only*. Thus, for this action, the device (d) passed to **ExternalModelMain()** is **NULL**.

If **malloc()** is used to allocate the memory pointed to by **info**, then the memory should be freed by the "**CLEANUP_MODEL**" (page 494) action.

"Unused" model parameters—items in **parameter_list** which were never looked up—can be listed by the "**PRECOMPUTE_MODEL_PARAMETERS**" (page 491) action.

For models that are actually instanced as devices, any remaining initialization tasks can be performed by the "**PRECOMPUTE_MODEL_PARAMETERS**" (page 491) action.

MODEL_MATCHES_DEVICE

The **MODEL_MATCHES_DEVICE** action compares model and device parameter values to find a match.

- Model parameter values are looked up in model->info if they have been stored there (if the "PARSE_MODEL_PARAMETERS" (page 489) action has been performed already).
- Device parameter values have not been stored; they are found with the LookupParameter functions.

If the comparison fails, then the **model_matches_device** member of the **ExternalModel** structure is set to **False**.

MODEL_MATCHES_DEVICE supports automatic model selection. Several .model commands in one input file can specify the same model name (with different extensions), and a device can have its model chosen automatically. This is done by comparing parameters between the device and the candidate models. (See "Automatic Model Selection" on page 485.)

If automatic model selection is not used for a model, then **MODEL_MATCHES_DEVICE** can be omitted.

PRECOMPUTE_MODEL_PARAMETERS

The **PRECOMPUTE_MODEL_PARAMETERS** action performs preparatory computations on a model parameter set.

PRECOMPUTE_MODEL_PARAMETERS can use the following function.

PrintUnusedParameterMeList "unused" model parameters—items in parameter_list which
were never looked up.

PARSE_MODEL_PARAMETERS acts on model parameter sets *only*. Thus, for this action, the device (d) passed to **ExternalModelMain()** is **NULL**.

PRECOMPUTE_DEVICE_PARAMETERS

The **PRECOMPUTE_DEVICE_PARAMETERS** action parses and precomputes a device parameter set.

At this point, the device has been matched with a model, and that model is passed to **ExternalModelMain()**. (A pointer to the model is also available in the model field of the **ExternalModelDevice** structure.) Like **ExternalModel, ExternalModelMain()** has a **parameter_list** field and an **info** field, and their use is analogous to their **ExternalModel** counterparts.

PRECOMPUTE_DEVICE_PARAMETERS can use the following functions.

LookupParameter()	Look up device parameter values.
PrintUnusedParameterMe ssage()	List unused device parameters.
VoltageSource()	Set up voltage sources.

PARASITIC_SETUP

The **PARASITIC_SETUP** action adds parasitic devices and internal nodes.

Parasitic devices are added after all device and model parameters have been resolved. Standard MOSFET models require at least parasitic resistors and diodes.

Parasitic devices can be added in parallel (between existing nodes), or in series with a device's terminal (requiring the addition of a new node).

If the device is a MOSFET, one of T-Spice's standard MOSFET parasitic models may be used.

Care must be taken to ensure that ".print" (page 122) commands account for parasitics properly.

PARASITIC_SETUP can use the following functions.

AddSeriesResistor()	Add a resistor in series with a given terminal. The return value is an ID number which can be used later to refer to the resistor. The noise modeling for series resistors is automatic if the noise_source_name field is not NULL .
AddParasiticDiode()	Add a diode in parallel with two given terminals. The return value is an ID number which can be used later to refer to the diode. A diode model must be given as well, with a call to the "NewParasiticDiodeModel() " (page 492) function.
NewParasiticDiodeModel()	Return a required diode <i>model</i> in conjunction with "AddParasiticDiode() " (page 492), setting all parameters to typical values.
	The parameter values can be modified as needed before the call to "AddParasiticDiode() " (page 492); they are the standard MOSFET parasitic diode parameters (see "Additional MOSFET Parameters" on page 455).
AddInternalNode()	Add a terminal to the device. The return value is the terminal number of the new terminal. The new terminal can be used to hold internal state information for the device.
	For example, a series resistor can be created by AddInternalNode() instead of " AddSeriesResistor() " (page 492) (see "Parasitic Effects and Internal Nodes" on page 485). It is then the model's responsibility to compute the resistor current.

EVALUATE_DEVICE

The **EVALUATE_DEVICE** action evaluates a device's terminal currents and charges, given terminal voltage values.

The terminal voltages are stored in **device->voltage**. In the case of current-controlled sources, one of the **device->voltage** values actually represents the current through the controlling voltage source.

EVALUATE_DEVICE sets the contents of **device->current** and **device->charge**.

EVALUATE_DEVICE can use the following function.

SetVoltageSourceValue()	Set the voltage value(s), if the device to be evaluated is or contains		
	one or more voltage sources. One of the arguments is a voltage		
	source ID number, which is the return value of a		
	"VoltageSource()" (page 491) function call.		

EVALUATE_DERIVATIVES

The **EVALUATE_DERIVATIVES** action evaluates the partial derivatives of the device's terminal currents and charges, with respect to its terminal voltages.

EVALUATE_DERIVATIVES can use the following functions.

ComputeNumericalDerivat ives()	Compute derivatives by differences. (Otherwise, if derivatives are available in analytic form, then they can be directly assigned to the matrices device->current_deriv and device->charge_deriv .)
SetVoltageSourceDerivati ve()	Set the derivative of a voltage value with respect to a particular device terminal voltage, if the device to be evaluated is or contains one or more voltage sources.

EVALUATE_DERIVATIVES may assume that the "**EVALUATE_DEVICE**" (page 492) action was performed just before with the same voltages.

NOISE_SETUP

The NOISE_SETUP action performs one-time initializations for noise analysis.

NOISE_SETUP can use the following function.

AddNoiseSource() Define noise sources with assigned values.

The device's voltage, current, and charge fields contain the appropriate values at the operating point at which the noise analysis is to be performed.

At the beginning of a noise analysis, noise sources are identified for each device, and any one-time frequency-independent precomputations are performed.

NOISE_SETUP can be ignored if the model does not contain any noise source models.

NOISE_EVALUATE

The **NOISE_EVALUATE** action re-evaluates frequency-dependent noise source contributions at each frequency point of a noise analysis.

NOISE_EVALUATE can use the following function.

SetNoiseSourceValue() Set a noise source's mean-square value.

Any frequency-dependent noise source values are set by **NOISE_EVALUATE**; if no such noise sources are present, then **NOISE_EVALUATE** can be omitted.

PRINT_SMALL_SIGNAL_PARAMS

The **PRINT_SMALL_SIGNAL_PARAMS** action defines small-signal parameters to be printed with the ".acmodel" (page 64) command.

PRINT_SMALL_SIGNAL_PARAMS can use the SmallSignalParameter...() functions.

SmallSignalParameterStri ng()	Defines a string parameter (char*) for printing.
SmallSignalParameterDou ble()	Defines a floating point (double) parameter for printing.
SmallSignalParameterInt()	Defines an integer parameter (int) for printing.

CLEANUP_DEVICE

The **CLEANUP_DEVICE** action frees any memory that has been allocated for the device structure, such as the **device->info** field.

CLEANUP_MODEL

The **CLEANUP_MODEL** action frees any memory that has been allocated for the model structure, such as the **model->info** field.

CLEANUP_MODEL is called *after* "**CLEANUP_DEVICE**" (page 494) has been performed for every instance of the model.

11 Parametric Analysis

Introduction

T-Spice is often required to study the effects of *variations* in parameter values on circuit performance. For example, parametric analysis can be used to evaluate multidimensional trends in the output over defined ranges of input values, or the sensitivity of circuit behavior to random fluctuations in fabrication conditions.

A large range of parameters may be systematically and automatically varied:

- External parameters (such as temperature)
- Simulation parameters (such as tolerances)
- Device parameters (such as input voltage level or transistor length)
- Model parameters (such as transistor threshold voltage)

Three types of parametric analysis are supported by T-Spice: *parameter sweeping*, *Monte Carlo analysis*, and *optimization*.

This chapter guides you through several tutorial problems in order to demonstrate some basic concepts of parametric analysis.

The example files for these tutorials can be found in the ...\examples\input subdirectory of the T-Spice Pro installation path.

Output File Formats

Results produced by parameter sweeps and Monte Carlo analysis are easily read in T-Spice output files. You can open a T-Spice output file from the T-Spice Simulation Manager by clicking on the **Show Output** button. Alternatively, select **File > Open** and browse within the **Open** dialog to select the output filename. T-Spice output files are text files; they are also readable in the text editor of your choice.

Analysis results for parameter sweeps are reported in table format, with section headings that contain the current values of the swept parameters. For example, if a **.step** command invokes several transient analyses, each analysis produces its own output section, the header of which shows the parameter values for that analysis (e.g., **TRANSIENT ANALYSIS – vdd=3**).

Results obtained from **.measure** commands are listed at the end of each output section corresponding to a specific parameter value. These measurements are summarized at the end of the sweep in a table labeled **TRANSFER ANALYSIS**. The use of a **.step** command causes **.measure** results to be plotted in W-Edit, with the swept variable as the *x*-axis.

Parameter Sweeps

In a *parameter sweep*, a specified parameter is held or initialized at a given value, all analyses requested by the input file are performed, and the results are recorded. Then the parameter is incremented by a set amount, and the same analyses are repeated. The cycle continues as the parameter is incremented through a defined range of values.

Parameter values may be swept *linearly*—in identical increments, typically through a limited range—or *logarithmically*—in exponential increments, typically through a range spanning multiple orders of magnitude. You can also specify a sweep over a list of values.

Parameter sweeping is performed by using the **sweep** option with one of the following commands:

- .ac (see ".ac" on page 61)
- .dc (see ".dc" on page 72)
- .step (see ".step" on page 141)
- .tran (see ".tran" on page 148)

Additionally, it is also possible to perform simultaneous parameter sweeps of several different variables using the command .data (see ".connect" on page 69).

Adding the **sweep** option to a .tran or .ac command instructs T-Spice to perform that analysis for all parameter values of the specified sweep. Using the **sweep** option with an analysis command is similar to using it with .step. A single .step command causes T-Spice to perform parameter sweeps for *all* analysis commands in the input file. If **sweep** is specified on an analysis command and a .step command is present, the **sweep** specified with the analysis command is nested inside the sweep specified with the .step command.

All input files listed for this chapter are in the directory <install_dir>\tutorial\input.

Example 1: Parametric Sweep

This example uses a ring oscillator to demonstrate the basic features of a parametric sweep.

T-Spice Input	ring2.cir
Output	ring2.out

T-Spice Input

```
* Circuit: ring2.sp
*
.SUBCKT inv in out Gnd Vdd
c2 out Gnd cap
mlp out in Vdd Vdd pmos L=5u W=12u
mn1 out in Gnd Gnd nmos L=5u W=8u
.ENDS
* Main circuit: ring2
cinv1 a7 Gnd 400ff
.include m12_125.md
Xinv1 a1 a2 Gnd Vdd inv
```

```
Xinv2 a2 a3 Gnd Vdd inv
Xinv3 a3 a4 Gnd Vdd inv
Xinv4 a4 a5 Gnd Vdd inv
Xinv5 a5 a6 Gnd Vdd inv
Xinv6 a6 a7 Gnd Vdd inv
Xinv7 a7 a1 Gnd Vdd inv
.measure tran period trig v(a2) val=3.0 fall=2 targ v(a2) val=3.0 fall=3
.measure tran pulsewidth trig v(a2) val=1.5 rise=2 targ v(a2) val=1.5 fall=2
.measure tran timedelay trig v(a2) val=3.0 fall=2 targ v(a1) val=3.0 fall=2
.param cap=800ff
.print tran a1
.step cap 200f 1000f 200f
.tran/powerup 1n 800n
vdd Vdd Gnd 3.0
* End of main circuit: ring2
```

In this example, instead of keeping the load capacitor in the inverter subcircuit constant, the capacitor is defined as a variable **cap** and T-Spice sweeps it over a range of **200fF** to **1000fF**. The **.param** statement sets a nominal value for **cap** and the **.step** command sweeps **cap** linearly from **200fF** to **1000fF** in increments of **200fF**.

The **.measure** statement measures the period, time delay, and pulse width of the ring oscillator at the different values of capacitance. In this example, period is measured at v(a2)=3V from its second falling edge to its third falling edge. Time delay is measured from the second falling edge of v(a2) at 3V to the second falling edge of v(a1) at 3V. Pulse width is measured from the second rising edge of v(a2) at 1.5V to the second falling edge of v(a2) at 1.5V.

Output

T-Spice reports the transient analysis results in five sections for cap=200fF, 400fF, 600fF, 800fF, and 1000fF.

Following is part of the output section for cap=200fF.

```
TRANSIENT ANALYSIS - cap=2e-013

Time<s> v(a1)<V>

0.0000e+000 0.0000e+000

1.0876e-010 1.9456e-002

4.9424e-010 3.3521e-001

8.9842e-010 6.0502e-001

1.2047e-009 7.0183e-001
```

The measurement results are reported at the end of each section.

```
MEASUREMENT RESULTS - cap=2e-013
period = 9.9026e-008
  Trigger = 1.7549e-007
  Target = 2.7452e-007
pulsewidth = 4.8288e-008
  Trigger = 1.3217e-007
  Target = 1.8046e-007
timedelay = 4.1316e-008
  Trigger = 1.7549e-007
  Target = 2.1681e-007
```

Measurement results are summarized in a table at the end of the output file. Because the **.step** command was used, measurement results will be plotted against the parameter **cap** in W-Edit.

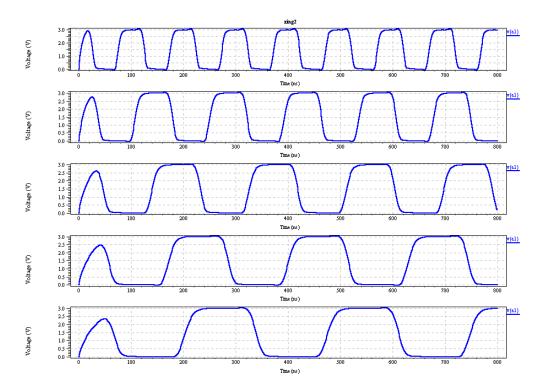
```
TRANSFER ANALYSIS
```

cap<>	period<>	pulsewidth<>	timedelay<>
2.0000e-013	9.9026e-008	4.8288e-008	4.1316e-008
4.0000e-013	1.4248e-007	6.9783e-008	5.9662e-008
6.0000e-013	1.8579e-007	9.1213e-008	7.8093e-008
8.0000e-013	2.2913e-007	1.1262e-007	9.6608e-008
1.0000e-012	2.7235e-007	1.3401e-007	1.1505e-007

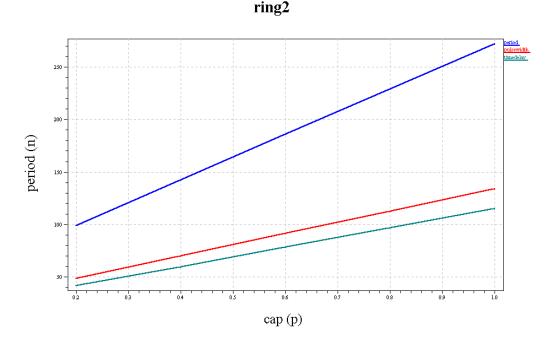
Waveform

The following two figures show the waveform output for this example. The first displays the output of the ring oscillator vs. time with different capacitance values; the second displays the period, time delay and pulse width in a single chart.

Ring oscillator versus time at different capacitances:



Period (blue), time delay (green) and pulse width (red) charted together:.



Monte Carlo Analysis

In a Monte Carlo analysis, T-Spice performs simulation runs using randomly chosen parameter values. The parameter values for each run are chosen from probability distributions defined by the user.

T-Spice's Monte Carlo analysis will generate a summary output of all simulation run measurement results after all runs are completed. T-Spice will also report, for each Monte Carlo iteration, the values of all expressions evaluated using probability distributions.

Monte Carlo analysis can be invoked using the keywords **sweep monte** with one of the following commands:

- ".ac" (page 61)
- ".dc" (page 72)
- ".step" (page 141)
- ".tran" (page 148)

Syntax and options for the keyword sweep are defined in the section describing ".step" (page 141).

Probability distributions are assigned to parameters by use of the **.param** command. For a complete description of the syntax of this command, see "**.param**" (page 116).

Example 2: Monte Carlo Analysis

This example demonstrates Monte Carlo Analysis on a CMOS inverter circuit.

Output

Input

invert5.cir invert5.out

Input

```
* Main circuit: invert5
c2 out Gnd 800ff
.include ml2_125mc.md
mln out in Gnd Gnd nmos L=5u W=8u
mlp out in Vdd Vdd pmos L=5u W=12u
.measure tran falltime trig v(out) val=2.8 fall=1 targ v(out) val=0.2 fall=1
.param vto_n=unif(0.622490, 0.5, 1) vto_p=unif(-0.63025, 0.5, 1)
.tran 2n 600n sweep monte=10
.print tran in out
vdd Vdd Gnd 3.0
vin in Gnd pwl (Ons OV 100ns OV 105ns 3V 200ns 3V 205ns OV 300ns
+ OV 305ns 3V 400ns 3V 405ns OV 500ns OV 505ns 3V 600ns 3V)
* End of main circuit: invert5
```

A Monte Carlo analysis sweeps parameter values that are chosen based on statistical variations. In this example, T-Spice varies the model parameter **vto** using random values chosen by probability distribution. In model file **ml2_125mc.md**, the **.model** statement specifies the **vto** parameter as two variables: **vto_n** for an n-channel MOSFET and **vto_p** for a p-channel MOSFET.

The .param statement defines the probability distribution, where vto_n=unif(0.622490, 0.5, 1) and vto_p=unif(-0.63025, 0.5, 1) select uniform distributions centered at 0.622490 and -0.63025 with relative variation of 50%. The keyword monte=10 in the .tran statement invokes Monte Carlo analysis with 10 runs. The .measure statement measures the falltime of the output pulse for different values of vto.

Output

T-Spice reports the transient analysis results in ten sections for the ten Monte Carlo runs.

Following is part of the output section for the first run.

```
TRANSIENT ANALYSIS - Monte-Carlo-index=1

Time<s> v(in)<V> v(out)<V>

0.0000e+000 0.0000e+000 2.9996e+000

6.0000e-010 0.0000e+000 2.9996e+000

2.6000e-009 0.0000e+000 2.9996e+000

4.6000e-009 0.0000e+000 2.9996e+000

6.6000e-009 0.0000e+000 2.9996e+000

8.5999e-009 0.0000e+000 2.9996e+000
```

Measurement results are reported at the end of each section.

MEASUREMENT RESULTS - Monte-Carlo-index=1

falltime = 1.2278e-008
Trigger = 1.0471e-007
Target = 1.1699e-007

At the end of the output file, T-Spice reports the Monte Carlo parameter values for each run:

MONTE CARLO PARAMETER VALUES

Index 1							
	parameter	Vto	for	model	nmos	=	3.1202e-001
	parameter	Vto	for	model	pmos	=	-6.7032e-001
Index 2							
	parameter	Vto	for	model	nmos	=	4.3157e-001
	parameter	Vto	for	model	pmos	=	-8.2483e-001
Index 3							
	parameter	Vto	for	model	nmos	=	6.7541e-001
	parameter	Vto	for	model	pmos	=	-6.1756e-001

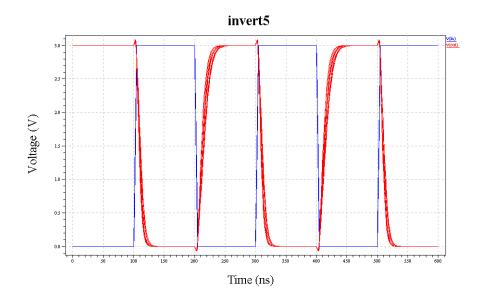
Measurement results are summarized along with the following statistical results from the analysis — minimum, maximum, mean, average deviation, variance, and sigma:

MONTE CARLO PARAMETER STATISTICS

VariableMinimumparameter vth0 for model NMOS325.8096parameter xl for model NMOS-22.8550nparameter xw for model NMOS-79.6264nparameter vth0 for model PMOS-513.5953mparameter xl for model PMOS-21.1612nparameter xw for model PMOS-66.7281n	Maximum 382.7094m 22.5583n -12.5077n -460.3336m 19.3704n -4.0675n	368.9319m 30 7.4712n 4 -46.2837n -4 -493.8904m -4 -318.9184p 2	Mean 65.2907m .2441n 45.0382n 493.1504m .7201n 38.3830n	AvgDev 14.6962m 10.7063n 21.0046n 12.4712m 11.3036n 21.2560n	Variance 278.8930u 149.6252a 503.2271a 211.9433u 155.8063a 424.9114a	Sigma 16.7000m 12.2321n 22.4327n 14.5582m 12.4822n 20.6133n
*WEDIT: XFER c	ycles Monte-0	Carlo-index	10			
*WEDIT: .step	Monte-Carlo-	index 1	10	1		
TRANSFER ANALY	SIS					
Index<>	AvgDelay<>			lTime<>		
1.0000e+000	9.4912e-010			05e-009		
2.0000e+000	9.0216e-010	1.8379e-00)9 1.59	57e-009		
3.0000e+000	9.1165e-010	1.9438e-00		61e-009		
4.0000e+000	9.4299e-010	2.0042e-00		35e-009		
5.0000e+000	9.2365e-010	1.9451e-00)9 1.57	45e-009		
6.0000e+000	9.0999e-010	1.8812e-00)9 1.58	10e-009		
7.0000e+000	9.3615e-010	1.9600e-00		34e-009		
8.0000e+000	9.1777e-010	1.9021e-00		70e-009		
9.0000e+000	9.2884e-010	1.9601e-00)9 1.57	07e-009		
1.0000e+001	9.3430e-010	2.0159e-00)9 1.52	45e-009		
Minimum	9.0216e-010	1.8379e-00)9 1.51	61e-009		
Maximum	9.4912e-010	2.0159e-00)9 1.59	57e-009		
Mean	9.2566e-010	1.9464e-00)9 1.56	77e-009		
Avgdev	1.2617e-011	4.4437e-01	L1 1.97	92e-011		
Variance	2.3398e-022	3.4592e-02	21 7.19	60e-022		
Sigma	1.5296e-011	5.8815e-01	2.68	25e-011		

Waveform

Concurrent with the analysis, W-Edit launches and displays the families of output traces from a Monte Carlo run.



Optimization

The T-Spice optimization feature allows circuit parameters to be tuned within given ranges to achieve the best possible circuit performance. T-Spice seeks to minimize the difference between performance measurements and a user-defined optimization goal. In order to specify an optimization, you must supply the following:

- [1] A list of parameters which can be adjusted to optimize performance. Each parameter is assigned a nominal, minimum, and maximum value with **.paramlimits**. The nominal value serves as the initial guess in the optimization process. (For a complete description of the syntax of the **.paramlimits** command, see **".paramlimits**" (page 120))
- [2] An optimization goal defined in terms of .optgoal commands and .measure results. T-Spice attempts to minimize the deviation of .measure results from their respective goal values defined in .optgoal. If multiple .optgoal commands are used, each .optgoal parameter has a weight value to indicate its relative importance. (For a complete description of the syntaxes, see ".macro *l.eom*" (page 90) or ".optgoal" (page 106).)
- [3] A **.optimize** command that invokes the optimization run. The optimization model and analysis name are specified using the **.optimize** command. (For a complete description of the **.optimize** command syntax, see **".optimize**" (page 107).)
- [4] A .model command which defines the optimization algorithm, as well as optimization algorithm parameters and tolerances. (For a complete description of the .model command syntax, see ".model" (page 99).)

Defining Optimization Parameters

Any parameter defined using **.param** can be used as an optimization parameter. Use the **.paramlimits** command to associate such a parameter with an optimization run, so that T-Spice can vary it during the optimization. There is no limit on how many optimization parameters an optimization run can have, but the optimization will be much faster with fewer parameters. The precise syntax for this keyword is described in **".paramlimits**" (page 120).

Defining Optimization Goals

Optimization goals are defined using **.optgoal**. The function of the **.optgoal** command is to link a **.measure** result to an optimization run and to specify a goal value for the measurement. During each optimization run, T-Spice calculates an optimization function based on the differences between measurements and their corresponding optimization goals. T-Spice uses this calculation to find parameter values that minimize the deviation of measurement results from goal values.

An optimization run can have multiple **.optgoal** commands, each of which is assigned a weight. The value of the optimization function for each run is obtained by summing the weighted individual goals: each **.optgoal** contributes a term of the form *weight* × (*goal-result*)/*goal*.

Curve-fit optimization can be performed by using the error function measurements available on the **.measure** command.

For more information on the relevant commands, see ".macro *l.eom*" (page 90) and ".optgoal" (page 106).

Invoking Optimization

A .optimize command invokes an optimization run using the parameters and goals specified by .paramlimits and .optgoal when these commands use a matching optimization run name. Only those parameters for which the run name matches are varied during the optimization run. The model keyword defines an optimization model, which is specified using a .model command with optimization algorithm parameters such as iteration count limits and convergence tolerances. The **analysisname** option identifies the .step, .ac, .dc, or .tran analysis that will be performed to evaluate the measurements for the optimization.

After an optimization, the optimized parameter values are used in all subsequent analyses specified in the same input file. This allows for *incremental optimization*: some parameters can be optimized while others are held fixed; other parameters can then be optimized based on the results of the first optimization. DC analyses are performed first, followed by AC analyses, and then transient analyses. Multiple analyses of the same type are performed in the order in which they are found in the input file.

The T-Spice wizard-style user interface will guide you in setting up optimization commands.

Example 3: Optimization

Input A	opamp_ac.cir
Input B	myopamp.cir
Output	myopamp.out

This tutorial will demonstrate the procedures to be followed in setting up an optimization command. We use the operational amplifier introduced in Example 4 to show how you can optimize output by varying

the output transistor's lengths and widths. We can use the existing netlist by adding optimization commands to the netlist.

This exercise uses the input file **opamp_ac.cir** as a base file to which we will add optimization commands in the course of the tutorial. The modified input file that you create will be named **myopamp.cir**. For reference, we have included a file called **opamp4.cir**, which represents what **myopamp.cir** should look like at the end of the tutorial.

- Open opamp.cir and choose File > Save As to rename the file. Name the file myopamp.cir.
- For simplicity, remove the statements .print ac vp(out) and .acmodel opamp1m.out (*) in the original netlist.
- Place the cursor at the beginning of any line, such as the line above the .include statement. Choose Edit
 Insert Command or click the Insert Command icon in the Command toolbar:



- \square In the left-hand pane of the **Command Tool**, click **Settings**. In the right-hand pane, click the **Parameters** button.
- With **Parameter type** set to **General**, enter the following values. For each value pair that you add, click **Add**. T-Spice will add the parameter to the list.

Parameter name	Parameter value	
13	6u	
w3	20u	
14	10u	
w4	6u	

When you have finished, the **Command Tool** will look like this:

T-Spice Command Tool			×
	<u>P</u> arameter type:	General]
Sectings Bus definition Global nodes Parameters Simulation options Temperature Partition	Parameter name: w4	Para <u>m</u> eter value: = 6u	
Table ✓· Table ✓· Voltage source ✓· Optimization	<u>A</u> dd List of parameters: w4=6u	<u>D</u> elete <u>C</u> lear	
	14=10u w3=20u 13=6u		2
		Insert Command Cance	

Click Insert Command. T-Spice will insert the following line into the netlist:

.param 13=6u w3=20u 14=10u w4=6u

- ✓ Next, edit the lengths and widths of output transistors mp3 and mn4 to optimize the results. For mp3, replace the existing length and width values with parameter names l3 and w3, respectively. Enclose these parameter names in single quotes ('). For mn4, replace the existing length and width values with parameter names l4 and w4, respectively.
- ✓ Next, add a .measure command. Place the cursor at the beginning of any line and choose Edit > Insert Command or click the Insert Command icon. Double-click Output, then click Measure under Output (or click the Measure button). The Command Tool will appear in a form suitable for entering a .measure command. Type or select the following values:

Field	Value
Analysis type:	AC
Measurement result name	gain
Measurement type	Signal statistics
Type of measurement	Maximum
Measured signal	vdb(out)

☑ Leave all other fields blank. The **Command Tool** dialog will look like this:

T-Spice Command Tool	K
Analysis Current source Files Initialization Output AC results AC small-signal model DC results Power Transient results Measure Settings Table Table	Analysis type: AC Measurement result name: gain Measurement type: Signal statistics Suppress printing Optimization Minimum value Suppress printing Goal (0): Minimum value (1.0e-12): Weight (1): Measured signal: Measured signal: Type of measurement: Measured signal: vdb(out)
⊡- Optimization	Optional From (default is To (default is end of beginning of analysis): Output signal:
	Insert Command Cancel

Click **Insert Command** to insert the command in the netlist. T-Spice inserts the following line in the netlist:

.measure ac gain max vdb(out)

For the **bandwidth** measurement, repeat the last step, using the following values:

Field	Value
Analysis type	AC
Measurement result name	bandwidth
Measurement type	Find-when
Find	x-value
When	Signal
Signal (name)	vdb(out)
equals value	15

☑ Leave all other fields blank. The **Command Tool** dialog will look like this:

T-Spice Command Tool		X
Analysis Current source Files Initialization Output AC results AC small-signal model DC results Power Transient results Measure Measure Table Voltage source Optimization	Analysis type: AC Measurement Find-when Optimization Goal (0): Weight (1):	Measurement bandwidth result name: Suppress printing Minimum value (1.0e-12):
	Find	C Value of signal eguals value 15 number 1
	Delay before crossing are cou	equals signal number 1
		Insert Command Cancel

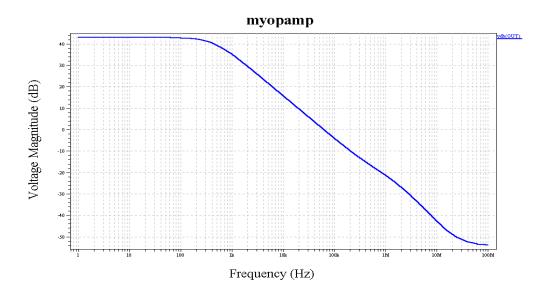
Click Insert Command. T-Spice inserts the following line in the netlist:

.measure ac bandwidth when vdb(out)=15 cross=1

☑ Now, run the simulation. Choose Simulation > Run Simulation, press F5, or click the Run Simulation icon in the Simulation toolbar. T-Spice displays the Run Simulation dialog.

Run Simulation		×
Input file name:	myopamp.cir	Browse
<u>O</u> utput file name:	myopamp.out	Browse
O <u>p</u> tions:		
⊂ <u>W</u> aveform options		not show
	Start Simulation	Cancel

Under Waveform options, select Show during, then click Start Simulation. T-Spice will simulate the circuit, then invoke W-Edit to display the following waveform:



Note that the amplifier has a gain of 43.1 dB and a bandwidth of 11.4 kHz. In the following procedure, we will use the T-Spice optimization feature to modify this design to achieve a gain of 20 dB while maximizing bandwidth.

Switch back to T-Spice. Choose Edit > Insert Command again. T-Spice displays the T-Spice Command Tool. In the left-hand tree, double-click Optimization; the Wizard will appear underneath.

T-Spice Command Tool	×
 Analysis Current source Files Initialization Output Settings Table Voltage source Optimization Wizard 	Optimization
	Insert Command Cancel

Click Wizard (or the Wizard button) to go to the first dialog, Optimization setup. Type optsize in the Optimization name field and type or select First AC Analysis as the analysis name.

T-Spice Command Tool		×
Analysis Current source Files Initialization	Optimization setup	
⊕ Output ⊕ Settings ⊕ Table	Optimization name: optsize	
B Voltage source ⊡ Optimization Wizard	Analysis name: First AC Analysis	
	<u>C</u> ontinue >	
	Insert Command Cancel	

- Click **Continue** to go to the next dialog, **Set optimization goals**. Enter **gain** for the first measurement name, with a target value of **20** (db) and a weight of **5**. Click **Add** to add this in the **List of optimization goals**.
- Repeat these steps to define the second measurement name **bandwidth**, target value **5e3** and weight **1**, and add them to the **List of optimization goals**. The **T-Spice Command Tool** dialog will look like this:

T-Spice Command Tool		×
Analysis Current source Files Initialization Output Settings Table Voltage source Optimization Wizard	Set optimization goals Measurement: Iarget value: bandwidth 5e3 Minimum Value (1e-12): Weight (1): 1e-12 1	
	Add Delete Clear List of optimization goals: bandwidth=5e3 minval=1e-12 weight=1 ▲ gain=20 minval=1e-12 weight=5 ▲ ▲ < Back Continue >	
	Insert Command Cancel	Ρ

Click **Continue** to go to the next dialog, **Set parameter limits**. First set an optimization goal for **I3**, using the first column of values in the following table:

Field	Values			
Parameter name	13	w3	14	w4
Minimum value	1u	1 u	1u	1u
Maximum value	20u	30u	20u	20u
Delta	0.5u	0.5u	0.5u	0.5u
Guess value	6u	20u	10u	6u

 \checkmark

Click Add to add these values to the List of optimization goals. The optimization goals for w3, l4, and w4 can be set in the same way. When you finish, the T-Spice Command Tool dialog will look like this:

T-Spice Command Tool	×
 Analysis Current source Files Initialization Output Settings Table Voltage source Optimization Wizard 	Set parameter limits Parameter name: w4 Minimum value: Maximum value: 1u 20u Delta (Optional): Guess value (Optional): 0.5u 6u Add Delete Delear List of parameters: Utention Iminval=1u maxval=20u delta=0.5u guess=5u W4 minval=1u maxval=20u delta=0.5u guess=10u W3 minval=1u maxval=20u delta=0.5u guess=20u I3 minval=1u maxval=20u delta=0.5u guess=6u Iminval=1u maxval=20u delta=0.5u guess=6u
	Insert Command Cancel

Click **Continue** to go to the next dialog, **Set optimization algorithm**. In the **Name** field, type **optmod**. For all other values, accept the defaults. The **T-Spice Command Tool** dialog will look like this:

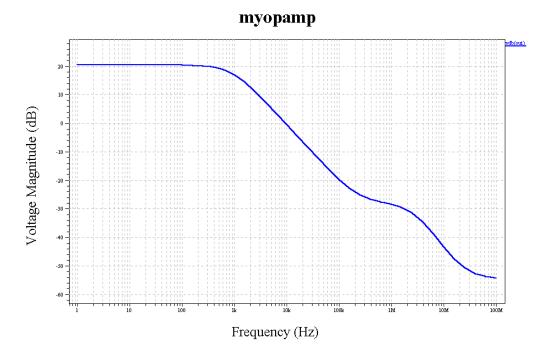
T-Spice Command Tool					×
 P-Analysis P-Current source P-Files P-Initialization P-Output P-Settings P-Table P-Voltage source P-Optimization └──Wizard 	Set optimization Algorithm type: Name: Itropt: Close: Difsiz: Max: Belin: Description:	algorithm [Levenberg-Marq [optmod] [20] [0.001] [1e-3] [600000] [0.001] [0.001] [<u>C</u> endif: C <u>u</u> t: <u>G</u> rad: <u>P</u> armin: Rel <u>o</u> ut:	1e-9 2 1e-6 0.1 0.001	
			Insert Comma	and Cancel	

Click **Continue** to go to the next dialog, **Insert command.** T-Spice displays your optimization commands in the dialog. Check them to make sure they are correct.

```
.optimize optsize model=optmod analysisname=ac
.paramlimits optsize 13 minval=1u maxval=20u delta=0.5u guess=6u
.paramlimits optsize w3 minval=1u maxval=30u delta=0.5u guess=20u
.paramlimits optsize 14 minval=1u maxval=20u delta=0.5u guess=10u
.paramlimits optsize w4 minval=1u maxval=20u delta=0.5u guess=6u
.optgoal optsize gain=20 minval=1e-12 weight=5
.optgoal optsize bandwidth=5e3 minval=1e-12 weight=1
.model optmod opt cendif=1e-9 close=0.001 cut=2 difsiz=1e-3 grad=1e-6
+ itropt=20 max=600000 parmin=0.1 relin=0.001 relout=0.001
```

- \blacksquare If you need to change a line, click **Back** to make changes.
- Click Insert Command. T-Spice inserts the optimization commands in the text editor.

Rerun the simulation. This time you will see the following waveform:



Output

The list of optimization model parameters is summarized in the output file, followed by the optimization results and the optimized parameter values for **I3**, **w3**, **I4**, and **w4**.

```
* BEGIN NON-GRAPHICAL DATA
```

```
Optimization model parameters:
  Level=1
  cendif=1e-009
  close=0.001
  cut=2
  difsiz=0.001
  grad=1e-006
  itropt=20
  max=600000
  parmin=0.1
  relin=0.001
  relout=0.001
* END NON-GRAPHICAL DATA
* BEGIN NON-GRAPHICAL DATA
Optimization results:
                   Residual = 0.359805
              Gradient norm = 0.363615
        Marquardt parameter = 16.384
       Function evaluations = 45
       Number of iterations = 16
```

Optimized parameter values:

13 = 9.5000e-006 w3 = 1.9000e-006 14 = 3.5000e-006 w4 = 1.2000e-006

* END NON-GRAPHICAL DATA

AC analysis results are reported in different sections for different optimization runs. In this example, only one optimization run—optsize—was performed.

```
AC ANALYSIS - OPTIMIZE=optsize

Frequency<Hz> vdb(out)<dB>

1.00000e+000 2.0533e+001

1.58489e+000 2.0533e+001

2.51189e+000 2.0533e+001

3.98107e+000 2.0533e+001

6.30957e+000 2.10533e+001

...
```

The measurement results are reported at the end of each section. Because of the difference in relative weight, **gain** (weight=5) has higher priority in the optimization than **bandwidth** (weight=1), and **gain** is much closer to its optimization goal.

```
gain = 2.0533e+001
    At = 1.0000e+000
bandwidth = 1.4642e+003
```

T-Spice also supports HSPICE-compatible optimization commands, as the following example shows.

Example 4: Optimization Using HSPICE-Compatible Commands

Input	opamp5.cir
Output	opamp5.out
Input	
* Circuit: opamp5.sp *	
<pre>* Main circuit: opamp5 .ac DEC 5 1 100MEG sweep optimize=optsize + results=gain bandwidth model=optmod .model optmod opt level=1 itropt=20 .param l4=optsize(10u, 1u, 20u,0.5u) l3=optsize(6u, 1u, 20u,0.5u) + w4=optsize(6u, 1u, 20u,0.5u) w3=optsize(20u, 1u, 30u, 0.5u) .measure ac gain max vdb(out) goal=20 weight=5 .measure ac bandwidth when vdb(out)=15 goal=5e3 ccomp vf1 out 2pF cout out Gnd 2pF mn1 vn1 vbias Gnd Gnd nmos L=10u W=6u mn2 vm1 in1 vn1 Gnd nmos L=6u W=6u mn3 vf1 in2 vn1 Gnd nmos L=6u W=6u mn4 out vbias Gnd Gnd nmos l='14' w='w4' .include ml2_125.md mp1 vm1 vm1 Vdd Vdd pmos L=6u W=6u</pre>	

```
mp2 vf1 vm1 Vdd Vdd pmos L=6u W=6u
mp3 out vf1 Vdd Vdd pmos l='13' w='w3'
.print ac vdb(out)
vbias vbias Gnd 0.8
Vdd Vdd Gnd 5.0
vdiff in2 in1 -0.0007 AC 1.0 90
vin1 in1 Gnd 2.0
* End of main circuit: opamp5
```

Output

The output of this example is the same as the output "Example 3: Optimization" on page 503.

The following references may be consulted for further information on various aspects of circuit design, modeling, and simulation.

- [1] P. Antognetti and G. Massobrio (eds.), *Semiconductor Device Modeling with SPICE*, 2nd ed. New York: McGraw-Hill, 1993.
- [2] M. A. Belkerdid and P. F. Wahid, "Rise time and frequency correlation for crosstalk in high-speed packaging," *IEPS Proc. Tech. Conf.* (Dallas), pp. 617–636, November 1988.
- [3] F. H. Branin, Jr., "Transient analysis of lossless transmission line," *Proc. IEEE (Letters)*, vol. 55, pp. 2012–2013, 1967.
- [4] T. Dhaene and D. De Zutter, "Selection of lumped element models for coupled lossy transmission lines," *IEEE Trans. Computer-Aided Design*, vol. 11, no. 7, pp. 805–815, July 1992.
- [5] D. Divekar, "Comments on GaAsFET Device and Circuit Simulation in SPICE," *IEEE Trans. Electron Devices*, vol. ED-34, no. 12, pp. 2564–2565, December 1987.
- [6] A. R. Djordjevic, T. K. Sakar, and R. G. Harrington, "Time-domain response of multiconductor transmission lines," *Proc. IEEE*, vol. 75, pp. 743–764, June 1987.
- [7] J. H. Huang, Z. H. Liu, M. C. Jeng, K. Hui, M. Chan, P. K. Ko, and C. Hu, *BSIM3 Manual (Version 2.0)*. Berkeley, CA: University of California, 1994.
- [8] P. K. Ko, C. Hu, et al., *BSIM3v3 Manual (Final Version)*. Berkeley, CA: University of California, 1995.
- [9] M. A. Maher, *A Charge-Controlled Model for MOS Transistors*. Department of Computer Science Document 5223:TR:86. Pasadena, CA: California Institute of Technology, 1989.
- [10] M. A. Maher and C. Mead, "A Physical Charge-Controlled Model for MOS Transistors," in *Advanced Research in VLSI*, P. Losleben (ed.). Cambridge, MA: MIT Press, 1987, p. 211.
- [11] C. Mead, Analog VLSI and Neural Systems. Reading, MA: Addison-Wesley, 1989.
- [12] L. W. Nagel, *SPICE2: A Computer Program to Simulate Semiconductor Circuits.* Electronics Research Laboratory Memorandum ERL-M520. Berkeley, CA: University of California, 1975.
- [13] I. W. Smith, H. Statz, A. Hans, and R. A. Pucel, "On Charge Nonconservation in FETs," *IEEE Trans. Electron Devices*, vol. ED-34, no. 12, pp. 2565–2568, December 1987.
- [14] H. Statz et al., "GaAsFET Device and Circuit Simulation in SPICE," *IEEE Trans. Electron Devices*, vol. ED-34, no. 3, pp. 160–169, February 1987.
- [15] Y. P. Tsivids, Operation and Modeling of the MOS Transistor. New York: McGraw-Hill, 1987.
- [16] A. Vladimirescu, *The SPICE Book*. New York: Wiley & Sons, 1994.

- [17] D. E. Ward, *Charge-Based Modeling of Capacitance in MOS Transistors*. Integrated Circuit Laboratory Report G201-11. Stanford, CA: Stanford University, 1981.
- [18] D. E. Ward and R. W. Dutton, "A Charge-Oriented Model for MOS Transistor Capacitances," *IEEE J. Solid State Circuits*, SC-13, 1978.
- [19] W. Liu et al., *BSIM3v3.2.2 MOSFET Model Users Manual*, Berkeley, CA: University of California, 1999.
- [20] W. Liu, X. Jin, et. al., *BSIM3v3.2.2 MOSFET Model User's Manual*. Berkeley, CA: University of California, 1999.
- [21] Matthias Bucher, Christophe Lallement, et. al., *The EPFL-EKV MOSFET Model Equations for Simulation Technical Report*. Lausanne, Switzerland: Electronics Laboratories, Swiss Federal Institute of Technology (EPFL), 1998.
- [22] P. Su, H. Wan, Z. H. Liu, S. Fung, et. al., *BSIMSOI3.1 MOSFET Model Users' Manual.* Berkeley, CA: University of California, 2003.
- [23] X. Xi, M. Dunga, et. al., *BSIM4.4.0 MOSFET Model User's Manual*. Berkeley, CA: University of California, 2004.

SYMBOLS

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